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MC9S08SE8
MC9S08SE4

Reference Manual

HCS08
Microcontrollers

Related Documentation:

- **MC9S08SE8 (Data Sheet)**
  Contains pin assignments and diagrams, all electrical specifications, and mechanical drawing outlines.

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MC9S08SE8RM
Rev. 3
4/2009

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MC9S08SE8 Features

8-Bit HCS08 Central Processor Unit (CPU)

- 20 MHz HCS08 CPU (central processor unit)
- 10 MHz internal bus frequency
- HC08 instruction set with added BGND
- Support for up to 32 interrupt/reset sources

On-Chip Memory

- Up to 8 KB of on-chip in-circuit programmable flash memory with block protection and security options
- Up to 512 bytes of on-chip RAM

Power-Saving Modes

Clock Source Options

- Oscillator (XOSC) — Loop-control Pierce oscillator; crystal or ceramic resonator range of 31.25 kHz to 38.4 kHz or 1 MHz to 16 MHz
- Internal Clock Source (ICS) — Internal clock source module containing a frequency-locked-loop (FLL) controlled by internal or external reference; precision trimming of internal reference allows 0.2% resolution and 2% deviation over temperature and voltage; supports bus frequencies from 1 MHz to 10 MHz.

System Protection

- Optional computer operating properly (COP) reset with option to run from independent 1 kHz internal clock source or the bus clock

Development Support

- Single-wire background debug interface

Peripherals

- **SCI** — Full duplex non-return to zero (NRZ); LIN master extended break generation; LIN slave extended break detection; wakeup on active edge

- **ADC** — 10-channel, 10-bit resolution; 2.5 μs conversion time; automatic compare function; 1.7 mV/°C temperature sensor; internal bandgap reference channel; runs in stop3
- **TPMx** — One 2-channel (TPM1) and one 1-channel (TPM2) 16-bit timer/pulse-width modulator (TPM) modules; selectable input capture, output compare, and edge-aligned PWM capability on each channel; timer module may be configured for buffered, centered PWM (CPWM) on all channels
- **KBI** — 8-pin keyboard interrupt module
- **RTC** — Real-time counter with binary- or decimal-based prescaler

Input/Output

- Software selectable pullups on ports when used as inputs
- Software selectable slew rate control on ports when used as outputs
- Software selectable drive strength on ports when used as outputs
- Master reset pin and power-on reset (POR)
- Internal pullup on $\overline{\text{RESET}}$, IRQ, and BKGD/MS pins to reduce customer system cost

Package Options

- 28-pin PDIP
- 28-pin SOIC
- 16-pin TSSOP

MC9S08SE8 MCU Series Reference Manual

Covers: MC9S08SE8
            MC9S08SE4

MC9S08SE8
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Revision History

To provide the most up-to-date information, the revision of our documents on the World Wide Web will be the most current. Your printed copy may be an earlier revision. To verify you have the latest information available, refer to:

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The following revision history table summarizes changes contained in this document.

Revision Number	Revision Date	Description of Changes
1	9/22/2008	Initial public released.
2	12/12/2008	Changed the MCG at 0xFFAF in Table 4-4 to ICS. Modified some typos.
3	4/7/2009	Updated Figure 4-2 and Figure 4-3. In Chapter 10, "Internal Clock Source (S08ICSV3)," added a note in Section 10.1.4.7, "Stop (STOP);" updated Figure 10-2 to reflect ICSERCLK is gated off when STOP is high or when ERCLKEN is low.

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Chapter 1
Device Overview

The MC9S08SE8 series MCUs are members of the low-cost, high-performance HCS08 family of 8-bit microcontroller units (MCUs). All MCUs in the family use the enhanced HCS08 core and are available with a variety of modules, memory sizes, memory types, and package types.

1.1   Devices in the MC9S08SE8 Series

Table 1-1 summarizes the feature set available in the MC9S08SE8 series of MCUs.

Table 1-1. MC9S08SE8 Series Features by MCU and Package

Feature	MC9S08SE8		MC9S08SE4	
Package	28-pin	16-pin	28-pin	16-pin
Flash size (bytes)	8,192		4,096	
RAM size (bytes)	512		256	
IRQ	yes		yes	
SCI	yes		yes	
KBI	8	6	8	6
ADC channels	10	8	10	8
TPM channels	3		3	
I/O pins	24	14	24	14

1.2   MCU Block Diagram

The block diagram in Figure 1-1 shows the structure of the MC9S08SE8 series MCU.

● pins not available on 16-pin packages
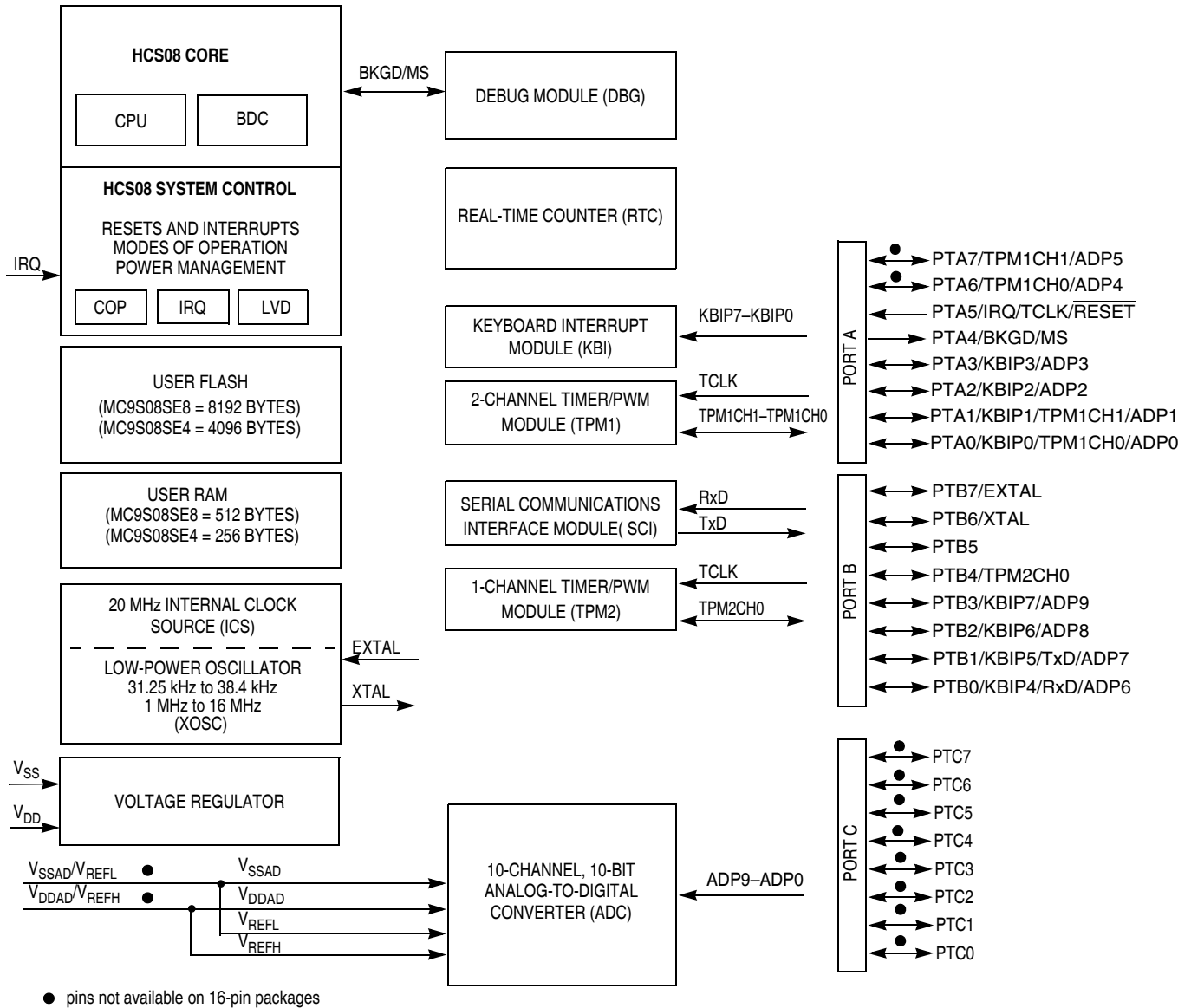
Notes:
   When PTA4 is configured as BKGD, pin is bi-directional.
   For the 16-pin packages: V_{SSAD}/V_{REFL} and V_{DDAD}/V_{REFH} are double bonded to V_{SS} and V_{DD} respectively.

Figure 1-1. MC9S08SE8 Series Block Diagram

Table 1-2 provides the functional version of the on-chip modules.

Table 1-2. Versions of On-Chip Modules

Module		Version
Central Processing Unit	(CPU)	3
Keyboard Interrupt	(KBI)	2
Internal Clock Source	(ICS)	3
Real-Time Counter	(RTC)	1
Serial Communications Interface	(SCI)	4
Analog-to-Digital Converter	(ADC)	1
Timer Pulse-Width Modulator	(TPM)	3
Debug Module	(DBG)	2

1.3   System Clock Distribution

Figure 1-2 is a simplified clock connection diagram. Some modules in the MCU have selectable clock inputs. The clock inputs to the modules indicate the clock(s) that are used to drive the module function.
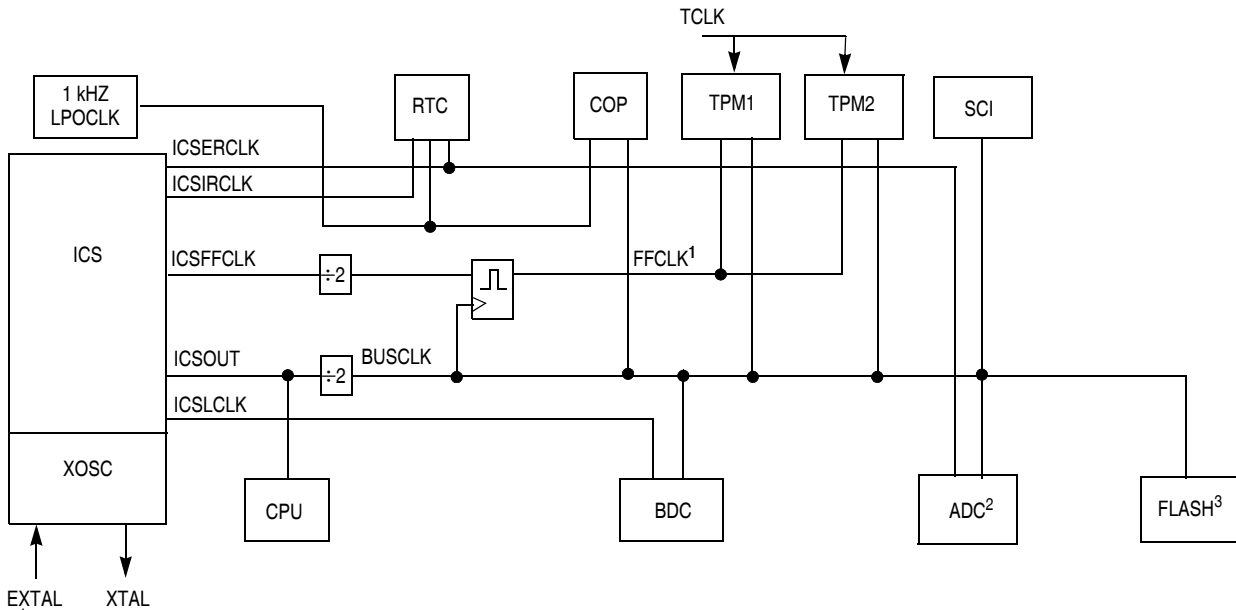
1   The fixed frequency clock (FFCLK) is internally synchronized to the bus clock and must not exceed one half of the bus clock frequency.

2   ADC has min and max frequency requirements. See the ADC chapter and data sheet for details.

3   Flash has frequency requirements for program and erase operation. See data sheet for details.

Figure 1-2. System Clock Distribution Diagram

The following defines the clocks used in this MCU:

- BUSCLK — The frequency of the bus is always half of ICSOUT.
- ICSOUT — Primary output of the ICS and is twice the bus frequency.
- ICSLCLK — Development tools can select this clock source to speed up BDC communications in systems where the bus clock is configured to run at a very slow frequency.
- ICSERCLK — External reference clock that can be selected as the RTC clock source and as the alternate clock for the ADC module.
- ICSIRCLK — Internal reference clock that can be selected as the RTC clock source.
- ICSFFCLK — Fixed frequency clock that can be selected as clock source for the TPM1 and TPM2.
- LPOCLK — Independent 1 kHz clock source that can be selected as the clock source for the COP and RTC modules.
- TCLK — External input clock source for TPM1, TPM2 and is referenced as TPMCLK in TPM chapters.

Chapter 2
Pins and Connections

This chapter describes signals that connect to package pins. It includes pinout diagrams, recommended system connections, and detailed descriptions of the signals.

2.1   Device Pin Assignment

Figure 2-1 - Figure 2-2 show the pin assignments for the MC9S08SE8 series devices.
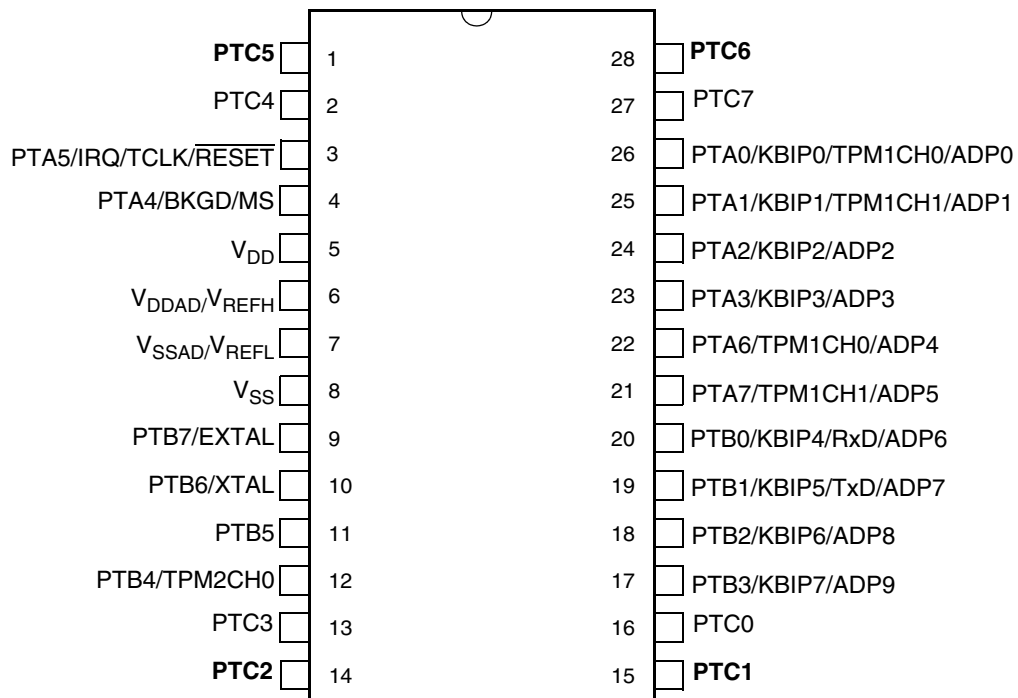
Pins in **bold** are lost in the next lower pin count package.

Figure 2-1. MC9S08SE8 in 28-Pin SOIC/PDIP Package
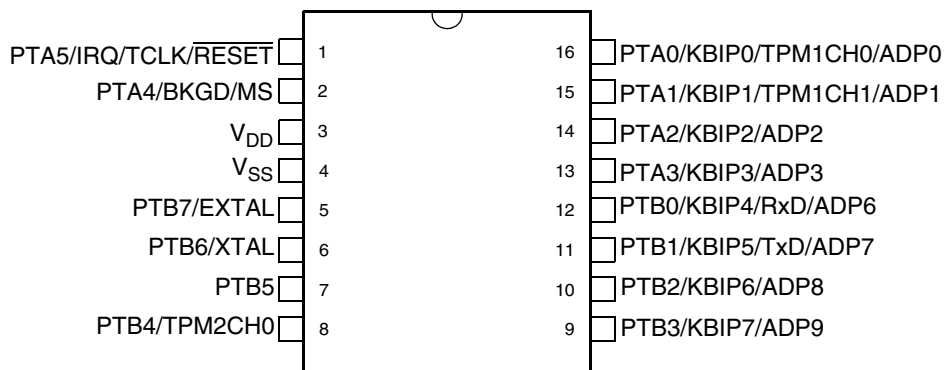
Figure 2-2. MC9S08SE8 in 16-Pin TSSOP Package

2.2   Recommended System Connections

Figure 2-3 shows pin connections that are common to MC9S08SE8 series application systems.

Figure 2-3. Basic System Connections
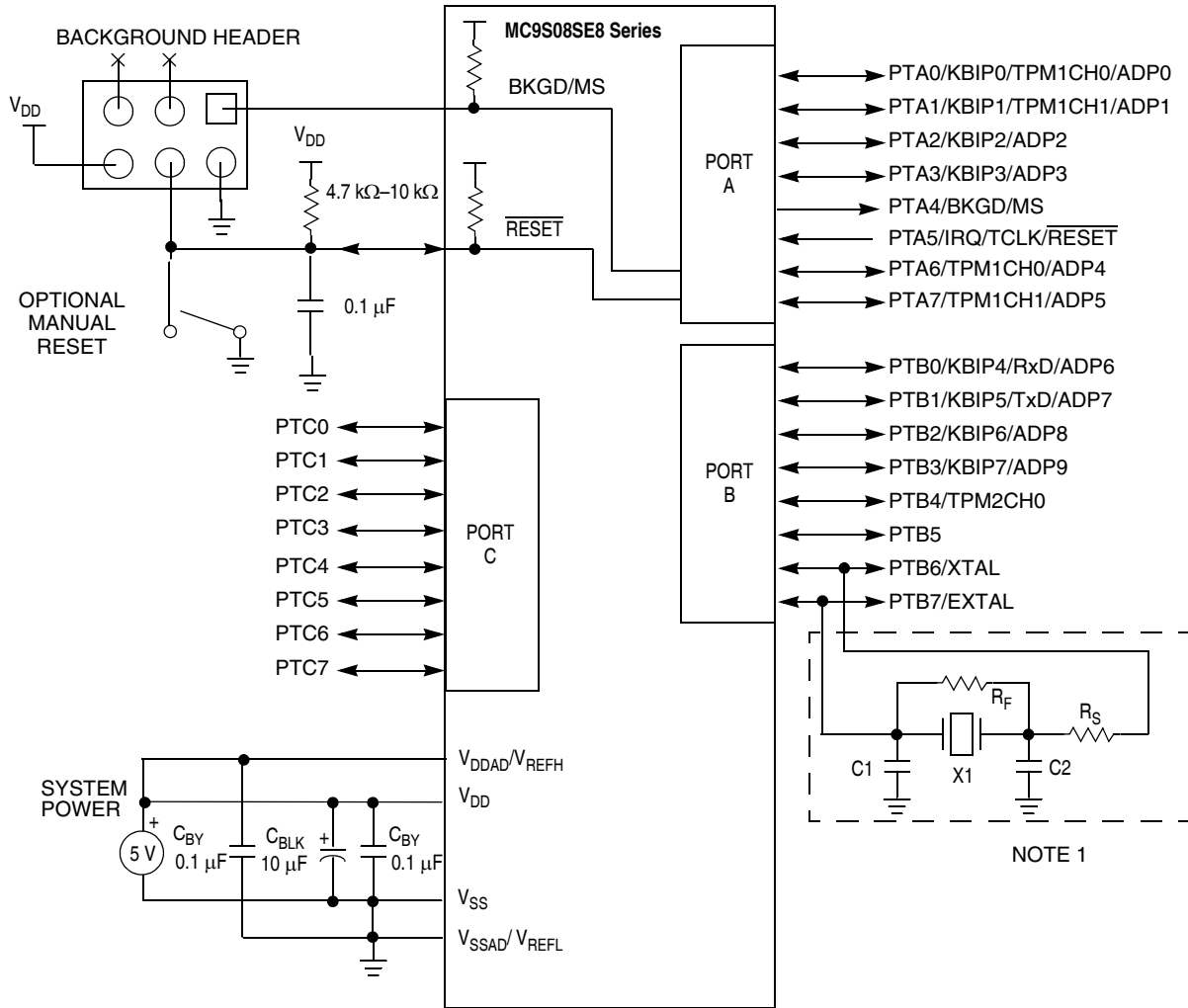
NOTES:
1. External crystal circuit not required if using the internal clock option.
2. $\overline{RESET}$ pin can only be used to reset into user mode, you can not enter BDM using $\overline{RESET}$ pin. BDM can be entered by holding MS low during POR or writing a 1 to BDFR in SBDFR with MS low after issuing BDM command.
3. RC filter on $\overline{RESET}$ pin recommended for noisy environments.
4. For the 16-pin package: V_{DDAD}/V_{REFH} and V_{SSAD}/V_{REFL} are double bonded to V_{DD} and V_{SS} respectively.
5. When PTA4 is configured as BKGD, pin becomes bi-directional.

2.2.1   Power

V_{DD} and V_{SS} are the primary power supply pins for the MCU. This voltage source supplies power to all I/O buffer circuitry and to an internal voltage regulator. The internal voltage regulator provides regulated lower-voltage source to the CPU and other internal circuitry of the MCU.

Typically, application systems have two separate capacitors across the power pins. In this case, there must be a bulk electrolytic capacitor, such as a 10 µF tantalum capacitor, to provide bulk charge storage for the

overall system and a 0.1 µF ceramic bypass capacitor located as near to the MCU power pins as practical to suppress high-frequency noise. Each pin must have a bypass capacitor for best noise suppression.

V_{DDAD} and V_{SSAD} are the analog power supply pins for MCU. This voltage source supplies power to the ADC module. A 0.1 µF ceramic bypass capacitor must be located as near to the MCU power pins as practical to suppress high-frequency noice. The V_{REFH} and V_{REFL} pins are the voltage reference high and voltage reference low inputs, respectively for the ADC module. For this MCU, V_{DDAD} shares the V_{REFH} pin and these pins are available only in the 28-pin packages. In the 16-pin package they are double bonded to the V_{DD} pin. For this MCU, V_{SSAD} shares the V_{REFL} pin and these pins are available only in the 28-pin packages. In the 16-pin package they are double bonded to the V_{SS} pin.

2.2.2   Oscillator (XOSC)

Immediately after reset, the MCU uses an internally generated clock provided by the clock source generator (ICS) module. For more information on the ICS, see Chapter 10, "Internal Clock Source (S08ICSV3)."

The oscillator (XOSC) in this MCU is a Pierce oscillator that can accommodate a crystal or ceramic resonator. Rather than a crystal or ceramic resonator, an external oscillator can be connected to the EXTAL input pin.

As shown in Figure 2-3, R_S (when used) and R_F must be low-inductance resistors such as carbon composition resistors. Wire-wound resistors and some metal film resistors have too much inductance. C1 and C2 must be high quality ceramic capacitors that are specifically designed for high-frequency applications.

R_F is used to provide a bias path to keep the EXTAL input in its linear range during crystal startup; its value is generally not critical. Typical systems use the one from 1 MΩ to 10 MΩ. Higher values are sensitive to humidity and lower values reduce gain and (in extreme cases) may prevent startup.

C1 and C2 are typically in the 5 pF to 25 pF range and are chosen to match the requirements of a specific crystal or resonator. Take into account printed circuit board (PCB) capacitance and MCU pin capacitance when selecting C1 and C2. The crystal manufacturer typically specifies a load capacitance that is the series combination of C1 and C2 (which are usually the same size). As a first-order approximation, use 10 pF as an estimate of combined pin and PCB capacitance for each oscillator pin (EXTAL and XTAL).

2.2.3 $\overline{\text{RESET}}$ Pin

After a power-on reset (POR), the PTA5/IRQ/TCLK/$\overline{\text{RESET}}$ pin defaults to a general-purpose input port pin, PTA5. Setting RSTPE in SOPT1 configures the pin to be the $\overline{\text{RESET}}$ pin with an open-drain drive containing an internal pullup device. After configured as $\overline{\text{RESET}}$, the pin will remain $\overline{\text{RESET}}$ until the next POR. The $\overline{\text{RESET}}$ pin if enabled can be used to reset the MCU from an external source when the pin is driven low.

Whenever any non-POR reset is initiated (whether from an external signal or from an internal system), the $\overline{\text{RESET}}$ pin, if enabled, is driven low for about 66 bus cycles. The reset circuitry decodes the cause of reset and records it by setting a corresponding bit in the system reset status register (SRS).

NOTE

This pin does not contain a clamp diode to V_{DD} and must not be driven above V_{DD}.

The voltage measured on the internally pulled up $\overline{RESET}$ pin will not be pulled to V_{DD}. The internal gates connected to this pin are pulled to V_{DD}. If the $\overline{RESET}$ pin is required to drive to a V_{DD} level, an external pullup must be used.

NOTE

In EMC-sensitive applications, an external RC filter is recommended on the $\overline{RESET}$. See Figure 2-3 for an example.

2.2.4 Background / Mode Select (BKGD/MS)

During a power-on-reset (POR) or background debug force reset (see Section 5.7.3, "System Background Debug Force Reset Register (SBDFR)," for more information), the PTA4/BKGD/MS pin functions as a mode selecting pin. Immediately after any reset, the pin functions as the background pin and can be used for background debug communication. When enabled as the BKGD/MS pin (BKGDPE = 1), an internal pullup device is automatically enabled.

The background debug communication function is enabled when BKGDPE in SOPT1 is set. BKGDPE is set following any reset of the MCU and must be cleared to use the PTA4/BKGD/MS pin's alternative pin function.

If nothing is connected to this pin, the MCU will enter normal operating mode at the rising edge of the internal reset after a POR or BDC force reset. If a debug system is connected to the 6-pin standard background debug header, it can hold BKGD/MS low during a POR or immediately after issuing a background debug force reset, which will force the MCU to active background mode.

The BKGD pin is primarily for background debug controller (BDC) communications by using a custom protocol that uses 16 clock cycles of the target MCU's BDC clock per bit time. The target MCU's BDC clock could be as fast as the maximum bus clock rate, so there must never be any significant capacitance connected to the BKGD/MS pin that could interfere with background serial communications.

Although the BKGD pin is a pseudo open-drain pin, the background debug communication protocol provides brief, actively driven, high speedup pulses to ensure fast rise time. Small capacitances from cables and the absolute value of the internal pullup device play almost no role in determining rise and fall times on the BKGD pin.

2.2.5 General-Purpose I/O and Peripheral Ports

The MC9S08SE8 series of MCUs support up to 22 general purpose I/O pins and one input-only pin, one output-only pin, that are shared with on-chip peripheral functions (timers, serial I/O, ADC, etc).

When a port pin is configured as a general purpose output or a peripheral uses the port pin as an output, software can select one of the two drive strengths and enable or disable slew rate control. When a port pin is configured as a general purpose input or a peripheral uses the port pin as an input, software can enable

a pullup device. Immediately after reset, all of these pins are configured as high-impedance general purpose inputs with internal pullup devices disabled.

When an on-chip peripheral system is controlling a pin, data direction control bits still determine what is read from port data registers even though the peripheral module controls the pin direction by controlling the enable for the pin's output buffer. For information about controlling these pins as general purpose I/O pins, see Chapter 6, "Parallel Input/Output Control."

The MC9S08SE8 series devices contain a ganged output drive feature that allows a safe and reliable method of allowing pins to be tied together externally to produce a higher output current drive. See Section 6.3, "Ganged Output," for more information for configuring the port pins for ganged output drive.

NOTE

To avoid extra current drain from floating input pins, the reset initialization routine in the application program must enable on-chip pullup devices or change the direction of the unused pins to output.

When using the 16-pin devices, the user must enable on-chip pullup devices or change the direction of non-bonded out port A and port C pins to output so the pins do not float.

Table 2-1. Pin Availability by Package Pin-Count

28 (SOIC/PDIP)	16 (TSSOP)	Port Pin	Alt 1	Alt 2	Alt 3
				<-- Lowest **Priority** --> Highest	
1	—	PTC5			
2	—	PTC4			
3	1	PTA5	IRQ	TCLK	$\overline{RESET}$
4	2	PTA4		BKGD	MS
5	3				V_{DD}
6	—			V_{DDAD}	V_{REFH}
7	—			V_{SSAD}	V_{REFL}
8	4				V_{SS}
9	5	PTB7	EXTAL		
10	6	PTB6	XTAL		
11	7	PTB5			
12	8	PTB4		TPM2CH0	
13	—	PTC3			
14	—	PTC2			
15	—	PTC1			
16	—	PTC0			
17	9	PTB3	KBIP7		ADP9
18	10	PTB2	KBIP6		ADP8
19	11	PTB1	KBIP5	TxD	ADP7
20	12	PTB0	KBIP4	RxD	ADP6
21	—	PTA7		TPM1CH1[1]	ADP5
22	—	PTA6		TPM1CH0[1]	ADP4
23	13	PTA3	KBIP3		ADP3
24	14	PTA2	KBIP2		ADP2
25	15	PTA1	KBIP1	TPM1CH1[1]	ADP1
26	16	PTA0	KBIP0	TPM1CH0[1]	ADP0
27	—	PTC7			
28	—	PTC6			

[1] TPM1 pins can be remapped to PTA7, PTA6 and PTA1,PTA0

Chapter 3
Modes of Operation

3.1   Introduction

The operating modes of the MC9S08SE8 series are described in this chapter. Entry into each mode, exit from each mode, and functionality while in each mode are described.

3.2   Features

- Active background mode for code development
- Wait mode
  - CPU shuts down to conserve power
  - System clocks are running
  - Full regulation is maintained
- Stop modes: System clocks are stopped
  - Stop3: All internal circuits are powered for fast recovery
  - Stop2: Partial power down of internal circuits, RAM content is retained

3.3   Run Mode

This is the normal operating mode for the MC9S08SE8 series. This mode is selected upon the MCU exiting reset if the BKGD/MS pin is high. In this mode, the CPU executes code from internal memory with execution beginning at the address fetched from memory at 0xFFFE–0xFFFF after reset.

3.4   Active Background Mode

The active background mode functions are managed through the background debug controller (BDC) in the HCS08 core. The BDC, together with the on-chip debug module (DBG), provides the means for analyzing MCU operation during software development.

Active background mode is entered in any of the following ways:

- When the BKGD/MS pin is low during POR or immediately after issuing a background debug force reset (see Section 5.7.3, "System Background Debug Force Reset Register (SBDFR)")
- When a BACKGROUND command is received through the BKGD/MS pin
- When a BGND instruction is executed
- When encountering a BDC breakpoint
- When encountering a DBG breakpoint

After entering active background mode, the CPU is held in a suspended state waiting for serial background commands rather than executing instructions from the user application program.

Background commands are of two types:

- Non-intrusive commands, defined as commands that can be issued while the user program is running. Non-intrusive commands can be issued through the BKGD/MS pin while the MCU is in run mode; non-intrusive commands can also be executed when the MCU is in the active background mode. Non-intrusive commands include:
  — Memory access commands
  — Memory-access-with-status commands
  — BDC register access commands
  — The BACKGROUND command
- Active background commands, which can only be executed while the MCU is in active background mode. Active background commands include commands to:
  — Read or write CPU registers
  — Trace one user program instruction at a time
  — Leave active background mode to return to the user application program (GO)

The active background mode is used to program a bootloader or user application program into the flash program memory before the MCU is operated in run mode for the first time. When the MC9S08SE8 series is shipped from the Freescale Semiconductor factory, the flash program memory is erased by default unless specifically noted so there is no program that could be executed in run mode until the flash memory is initially programmed. The active background mode can also be used to erase and reprogram the flash memory after it has been previously programmed.

For additional information about the active background mode, refer to Chapter 14, "Development Support."

3.5   Wait Mode

Wait mode is entered by executing a WAIT instruction. Upon execution of the WAIT instruction, the CPU enters a low-power state in which it is not clocked. The I bit in CCR is cleared when the CPU enters the wait mode, enabling interrupts. When an interrupt request occurs, the CPU exits the wait mode and resumes processing, beginning with the stacking operations leading to the interrupt service routine.

While the MCU is in wait mode, there are some restrictions on which background debug commands can be used. Only the BACKGROUND command and memory-access-with-status commands are available when the MCU is in wait mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in stop or wait mode. The BACKGROUND command can be used to wake the MCU from wait mode and enter active background mode.

3.6   Stop Modes

One of two stop modes is entered upon execution of a STOP instruction when STOPE in SOPT1 is set. In any stop mode, the bus and CPU clocks are halted. The ICS module can be configured to leave the reference clocks running. See Chapter 10, "Internal Clock Source (S08ICSV3)," for more information.

Table 3-1 shows all of the control bits that affect stop mode selection and the mode selected under various conditions. The selected mode is entered following the execution of a STOP instruction.

Table 3-1. Stop Mode Selection

STOPE	ENBDM [1]	LVDE	LVDSE	PPDC	Stop Mode
0	x	x		x	Stop modes disabled; illegal opcode reset if STOP instruction executed
1	1	x		x	Stop3 with BDM enabled [2]
1	0	Both bits must be 1		0	Stop3 with voltage regulator active
1	0	Either bit a 0		0	Stop3
1	0	Either bit a 0		1	Stop2

[1] ENBDM is located in the BDCSCR, which is only accessible through BDC commands, see Section 14.4.1.1, "BDC Status and Control Register (BDCSCR)."

[2] When in stop3 mode with BDM enabled, The S_{IDD} will be near R_{IDD} levels because internal clocks are enabled.

3.6.1   Stop3 Mode

Stop3 mode is entered by executing a STOP instruction under the conditions as shown in Table 3-1. The states of all of the internal registers and logic, RAM contents, and I/O pin states are maintained.

Stop3 can be exited by asserting $\overline{\text{RESET}}$ if enabled, or by an interrupt from one of the following sources: the real-time counter (RTC), LVD system, ADC, SCI or any pin interrupts.

If stop3 is exited by means of the $\overline{\text{RESET}}$ pin, then the MCU is reset and operation will resume after taking the reset vector. Exit by means of one of the internal interrupt sources results in the MCU taking the appropriate interrupt vector.

3.6.1.1   LVD Enabled in Stop Mode

The LVD system is capable of generating an interrupt or a reset when the supply voltage drops below the LVD voltage. For configuring the LVD system for interrupt or reset, refer to Section 5.6, "Low-Voltage Detect (LVD) System." If the LVD is enabled in stop (LVDE and LVDSE bits in SPMSC1 both set) at the time the CPU executes a STOP instruction, then the voltage regulator remains active during stop mode.

For the ADC to operate in stop mode, the LVD must be enabled when entering stop3.

3.6.1.2   Active BDM Enabled in Stop Mode

Entry into the active background mode from run mode is enabled if ENBDM in BDCSCR is set. This register is described in Chapter 14, "Development Support." If ENBDM is set when the CPU executes a

STOP instruction, the system clocks to the background debug logic remain active when the MCU enters stop mode. Because of this, background debug communication remains possible. In addition, the voltage regulator does not enter its low-power standby state but maintains full internal regulation.

Most background commands are not available in stop mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in stop or wait mode. The BACKGROUND command can be used to wake the MCU from stop and enter active background mode if the ENBDM bit is set. After entering background debug mode, all background commands are available.

3.6.2   Stop2 Mode

Stop2 mode is entered by executing a STOP instruction under the conditions as shown in Table 3-1. Most of the internal circuitry of the MCU is powered off in stop2 with the exception of the RAM. Upon entering stop2, all I/O pin control signals are latched so that the pins retain their states during stop2.

Exit from stop2 is performed by asserting the wakeup pin (PTA5/IRQ/TCLK/$\overline{\text{RESET}}$) on the MCU.

In addition, the real-time counter (RTC) can wake the MCU from stop2, if enabled.

Upon wakeup from stop2 mode, the MCU starts up as from a power-on reset (POR):

- All module control and status registers are reset
- The LVD reset function is enabled and the MCU remains in the reset state if V_{DD} is below the LVD trip point (low trip point selected due to POR)
- The CPU takes the reset vector

In addition to the above, upon waking up from stop2, the PPDF bit in SPMSC2 is set. This flag is used to direct user code to go to a stop2 recovery routine. PPDF remains set and the I/O pin states remain latched until a 1 is written to PPDACK in SPMSC2.

To maintain I/O states for pins that were configured as general-purpose I/O before entering stop2, the user must restore the contents of the I/O port registers, which have been saved in RAM, to the port registers before writing to the PPDACK bit. If the port registers are not restored from RAM before writing to PPDACK, then the pins will switch to their reset states when PPDACK is written.

For pins that were configured as peripheral I/O, the user must reconfigure the peripheral module that interfaces to the pin before writing to the PPDACK bit. If the peripheral module is not enabled before writing to PPDACK, the pins will be controlled by their associated port control registers when the I/O latches are opened.

3.6.3   On-Chip Peripheral Modules in Stop Modes

When the MCU enters any stop mode, system clocks to the internal peripheral modules are stopped. Even in the exception case (ENBDM = 1), where clocks to the background debug logic continue to operate, clocks to the peripheral systems are halted to reduce power consumption. Refer to Section 3.6.2, "Stop2 Mode," and Section 3.6.1, "Stop3 Mode," for specific information on system behavior in stop modes.

Table 3-2. Stop Mode Behavior

Peripheral	Mode	
	Stop2	**Stop3**
CPU	Off	Standby
RAM	Standby	Standby
Flash	Off	Standby
Parallel Port Registers	Off	Standby
ADC	Off	Optionally On[1]
BDM	Off[2]	Optionally On
ICS	Off	Optionally On[3]
LVD/LVW	Off[4]	Optionally On
RTC	Optionally On	Optionally On
SCI	Off	Standby
TPM	Off	Standby
Voltage Regulator	Standby	Optionally On[5]
XOSC	Off	Optionally On[6]
I/O Pins	States Held	States Held

[1] Requires the asynchronous ADC clock and LVD to be enabled, else in standby.

[2] If ENBDM is set when entering stop2, the MCU will actually enter stop3.

[3] REFSTEN set in ICSC1, else in standby.

[4] If LVDSE is set when entering stop2, the MCU will actually enter stop3.

[5] Voltage regulator will be on if BDM is enabled or if LVD is enabled when entering stop3.

[6] EREFSTEN set in ICSC2, else in standby. For high frequency range (RANGE in ICSC2 set) requires the LVD to also be enabled in stop3.

Chapter 4
Memory

4.1 MC9S08SE8 Series Memory Map

As shown in Figure 4-1, on-chip memory in the MC9S08SE8 series of MCUs consists of RAM, flash program memory for nonvolatile data storage, and I/O and control/status registers. The registers are divided into three groups:

- Direct-page registers (0x0000 through 0x007F)
- High-page registers (0x1800 through 0x185F)
- Nonvolatile registers (0xFFB0 through 0xFFBF)
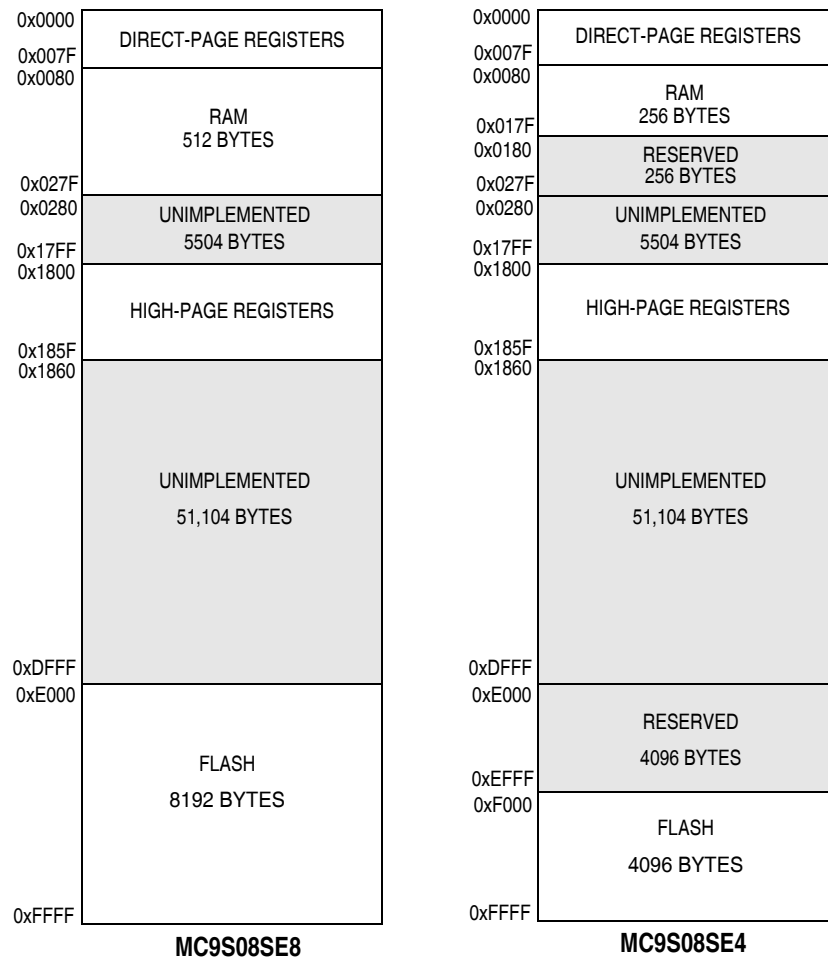
Figure 4-1. MC9S08SE8/4 Memory Map

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4.2 Reset and Interrupt Vector Assignments

Table 4-1 shows address assignments for reset and interrupt vectors. The vector names shown in this table are the labels used in the Freescale Semiconductor provided equate file for the MC9S08SE8 series.

Table 4-1. Reset and Interrupt Vectors

Address (High/Low)	Vector	Vector Name
0xFFC0:0xFFC1	Unused vector space[1]	—
0xFFC2:0xFFC3	Unused vector space	—
0xFFC4:0xFFC5	Unused vector space	—
0xFFC6:0xFFC7	Unused vector space	—
0xFFC8:0xFFC9	Unused vector space	—
0xFFCA:0xFFCB	Unused vector space	—
0xFFCC:0xFFCD	RTC	Vrtc
0xFFCE:0xFFCF	Unused vector space	—
0xFFD0:0xFFD1	ADC Conversion	Vadc
0xFFD2:0xFFD3	Unused vector space	—
0xFFD4:0xFFD5	Unused vector space	—
0xFFD6:0xFFD7	KBI	Vkeyboard
0xFFD8:0xFFD9	Unused vector space	—
0xFFDA:0xFFDB	SCI Transmit	Vscitx
0xFFDC:0xFFDD	SCI Receive	Vscirx
0xFFDE:0xFFDF	SCI Error	Vsc1err
0xFFE0:0xFFE1	Unused vector space	—
0xFFE2:0xFFE3	TPM2 Overflow	Vtpm2ovf
0xFFE4:0xFFE5	Unused vector space	—
0xFFE6:0xFFE7	TPM2 Channel 0	Vtpm2ch0
0xFFE8:0xFFE9	TPM1 Overflow	Vtpm1ovf
0xFFEA:0xFFEB	Unused vector space	—
0xFFEC:0xFFED	Unused vector space	—
0xFFEE:0xFFEF	Unused vector space	—
0xFFF0:0xFFF1	Unused vector space	—
0xFFF2:0xFFF3	TPM1 Channel 1	Vtpm1ch1
0xFFF4:0xFFF5	TPM1 Channel 0	Vtpm1ch0
0xFFF6:0xFFF7	Unused vector space	—
0xFFF8:0xFFF9	Low Voltage Detect	Vlvd
0xFFFA:0xFFFB	IRQ	Virq
0xFFFC:0xFFFD	SWI	Vswi
0xFFFE:0xFFFF	Reset	Vreset

[1] Unused vector space is available for use as general flash memory. However, other devices in the S08 family of MCUs may use these locations as interrupt vectors. Therefore, care must be taken when using these locations if the code will be ported to other MCUs.

4.3   Register Addresses and Bit Assignments

The registers in the MC9S08SE8 series are divided into these three groups:

- Direct-page registers are located in the first 128 locations in the memory map; these are accessible with efficient direct addressing mode instructions.

- High-page registers are used much less often, so they are located above 0x1800 in the memory map. This leaves more room in the direct page for more frequently used registers and RAM.

- The nonvolatile register area consists of a block of 16 locations in flash memory at 0xFFB0–0xFFBF. Nonvolatile register locations include:

  — NVPROT and NVOPT are loaded into working registers at reset

  — An 8-byte backdoor comparison key that optionally allows a user to gain controlled access to secure memory

  Because the nonvolatile register locations are flash memory, they must be erased and programmed like other flash memory locations.

Direct-page registers can be accessed with efficient direct addressing mode instructions. Bit manipulation instructions can be used to access any bit in any direct-page register. Table 4-2 is a summary of all user-accessible direct-page registers and control bits.

- The direct page registers in Table 4-2 can use the more efficient direct addressing mode, which requires only the lower byte of the address. Because of this, the lower byte of the address in column one is shown in bold text.

- In Table 4-3 and Table 4-4, the whole address in column one is shown in bold.

- In Table 4-2, Table 4-3, and Table 4-4, the register names in column two are shown in bold to set them apart from the bit names to the right.

- Cells that are not associated with named bits are shaded.

- A shaded cell with a 0 indicates this unused bit always reads as a 0.

- Shaded cells with dashes indicate unused or reserved bit locations that could read as 1s or 0s.

Table 4-2. Direct-Page Register Summary (Sheet 1 of 2)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x0000	**PTAD**	PTAD7	PTAD6	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
0x0001	**PTADD**	PTADD7	PTADD6	—	—	PTADD3	PTADD2	PTADD1	PTADD0
0x0002	**PTBD**	PTBD7	PTBD6	PTBD5	PTBD4	PTBD3	PTBD2	PTBD1	PTBD0
0x0003	**PTBDD**	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0
0x0004	**PTCD**	PTCD7	PTCD6	PTCD5	PTCD4	PTCD3	PTCD2	PTCD1	PTCD0
0x0005	**PTCDD**	PTCDD7	PTCDD6	PTCDD5	PTCDD4	PTCDD3	PTCDD2	PTCDD1	PTCDD0
0x0006– 0x000F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0010	**ADCSC1**	COCO	AIEN	ADCO	ADCH				
0x0011	**ADCSC2**	ADACT	ADTRG	ACFE	ACFGT	0	0	0	0
0x0012	**ADCRH**	0	0	0	0	0	0	ADR9	ADR8
0x0013	**ADCRL**	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0
0x0014	**ADCCVH**	0	0	0	0	0	0	ADCV9	ADCV8
0x0015	**ADCCVL**	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0
0x0016	**ADCCFG**	ADLPC	ADIV		ADLSMP	MODE		ADICLK	
0x0017	**APCTL1**	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
0x0018	**APCTL2**	0	0	0	0	0	0	ADPC9	ADPC8
0x0019	Reserved	—	—	—	—	—	—	—	—
0x001A	**IRQSC**	0	IRQPDD	IRQEDG	IRQPE	IRQF	IRQACK	IRQIE	IRQMOD
0x001B	Reserved	—	—	—	—	—	—	—	—
0x001C	**KBISC**	0	0	0	0	KBF	KBACK	KBIE	KBMOD
0x001D	**KBIPE**	KBIPE7	KBIPE6	KBIPE5	KBIPE4	KBIPE3	KBIPE2	KBIPE1	KBIPE0
0x001E	**KBIES**	KBEDG7	KBEDG6	KBEDG5	KBEDG4	KBEDG3	KBEDG2	KBEDG1	KBEDG0
0x001F	Reserved	—	—	—	—	—	—	—	—
0x0020	**TPM1SC**	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0021	**TPM1CNTH**	Bit 15	14	13	12	11	10	9	Bit 8
0x0022	**TPM1CNTL**	Bit 7	6	5	4	3	2	1	Bit 0
0x0023	**TPM1MODH**	Bit 15	14	13	12	11	10	9	Bit 8
0x0024	**TPM1MODL**	Bit 7	6	5	4	3	2	1	Bit 0
0x0025	**TPM1C0SC**	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0026	**TPM1C0VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x0027	**TPM1C0VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x0028	**TPM1C1SC**	CH1F	CH1IE	MS1B	MS1A	ELS1B	ELS1A	0	0
0x0029	**TPM1C1VH**	Bit 15	14	13	12	11	10	9	Bit 8
0x002A	**TPM1C1VL**	Bit 7	6	5	4	3	2	1	Bit 0
0x002B– 0x0037	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0038	**SCIBDH**	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
0x0039	**SCIBDL**	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0

Table 4-2. Direct-Page Register Summary (Sheet 2 of 2)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x003A	SCIC1	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
0x003B	SCIC2	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
0x003C	SCIS1	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
0x003D	SCIS2	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
0x003E	SCIC3	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
0x003F	SCID	Bit 7	6	5	4	3	2	1	Bit 0
0x0040– 0x0047	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0048	ICSC1	CLKS		RDIV			IREFS	IRCLKEN	IREFSTEN
0x0049	ICSC2	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
0x004A	ICSTRM	TRIM							
0x004B	ICSSC	DRS/DRST		DMX32	IREFST	CLKST		OSCINIT	FTRIM
0x004C– 0x005F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x0060	TPM2SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
0x0061	TPM2CNTH	Bit 15	14	13	12	11	10	9	Bit 8
0x0062	TPM2CNTL	Bit 7	6	5	4	3	2	1	Bit 0
0x0063	TPM2MODH	Bit 15	14	13	12	11	10	9	Bit 8
0x0064	TPM2MODL	Bit 7	6	5	4	3	2	1	Bit 0
0x0065	TPM2C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
0x0066	TPM2C0VH	Bit 15	14	13	12	11	10	9	Bit 8
0x0067	TPM2C0VL	Bit 7	6	5	4	3	2	1	Bit 0
0x0068– 0x006B	Reserved	—	—	—	—	—	—	—	—
0x006C	RTCSC	RTIF	RTCLKS		RTIE	RTCPS			
0x006D	RTCCNT	RTCCNT							
0x006E	RTCMOD	RTCMOD							
0x006F– 0x007F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —

High-page registers, shown in Table 4-3, are accessed much less often than other I/O and control registers so they have been located outside the direct addressable memory space, starting at 0x1800.

Table 4-3. High-Page Register Summary (Sheet 1 of 2)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x1800	SRS	POR	PIN	COP	ILOP	ILAD	0	LVD	0
0x1801	SBDFR	0	0	0	0	0	0	0	BDFR
0x1802	SOPT1	COPT		STOPE	0	0	TPM1PS	BKGDPE	RSTPE
0x1803	SOPT2	COPCLKS	COPW	0	0	0	0	0	0
0x1804– 0x1805	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1806	SDIDH	0	—	—	—	ID11	ID10	ID9	ID8
0x1807	SDIDL	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
0x1808	Reserved	—	—	—	—	—	—	—	—
0x1809	SPMSC1	LVWF	LVWACK	LVWIE	LVDRE	LVDSE	LVDE	0	BGBE
0x180A	SPMSC2	0	0	LVDV	LVWV	PPDF	PPDACK	0	PPDC
0x180B– 0x180F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1810	DBGCAH	Bit 15	14	13	12	11	10	9	Bit 8
0x1811	DBGCAL	Bit 7	6	5	4	3	2	1	Bit 0
0x1812	DBGCBH	Bit 15	14	13	12	11	10	9	Bit 8
0x1813	DBGCBL	Bit 7	6	5	4	3	2	1	Bit 0
0x1814	DBGFH	Bit 15	14	13	12	11	10	9	Bit 8
0x1815	DBGFL	Bit 7	6	5	4	3	2	1	Bit 0
0x1816	DBGC	DBGEN	ARM	TAG	BRKEN	RWA	RWAEN	RWB	RWBEN
0x1817	DBGT	TRGSEL	BEGIN	0	0	TRG3	TRG2	TRG1	TRG0
0x1818	DBGS	AF	BF	ARMF	0	CNT3	CNT2	CNT1	CNT0
0x1819– 0x181F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1820	FCDIV	DIVLD	PRDIV8	DIV					
0x1821	FOPT	KEYEN	FNORED	0	0	0	0	SEC01	SEC00
0x1822	Reserved	—	—	—	—	—	—	—	—
0x1823	FCNFG	0	0	KEYACC	0	0	0	0	0
0x1824	FPROT	FPS							FPDIS
0x1825	FSTAT	FCBEF	FCCF	FPVIOL	FACCERR	0	FBLANK	0	0
0x1826	FCMD	FCMD							
0x1827– 0x183F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0x1840	PTAPE	PTAPE7	PTAPE6	PTAPE5	—	PTAPE3	PTAPE2	PTAPE1	PTAPE0
0x1841	PTASE	PTASE7	PTASE6	—	PTASE4	PTASE3	PTASE2	PTASE1	PTASE0
0x1842	PTADS	PTADS7	PTADS6	—	PTADS4	PTADS3	PTADS2	PTADS1	PTADS0
0x1843	Reserved	—	—	—	—	—	—	—	—
0x1844	PTBPE	PTBPE7	PTBPE6	PTBPE5	PTBPE4	PTBPE3	PTBPE2	PTBPE1	PTBPE0

Table 4-3. High-Page Register Summary (Sheet 2 of 2)

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0x1845	**PTBSE**	PTBSE7	PTBSE6	PTBSE5	PTBSE4	PTBSE3	PTBSE2	PTBSE1	PTBSE0
0x1846	**PTBDS**	PTBDS7	PTBDS6	PTBDS5	PTBDS4	PTBDS3	PTBDS2	PTBDS1	PTBDS0
0x1847	Reserved	—	—	—	—	—	—	—	—
0x1848	**PTCPE**	PTCPE7	PTCPE6	PTCPE5	PTCPE4	PTCPE3	PTCPE2	PTCPE1	PTCPE0
0x1849	**PTCSE**	PTCSE7	PTCSE6	PTCSE5	PTCSE4	PTCSE3	PTCSE2	PTCSE1	PTCSE0
0x184A	**PTCDS**	PTCDS7	PTCDS6	PTCDS5	PTCDS4	PTCDS3	PTCDS2	PTCDS1	PTCDS0
0x184B	**GNGC**	GNGPS7	GNGPS6	GNGPS5	GNGPS4	GNGPS3	GNGPS2	GNGPS1	GNGEN
0x184C–0x185F	Reserved	— —	— —	— —	— —	— —	— —	— —	— —

Nonvolatile flash registers, shown in Table 4-4, are located in the flash memory. These registers include an 8-byte backdoor key, NVBACKKEY, which can be used to gain access to secure memory resources. During reset events, the contents of NVPROT and NVOPT in the nonvolatile register area of the flash memory are transferred into corresponding FPROT and FOPT working registers in the high-page registers to control security and block protection options.

The factory ICS trim value is stored in the flash information row (IFR[1]) and will be loaded into the ICSTRM and ICSSC registers after any reset. The internal reference trim values stored in flash, TRIM and FTRIM, can be programmed by third party programmers and must be copied into the corresponding ICS registers by user code to override the factory trim.

NOTE

When the MCU is in active BDM, the trim value in the IFR will not be loaded, the ICSTRM register will reset to 0x80 and the FTRIM bit in the ICSSC register will be reset to 0.

---

1. IFR — Nonvolatile information memory that can be only accessed during production test. During production test, system initialization, configuration and test information is stored in the IFR. This information cannot be read or modified in normal user or background debug modes.

Table 4-4. Nonvolatile Register Summary

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0xFFAE	Reserved for storage of FTRIM	0	0	0	0	0	0	0	FTRIM
0xFFAF	Reserved for storage of ICSTRIM	TRIM							
0xFFB0–0xFFB7	**NVBACKKEY**	8-Byte Comparison Key							
0xFFB8–0xFFBC	Reserved	—	—	—	—	—	—	—	—
		—	—	—	—	—	—	—	—
0xFFBD	**NVPROT**	FPS							FPDIS
0xFFBE	Reserved	—	—	—	—	—	—	—	—
0xFFBF	**NVOPT**	KEYEN	FNORED	0	0	0	0	SEC0	

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the flash if needed (normally through the background debug interface) and verifying that flash is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC) to the unsecured state (1:0).

4.4   RAM

The MC9S08SE8 series includes static RAM. The locations in RAM below 0x0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data when the MCU is in low-power wait, stop2, or stop3 mode. At power-on, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention (V_{RAM}).

For compatibility with M68HC05 MCUs, the HCS08 resets the stack pointer to 0x00FF. In the MC9S08SE8 series, reinitialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following two instructions sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM in the Freescale Semiconductor provided equate file).

```
        LDHX    #RamLast+1    ;point one past RAM
        TXS                   ;SP<-(H:X-1)
```

When security is enabled, the RAM is considered a secure memory resource and is not accessible through BDM or through code executing from non-secure memory. See Section 4.6, "Security," for a detailed description of the security feature.

4.5   Flash Memory

The flash memory is primarily for program storage. In-circuit programming allows the operating program to be loaded into the flash memory after final assembly of the application product. It is possible to program the entire array through the single-wire background debug interface. Because no special voltages are needed for flash erase and programming operations, in-application programming is also possible through other software-controlled communication paths. For a more detailed discussion of in-circuit and in-application programming, refer to the *HCS08 Family Reference Manual, Volume I,* Freescale Semiconductor document order number HCS08RMv1.

4.5.1 Features

Features of the flash memory include:

- Flash size
    - MC9S08SE8: 8,192 bytes (16 pages of 512 bytes each)
    - MC9S08SE4: 4,096 bytes (8 pages of 512 bytes each)
- Single power supply program and erase
- Command interface for fast program and erase operation
- Up to 100,000 program/erase cycles at typical voltage and temperature
- Flexible block protection
- Security feature for flash and RAM
- Auto power-down for low-frequency read accesses

4.5.2 Program and Erase Times

Before any program or erase command can be accepted, the flash clock divider register (FCDIV) must be written to set the internal clock for the flash module to a frequency (f_{FCLK}) between 150 kHz and 200 kHz (see Section 4.7.1, "Flash Clock Divider Register (FCDIV)"). This register can be written only once, so normally this write is done during reset initialization. FCDIV cannot be written if the access error flag, FACCERR in FSTAT, is set. The user must ensure that FACCERR is not set before writing to the FCDIV register. One period of the resulting clock ($1/f_{FCLK}$) is used by the command processor to time program and erase pulses. An integer number of these timing pulses are used by the command processor to complete a program or erase command.

Table 4-5 shows program and erase times. The bus clock frequency and FCDIV determine the frequency of FCLK (f_{FCLK}). The time for one cycle of FCLK is $t_{FCLK} = 1/f_{FCLK}$. The times are shown as a number of cycles of FCLK and as an absolute time for the case where $t_{FCLK} = 5$ μs. Program and erase times shown include overhead for the command state machine and enabling and disabling of program and erase voltages.

Table 4-5. Program and Erase Times

Parameter	Cycles of FCLK	Time if FCLK = 200 kHz
Byte program	9	45 μs
Byte program (burst)	4	20 μs[1]
Page erase	4000	20 ms
Mass erase	20,000	100 ms

[1] Excluding start/end overhead

4.5.3   Program and Erase Command Execution

The steps for executing any of the commands are listed below. The FCDIV register must be initialized and any error flags cleared before beginning command execution. The command execution steps are:

1. Write a data value to an address in the flash array. The address and data information from this write is latched into the flash interface. This write is a required first step in any command sequence. For erase and blank check commands, the value of the data is not important. For page erase commands, the address may be any address in the 512-byte page of flash to be erased. For mass erase and blank check commands, the address can be any address in the flash memory.Whole pages of 512 bytes are the smallest block of flash that may be erased.

NOTE

Do not program any byte in the flash more than once after a successful erase operation. Reprogramming bits to a byte that is already programmed is not allowed without first erasing the page in which the byte resides or mass erasing the entire flash memory. Programming without first erasing may disturb data stored in the flash.

2. Write the command code for the desired command to FCMD. The five valid commands are blank check (0x05), byte program (0x20), burst program (0x25), page erase (0x40), and mass erase (0x41). The command code is latched into the command buffer.

3. Write a 1 to the FCBEF bit in FSTAT to clear FCBEF and launch the command (including its address and data information).

A partial command sequence can be aborted manually by writing a 0 to FCBEF any time after the write to the memory array and before writing the 1 that clears FCBEF and launches the complete command. Aborting a command in this way sets the FACCERR access error flag, which must be cleared before starting a new command.

A strictly monitored procedure must be obeyed or the command will not be accepted. This minimizes the possibility of any unintended changes to the flash memory contents. The command complete flag (FCCF) indicates when a command is complete. The command sequence must be completed by clearing FCBEF to launch the command. Figure 4-2 is a flowchart for executing all of the commands except for burst programming. The FCDIV register must be initialized before using any flash commands. This must be done only once following a reset.

PROGRAM AND ERASE FLOW

WRITE TO FCDIV[1]

[1] Required only once after reset.

START

FCBEF? 0

1

FACCERR OR FPVIOL? 0

CLEAR ERRORS

WRITE TO FLASH TO BUFFER ADDRESS AND DATA

WRITE COMMAND TO FCMD

WRITE 1 TO FCBEF TO LAUNCH COMMAND AND CLEAR FCBEF [2]

[2] Wait at least four bus cycles before checking FCBEF or FCCF.

[3]During this time, avoid actions that woudl result in an FACCERR error. Such as executing a STOP instruction or writing to the flash.

Reads of the flash during program or erase are ignored and invalid data is returned.

FPVIOL OR FACCERR? YES → ERROR EXIT

NO

FCCF? [3] 0

1

DONE

Figure 4-2. Flash Program and Erase Flowchart

4.5.4 Burst Program Execution

The burst program command is used to program sequential bytes of data in less time than would be required using the standard program command. This is possible because the high voltage to the flash array does not need to be disabled between program operations. Ordinarily, when a program or erase command is issued, an internal charge pump associated with the flash memory must be enabled to supply high voltage to the array. Upon completion of the command, the charge pump is turned off. When a burst program command is issued, the charge pump is enabled and then remains enabled after completion of the burst program operation if these two conditions are met:

- The next burst program command has been queued before the current program operation has completed.

- The next sequential address selects a byte on the same physical row as the current byte being programmed. A row of flash memory consists of 64 bytes. A byte within a row is selected by addresses A5 through A0. A new row begins when addresses A5 through A0 are all zero.

The first byte of a series of sequential bytes being programmed in burst mode will take the same amount of time to program as a byte programmed in standard mode. Subsequent bytes will program in the burst program time provided that the conditions above are met. In the case the next sequential address is the beginning of a new row, the program time for that byte will be the standard time instead of the burst time. This is because the high voltage to the array must be disabled and then enabled again. If a new burst command has not been queued before the current command completes, then the charge pump will be disabled and high voltage removed from the array.
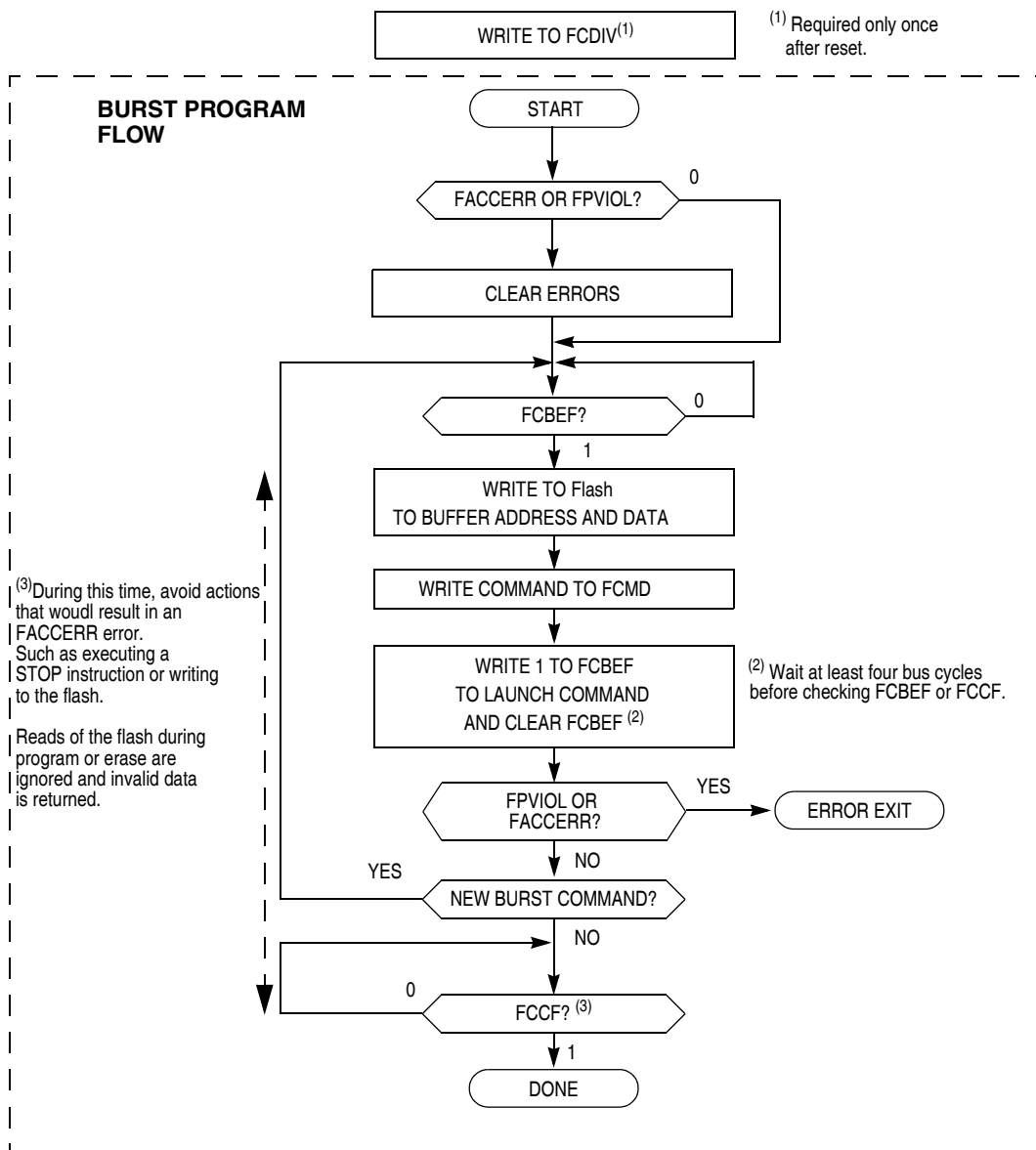
Figure 4-3. Flash Burst Program Flowchart

4.5.5   Access Errors

An access error occurs whenever the command execution protocol is violated.

Any of the following specific actions will cause the access error flag (FACCERR) in FSTAT to be set. FACCERR must be cleared by writing a 1 to FACCERR in FSTAT before any command can be processed.

- Writing to a flash address before the internal flash clock frequency has been set by writing to the FCDIV register
- Writing to a flash address while FCBEF is not set (a new command cannot be started until the command buffer is empty)
- Writing a second time to a flash address before launching the previous command (there is only one write to flash for every command)
- Writing a second time to FCMD before launching the previous command (There is only one write to FCMD for every command.)
- Writing to any flash control register other than FCMD after writing to a flash address
- Writing any command code other than the five allowed codes (0x05, 0x20, 0x25, 0x40, or 0x41) to FCMD
- Accessing (read or write) any flash control register other than the write to FSTAT (to clear FCBEF and launch the command) after writing the command to FCMD
- The MCU enters stop mode while a program or erase command is in progress (the command is aborted)
- Writing the byte program, burst program, or page erase command code (0x20, 0x25, or 0x40) with a background debug command while the MCU is secured (the background debug controller can only do blank check and mass erase commands when the MCU is secure)
- Writing 0 to FCBEF to cancel a partial command

4.5.6   Flash Block Protection

The block protection feature prevents the protected region of flash from program or erase changes. Block protection is controlled through the flash protection register (FPROT). When enabled, block protection begins at any 512 byte boundary below the last address of flash, 0xFFFF. (See Section 4.7.4, "Flash Protection Register (FPROT and NVPROT).")

After exit from reset, FPROT is loaded with the contents of the NVPROT location, which is in the nonvolatile register block of the flash memory. FPROT cannot be changed directly from application software, so a runaway program cannot alter the block protection settings. Because NVPROT is within the last 512 bytes of flash, if any amount of memory is protected, NVPROT is itself protected and cannot be altered (intentionally or unintentionally) by the application software. FPROT can be written through background debug commands, which allows a way to erase and reprogram a protected flash memory.

The block protection mechanism is illustrated in Figure 4-4. The FPS bits are used as the upper bits of the last address of unprotected memory. This address is formed by concatenating FPS7:FPS1 with logic 1 bits as shown. For example, to protect the last 1536 bytes of memory (addresses 0xFA00:0xFFFF), the FPS bits must be set to 1111 100, which results in the value 0xF9FF as the last address of unprotected memory. In addition to programming the FPS bits to the appropriate value, FPDIS (bit 0 of NVPROT) must be

programmed to logic 0 to enable block protection. Therefore, the value 0xF8 must be programmed into NVPROT to protect addresses 0xFA00 through 0xFFFF.
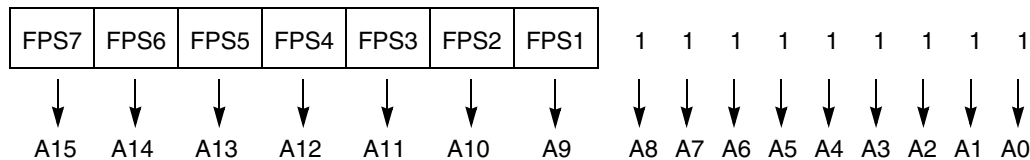
Figure 4-4. Block Protection Mechanism

One use for block protection is to block protect an area of flash memory for a bootloader program. This bootloader program then can be used to erase the rest of the flash memory and reprogram it. Because the bootloader is protected, it remains intact even if MCU power is lost in the middle of an erase and reprogram operation.

4.5.7   Vector Redirection

Whenever any block protection is enabled, the reset and interrupt vectors will be protected. Vector redirection allows users to modify interrupt vector information without unprotecting bootloader and reset vector space. Vector redirection is enabled by programming the FNORED bit in the NVOPT register located at address 0xFFBF to zero. For redirection to occur, at least some portion but not all of the flash memory must be block protected by programming the NVPROT register located at address 0xFFBD. All of the interrupt vectors (memory locations 0xFFC0–0xFFFD) are redirected, though the reset vector (0xFFFE:FFFF) is not.

For example, if 512 bytes of flash are protected, the protected address region is from 0xFE00 through 0xFFFF. The interrupt vectors (0xFFC0–0xFFFD) are redirected to the locations 0xFDC0–0xFDFD. Now, if an KBI interrupt is taken for instance, the values in the locations 0xFDD6:FDD7 are used for the vector instead of the values in the locations 0xFFD6:FFD7. This allows the user to reprogram the unprotected portion of the flash with new program code including new interrupt vector values while leaving the protected area, which includes the default vector locations, unchanged.

4.6   Security

The MC9S08SE8 series include circuitry to prevent unauthorized access to the contents of flash and RAM memory. When security is engaged, flash and RAM are considered secure resources. Direct-page registers, high-page registers, and the background debug controller are considered unsecured resources. Programs executing within secure memory have normal access to any MCU memory locations and resources. Attempts to access a secure memory location with a program executing from an unsecured memory space or through the background debug interface are blocked (writes are ignored and reads return all 0s).

Security is engaged or disengaged based on the state of two nonvolatile register bits (SEC01:SEC00) in the FOPT register. During reset, the contents of the nonvolatile location NVOPT are copied from flash into the working FOPT register in high-page register space. A user engages security by programming the NVOPT location which can be done at the same time the flash memory is programmed. The 1:0 state disengages security and the other three combinations engage security. Notice the erased state (1:1) makes the MCU secure. During development, whenever the flash is erased, immediately program the SEC00 bit

to 0 in NVOPT so SEC01:SEC00 = 1:0. This would allow the MCU to remain unsecured after a subsequent reset.

The on-chip debug module cannot be enabled while the MCU is secure. The separate background debug controller can still be used for background memory access commands of unsecured resources.

A user can choose to allow or disallow a security unlocking mechanism through an 8-byte backdoor security key. If the nonvolatile KEYEN bit in NVOPT/FOPT is 0, the backdoor key is disabled and there is no way to disengage security without completely erasing all flash locations. If KEYEN is 1, a secure user program can temporarily disengage security by:

1. Writing 1 to KEYACC in the FCNFG register. This makes the flash module interpret writes to the backdoor comparison key locations (NVBACKKEY through NVBACKKEY+7) as values to be compared against the key rather than as the first step in a flash program or erase command.

2. Writing the user-entered key values to the NVBACKKEY through NVBACKKEY+7 locations. These writes must be done in order starting with the value for NVBACKKEY and ending with NVBACKKEY+7. STHX must not be used for these writes because these writes cannot be done on adjacent bus cycles. User software normally would get the key codes from outside the MCU system through a communication interface such as a serial I/O.

3. Writing 0 to KEYACC in the FCNFG register. If the 8-byte key that was just written matches the key stored in the flash locations, SEC01:SEC00 are automatically changed to 1:0 and security will be disengaged until the next reset.

The security key can be written only from secure memory (RAM or flash), so it cannot be entered through background commands without the cooperation of a secure user program.

The backdoor comparison key (NVBACKKEY through NVBACKKEY+7) is located in flash memory locations in the nonvolatile register space, so users can program these locations exactly as they would program any other flash memory location. The nonvolatile registers are in the same 512-byte block of flash as the reset and interrupt vectors, so block protecting that space also block protects the backdoor comparison key. Block protects cannot be changed from user application programs, so if the vector space is block protected, the backdoor security key mechanism cannot permanently change the block protect, security settings, or the backdoor key.

Security can always be disengaged through the background debug interface by taking these steps:

1. Disable any block protections by writing FPROT. FPROT can be written only with background debug commands, not from application software.

2. Mass erase flash if necessary.

3. Blank check flash. Provided flash is completely erased, security is disengaged until the next reset.

   To avoid returning to secure mode after the next reset, program NVOPT so SEC01:SEC00 = 1:0.

4.7   Flash Registers and Control Bits

The flash module has nine 8-bit registers in the high-page register space, two locations (NVOPT, NVPROT) in the nonvolatile register space in flash memory are copied into corresponding high-page control registers (FOPT, FPROT) at reset. There is also an 8-byte comparison key in flash memory. Refer to Table 4-3 and Table 4-4 for the absolute address assignments for all flash registers. This section refers

to registers and control bits only by their names. A Freescale Semiconductor provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

4.7.1   Flash Clock Divider Register (FCDIV)

Bit 7 of this register is a read-only flag. Bits 6:0 may be read at any time but can be written only one time. Before any erase or programming operations are possible, write to this register to set the frequency of the clock for the nonvolatile memory system within acceptable limits.

	7	6	5	4	3	2	1	0
R	DIVLD	PRDIV8			DIV			
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved
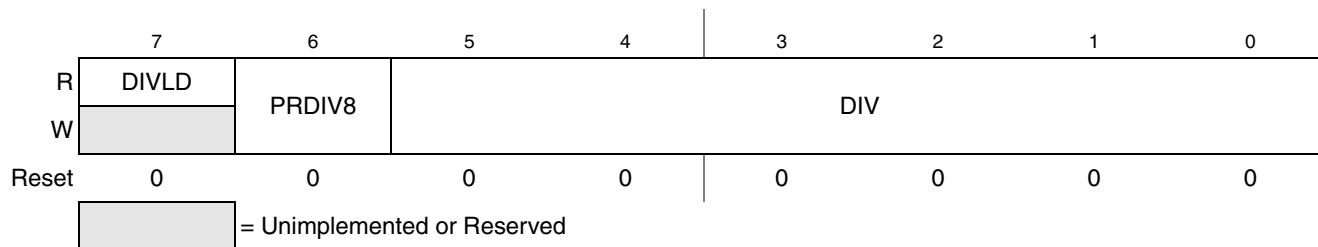
Figure 4-5. Flash Clock Divider Register (FCDIV)

Table 4-6. FCDIV Register Field Descriptions

Field	Description
7 DIVLD	**Divisor Loaded Status Flag** — When set, this read-only status flag indicates that the FCDIV register has been written since reset. Reset clears this bit and the first write to this register causes this bit to become set regardless of the data written. 0 FCDIV has not been written since reset; erase and program operations disabled for flash.1FCDIV has been written since reset; erase and program operations enabled for flash.
6 PRDIV8	**Prescale (Divide) Flash Clock by 8** 0 Clock input to the flash clock divider is the bus rate clock. 1 Clock input to the flash clock divider is the bus rate clock divided by 8
5:0 DIV	**Divisor for Flash Clock Divider** — The flash clock divider divides the bus rate clock (or the bus rate clock divided by 8 if PRDIV8 = 1) by the value in the 6-bit DIV field plus one. The resulting frequency of the internal flash clock must fall within the range of 200 kHz to 150 kHz for proper flash operations Program/Erase timing pulses are one cycle of this internal flash clock which corresponds to a range of 5 μs to 6.7 μs. The automated programming logic uses an integer number of these pulses to complete an erase or program operation. See Equation 4-1 and Equation 4-2.

$$\text{If PRDIV8 = 0} - f_{FCLK} = f_{Bus} \div (DIV + 1) \qquad \textit{Eqn. 4-1}$$

$$\text{If PRDIV8 = 1} - f_{FCLK} = f_{Bus} \div (8 \times (DIV + 1)) \qquad \textit{Eqn. 4-2}$$

Table 4-7 shows the appropriate values for PRDIV8 and DIV for selected bus frequencies.

Table 4-7. Flash Clock Divider Settings

f_{Bus}	PRDIV8 (Binary)	DIV (Decimal)	f_{FCLK}	Program/Erase Timing Pulse (5 μs Min, 6.7 μs Max)
20 MHz	1	12	192.3 kHz	5.2 μs
10 MHz	0	49	200 kHz	5 μs
8 MHz	0	39	200 kHz	5 μs
4 MHz	0	19	200 kHz	5 μs
2 MHz	0	9	200 kHz	5 μs
1 MHz	0	4	200 kHz	5 μs
200 kHz	0	0	200 kHz	5 μs
150 kHz	0	0	150 kHz	6.7 μs

4.7.2 Flash Options Register (FOPT and NVOPT)

During reset, the contents of the nonvolatile location NVOPT are copied from flash into FOPT. To change the value in this register, erase and reprogram the NVOPT location in flash memory as usual and then issue a new MCU reset.

	7	6	5	4	3	2	1	0
R	KEYEN	FNORED	0	0	0	0	SEC01	SEC00
W								

Reset   This register is loaded from nonvolatile location NVOPT during reset.

☐ = Unimplemented or Reserved
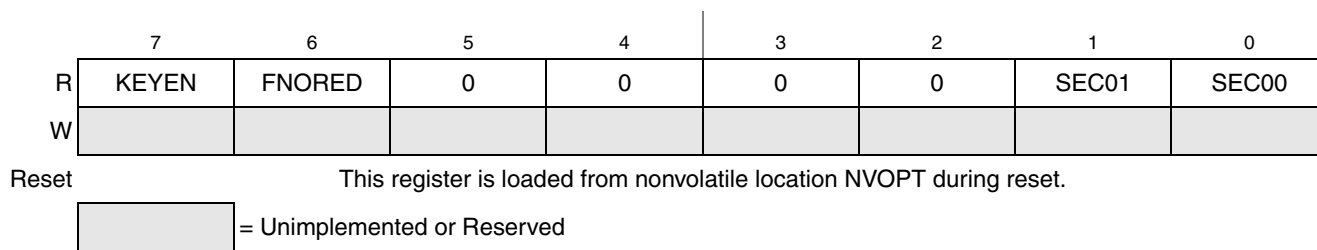
Figure 4-6. Flash Options Register (FOPT)

Table 4-8. FOPT Register Field Descriptions

Field	Description
7 KEYEN	**Backdoor Key Mechanism Enable** — When this bit is 0, the backdoor key mechanism cannot be used to disengage security. The backdoor key mechanism is accessible only from user (secured) firmware. BDM commands cannot be used to write key comparison values that would unlock the backdoor key. For more detailed information about the backdoor key mechanism, refer to Section 4.6, "Security." 0 No backdoor key access allowed. 1 If user firmware writes an 8-byte value that matches the nonvolatile backdoor key (NVBACKKEY through NVBACKKEY+7 in that order), security is temporarily disengaged until the next MCU reset.
6 FNORED	**Vector Redirection Disable** — When this bit is 1, then vector redirection is disabled. 0 Vector redirection enabled. 1 Vector redirection disabled.
1:0 SEC0[1:0]	**Security State Code** — This 2-bit field determines the security state of the MCU as shown in Table 4-9. When the MCU is secure, the contents of RAM and flash memory cannot be accessed by instructions from any unsecured source including the background debug interface.SEC01:SEC00 changes to 1:0 after successful backdoor key entry or a successful blank check of flash. For more detailed information about security, refer to Section 4.6, "Security."

Table 4-9. Security States[1]

SEC01:SEC00	Description
0:0	secure
0:1	secure
1:0	unsecured
1:1	secure

[1] SEC01:SEC00 changes to 1:0 after successful backdoor key entry or a successful blank check of flash.

4.7.3   Flash Configuration Register (FCNFG)

	7	6	5	4	3	2	1	0
R	0	0	KEYACC	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved
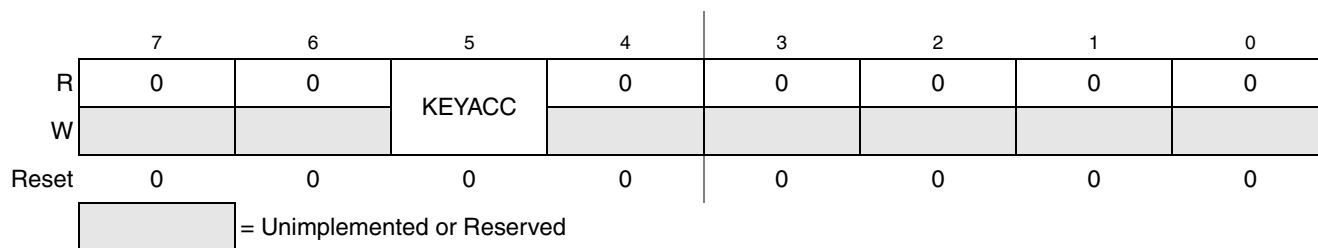
Figure 4-7. Flash Configuration Register (FCNFG)

Table 4-10. FCNFG Register Field Descriptions

Field	Description
5 KEYACC	**Enable Writing of Access Key** — This bit enables writing of the backdoor comparison key. For more detailed information about the backdoor key mechanism, refer to Section 4.6, "Security." 0 Writes to 0xFFB0–0xFFB7 are interpreted as the start of a flash programming or erase command. 1 Writes to NVBACKKEY (0xFFB0–0xFFB7) are interpreted as comparison key writes.

4.7.4   Flash Protection Register (FPROT and NVPROT)

During reset, the contents of the nonvolatile location NVPROT is copied from flash into FPROT. This register can be read at any time, but user program writes have no meaning or effect.

	7	6	5	4	3	2	1	0
R				FPS[1]				FPDIS[1]
W								
Reset	This register is loaded from nonvolatile location NVPROT during reset.							
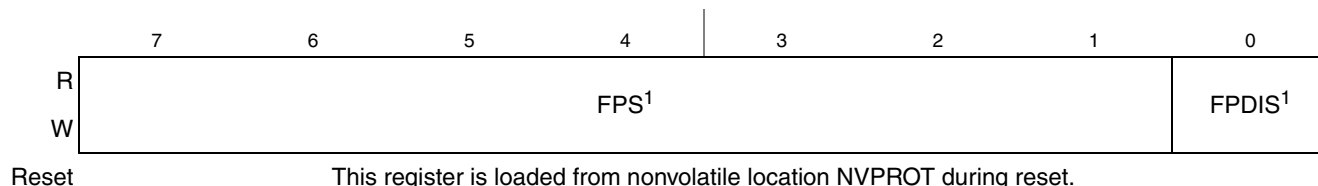
[1] Background commands can be used to change the contents of these bits in FPROT.

Figure 4-8. Flash Protection Register (FPROT)

Table 4-11. FPROT Register Field Descriptions

Field	Description
7:1 FPS	**Flash Protect Select Bits** — When FPDIS = 0, this 7-bit field determines the ending address of unprotected flash locations at the high address end of the flash. Protected flash locations cannot be erased or programmed.
0 FPDIS	**Flash Protection Disable** 0 Flash block specified by FPS7:FPS1 is block protected (program and erase not allowed). 1 No flash block is protected.

4.7.5   Flash Status Register (FSTAT)

	7	6	5	4	3	2	1	0
R	FCBEF	FCCF	FPVIOL	FACCERR	0	FBLANK	0	0
W								
Reset	1	1	0	0	0	0	0	0

= Unimplemented or Reserved
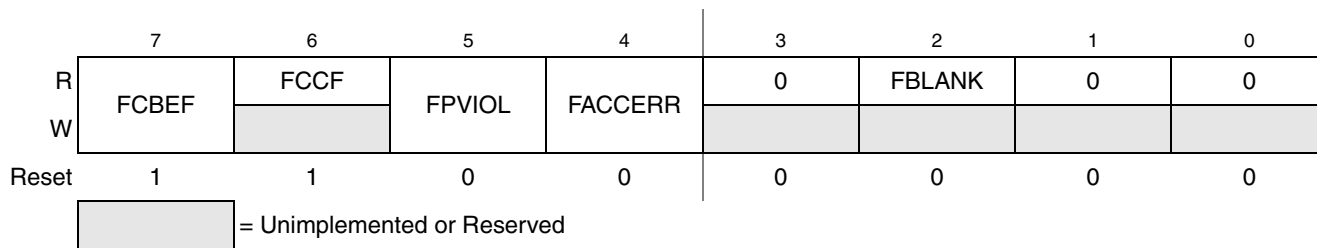
Figure 4-9. Flash Status Register (FSTAT)

Table 4-12. FSTAT Register Field Descriptions

Field	Description
7 FCBEF	**Flash Command Buffer Empty Flag** — The FCBEF bit is used to launch commands. It also indicates that the command buffer is empty so that a new command sequence can be executed when performing burst programming. The FCBEF bit is cleared by writing a 1 to it or when a burst program command is transferred to the array for programming. Only burst program commands can be buffered. 0 Command buffer is full (not ready for additional commands). 1 A new burst program command can be written to the command buffer.
6 FCCF	**Flash Command Complete Flag** — FCCF is set automatically when the command buffer is empty and no command is being processed. FCCF is cleared automatically when a new command is started (by writing 1 to FCBEF to register a command). Writing to FCCF has no meaning or effect. 0 Command in progress 1 All commands complete
5 FPVIOL	**Protection Violation Flag** — FPVIOL is set automatically when a command is written that attempts to erase or program a location in a protected block (the erroneous command is ignored). FPVIOL is cleared by writing a 1 to FPVIOL. 0 No protection violation. 1 An attempt was made to erase or program a protected location.

Table 4-12. FSTAT Register Field Descriptions (continued)

Field	Description
4 FACCERR	**Access Error Flag** — FACCERR is set automatically when the proper command sequence is not obeyed exactly (the erroneous command is ignored), if a program or erase operation is attempted before the FCDIV register has been initialized, or if the MCU enters stop while a command was in progress. For a more detailed discussion of the exact actions that are considered access errors, see Section 4.5.5, "Access Errors." FACCERR is cleared by writing a 1 to FACCERR. Writing a 0 to FACCERR has no meaning or effect. 0 No access error. 1 An access error has occurred.
2 FBLANK	**Flash Verified as All Blank (erased) Flag** — FBLANK is set automatically at the conclusion of a blank check command if the entire flash array was verified to be erased. FBLANK is cleared by clearing FCBEF to write a new valid command. Writing to FBLANK has no meaning or effect. 0 After a blank check command is completed and FCCF = 1, FBLANK = 0 indicates the flash array is not completely erased. 1 After a blank check command is completed and FCCF = 1, FBLANK = 1 indicates the flash array is completely erased (all 0xFF).

4.7.6 Flash Command Register (FCMD)

Only five command codes are recognized in normal user modes as shown in Table 4-13. Refer to Section 4.5.3, "Program and Erase Command Execution," for a detailed discussion of flash programming and erase operations.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W	FCMD							
Reset	0	0	0	0	0	0	0	0
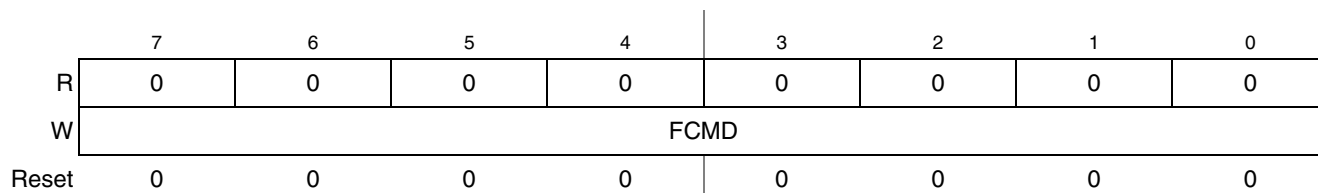
Figure 4-10. Flash Command Register (FCMD)

Table 4-13. Flash Commands

Command	FCMD	Equate File Label
Blank check	0x05	mBlank
Byte program	0x20	mByteProg
Byte program — burst mode	0x25	mBurstProg
Page erase (512 bytes/page)	0x40	mPageErase
Mass erase (all flash)	0x41	mMassErase

All other command codes are illegal and generate an access error.

It is not necessary to perform a blank check command after a mass erase operation. Only blank check is required as part of the security unlocking mechanism.

Chapter 5
Resets, Interrupts, and General System Control

5.1   Introduction

This chapter discusses basic reset and interrupt mechanisms and the various sources of reset and interrupt in the MC9S08SE8 series. Some interrupt sources from peripheral modules are discussed in greater detail in other chapters of this reference manual. This chapter gathers basic information about all reset and interrupt sources in one place for easy reference. A few reset and interrupt sources, including the computer operating properly (COP) watchdog are not part of on-chip peripheral systems with their own chapters.

5.2   Features

Reset and interrupt features include:

- Multiple sources of reset for flexible system configuration and reliable operation
- System reset status register (SRS) to indicate source of most recent reset
- Separate interrupt vector for each module (reduces polling overhead) (see Table 5-2)

5.3   MCU Reset

Resetting the MCU provides a way to start processing from a known set of initial conditions. During reset, most control and status registers are forced to initial values and the program counter is loaded from the reset vector (0xFFFE:0xFFFF). On-chip peripheral modules are disabled and I/O pins are initially configured as general-purpose high-impedance inputs with pullup devices disabled. The I bit in the condition code register (CCR) is set to block maskable interrupts, so the user program has a chance to initialize the stack pointer (SP) and system control settings. SP is forced to 0x00FF at reset.

The MC9S08SE8 series have the following sources for reset:

- Power-on reset (POR)
- External pin reset (PIN) — enabled using RSTPE in SOPT1
- Low-voltage detect (LVD)
- Computer operating properly (COP) timer
- Illegal opcode detect (ILOP)
- Illegal address detect (ILAD) — access of any address in memory map that is listed as unimplemented will produce an illegal address reset
- Background debug forced reset

Each of these sources, with the exception of the background debug forced reset, has an associated bit in the system reset status (SRS) register.

5.4 Computer Operating Properly (COP) Watchdog

The COP watchdog is used to force a system reset when the application software fails to execute as expected. To prevent a system reset from the COP timer (when it is enabled), application software must reset the COP counter periodically. If the application program gets lost and fails to reset the COP counter before it times out, a system reset is generated to force the system back to a known starting point.

After any reset, the COP watchdog is enabled (see Section 5.7.4, "System Options Register 1 (SOPT1)," for additional information). If the COP watchdog is not used in an application, it can be disabled by clearing COPT bits in SOPT1.

The COP counter is reset by writing 0x0055 and 0x00AA (in this order) to the address of SRS during the selected timeout period. Writes do not affect the data in the read-only SRS. As soon as the write sequence is done, the COP timeout period is restarted. If the program fails to do this during the time-out period, the MCU will reset. Also, if any value other than 0x0055 or 0x00AA is written to SRS, the MCU is immediately reset.

The COPCLKS bit in SOPT2 (see Section 5.7.5, "System Options Register 2 (SOPT2)," for additional information) selects the clock source used for the COP timer. The clock source options are either the bus clock or an internal 1 kHz clock source. With each clock source, there are three associated time-outs controlled by the COPT bits in SOPT1. Table 5-1 summaries the control functions of the COPCLKS and COPT bits. The COP watchdog defaults to operate from the 1 kHz clock source and the longest time-out (2^{10} cycles).

Table 5-1. COP Configuration Options

Control Bits		Clock Source	COP Window[1] Opens (COPW = 1)	COP Overflow Count
COPCLKS	COPT[1:0]			
N/A	0:0	N/A	N/A	COP is disabled
0	0:1	1 kHz	N/A	2^5 cycles (32 ms[2])
0	1:0	1 kHz	N/A	2^8 cycles (256 ms[2])
0	1:1	1 kHz	N/A	2^{10} cycles (1.024 s[2])
1	0:1	Bus	6144 cycles	2^{13} cycles
1	1:0	Bus	49,152 cycles	2^{16} cycles
1	1:1	Bus	196,608 cycles	2^{18} cycles

[1] Windowed COP operation requires the user to clear the COP timer in the last 25% of the selected timeout period. This column displays the minimum number of clock counts required before the COP timer can be reset when in windowed COP mode (COPW = 1).

[2] Values shown in milliseconds based on t_{LPO} = 1 ms. See t_{LPO} in the MC9S08SE8 Series *Data Sheet* for the tolerance of this value.

When the bus clock source is selected, windowed COP operation is available by setting COPW in the SOPT2 register. In this mode, writes to the SRS register to clear the COP timer must occur in the last 25% of the selected timeout period. A premature write immediately resets the MCU. When the 1 kHz clock source is selected, windowed COP operation is not available.

The COP counter is initialized by the first writes to the SOPT1 and SOPT2 registers after any system reset. Subsequent writes to SOPT1 and SOPT2 have no effect on COP operation. Even if the application will use the reset default settings of COPT, COPCLKS, and COPW bits, the user must write to the write-once SOPT1 and SOPT2 registers during reset initialization to lock in the settings. This will prevent accidental changes if the application program gets lost.

The write to SRS that services (clears) the COP counter must not be placed in an interrupt service routine (ISR) because the ISR could continue to be executed periodically even if the main application program fails.

If the bus clock source is selected, the COP counter does not increment while the MCU is in background debug mode or while the system is in stop mode. The COP counter resumes when the MCU exits background debug mode or stop mode.

If the 1 kHz clock source is selected, the COP counter is re-initialized to zero upon entry to background debug mode or stop mode and begins from zero upon exit from background debug mode or stop mode.

5.5   Interrupts

Interrupts provide a way to save the current CPU status and registers, execute an interrupt service routine (ISR), and then restore the CPU status so processing resumes where it left off before the interrupt. Other than the software interrupt (SWI), which is a program instruction, interrupts are caused by hardware events such as an edge on the IRQ pin or a timer-overflow event. The debug module can also generate an SWI under certain circumstances.

If an event occurs in an enabled interrupt source, an associated read-only status flag will become set. The CPU will not respond unless the local interrupt enable is a 1 to enable the interrupt and the I bit in the CCR is 0 to allow interrupts. The global interrupt mask (I bit) in the CCR is initially set after reset which prevents all maskable interrupt sources. The user program initializes the stack pointer and performs other system setup before clearing the I bit to allow the CPU to respond to interrupts.

When the CPU receives a qualified interrupt request, it completes the current instruction before responding to the interrupt. The interrupt sequence obeys the same cycle-by-cycle sequence as the SWI instruction and consists of:

- Saving the CPU registers on the stack
- Setting the I bit in the CCR to mask further interrupts
- Fetching the interrupt vector for the highest-priority interrupt that is currently pending
- Filling the instruction queue with the first three bytes of program information starting from the address fetched from the interrupt vector locations

While the CPU is responding to the interrupt, the I bit is automatically set to avoid the possibility of another interrupt interrupting the ISR itself (this is called nesting of interrupts). Normally, the I bit is restored to 0 when the CCR is restored from the value stacked on entry to the ISR. In rare cases, the I bit can be cleared inside an ISR (after clearing the status flag that generated the interrupt) so that other interrupts can be serviced without waiting for the first service routine to finish. This practice is not recommended for anyone other than the most experienced programmers because it can lead to subtle program errors that are difficult to debug.

The interrupt service routine ends with a return-from-interrupt (RTI) instruction which restores the CCR, A, X, and PC registers to their pre-interrupt values by reading the previously saved information from the stack.

NOTE

For compatibility with M68HC08 devices, the H register is not automatically saved and restored. Push H onto the stack at the start of the interrupt service routine (ISR) and restore it immediately before the RTI that is used to return from the ISR.

If more than one interrupt is pending when the I bit is cleared, the highest priority source is serviced first (see Table 5-2).

5.5.1   Interrupt Stack Frame

Figure 5-1 shows the contents and organization of a stack frame. Before the interrupt, the stack pointer (SP) points at the next available byte location on the stack. The current values of CPU registers are stored on the stack starting with the low-order byte of the program counter (PCL) and ending with the CCR. After stacking, the SP points at the next available location on the stack which is the address that is one less than the address where the CCR was saved. The PC value that is stacked is the address of the instruction in the main program that would have executed next if the interrupt had not occurred.
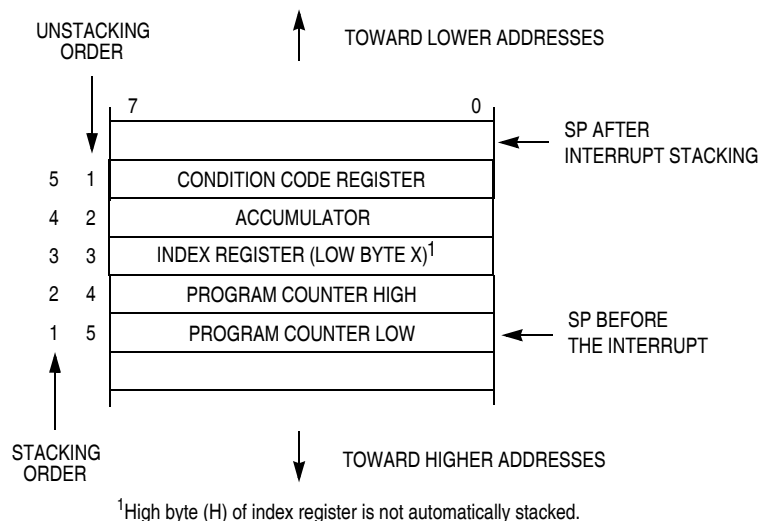
Figure 5-1. Interrupt Stack Frame

When an RTI instruction is executed, these values are recovered from the stack in reverse order. As part of the RTI sequence, the CPU fills the instruction pipeline by reading three bytes of program information, starting from the PC address recovered from the stack.

The status flag corresponding to the interrupt source must be acknowledged (cleared) before returning from the ISR. Typically, the flag is cleared at the beginning of the ISR so that if another interrupt is generated by the same source, it will be registered so it can be serviced after completion of the current ISR.

5.5.2 External Interrupt Request Pin (IRQ)

External interrupts are managed by the IRQ status and control register, IRQSC. When the IRQ function is enabled, synchronous logic monitors the pin for edge-only or edge-and-level events. When the MCU is in stop mode and system clocks are shut down, a separate asynchronous path is used so the IRQ (if enabled) can wake the MCU.

5.5.2.1 Pin Configuration Options

The IRQ pin enable (IRQPE) control bit in IRQSC must be 1 in order for the IRQ pin to act as the interrupt request (IRQ) input. As an IRQ input, the user can choose the polarity of edges or levels detected (IRQEDG), whether the pin detects edges-only or edges and levels (IRQMOD), and whether an event causes an interrupt or only sets the IRQF flag which can be polled by software.

The IRQ pin, when enabled, defaults to use an internal pull device (IRQPDD = 0), the device is a pullup or pulldown depending on the polarity chosen. If the user desires to use an external pullup or pulldown, the IRQPDD can be written to a 1 to turn off the internal device.

BIH and BIL instructions may be used to detect the level on the IRQ pin when the pin is configured to act as the IRQ input.

NOTE

This pin does not contain a clamp diode to V_{DD} and must not be driven above V_{DD}.

The voltage measured on the internally pulled up IRQ pin will not be pulled to V_{DD}. The internal gates connected to this pin are pulled to V_{DD}. If the IRQ pin is required to drive to a V_{DD} level, an external pullup must be used.

NOTE

When enabling the IRQ pin for use, the IRQF will be set, and should be cleared prior to enabling the interrupt. When configuring the pin for falling edge and level sensitivity in a 5V system, it is necessary to wait at least 6 cycles between clearing the flag and enabling the interrupt.

5.5.2.2 Edge and Level Sensitivity

The IRQMOD control bit reconfigures the detection logic, so it detects edge events and pin levels. In the edge and level detection mode, the IRQF status flag becomes set when an edge is detected (when the IRQ pin changes from the deasserted to the asserted level), but the flag is continuously set (and cannot be cleared) as long as the IRQ pin remains at the asserted level.

5.5.3 Interrupt Vectors, Sources, and Local Masks

Table 5-2 provides a summary of all interrupt sources. Higher priority sources are located toward the bottom of the table. The high order byte of the address for the interrupt service routine is located at the first address in the vector address column, and the low order byte of the address for the interrupt service routine is located at the next higher address.

When an interrupt condition occurs, an associated flag bit becomes set. If the associated local interrupt enable is 1, an interrupt request is sent to the CPU. Within the CPU, if the global interrupt mask (I bit in the CCR) is 0, the CPU will finish the current instruction; stack the PCL, PCH, X, A, and CCR CPU registers; set the I bit; and then fetch the interrupt vector for the highest priority pending interrupt. Processing then continues in the interrupt service routine.

Table 5-2. Vector Summary

Vector Priority	Vector Number	Address (High/Low)	Vector Name	Module	Source	Enable	Description
Lowest	31	0xFFC0/0xFFC1	—	—	—	—	—
	30	0xFFC2/0xFFC3	—	—	—	—	—
	29	0xFFC4/0xFFC5	—	—	—	—	—
	28	0xFFC6/0xFFC7	—	—	—	—	—
	27	0xFFC8/0xFFC9	—	—	—	—	—
	26	0xFFCA/0xFFCB	—	—	—	—	—
	25	0xFFCC/0xFFCD	Vrtc	RTC	RTIF	RTIE	Real-time interrupt
	24	0xFFCE/0xFFCF	—	—	—	—	—
	23	0xFFD0/0xFFD1	Vadc	ADC	COCO, ACFF	AIEN, ACFIE	ADC
	22	0xFFD2/0xFFD3	—	—	—	—	—
	21	0xFFD4/0xFFD5	—	—	—	—	—
	20	0xFFD6/0xFFD7	Vkeyboard	KBI	KBF	KBIE	Keyboard pins
	19	0xFFD8/0xFFD9	—	—	—	—	—
	18	0xFFDA/0xFFDB	Vscitx	SCI	TDRE, TC	TIE, TCIE	SCI transmit
	17	0xFFDC/0xFFDD	Vscirx	SCI	IDLE, RDRF	ILIE, RIE	SCI receive
	16	0xFFDE/0xFFDF	Vscierr	SCI	OR, NF, FE, PF	ORIE, NFIE, FEIE, PFIE	SCI error
	15	0xFFE0/0xFFE1	—	—	—	—	—
	14	0xFFE2/0xFFE3	Vtpm2ovf	TPM2	TOF	TOIE	TPM2 overflow
	13	0xFFE4/0xFFE5	—	—	—	—	—
	12	0xFFE6/0xFFE7	Vtpm2ch0	TPM2	CH0F	CH0IE	TPM2 channel 0
	11	0xFFE8/0xFFE9	Vtpm1ovf	TPM1	TOF	TOIE	TPM1 overflow
	10	0xFFEA/0xFFEB	—	—	—	—	—
	9	0xFFEC/0xFFED	—	—	—	—	—
	8	0xFFEE/0xFFEF	—	—	—	—	—
	7	0xFFF0/0xFFF1	—	—	—	—	—
	6	0xFFF2/0xFFF3	Vtpm1ch1	TPM1	CH1F	CH1IE	TPM1 channel 1
	5	0xFFF4/0xFFF5	Vtpm1ch0	TPM1	CH0F	CH0IE	TPM1 channel 0
	4	0xFFF6/0xFFF7	—	—	—	—	—
	3	0xFFF8/0xFFF9	Vlvd	System control	LVWF	LVWIE	Low-voltage warning
	2	0xFFFA/0xFFFB	Virq	IRQ	IRQF	IRQIE	IRQ pin
	1	0xFFFC/0xFFFD	Vswi	Core	SWI Instruction	—	Software interrupt
Highest	0	0xFFFE/0xFFFF	Vreset	System control	COP, LVD, $\overline{\text{RESET}}$ pin, Illegal opcode, Illegal address	COPT LVDRE — — —	Watchdog timer Low-voltage detect External pin Illegal opcode Illegal address

5.6 Low-Voltage Detect (LVD) System

The MC9S08SE8 series include a system to protect against low voltage conditions to protect memory contents and control MCU system states during supply voltage variations. The system comprises a power-on reset (POR) circuit and a LVD circuit with trip voltages for warning and detection. The LVD circuit is enabled when LVDE in SPMSC1 is set to 1. The LVD is disabled upon entering any of the stop modes unless LVDSE is set in SPMSC1. If LVDSE and LVDE are both set, then the MCU cannot enter stop2, and the current consumption in stop3 with the LVD enabled will be higher.

5.6.1 Power-On Reset Operation

When power is initially applied to the MCU, or when the supply voltage drops below the power-on reset re-arm voltage level, V_{POR}, the POR circuit will cause a reset condition. As the supply voltage rises, the LVD circuit will hold the MCU in reset until the supply has risen above the low voltage detection low threshold, V_{LVDL}. Both the POR bit and the LVD bit in SRS are set following a POR.

5.6.2 Low-Voltage Detection (LVD) Reset Operation

The LVD can be configured to generate a reset upon detection of a low voltage condition by setting LVDRE to 1. The low voltage detection threshold is determined by the LVDV bit. After an LVD reset has occurred, the LVD system will hold the MCU in reset until the supply voltage has risen above the low voltage detection threshold. The LVD bit in the SRS register is set following an LVD reset or POR.

5.6.3 Low-Voltage Warning (LVW) Interrupt Operation

The LVD system has a low voltage warning flag to indicate user that the supply voltage is approaching the low voltage condition. When a low voltage warning condition is detected and is configured for interrupt operation (LVWIE set to 1), LVWF in SPMSC1 will be set and an LVW interrupt request will occur.

5.7 Reset, Interrupt, and System Control Registers and Control Bits

One 8-bit register in the direct-page register space and eight 8-bit registers in the high-page register space are related to reset and interrupt systems.

Refer to Table 4-2 and Table 4-3 in Chapter 4, "Memory," of this reference manual for the absolute address assignments for all registers. This section refers to registers and control bits only by their names. A Freescale provided equate or header file is used to translate these names into the appropriate absolute addresses.

Some control bits in the SOPT1 and SPMSC2 registers are related to modes of operation. Although brief descriptions of these bits are provided here, the related functions are discussed in greater detail in Chapter 3, "Modes of Operation."

5.7.1 Interrupt Pin Request Status and Control Register (IRQSC)

This direct-page register includes status and control bits, which are used to configure the IRQ function, report status, and acknowledge IRQ events.

	7	6	5	4	3	2	1	0
R	0	IRQPDD	IRQEDG	IRQPE	IRQF	0	IRQIE	IRQMOD
W		IRQPDD	IRQEDG	IRQPE		IRQACK	IRQIE	IRQMOD
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved
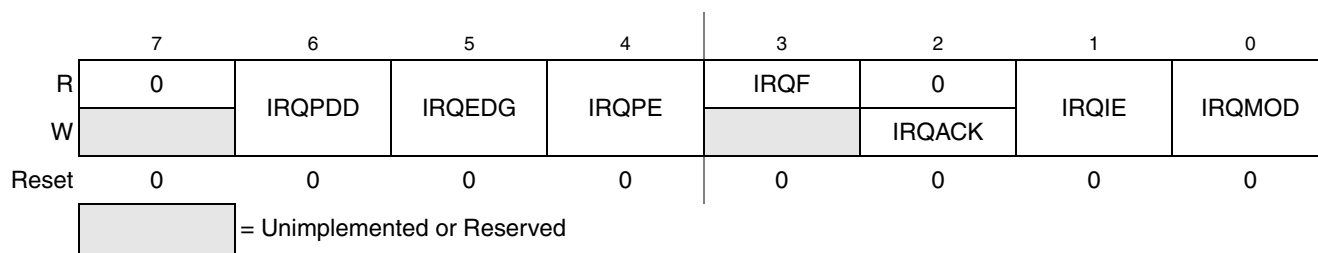
Figure 5-2. Interrupt Request Status and Control Register (IRQSC)

Table 5-3. IRQSC Register Field Descriptions

Field	Description
6 IRQPDD	**Interrupt Request (IRQ) Pull Device Disable** — This read/write control bit is used to disable the internal pullup device when the IRQ pin is enabled (IRQPE = 1) allowing for an external device to be used. 0 IRQ pull device enabled if IRQPE = 1. 1 IRQ pull device disabled if IRQPE = 1.
5 IRQEDG	**Interrupt Request (IRQ) Edge Select** — This read/write control bit is used to select the polarity of edges or levels on the IRQ pin that cause IRQF to be set. The IRQMOD control bit determines whether the IRQ pin is sensitive to both edges and levels or only edges. When the IRQ pin is enabled as the IRQ input and is configured to detect rising edges. When IRQEDG = 1 and the internal pull device is enabled, the pullup device is reconfigured as an optional pulldown device. 0 IRQ is falling edge or falling edge/low-level sensitive. 1 IRQ is rising edge or rising edge/high-level sensitive.
4 IRQPE	**$\overline{IRQ}$ Pin Enable** — This read/write control bit enables the IRQ pin function. When this bit is set, the IRQ pin can be used as an interrupt request. 0 IRQ pin function is disabled. 1 IRQ pin function is enabled.
3 IRQF	**IRQ Flag** — This read-only status bit indicates when an interrupt request event has occurred. 0 No IRQ request. 1 IRQ event detected.
2 IRQACK	**IRQ Acknowledge** — This write-only bit is used to acknowledge interrupt request events (write 1 to clear IRQF). Writing 0 has no meaning or effect. Reads always return 0. If edge-and-level detection is selected (IRQMOD = 1), IRQF cannot be cleared while the IRQ pin remains at its asserted level.
1 IRQIE	**IRQ Interrupt Enable** — This read/write control bit determines whether IRQ events generate an interrupt request. 0 Interrupt request when IRQF set is disabled (use polling). 1 Interrupt requested whenever IRQF = 1.
0 IRQMOD	**IRQ Detection Mode** — This read/write control bit selects either edge-only detection or edge-and-level detection. The IRQEDG control bit determines the polarity of edges and levels that are detected as interrupt request events. See Section 5.5.2.2, "Edge and Level Sensitivity," for more details. 0 IRQ event on falling edges or rising edges only. 1 IRQ event on falling edges and low levels or on rising edges and high levels.

5.7.2 System Reset Status Register (SRS)

This high-page register includes read-only status flags to indicate the source of the most recent reset. When a debug host forces reset by writing 1 to BDFR in the SBDFR register, none of the status bits in SRS will be set. Writing any value to this register address causes a COP reset when the COP is enabled except for the values 0x55 and 0xAA. Writing a 0x55—0xAA sequence to this address clears the COP watchdog timer without affecting the contents of this register. The reset state of these bits depends on what caused the MCU to reset.

	7	6	5	4	3	2	1	0
R	POR	PIN	COP	ILOP	ILAD	0	LVD	0
W	Writing 0x55, 0xAA to SRS address clears COP watchdog timer.							
POR:	1	0	0	0	0	0	1	0
LVR:	u[1]	0	0	0	0	0	1	0
Any other reset:	0	Note[2]	Note[2]	Note[2]	Note[2]	0	0	0

[1] u = unaffected

[2] Any of these reset sources that are active at the time of reset entry will cause the corresponding bit(s) to be set; bits corresponding to sources that are not active at the time of reset entry will be cleared.

Figure 5-3. System Reset Status (SRS)

Table 5-4. SRS Register Field Descriptions

Field	Description
7 POR	**Power-On Reset** — Reset was caused by the power-on detection logic. Because the internal supply voltage was ramping up at the time, the low-voltage reset (LVD) status bit is also set to indicate that the reset occurred while the internal supply was below the LVD threshold. 0 Reset not caused by POR. 1 POR caused reset.
6 PIN	**External Reset Pin** — Reset was caused by an active-low level on the external reset pin. 0 Reset not caused by external reset pin. 1 Reset came from external reset pin.
5 COP	**Computer Operating Properly (COP) Watchdog** — Reset was caused by the COP watchdog timer timing out. This reset source can be blocked by COPE = 0. 0 Reset not caused by COP timeout. 1 Reset caused by COP timeout.
4 ILOP	**Illegal Opcode** — Reset was caused by an attempt to execute an unimplemented or illegal opcode. The STOP instruction is considered illegal if stop is disabled by STOPE = 0 in the SOPT register. The BGND instruction is considered illegal if active background mode is disabled by ENBDM = 0 in the BDCSC register. 0 Reset not caused by an illegal opcode. 1 Reset caused by an illegal opcode.

Table 5-4. SRS Register Field Descriptions (continued)

Field	Description
3 ILAD	**Illegal Address** — Reset was caused by an attempt to access either data or an instruction at an unimplemented memory address. 0 Reset not caused by an illegal address 1 Reset caused by an illegal address
1 LVD	**Low Voltage Detect** — If the LVDRE bit is set and the supply drops below the LVD trip voltage, an LVD reset will occur. This bit is also set by POR. 0 Reset not caused by LVD trip or POR. 1 Reset caused by LVD trip or POR.

5.7.3 System Background Debug Force Reset Register (SBDFR)

This high-page register contains a single write-only control bit. A serial background command such as WRITE_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								BDFR[1]
Reset:	0	0	0	0	0	0	0	0

        = Unimplemented or Reserved
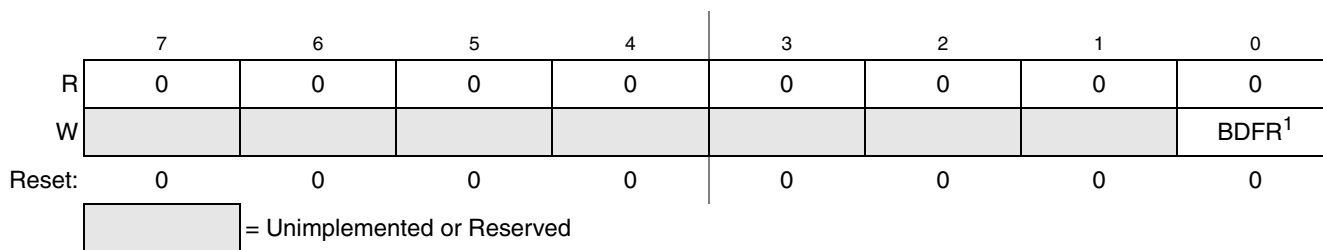
[1] BDFR is writable through only serial background debug commands, not from user programs.

Figure 5-4. System Background Debug Force Reset Register (SBDFR)

Table 5-5. SBDFR Register Field Descriptions

Field	Description
0 BDFR	**Background Debug Force Reset** — A serial background command such as WRITE_BYTE can be used to allow an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program.

5.7.4 System Options Register 1 (SOPT1)

Some bits in this high-page register are write-once, so only the first write to these bits after reset is honored. It can be read at any time. Any subsequent attempt to write to SOPT1 (intentionally or unintentionally) is ignored to avoid accidental changes to these sensitive settings. SOPT1 must be written during the user's reset initialization program to set the desired controls even if the desired settings are the same as the reset settings.

	7	6	5	4	3	2	1	0
R	COPT		STOPE	0	0	TPM1PS	BKGDPE	RSTPE
W								
Reset:	1	1	0	0	0	0	1	u[1]
POR:	1	1	0	0	0	0	1	0
LVR:	1	1	0	0	0	0	1	u

= Unimplemented or Reserved

[1] u = unaffected

Figure 5-5. System Options Register 1 (SOPT1)

Table 5-6. SOPT1 Register Field Descriptions

Field	Description
7:6 COPT[1:0]	**COP Watchdog Timeout** — These write-once bits select the timeout period of the COP. COPT along with COPCLKS in SOPT2 defines the COP timeout period. See Table 5-1.
5 STOPE	**Stop Mode Enable** — This write-once bit is used to enable stop mode. If stop mode is disabled and a user program attempts to execute a STOP instruction, an illegal opcode reset is forced. 0 Stop mode disabled. 1 Stop mode enabled.
2 TPM1PS	**TPM1 Pins Select** — This bit selects the location of the TPM1CH0 and TPM1CH1 pins of the TPM1 module. 0 TPM1CH0 on PTA0, TPM1CH1 on PTA1. 1 TPM1CH0 on PTA6, TPM1CH1 on PTA7.
1 BKGDPE	**Background Debug Mode Pin Enable** — This write-once bit when set enables the PTA4/BKGD/MS pin to function as BKGD/MS. When clear, the pin functions as one of its output-only alternative functions. This pin defaults to the BKGD/MS function following any MCU reset. 0 PTA4/BKGD/MS pin functions as PTA4. 1 PTA4/BKGD/MS pin functions as BKGD/MS.
0 RSTPE	**$\overline{RESET}$ Pin Enable** — This write-once bit when set enables the PTA5/IRQ/TCLK/$\overline{RESET}$ pin to function as $\overline{RESET}$. When clear, the pin functions as one of its alternative functions. This pin defaults to a general-purpose input port function following a POR reset. When configured as $\overline{RESET}$, the pin will be unaffected by LVR or other internal resets. When RSTPE is set, an internal pullup device is enabled on $\overline{RESET}$. 0 PTA5/IRQ/TCLK/$\overline{RESET}$ pin functions as PTA5, IRQ or TCLK. 1 PTA5/IRQ/TCLK/$\overline{RESET}$ pin functions as $\overline{RESET}$.

5.7.5 System Options Register 2 (SOPT2)

This high page register contains bits to configure MCU specific features on the MC9S08SE8 Series devices.

	7	6	5	4	3	2	1	0
R	COPCLKS[1]	COPW[1]	0	0	0	0	0	0
W								
Reset:	0	0	0	0	0	0	0	0

[ ] = Unimplemented or Reserved
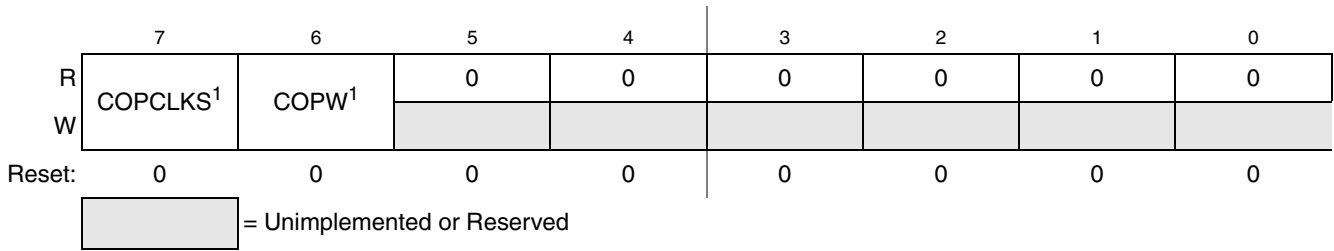
[1] This bit can be written only once after reset. Additional writes are ignored.

Figure 5-6. System Options Register 2 (SOPT2)

Table 5-7. SOPT2 Register Field Descriptions

Field	Description
7 COPCLKS	**COP Watchdog Clock Select** — This write-once bit selects the clock source of the COP watchdog. 0 Internal 1-kHz clock is source to COP. 1 Bus clock is source to COP.
6 COPW	**COP Window** — This write-once bit selects the COP operation mode. When set, the 0x55–0xAA write sequence to the SRS register must occur in the last 25% of the selected period. Any write to the SRS register during the first 75% of the selected period will reset the MCU. 0 Normal COP operation. 1 Window COP operation (only if COPCLKS = 1).

5.7.6 System Device Identification Register (SDIDH, SDIDL)

These high-page read-only registers are included, so host development systems can identify the HCS08 derivative and revision number. This allows the development software to recognize where specific memory blocks, registers, and control bits are located in a target MCU.

	7	6	5	4	3	2	1	0
R	0				ID11	ID10	ID9	ID8
W								
Reset:	0[1]	—	—	—	0	0	0	0

[ ] = Unimplemented or Reserved
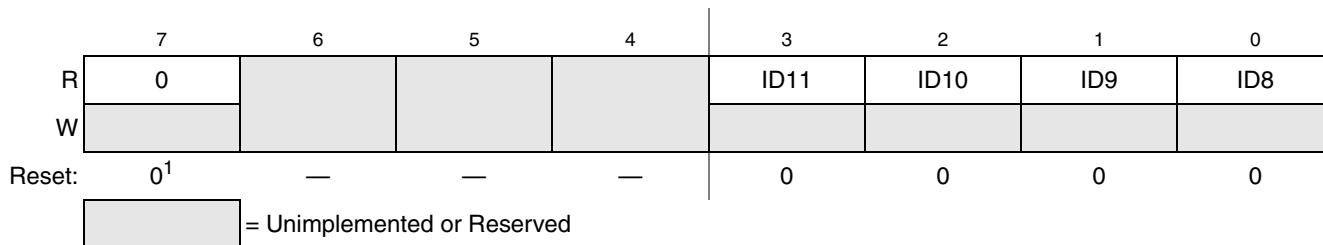
[1] Bit 7 is a mask option tie off that is used internally to determine that the device is an MC9S08SE8 Series.

Figure 5-7. System Device Identification Register — High (SDIDH)

Table 5-8. SDIDH Register Field Descriptions

Field	Description
7	Bit 7 will read as a 0 for the MC9S08SE8 series devices; writes have no effect.
6:4 Reserved	Bits 6:4 are reserved. Reading these bits will result in an indeterminate value; writes have no effect.
3:0 ID[11:8]	**Part Identification Number** — Each derivative in the HCS08 family has a unique identification number. The MC9S08SE8 is hard coded to the value 0x025. See also ID bits in Table 5-9.

	7	6	5	4	3	2	1	0
R	ID7	ID6	ID5	ID4	ID3	ID2	ID1	ID0
W								
Reset:	0	0	1	0	0	1	0	1

[ ] = Unimplemented or Reserved
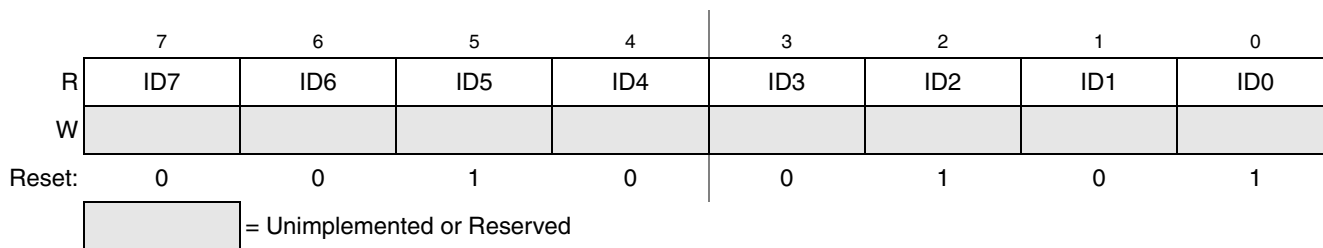
Figure 5-8. System Device Identification Register — Low (SDIDL)

Table 5-9. SDIDL Register Field Descriptions

Field	Description
7:0 ID[7:0]	**Part Identification Number** — Each derivative in the HCS08 family has a unique identification number. The MC9S08SE8 is hard coded to the value 0x025. See also ID bits in Table 5-8.

5.7.7 System Power Management Status and Control 1 Register (SPMSC1)

This high-page register contains status and control bits to support the low voltage detect function, and to enable the bandgap voltage reference for use by the ADC module.

	7	6	5	4	3	2	1	0
R	LVWF[1]	0	LVWIE	LVDRE[2]	LVDSE[2]	LVDE[2]	0	BGBE
W		LVWACK						
Reset:	0	0	0	1	1	1	0	0

= Unimplemented or Reserved
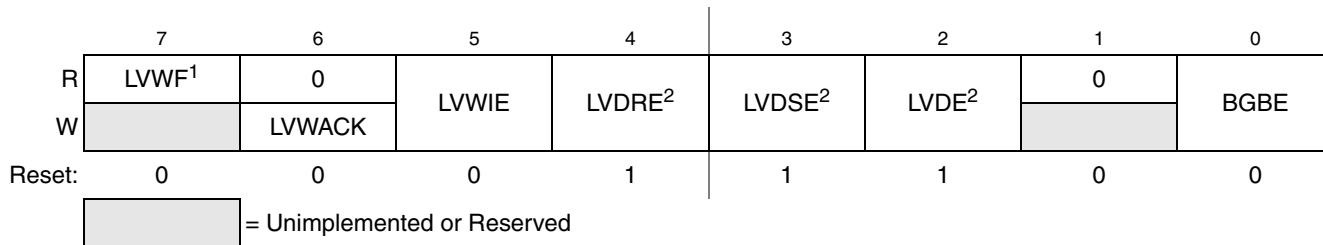
[1] LVWF will be set in the case when V_{Supply} transitions below the trip point or after reset and V_{Supply} is already below V_{LVW}.

[2] This bit can be written only once after reset. Additional writes are ignored.

Figure 5-9. System Power Management Status and Control 1 Register (SPMSC1)

Table 5-10. SPMSC1 Register Field Descriptions

Field	Description
7 LVWF	**Low-Voltage Warning Flag** — The LVWF bit indicates the low voltage warning status. 0 Low voltage warning is not present. 1 Low voltage warning is present or was present.
6 LVWACK	**Low-Voltage Warning Acknowledge** — The LVWF bit indicates the low voltage warning status. Writing a 1 to LVWACK clears LVWF to a 0 if a low voltage warning is not present.
5 LVWIE	**Low-Voltage Warning Interrupt Enable** — This bit enables hardware interrupt requests for LVWF. 0 Hardware interrupt disabled (use polling). 1 Request a hardware interrupt when LVWF = 1.
4 LVDRE	**Low-Voltage Detect Reset Enable** — This write-once bit enables LVD events to generate a hardware reset (provided LVDE = 1). 0 LVD events do not generate hardware resets. 1 Force an MCU reset when an enabled low-voltage detect event occurs.
3 LVDSE	**Low-Voltage Detect Stop Enable** — Provided LVDE = 1, this write-once bit determines whether the low-voltage detect function operates when the MCU is in stop mode. 0 Low-voltage detect disabled during stop mode. 1 Low-voltage detect enabled during stop mode.
2 LVDE	**Low-Voltage Detect Enable** — This write-once bit enables low-voltage detect logic and qualifies the operation of other bits in this register. 0 LVD logic disabled. 1 LVD logic enabled.
0 BGBE	**Bandgap Buffer Enable** — This bit enables an internal buffer for the bandgap voltage reference for use by the ADC module on one of its internal channels. 0 Bandgap buffer disabled. 1 Bandgap buffer enabled.

5.7.8 System Power Management Status and Control 2 Register (SPMSC2)

This register is used to report the status of the low voltage warning function, and to configure the stop mode behavior of the MCU.

	7	6	5	4	3	2	1	0
R	0	0	LVDV[1]	LVWV	PPDF	0	0	PPDC[2]
W						PPDACK		
Power-on Reset:	0	0	0	0	0	0	0	0
LVD Reset:	0	0	u	u	0	0	0	0
Any other Reset:	0	0	u	u	0	0	0	0

☐ = Unimplemented or Reserved   u = Unaffected by reset

[1] This bit can be written only once after power-on reset. Additional writes are ignored.

[2] This bit can be written only once after reset. Additional writes are ignored.

Figure 5-10. System Power Management Status and Control 2 Register (SPMSC2)

Table 5-11. SPMSC2 Register Field Descriptions

Field	Description
5 LVDV	**Low-Voltage Detect Voltage Select** — This write-once bit selects the low voltage detect (LVD) trip point setting. It also selects the warning voltage range. See Table 5-12.
4 LVWV	**Low-Voltage Warning Voltage Select** — This bit selects the low voltage warning (LVW) trip point voltage. See Table 5-12.
3 PPDF	**Partial Power Down Flag** — This read-only status bit indicates that the MCU has recovered from stop2 mode. 0 MCU has not recovered from stop2 mode. 1 MCU recovered from stop2 mode.
2 PPDACK	**Partial Power Down Acknowledge** — Writing a 1 to PPDACK clears the PPDF bit.
0 PPDC	**Partial Power Down Control** — This write-once bit controls whether stop2 or stop3 mode is selected. 0 Stop3 mode enabled. 1 Stop2, partial power down, mode enabled.

Table 5-12. LVD and LVW trip point typical values[1]

LVDV:LVWV	LVW Trip Point	LVD Trip Point
0:0	V_{LVW0} = 2.74 V	V_{LVD0} = 2.56 V
0:1	V_{LVW1} = 2.92 V	
1:0	V_{LVW2} = 4.3 V	V_{LVD1} = 4.0 V
1:1	V_{LVW3} = 4.6 V	

[1] See MC9S08SE8 Series *Data Sheet* for minimum and maximum values.

Chapter 6
Parallel Input/Output Control

This chapter explains software controls related to parallel input/output (I/O) and pin control. The MC9S08SE8 has three parallel I/O ports which include a total of 22 I/O pins, one input-only pin and one output-only pin. See Chapter 2, "Pins and Connections," for more information about pin assignments and external hardware of these pins.

Many of these I/O pins are shared with on-chip peripherals as shown in Table 2-1. The peripheral modules have priority over the I/Os, so when a peripheral is enabled, the I/O functions are disabled.

After reset, the shared peripheral functions are disabled and the pins are configured as inputs (PTxDDn = 0). The pin control functions for each pin (except for output only pin PTA4 which defaults to BKGD/MS pin) are configured as follows: slew rate control enabled (PTxSEn = 1), low drive strength selected (PTxDSn = 0), and internal pullups disabled (PTxPEn = 0).

NOTE

Not all I/O pins are available on all packages. To avoid extra current drain from floating input pins, the user's reset initialization routine in the application program must either enable on-chip pullup devices or change the direction of unconnected pins to outputs so the pins do not float.

6.1   Port Data and Data Direction

Reading and writing of parallel I/Os are performed through the port data registers. The direction, input or output, is controlled through the port data direction registers. The parallel I/O port function for an individual pin is illustrated in the block diagram shown in Figure 6-1.
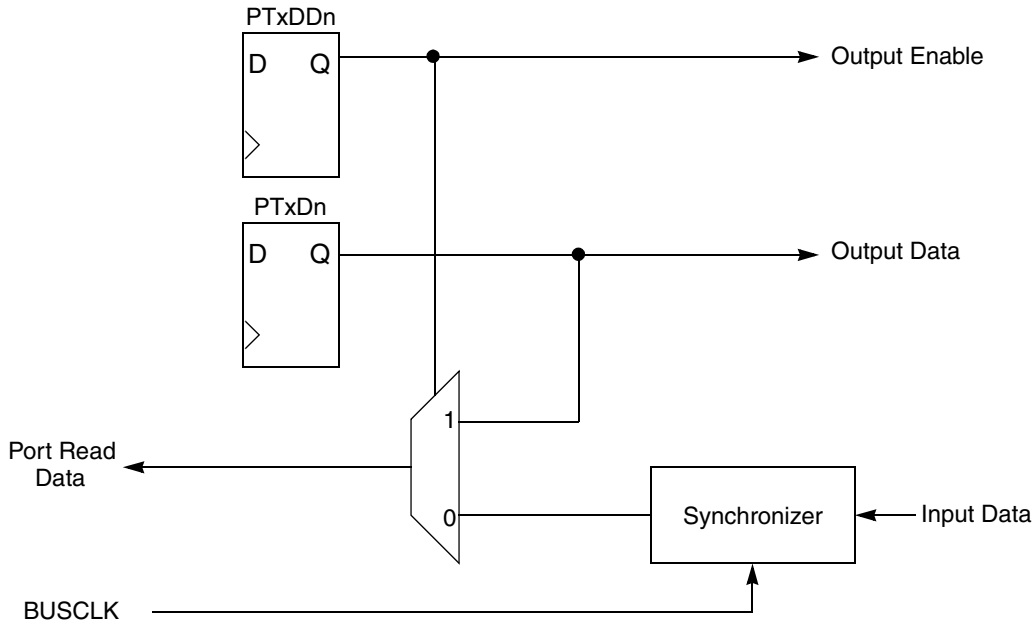
Figure 6-1. Parallel I/O Block Diagram

The data direction control bit (PTxDDn) determines whether the output buffer for the associated pin is enabled, and also controls the source for port data register reads. The input buffer for the associated pin is always enabled unless the pin is enabled as an analog function or is an output-only pin.

When a shared digital function is enabled for a pin, the output buffer is controlled by the shared function. However, the data direction register bit will continue to control the source for reads of the port data register.

When a shared analog function is enabled for a pin, both the input and output buffers are disabled. A value of 0 is read for any port data bit where the bit is an input (PTxDDn = 0) and the input buffer is disabled. In general, whenever a pin is shared with both an alternate digital function and an analog function, the analog function has priority such that if both the digital and analog functions are enabled, the analog function controls the pin.

Write to the port data register before changing the direction of a port pin to become an output. This ensures that the pin will not be driven momentarily with an old data value that happened to be in the port data register.

6.2 Pin Control

The pin control registers are located in the high-page register block of the memory. These registers are used to control pullups, slew rate, and drive strength for the I/O pins. The pin control registers operate independently of the parallel I/O registers.

6.2.1 Internal Pullup Enable

An internal pullup device can be enabled for each port pin by setting the corresponding bit in one of the pullup enable register (PTxPEn). The pullup device is disabled if the pin is configured as an output by the parallel I/O control logic or any shared peripheral function regardless of the state of the corresponding pullup enable register bit. The pullup device is also disabled if the pin is controlled by an analog function.

6.2.2 Output Slew Rate Control Enable

Slew rate control can be enabled for each port pin by setting the corresponding bit in one of the slew rate control register (PTxSEn). When enabled, slew control limits the rate at which an output can transit in order to reduce EMC emissions. Slew rate control has no effect on pins that are configured as inputs.

6.2.3 Output Drive Strength Select

An output pin can be selected to have high output drive strength by setting the corresponding bit in one of the drive strength select register (PTxDSn). When high drive is selected, a pin is capable of sourcing and sinking greater current. Even though every I/O pin can be selected as high drive, the total current source and sink limits for the MCU must not be exceeded. Drive strength selection affects the DC behavior of I/O pins. However, the AC behavior is also affected. High drive allows a pin to drive a greater load with the same switching speed as a low drive enabled pin into a smaller load. Because of this, the EMC emissions may be affected by enabling pins as high drive.

6.3 Ganged Output

The MC9S08SE8 series devices contain a feature that allows for up to eight port pins to be tied together externally to allow higher output current drive. The ganged output drive control register (GNGC) is used to enabled the ganged output feature and select which port pins will be used as ganged outputs. The GNGEN bit in GNGC enables ganged output. The GNGPS[7:1] bits are used to select which pin will be part of the ganged output.

When GNGEN is set, any pin that is enabled as a ganged output will be automatically configured as an output and follow the data, drive strength and slew rate control of PTC0. The ganged output drive pin mapping is shown in Table 6-1.

NOTE

See the DC characteristics in the electrical section for maximum Port I/O currents allowed for this MCU.

When a pin is enabled as ganged output, this feature will have priority over any digital module. An enabled analog function will have priority over the ganged output pin. See Table 2-1 for information on pin priority.

Table 6-1. Ganged Output Pin Enable

	GNGC Register Bits							
	GNGPS7	**GNGPS6**	**GNGPS5**	**GNGPS4**	**GNGPS3**	**GNGPS2**	**GNGPS1**	**GNGEN**
Port Pin [1]	PTB5	PTB4	PTB3	PTB2	PTC3	PTC2	PTC1	PTC0
Data Direction Control	Pin is automatically configured as output when pin is enabled as ganged output.							
Data Control	PTCD0 in PTCD controls data value of output							
Drive Strength Control	PTCDS0 in PTCDS controls drive strength of output							
Slew Rate Control	PTCSE0 in PTCSE controls slew rate of output							

[1] When GNGEN = 1, PTC0 is forced to an output, regardless of the value in PTCDD0 in PTCDD.

6.4   Pin Behavior in Stop Modes

Depending on the stop mode, I/O functions differently as the result of executing a STOP instruction. An explanation I/O pin behavior for the various stop modes follows:

- Stop2 mode is a partial power-down mode, whereby I/O latches are maintained in their state as before the STOP instruction was executed. CPU register status and the state of I/O registers must be saved in RAM before the STOP instruction is executed to place the MCU in stop2 mode. Upon recovery from stop2 mode, before accessing any I/O, the user must examine the state of the PPDF bit in the SPMSC2 register. If the PPDF bit is 0, I/O must be initialized as if a power on reset had occurred. If the PPDF bit is 1, I/O data previously stored in RAM, before the STOP instruction was executed, peripherals may require being initialized and restored to their pre-stop condition. The user must then write a 1 to the PPDACK bit in the SPMSC2 register. Access to I/O is now permitted again in the user application program.

- In stop3 mode, all I/O is maintained because internal logic circuity stays powered up. Upon recovery, normal I/O function is available to the user.

6.5   Parallel I/O and Pin Control Registers

This section provides information about the registers associated with the parallel I/O ports and pin control functions. The data and data direction registers are located in page zero of the memory map. The pullup, slew rate, drive strength, and interrupt control registers are located in the high page section of the memory map.

Refer to tables in Chapter 4, "Memory," for the absolute address assignments for all parallel I/O and their pin control registers. This section refers to registers and control bits only by their names. A Freescale Semiconductor provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

6.5.1 Port A Registers

Port A parallel I/O function is controlled by the registers listed below.

6.5.1.1 Port A Data Register (PTAD)

	7	6	5	4	3	2	1	0
R	PTAD7	PTAD6	PTA5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
W								
Reset:	0	0	0	0	0	0	0	0
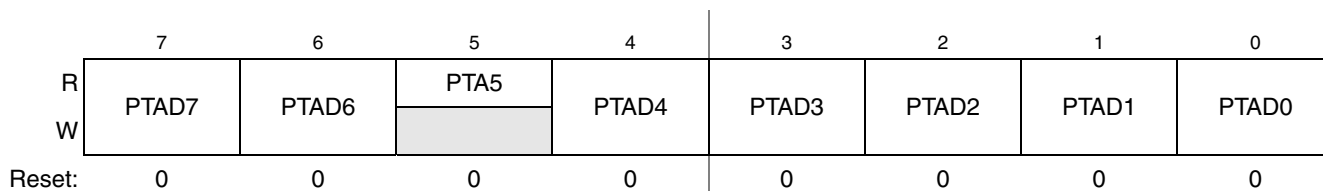
Figure 6-2. Port A Data Register (PTAD)

Table 6-2. PTAD Register Field Descriptions

Field	Description
7:0 PTAD[7:0]	**Port A Data Register Bits** — For port A pins that are inputs, reads return the logic level on the pin. For port A pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port A pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTAD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups/pulldowns disabled.

6.5.1.2 Port A Data Direction Register (PTADD)

	7	6	5	4	3	2	1	0
R	PTADD7	PTADD6	R	R	PTADD3	PTADD2	PTADD1	PTADD0
W								
Reset:	0	0	0	0	0	0	0	0

R	= Reserved
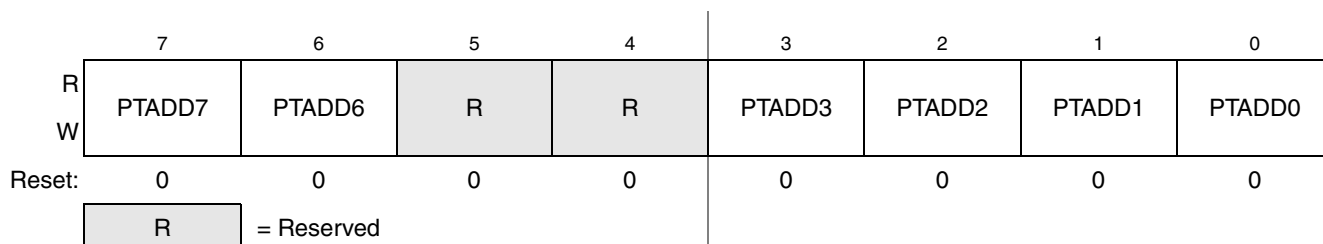
Figure 6-3. Port A Data Direction Register (PTADD)

Table 6-3. PTADD Register Field Descriptions

Field	Description
7:6, 3:0 PTADD[7:6, 3:0]	**Data Direction for Port A Bits** — These read/write bits control the direction of port A pins and what is read for PTAD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port A bit n and PTAD reads return the contents of PTADn.

6.5.1.3 Port A Pull Enable Register (PTAPE)

	7	6	5	4	3	2	1	0
R	PTAPE7	PTAPE6	PTAPE5	R	PTAPE3	PTAPE2	PTAPE1	PTAPE0
W								
Reset:	0	0	0	0	0	0	0	0

R	= Reserved
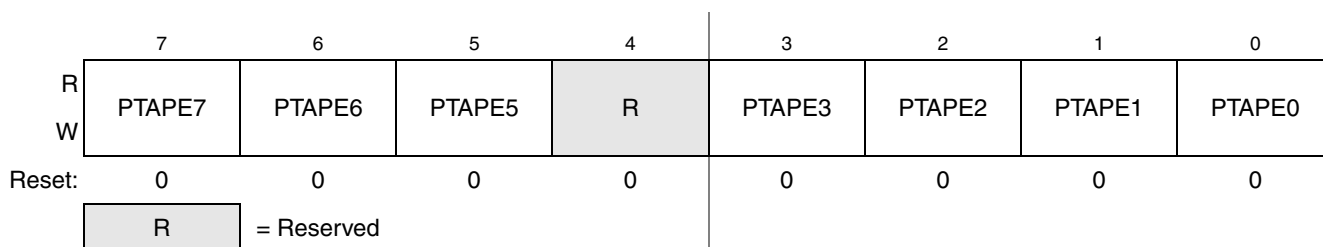
Figure 6-4. Internal Pull Enable for Port A Register (PTAPE)

Table 6-4. PTAPE Register Field Descriptions

Field	Description
7:5, 3:0 PTAPE[7:5, 3:0]	**Internal Pull Enable for Port A Bits** — Each of these control bits determines if the internal pullup or pulldown device is enabled for the associated PTA pin. For port A pins (except for PTA5) that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pullup/pulldown device disabled for port A bit n. 1 Internal pullup/pulldown device enabled for port A bit n.

6.5.1.4 Port A Slew Rate Enable Register (PTASE)

	7	6	5	4	3	2	1	0
R	PTASE7	PTASE6	R	PTASE4	PTASE3	PTASE2	PTASE1	PTASE0
W								
Reset:	1	1	1	1	1	1	1	1

R	= Reserved
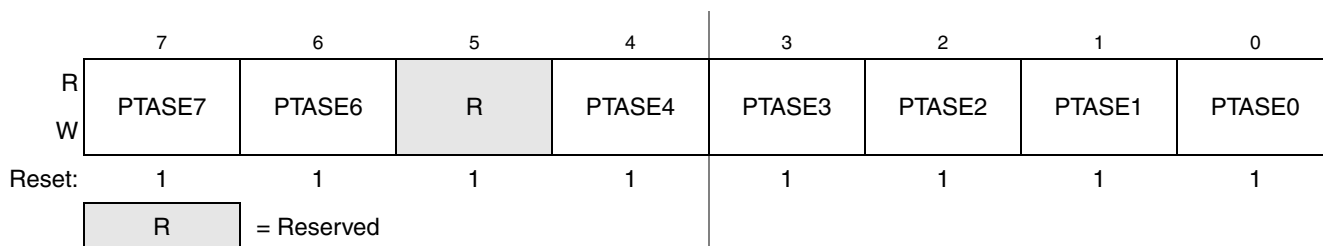
Figure 6-5. Slew Rate Enable for Port A Register (PTASE)

Table 6-5. PTASE Register Field Descriptions

Field	Description
7:6,4:0 PTASE [7:6, 4:0]	**Output Slew Rate Enable for Port A Bits** — Each of these control bits determines if the output slew rate control is enabled for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port A bit n. 1 Output slew rate control enabled for port A bit n.
5 Reserved	**Reserved Bits** — These bits are unused on this MCU, writes have no affect and could read as 1s or 0s.

6.5.1.5 Port A Drive Strength Selection Register (PTADS)

	7	6	5	4	3	2	1	0
R W	PTADS7	PTADS6	R	PTADS4	PTADS3	PTADS2	PTADS1	PTADS0
Reset:	0	0	0	0	0	0	0	0

R	= Reserved
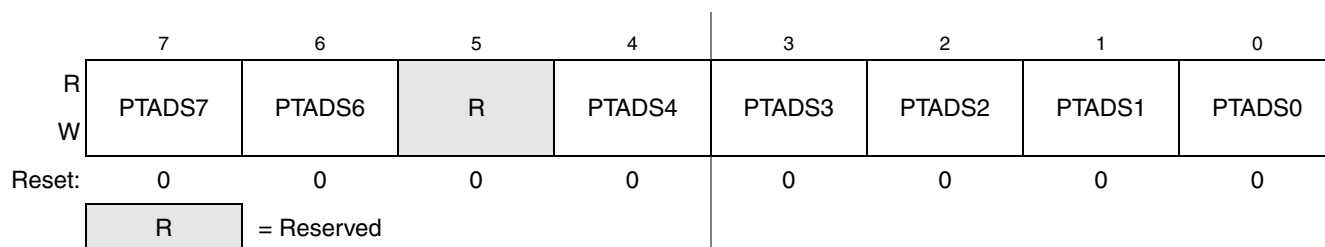
Figure 6-6. Drive Strength Selection for Port A Register (PTADS)

Table 6-6. PTADS Register Field Descriptions

Field	Description
7:6, 4:0 PTADS [7:6, 4:0]	**Output Drive Strength Selection for Port A Bits** — Each of these control bits selects between low and high output drive for the associated PTA pin. For port A pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port A bit n. 1 High output drive strength selected for port A bit n.
5 Reserved	**Reserved Bits** — These bits are unused on this MCU, writes have no affect and could read as 1s or 0s.

6.5.2 Port B Registers

Port B is controlled by the registers listed below.

6.5.2.1 Port B Data Register (PTBD)

	7	6	5	4	3	2	1	0
R W	PTBD7	PTBD6	PTBD5	PTBD4	PTBD3	PTBD2	PTBD1	PTBD0
Reset:	0	0	0	0	0	0	0	0
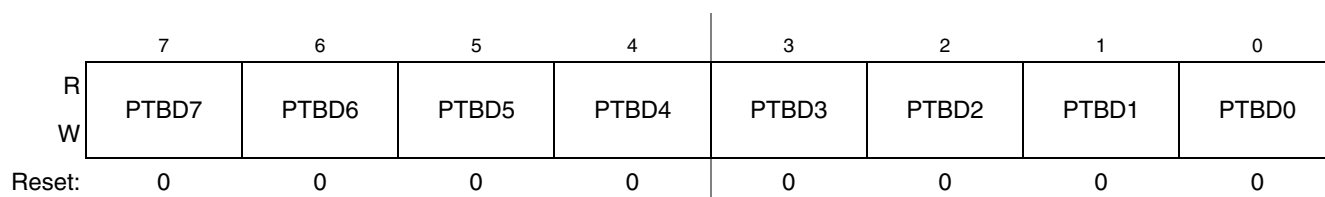
Figure 6-7. Port B Data Register (PTBD)

Table 6-7. PTBD Register Field Descriptions

Field	Description
7:0 PTBD[7:0]	**Port B Data Register Bits** — For port B pins that are inputs, reads return the logic level on the pin. For port B pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port B pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTBD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups/pulldowns disabled.

6.5.2.2 Port B Data Direction Register (PTBDD)

	7	6	5	4	3	2	1	0
R W	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0
Reset:	0	0	0	0	0	0	0	0
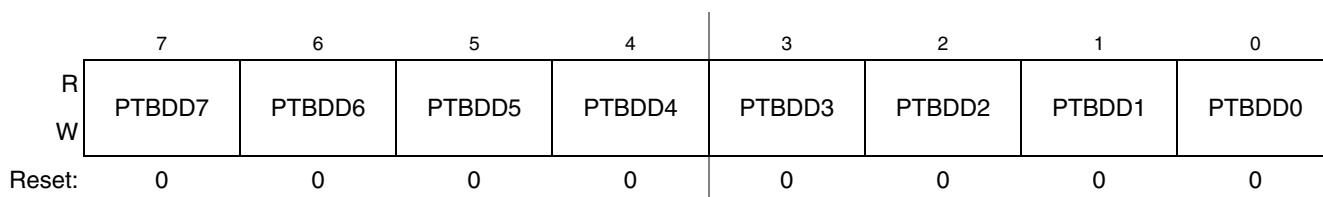
Figure 6-8. Port B Data Direction Register (PTBDD)

Table 6-8. PTBDD Register Field Descriptions

Field	Description
7:0 PTBDD[7:0]	**Data Direction for Port B Bits** — These read/write bits control the direction of port B pins and what is read for PTBD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port B bit n and PTBD reads return the contents of PTBDn.

6.5.2.3 Port B Pull Enable Register (PTBPE)

	7	6	5	4	3	2	1	0
R W	PTBPE7	PTBPE6	PTBPE5	PTBPE4	PTBPE3	PTBPE2	PTBPE1	PTBPE0
Reset:	0	0	0	0	0	0	0	0
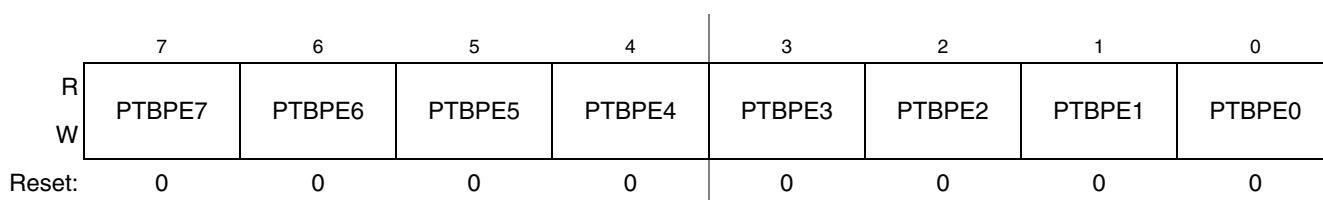
Figure 6-9. Internal Pull Enable for Port B Register (PTBPE)

Table 6-9. PTBPE Register Field Descriptions

Field	Description
7:0 PTBPE[7:0]	**Internal Pull Enable for Port B Bits** — Each of these control bits determines if the internal pullup or pulldown device is enabled for the associated PTB pin. For port B pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pullup/pulldown device disabled for port B bit n. 1 Internal pullup/pulldown device enabled for port B bit n.

6.5.2.4 Port B Slew Rate Enable Register (PTBSE)

	7	6	5	4	3	2	1	0
R	PTBSE7	PTBSE6	PTBSE5	PTBSE4	PTBSE3	PTBSE2	PTBSE1	PTBSE0
W								
Reset:	1	1	1	1	1	1	1	1
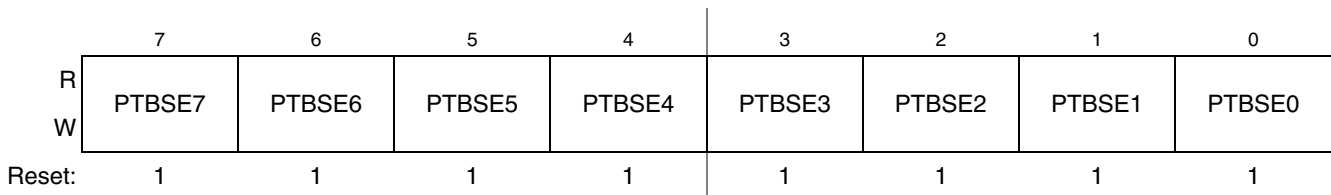
Figure 6-10. Slew Rate Enable for Port B Register (PTBSE)

Table 6-10. PTBSE Register Field Descriptions

Field	Description
7:0 PTBSE[7:0]	**Output Slew Rate Enable for Port B Bits** — Each of these control bits determines if the output slew rate control is enabled for the associated PTB pin. For port B pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port B bit n. 1 Output slew rate control enabled for port B bit n.

6.5.2.5 Port B Drive Strength Selection Register (PTBDS)

	7	6	5	4	3	2	1	0
R	PTBDS7	PTBDS6	PTBDS5	PTBDS4	PTBDS3	PTBDS2	PTBDS1	PTBDS0
W								
Reset:	0	0	0	0	0	0	0	0

Figure 6-11. Drive Strength Selection for Port B Register (PTBDS)

Table 6-11. PTBDS Register Field Descriptions

Field	Description
7:0 PTBDS[7:0]	**Output Drive Strength Selection for Port B Bits** — Each of these control bits selects between low and high output drive for the associated PTB pin. For port B pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port B bit n. 1 High output drive strength selected for port B bit n.

6.5.3 Port C Registers

Port C is controlled by the registers listed below.

6.5.3.1 Port C Data Register (PTCD)

	7	6	5	4	3	2	1	0
R	PTCD7	PTCD6	PTCD5	PTCD4	PTCD3	PTCD2	PTCD1	PTCD0
W								
Reset:	0	0	0	0	0	0	0	0
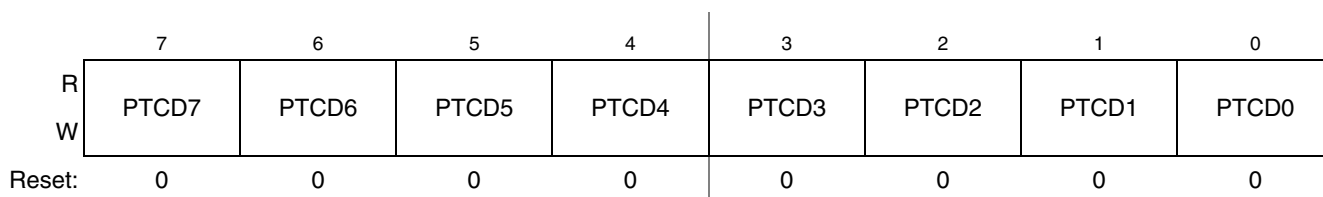
Figure 6-12. Port C Data Register (PTCD)

Table 6-12. PTCD Register Field Descriptions

Field	Description
7:0 PTCD[7:0]	**Port C Data Register Bits** — For port C pins that are inputs, reads return the logic level on the pin. For port C pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port C pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTCD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pullups disabled.

6.5.3.2 Port C Data Direction Register (PTCDD)

	7	6	5	4	3	2	1	0
R	PTCDD7	PTCDD6	PTCDD5	PTCDD4	PTCDD3	PTCDD2	PTCDD1	PTCDD0
W								
Reset:	0	0	0	0	0	0	0	0
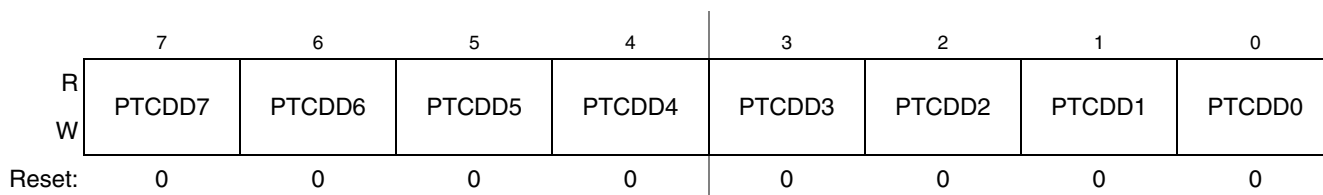
Figure 6-13. Port C Data Direction Register (PTCDD)

Table 6-13. PTCDD Register Field Descriptions

Field	Description
7:0 PTCDD[7:0]	**Data Direction for Port C Bits** — These read/write bits control the direction of port C pins and what is read for PTCD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port C bit n and PTCD reads return the contents of PTCDn.

6.5.3.3 Port C Pull Enable Register (PTCPE)

	7	6	5	4	3	2	1	0
R	PTCPE7	PTCPE6	PTCPE5	PTCPE4	PTCPE3	PTCPE2	PTCPE1	PTCPE0
W								
Reset:	0	0	0	0	0	0	0	0
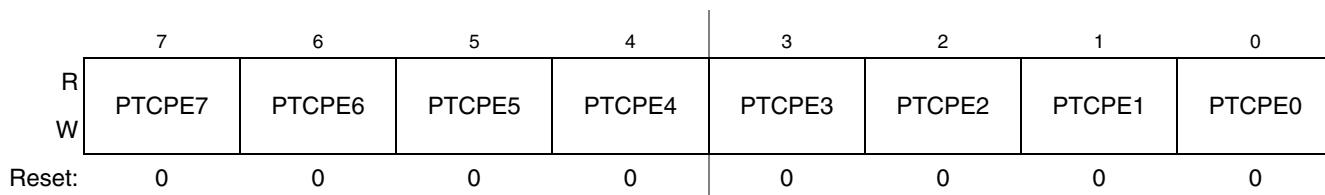
Figure 6-14. Internal Pull Enable for Port C Register (PTCPE)

Table 6-14. PTCPE Register Field Descriptions

Field	Description
7:0 PTCPE[7:0]	**Internal Pull Enable for Port C Bits** — Each of these control bits determines if the internal pullup device is enabled for the associated PTC pin. For port C pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pullup device disabled for port C bit n. 1 Internal pullup device enabled for port C bit n.

6.5.3.4 Port C Slew Rate Enable Register (PTCSE)

	7	6	5	4	3	2	1	0
R	PTCSE7	PTCSE6	PTCSE5	PTCSE4	PTCSE3	PTCSE2	PTCSE1	PTCSE0
W								
Reset:	1	1	1	1	1	1	1	1
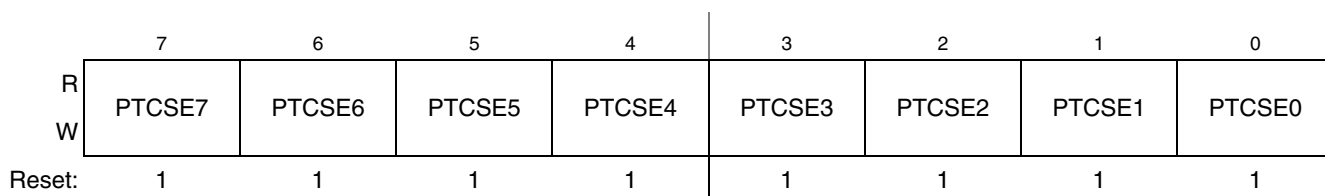
Figure 6-15. Slew Rate Enable for Port C Register (PTCSE)

Table 6-15. PTCSE Register Field Descriptions

Field	Description
7:0 PTCSE[7:0]	**Output Slew Rate Enable for Port C Bits** — Each of these control bits determines if the output slew rate control is enabled for the associated PTC pin. For port C pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port C bit n. 1 Output slew rate control enabled for port C bit n.

6.5.3.5 Port C Drive Strength Selection Register (PTCDS)

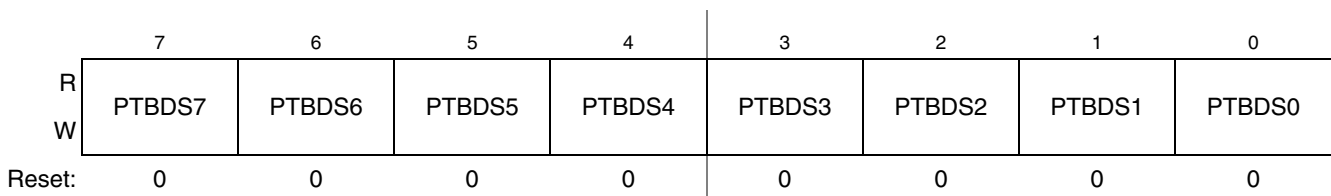|	7	6	5	4	3	2	1	0
R W	PTCDS7	PTCDS6	PTCDS5	PTCDS4	PTCDS3	PTCDS2	PTCDS1	PTCDS0
Reset:	0	0	0	0	0	0	0	0
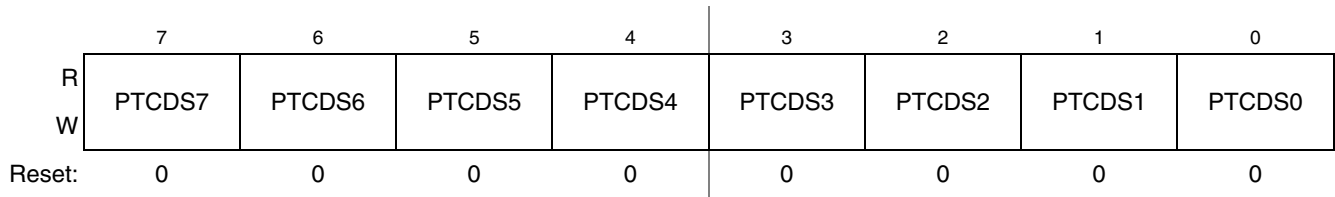
Figure 6-16. Drive Strength Selection for Port C Register (PTCDS)

Table 6-16. PTCDS Register Field Descriptions

Field	Description
7:0 PTCDS[7:0]	**Output Drive Strength Selection for Port C Bits** — Each of these control bits selects between low and high output drive for the associated PTC pin. For port C pins that are configured as inputs, these bits have no effect. 0 Low output drive strength selected for port C bit n. 1 High output drive strength selected for port C bit n.

6.5.3.6 Ganged Output Drive Control Register (GNGC)

	7	6	5	4	3	2	1	0
R W	GNGPS7	GNGPS6	GNGPS5	GNGPS4	GNGPS3	GNGPS2	GNGPS1	GNGEN
Reset:	0	0	0	0	0	0	0	0
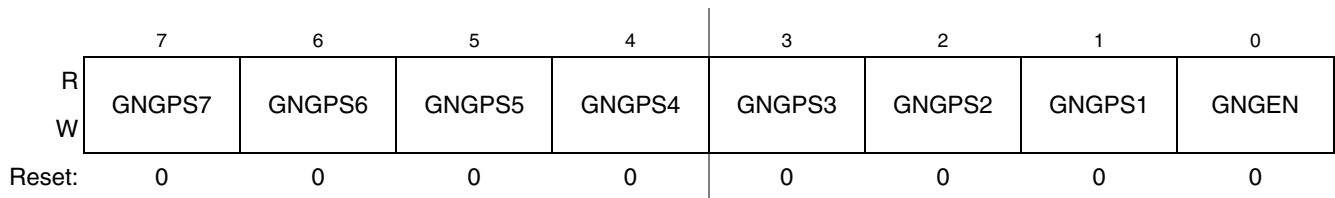
Figure 6-17. Ganged Output Drive Control Register (GNGC)

Table 6-17. GNGC Register Field Descriptions

Field	Description
7:1 GNGP[7:1]	**Ganged Output Pin Select Bits**— These control bits select whether the associated pin (see Table 6-1 for pins available) is enabled for ganged output. When GNGEN = 1, all enabled ganged output pins will be controlled by the data, drive strength and slew rate settings for PTC0. 0 Associated pin is not part of the ganged output drive. 1 Associated pin is part of the ganged output drive. Requires GNGEN = 1.
0 GNGEN	**Ganged Output Drive Enable Bit**— This control bit selects whether the ganged output drive feature is enabled. 0 Ganged output drive disabled. 1 Ganged output drive enabled. PTC0 forced to output regardless of the value of PTCDD0 in PTCDD.

Chapter 7
Central Processor Unit (S08CPUV3)

7.1 Introduction

This section provides summary information about the registers, addressing modes, and instruction set of the CPU of the HCS08 Family. For a more detailed discussion, refer to the *HCS08 Family Reference Manual, volume 1,* Freescale Semiconductor document order number HCS08RMV1/D.

The HCS08 CPU is fully source- and object-code-compatible with the M68HC08 CPU. Several instructions and enhanced addressing modes were added to improve C compiler efficiency and to support a new background debug system which replaces the monitor mode of earlier M68HC08 microcontrollers (MCU).

7.1.1 Features

Features of the HCS08 CPU include:

- Object code fully upward-compatible with M68HC05 and M68HC08 Families
- All registers and memory are mapped to a single 64-Kbyte address space
- 16-bit stack pointer (any size stack anywhere in 64-Kbyte address space)
- 16-bit index register (H:X) with powerful indexed addressing modes
- 8-bit accumulator (A)
- Many instructions treat X as a second general-purpose 8-bit register
- Seven addressing modes:
  — Inherent — Operands in internal registers
  — Relative — 8-bit signed offset to branch destination
  — Immediate — Operand in next object code byte(s)
  — Direct — Operand in memory at 0x0000–0x00FF
  — Extended — Operand anywhere in 64-Kbyte address space
  — Indexed relative to H:X — Five submodes including auto increment
  — Indexed relative to SP — Improves C efficiency dramatically
- Memory-to-memory data move instructions with four address mode combinations
- Overflow, half-carry, negative, zero, and carry condition codes support conditional branching on the results of signed, unsigned, and binary-coded decimal (BCD) operations
- Efficient bit manipulation instructions
- Fast 8-bit by 8-bit multiply and 16-bit by 8-bit divide instructions
- STOP and WAIT instructions to invoke low-power operating modes

7.2 Programmer's Model and CPU Registers

Figure 7-1 shows the five CPU registers. CPU registers are not part of the memory map.

Figure 7-1. CPU Registers

7.2.1 Accumulator (A)

The A accumulator is a general-purpose 8-bit register. One operand input to the arithmetic logic unit (ALU) is connected to the accumulator and the ALU results are often stored into the A accumulator after arithmetic and logical operations. The accumulator can be loaded from memory using various addressing modes to specify the address where the loaded data comes from, or the contents of A can be stored to memory using various addressing modes to specify the address where data from A will be stored.

Reset has no effect on the contents of the A accumulator.

7.2.2 Index Register (H:X)

This 16-bit register is actually two separate 8-bit registers (H and X), which often work together as a 16-bit address pointer where H holds the upper byte of an address and X holds the lower byte of the address. All indexed addressing mode instructions use the full 16-bit value in H:X as an index reference pointer; however, for compatibility with the earlier M68HC05 Family, some instructions operate only on the low-order 8-bit half (X).

Many instructions treat X as a second general-purpose 8-bit register that can be used to hold 8-bit data values. X can be cleared, incremented, decremented, complemented, negated, shifted, or rotated. Transfer instructions allow data to be transferred from A or transferred to A where arithmetic and logical operations can then be performed.

For compatibility with the earlier M68HC05 Family, H is forced to 0x00 during reset. Reset has no effect on the contents of X.

7.2.3 Stack Pointer (SP)

This 16-bit address pointer register points at the next available location on the automatic last-in-first-out (LIFO) stack. The stack may be located anywhere in the 64-Kbyte address space that has RAM and can be any size up to the amount of available RAM. The stack is used to automatically save the return address for subroutine calls, the return address and CPU registers during interrupts, and for local variables. The AIS (add immediate to stack pointer) instruction adds an 8-bit signed immediate value to SP. This is most often used to allocate or deallocate space for local variables on the stack.

SP is forced to 0x00FF at reset for compatibility with the earlier M68HC05 Family. HCS08 programs normally change the value in SP to the address of the last location (highest address) in on-chip RAM during reset initialization to free up direct page RAM (from the end of the on-chip registers to 0x00FF).

The RSP (reset stack pointer) instruction was included for compatibility with the M68HC05 Family and is seldom used in new HCS08 programs because it only affects the low-order half of the stack pointer.

7.2.4 Program Counter (PC)

The program counter is a 16-bit register that contains the address of the next instruction or operand to be fetched.

During normal program execution, the program counter automatically increments to the next sequential memory location every time an instruction or operand is fetched. Jump, branch, interrupt, and return operations load the program counter with an address other than that of the next sequential location. This is called a change-of-flow.

During reset, the program counter is loaded with the reset vector that is located at 0xFFFE and 0xFFFF. The vector stored there is the address of the first instruction that will be executed after exiting the reset state.

7.2.5 Condition Code Register (CCR)

The 8-bit condition code register contains the interrupt mask (I) and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code bits in general terms. For a more detailed explanation of how each instruction sets the CCR bits, refer to the *HCS08 Family Reference Manual, volume 1,* Freescale Semiconductor document order number HCS08RMv1.

Figure 7-2. Condition Code Register

Table 7-1. CCR Register Field Descriptions

Field	Description
7 V	**Two's Complement Overflow Flag** — The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag. 0 No overflow 1 Overflow
4 H	**Half-Carry Flag** — The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C condition code bits to automatically add a correction value to the result from a previous ADD or ADC on BCD operands to correct the result to a valid BCD value. 0 No carry between bits 3 and 4 1 Carry between bits 3 and 4
3 I	**Interrupt Mask Bit** — When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the first instruction of the interrupt service routine is executed. Interrupts are not recognized at the instruction boundary after any instruction that clears I (CLI or TAP). This ensures that the next instruction after a CLI or TAP will always be executed without the possibility of an intervening interrupt, provided I was set. 0 Interrupts enabled 1 Interrupts disabled
2 N	**Negative Flag** — The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result. Simply loading or storing an 8-bit or 16-bit value causes N to be set if the most significant bit of the loaded or stored value was 1. 0 Non-negative result 1 Negative result
1 Z	**Zero Flag** — The CPU sets the zero flag when an arithmetic operation, logic operation, or data manipulation produces a result of 0x00 or 0x0000. Simply loading or storing an 8-bit or 16-bit value causes Z to be set if the loaded or stored value was all 0s. 0 Non-zero result 1 Zero result
0 C	**Carry/Borrow Flag** — The CPU sets the carry/borrow flag when an addition operation produces a carry out of bit 7 of the accumulator or when a subtraction operation requires a borrow. Some instructions — such as bit test and branch, shift, and rotate — also clear or set the carry/borrow flag. 0 No carry out of bit 7 1 Carry out of bit 7

7.3   Addressing Modes

Addressing modes define the way the CPU accesses operands and data. In the HCS08, all memory, status and control registers, and input/output (I/O) ports share a single 64-Kbyte linear address space so a 16-bit binary address can uniquely identify any memory location. This arrangement means that the same instructions that access variables in RAM can also be used to access I/O and control registers or nonvolatile program space.

Some instructions use more than one addressing mode. For instance, move instructions use one addressing mode to specify the source operand and a second addressing mode to specify the destination address. Instructions such as BRCLR, BRSET, CBEQ, and DBNZ use one addressing mode to specify the location of an operand for a test and then use relative addressing mode to specify the branch destination address when the tested condition is true. For BRCLR, BRSET, CBEQ, and DBNZ, the addressing mode listed in the instruction set tables is the addressing mode needed to access the operand to be tested, and relative addressing mode is implied for the branch destination.

7.3.1   Inherent Addressing Mode (INH)

In this addressing mode, operands needed to complete the instruction (if any) are located within CPU registers so the CPU does not need to access memory to get any operands.

7.3.2   Relative Addressing Mode (REL)

Relative addressing mode is used to specify the destination location for branch instructions. A signed 8-bit offset value is located in the memory location immediately following the opcode. During execution, if the branch condition is true, the signed offset is sign-extended to a 16-bit value and is added to the current contents of the program counter, which causes program execution to continue at the branch destination address.

7.3.3   Immediate Addressing Mode (IMM)

In immediate addressing mode, the operand needed to complete the instruction is included in the object code immediately following the instruction opcode in memory. In the case of a 16-bit immediate operand, the high-order byte is located in the next memory location after the opcode, and the low-order byte is located in the next memory location after that.

7.3.4   Direct Addressing Mode (DIR)

In direct addressing mode, the instruction includes the low-order eight bits of an address in the direct page (0x0000–0x00FF). During execution a 16-bit address is formed by concatenating an implied 0x00 for the high-order half of the address and the direct address from the instruction to get the 16-bit address where the desired operand is located. This is faster and more memory efficient than specifying a complete 16-bit address for the operand.

7.3.5 Extended Addressing Mode (EXT)

In extended addressing mode, the full 16-bit address of the operand is located in the next two bytes of program memory after the opcode (high byte first).

7.3.6 Indexed Addressing Mode

Indexed addressing mode has seven variations including five that use the 16-bit H:X index register pair and two that use the stack pointer as the base reference.

7.3.6.1 Indexed, No Offset (IX)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair as the address of the operand needed to complete the instruction.

7.3.6.2 Indexed, No Offset with Post Increment (IX+)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair as the address of the operand needed to complete the instruction. The index register pair is then incremented (H:X = H:X + 0x0001) after the operand has been fetched. This addressing mode is only used for MOV and CBEQ instructions.

7.3.6.3 Indexed, 8-Bit Offset (IX1)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair plus an unsigned 8-bit offset included in the instruction as the address of the operand needed to complete the instruction.

7.3.6.4 Indexed, 8-Bit Offset with Post Increment (IX1+)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair plus an unsigned 8-bit offset included in the instruction as the address of the operand needed to complete the instruction. The index register pair is then incremented (H:X = H:X + 0x0001) after the operand has been fetched. This addressing mode is used only for the CBEQ instruction.

7.3.6.5 Indexed, 16-Bit Offset (IX2)

This variation of indexed addressing uses the 16-bit value in the H:X index register pair plus a 16-bit offset included in the instruction as the address of the operand needed to complete the instruction.

7.3.6.6 SP-Relative, 8-Bit Offset (SP1)

This variation of indexed addressing uses the 16-bit value in the stack pointer (SP) plus an unsigned 8-bit offset included in the instruction as the address of the operand needed to complete the instruction.

7.3.6.7 SP-Relative, 16-Bit Offset (SP2)

This variation of indexed addressing uses the 16-bit value in the stack pointer (SP) plus a 16-bit offset included in the instruction as the address of the operand needed to complete the instruction.

7.4 Special Operations

The CPU performs a few special operations that are similar to instructions but do not have opcodes like other CPU instructions. In addition, a few instructions such as STOP and WAIT directly affect other MCU circuitry. This section provides additional information about these operations.

7.4.1 Reset Sequence

Reset can be caused by a power-on-reset (POR) event, internal conditions such as the COP (computer operating properly) watchdog, or by assertion of an external active-low reset pin. When a reset event occurs, the CPU immediately stops whatever it is doing (the MCU does not wait for an instruction boundary before responding to a reset event). For a more detailed discussion about how the MCU recognizes resets and determines the source, refer to the Resets, Interrupts, and System Configuration chapter.

The reset event is considered concluded when the sequence to determine whether the reset came from an internal source is done and when the reset pin is no longer asserted. At the conclusion of a reset event, the CPU performs a 6-cycle sequence to fetch the reset vector from 0xFFFE and 0xFFFF and to fill the instruction queue in preparation for execution of the first program instruction.

7.4.2 Interrupt Sequence

When an interrupt is requested, the CPU completes the current instruction before responding to the interrupt. At this point, the program counter is pointing at the start of the next instruction, which is where the CPU should return after servicing the interrupt. The CPU responds to an interrupt by performing the same sequence of operations as for a software interrupt (SWI) instruction, except the address used for the vector fetch is determined by the highest priority interrupt that is pending when the interrupt sequence started.

The CPU sequence for an interrupt is:

1. Store the contents of PCL, PCH, X, A, and CCR on the stack, in that order.
2. Set the I bit in the CCR.
3. Fetch the high-order half of the interrupt vector.
4. Fetch the low-order half of the interrupt vector.
5. Delay for one free bus cycle.
6. Fetch three bytes of program information starting at the address indicated by the interrupt vector to fill the instruction queue in preparation for execution of the first instruction in the interrupt service routine.

After the CCR contents are pushed onto the stack, the I bit in the CCR is set to prevent other interrupts while in the interrupt service routine. Although it is possible to clear the I bit with an instruction in the

interrupt service routine, this would allow nesting of interrupts (which is not recommended because it leads to programs that are difficult to debug and maintain).

For compatibility with the earlier M68HC05 MCUs, the high-order half of the H:X index register pair (H) is not saved on the stack as part of the interrupt sequence. The user must use a PSHH instruction at the beginning of the service routine to save H and then use a PULH instruction just before the RTI that ends the interrupt service routine. It is not necessary to save H if you are certain that the interrupt service routine does not use any instructions or auto-increment addressing modes that might change the value of H.

The software interrupt (SWI) instruction is like a hardware interrupt except that it is not masked by the global I bit in the CCR and it is associated with an instruction opcode within the program so it is not asynchronous to program execution.

7.4.3 Wait Mode Operation

The WAIT instruction enables interrupts by clearing the I bit in the CCR. It then halts the clocks to the CPU to reduce overall power consumption while the CPU is waiting for the interrupt or reset event that will wake the CPU from wait mode. When an interrupt or reset event occurs, the CPU clocks will resume and the interrupt or reset event will be processed normally.

If a serial BACKGROUND command is issued to the MCU through the background debug interface while the CPU is in wait mode, CPU clocks will resume and the CPU will enter active background mode where other serial background commands can be processed. This ensures that a host development system can still gain access to a target MCU even if it is in wait mode.

7.4.4 Stop Mode Operation

Usually, all system clocks, including the crystal oscillator (when used), are halted during stop mode to minimize power consumption. In such systems, external circuitry is needed to control the time spent in stop mode and to issue a signal to wake up the target MCU when it is time to resume processing. Unlike the earlier M68HC05 and M68HC08 MCUs, the HCS08 can be configured to keep a minimum set of clocks running in stop mode. This optionally allows an internal periodic signal to wake the target MCU from stop mode.

When a host debug system is connected to the background debug pin (BKGD) and the ENBDM control bit has been set by a serial command through the background interface (or because the MCU was reset into active background mode), the oscillator is forced to remain active when the MCU enters stop mode. In this case, if a serial BACKGROUND command is issued to the MCU through the background debug interface while the CPU is in stop mode, CPU clocks will resume and the CPU will enter active background mode where other serial background commands can be processed. This ensures that a host development system can still gain access to a target MCU even if it is in stop mode.

Recovery from stop mode depends on the particular HCS08 and whether the oscillator was stopped in stop mode. Refer to the Modes of Operation chapter for more details.

7.4.5   BGND Instruction

The BGND instruction is new to the HCS08 compared to the M68HC08. BGND would not be used in normal user programs because it forces the CPU to stop processing user instructions and enter the active background mode. The only way to resume execution of the user program is through reset or by a host debug system issuing a GO, TRACE1, or TAGGO serial command through the background debug interface.

Software-based breakpoints can be set by replacing an opcode at the desired breakpoint address with the BGND opcode. When the program reaches this breakpoint address, the CPU is forced to active background mode rather than continuing the user program.

7.5 HCS08 Instruction Set Summary

Table 7-2 provides a summary of the HCS08 instruction set in all possible addressing modes. The table shows operand construction, execution time in internal bus clock cycles, and cycle-by-cycle details for each addressing mode variation of each instruction.

Table 7-2. Instruction Set Summary (Sheet 1 of 9)
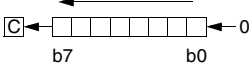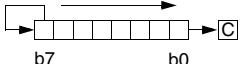
Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR V 1 1 H	I N Z C
ADC #opr8i ADC opr8a ADC opr16a ADC oprx16,X ADC oprx8,X ADC ,X ADC oprx16,SP ADC oprx8,SP	Add with Carry A ← (A) + (M) + (C)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A9 ii B9 dd C9 hh ll D9 ee ff E9 ff F9 9E D9 ee ff 9E E9 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↕ 1 1 ↕	– ↕ ↕ ↕

ADD #opr8i
ADD opr8a
ADD opr16a
ADD oprx16,X
ADD oprx8,X
ADD ,X
ADD oprx16,SP
ADD oprx8,SP
	Add without Carry
	A ← (A) + (M)
		IMM
		DIR
		EXT
		IX2
		IX1
		IX
		SP2
		SP1
			AB ii
			BB dd
			CB hh ll
			DB ee ff
			EB ff
			FB
			9E DB ee ff
			9E EB ff
				2
				3
				4
				4
				3
				3
				5
				4
					pp
					rpp
					prpp
					prpp
					rpp
					rfp
					pprpp
					prpp
						↕ 1 1 ↕	– ↕ ↕ ↕

AIS #opr8i	Add Immediate Value (Signed) to Stack Pointer SP ← (SP) + (M)	IMM	A7 ii	2	pp	– 1 1 –	– – – –
AIX #opr8i	Add Immediate Value (Signed) to Index Register (H:X) H:X ← (H:X) + (M)	IMM	AF ii	2	pp	– 1 1 –	– – – –
AND #opr8i AND opr8a AND opr16a AND oprx16,X AND oprx8,X AND ,X AND oprx16,SP AND oprx8,SP	Logical AND A ← (A) & (M)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A4 ii B4 dd C4 hh ll D4 ee ff E4 ff F4 9E D4 ee ff 9E E4 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 –	– ↕ ↕ –
ASL opr8a ASLA ASLX ASL oprx8,X ASL ,X ASL oprx8,SP	Arithmetic Shift Left (Same as LSL)	DIR INH INH IX1 IX SP1	38 dd 48 58 68 ff 78 9E 68 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕
ASR opr8a ASRA ASRX ASR oprx8,X ASR ,X ASR oprx8,SP	Arithmetic Shift Right 	DIR INH INH IX1 IX SP1	37 dd 47 57 67 ff 77 9E 67 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕
BCC rel	Branch if Carry Bit Clear (if C = 0)	REL	24 rr	3	ppp	– 1 1 –	– – – –

Table 7-2. Instruction Set Summary (Sheet 2 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR			
						V 1 1 H		**I N Z C**	
BCLR *n,opr8a*	Clear Bit n in Memory (Mn ← 0)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	11 dd 13 dd 15 dd 17 dd 19 dd 1B dd 1D dd 1F dd	5 5 5 5 5 5 5 5	rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp	– 1 1 –		– – – –	
BCS *rel*	Branch if Carry Bit Set (if C = 1) (Same as BLO)	REL	25 rr	3	ppp	– 1 1 –		– – – –	
BEQ *rel*	Branch if Equal (if Z = 1)	REL	27 rr	3	ppp	– 1 1 –		– – – –	
BGE *rel*	Branch if Greater Than or Equal To (if N ⊕ V = 0) (Signed)	REL	90 rr	3	ppp	– 1 1 –		– – – –	
BGND	Enter active background if ENBDM=1 Waits for and processes BDM commands until GO, TRACE1, or TAGGO	INH	82	5+	fp...ppp	– 1 1 –		– – – –	
BGT *rel*	Branch if Greater Than (if Z | (N ⊕ V) = 0) (Signed)	REL	92 rr	3	ppp	– 1 1 –		– – – –	
BHCC *rel*	Branch if Half Carry Bit Clear (if H = 0)	REL	28 rr	3	ppp	– 1 1 –		– – – –	
BHCS *rel*	Branch if Half Carry Bit Set (if H = 1)	REL	29 rr	3	ppp	– 1 1 –		– – – –	
BHI *rel*	Branch if Higher (if C | Z = 0)	REL	22 rr	3	ppp	– 1 1 –		– – – –	
BHS *rel*	Branch if Higher or Same (if C = 0) (Same as BCC)	REL	24 rr	3	ppp	– 1 1 –		– – – –	
BIH *rel*	Branch if IRQ Pin High (if IRQ pin = 1)	REL	2F rr	3	ppp	– 1 1 –		– – – –	
BIL *rel*	Branch if IRQ Pin Low (if IRQ pin = 0)	REL	2E rr	3	ppp	– 1 1 –		– – – –	
BIT #*opr8i* BIT *opr8a* BIT *opr16a* BIT *oprx16,X* BIT *oprx8,X* BIT ,X BIT *oprx16,SP* BIT *oprx8,SP*	Bit Test (A) & (M) (CCR Updated but Operands Not Changed)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A5 ii B5 dd C5 hh ll D5 ee ff E5 ff F5 9E D5 ee ff 9E E5 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 –		– ↕ ↕ –	
BLE *rel*	Branch if Less Than or Equal To (if Z | (N ⊕ V) = 1) (Signed)	REL	93 rr	3	ppp	– 1 1 –		– – – –	
BLO *rel*	Branch if Lower (if C = 1) (Same as BCS)	REL	25 rr	3	ppp	– 1 1 –		– – – –	
BLS *rel*	Branch if Lower or Same (if C | Z = 1)	REL	23 rr	3	ppp	– 1 1 –		– – – –	
BLT *rel*	Branch if Less Than (if N ⊕ V = 1) (Signed)	REL	91 rr	3	ppp	– 1 1 –		– – – –	
BMC *rel*	Branch if Interrupt Mask Clear (if I = 0)	REL	2C rr	3	ppp	– 1 1 –		– – – –	
BMI *rel*	Branch if Minus (if N = 1)	REL	2B rr	3	ppp	– 1 1 –		– – – –	
BMS *rel*	Branch if Interrupt Mask Set (if I = 1)	REL	2D rr	3	ppp	– 1 1 –		– – – –	
BNE *rel*	Branch if Not Equal (if Z = 0)	REL	26 rr	3	ppp	– 1 1 –		– – – –	

Table 7-2. Instruction Set Summary (Sheet 3 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	V 1 1 H	I N Z C
BPL *rel*	Branch if Plus (if N = 0)	REL	2A rr	3	ppp	– 1 1 –	– – – –
BRA *rel*	Branch Always (if I = 1)	REL	20 rr	3	ppp	– 1 1 –	– – – –
BRCLR *n,opr8a,rel*	Branch if Bit *n* in Memory Clear (if (Mn) = 0)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 dd rr 03 dd rr 05 dd rr 07 dd rr 09 dd rr 0B dd rr 0D dd rr 0F dd rr	5 5 5 5 5 5 5 5	rpppp rpppp rpppp rpppp rpppp rpppp rpppp rpppp	– 1 1 –	– – – ↕
BRN *rel*	Branch Never (if I = 0)	REL	21 rr	3	ppp	– 1 1 –	– – – –
BRSET *n,opr8a,rel*	Branch if Bit *n* in Memory Set (if (Mn) = 1)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 dd rr 02 dd rr 04 dd rr 06 dd rr 08 dd rr 0A dd rr 0C dd rr 0E dd rr	5 5 5 5 5 5 5 5	rpppp rpppp rpppp rpppp rpppp rpppp rpppp rpppp	– 1 1 –	– – – ↕
BSET *n,opr8a*	Set Bit *n* in Memory (Mn ← 1)	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	10 dd 12 dd 14 dd 16 dd 18 dd 1A dd 1C dd 1E dd	5 5 5 5 5 5 5 5	rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp rfwpp	– 1 1 –	– – – –
BSR *rel*	Branch to Subroutine PC ← (PC) + $0002 push (PCL); SP ← (SP) − $0001 push (PCH); SP ← (SP) − $0001 PC ← (PC) + *rel*	REL	AD rr	5	ssppp	– 1 1 –	– – – –
CBEQ *opr8a,rel* CBEQA #*opr8i,rel* CBEQX #*opr8i,rel* CBEQ *oprx8,X+,rel* CBEQ ,X+,*rel* CBEQ *oprx8,SP,rel*	Compare and... Branch if (A) = (M) Branch if (A) = (M) Branch if (X) = (M) Branch if (A) = (M) Branch if (A) = (M) Branch if (A) = (M)	DIR IMM IMM IX1+ IX+ SP1	31 dd rr 41 ii rr 51 ii rr 61 ff rr 71 rr 9E 61 ff rr	5 4 4 5 5 6	rpppp pppp pppp rpppp rfppp prpppp	– 1 1 –	– – – –
CLC	Clear Carry Bit (C ← 0)	INH	98	1	p	– 1 1 –	– – – 0
CLI	Clear Interrupt Mask Bit (I ← 0)	INH	9A	1	p	– 1 1 –	0 – – –
CLR *opr8a* CLRA CLRX CLRH CLR *oprx8,X* CLR ,X CLR *oprx8,SP*	Clear M ← $00 A ← $00 X ← $00 H ← $00 M ← $00 M ← $00 M ← $00	DIR INH INH INH IX1 IX SP1	3F dd 4F 5F 8C 6F ff 7F 9E 6F ff	5 1 1 1 5 4 6	rfwpp p p p rfwpp rfwp prfwpp	0 1 1 –	– 0 1 –

Table 7-2. Instruction Set Summary (Sheet 4 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR			
						V 1 1 H		**I N Z C**	

CMP #opr8i
CMP opr8a
CMP opr16a
CMP oprx16,X
CMP oprx8,X
CMP ,X
CMP oprx16,SP
CMP oprx8,SP
	Compare Accumulator with Memory
	A – M
	(CCR Updated But Operands Not Changed)
		IMM
		DIR
		EXT
		IX2
		IX1
		IX
		SP2
		SP1
			A1 ii
			B1 dd
			C1 hh ll
			D1 ee ff
			E1 ff
			F1
			9E D1 ee ff
			9E E1 ff
				2
				3
				4
				4
				3
				3
				5
				4
					pp
					rpp
					prpp
					prpp
					rpp
					rfp
					pprpp
					prpp
						↕ 1 1 –	– ↕ ↕ ↕	

COM opr8a COMA COMX COM oprx8,X COM ,X COM oprx8,SP	Complement M ← (M̄)= $FF – (M) (One's Complement) A ← (Ā) = $FF – (A) X ← (X̄) = $FF – (X) M ← (M̄) = $FF – (M) M ← (M̄) = $FF – (M) M ← (M̄) = $FF – (M)	DIR INH INH IX1 IX SP1	33 dd 43 53 63 ff 73 9E 63 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	0 1 1 –	– ↕ ↕ 1	
CPHX opr16a CPHX #opr16i CPHX opr8a CPHX oprx8,SP	Compare Index Register (H:X) with Memory (H:X) – (M:M + $0001) (CCR Updated But Operands Not Changed)	EXT IMM DIR SP1	3E hh ll 65 jj kk 75 dd 9E F3 ff	6 3 5 6	prrfpp ppp rrfpp prrfpp	↕ 1 1 –	– ↕ ↕ ↕	
CPX #opr8i CPX opr8a CPX opr16a CPX oprx16,X CPX oprx8,X CPX ,X CPX oprx16,SP CPX oprx8,SP	Compare X (Index Register Low) with Memory X – M (CCR Updated But Operands Not Changed)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A3 ii B3 dd C3 hh ll D3 ee ff E3 ff F3 9E D3 ee ff 9E E3 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↕ 1 1 –	– ↕ ↕ ↕	
DAA	Decimal Adjust Accumulator After ADD or ADC of BCD Values	INH	72	1	p	U 1 1–	– ↕ ↕ ↕	
DBNZ opr8a,rel DBNZA rel DBNZX rel DBNZ oprx8,X,rel DBNZ ,X,rel DBNZ oprx8,SP,rel	Decrement A, X, or M and Branch if Not Zero (if (result) ≠ 0) DBNZX Affects X Not H	DIR INH INH IX1 IX SP1	3B dd rr 4B rr 5B rr 6B ff rr 7B rr 9E 6B ff rr	7 4 4 7 6 8	rfwpppp fppp fppp rfwppppp rfwppp prfwppppp	– 1 1–	– – – –	
DEC opr8a DECA DECX DEC oprx8,X DEC ,X DEC oprx8,SP	Decrement M ← (M) – $01 A ← (A) – $01 X ← (X) – $01 M ← (M) – $01 M ← (M) – $01 M ← (M) – $01	DIR INH INH IX1 IX SP1	3A dd 4A 5A 6A ff 7A 9E 6A ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ –	
DIV	Divide A ← (H:A)÷(X); H ← Remainder	INH	52	6	fffffp	– 1 1–	– – ↕ ↕	
EOR #opr8i EOR opr8a EOR opr16a EOR oprx16,X EOR oprx8,X EOR ,X EOR oprx16,SP EOR oprx8,SP	Exclusive OR Memory with Accumulator A ← (A ⊕ M)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A8 ii B8 dd C8 hh ll D8 ee ff E8 ff F8 9E D8 ee ff 9E E8 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 –	– ↕ ↕ –	

Table 7-2. Instruction Set Summary (Sheet 5 of 9)
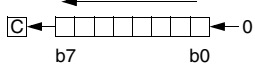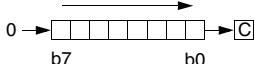
Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	V 1 1 H	I N Z C
INC opr8a INCA INCX INC oprx8,X INC ,X INC oprx8,SP	Increment M ← (M) + $01 A ← (A) + $01 X ← (X) + $01 M ← (M) + $01 M ← (M) + $01 M ← (M) + $01	DIR INH INH IX1 IX SP1	3C dd 4C 5C 6C ff 7C 9E 6C ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ –
JMP opr8a JMP opr16a JMP oprx16,X JMP oprx8,X JMP ,X	Jump PC ← Jump Address	DIR EXT IX2 IX1 IX	BC dd CC hh ll DC ee ff EC ff FC	3 4 4 3 3	ppp pppp pppp ppp ppp	– 1 1 –	– – – –
JSR opr8a JSR opr16a JSR oprx16,X JSR oprx8,X JSR ,X	Jump to Subroutine PC ← (PC) + n (n = 1, 2, or 3) Push (PCL); SP ← (SP) – $0001 Push (PCH); SP ← (SP) – $0001 PC ← Unconditional Address	DIR EXT IX2 IX1 IX	BD dd CD hh ll DD ee ff ED ff FD	5 6 6 5 5	ssppp pssppp pssppp ssppp ssppp	– 1 1 –	– – – –

LDA #opr8i
LDA opr8a
LDA opr16a
LDA oprx16,X
LDA oprx8,X
LDA ,X
LDA oprx16,SP
LDA oprx8,SP
	Load Accumulator from Memory
	A ← (M)
		IMM
		DIR
		EXT
		IX2
		IX1
		IX
		SP2
		SP1
			A6 ii
			B6 dd
			C6 hh ll
			D6 ee ff
			E6 ff
			F6
			9E D6 ee ff
			9E E6 ff
				2
				3
				4
				4
				3
				3
				5
				4
					pp
					rpp
					prpp
					prpp
					rpp
					rfp
					pprpp
					prpp
						0 1 1 –	– ↕ ↕ –

LDHX #opr16i
LDHX opr8a
LDHX opr16a
LDHX ,X
LDHX oprx16,X
LDHX oprx8,X
LDHX oprx8,SP
	Load Index Register (H:X)
	H:X ← (M:M + $0001)
		IMM
		DIR
		EXT
		IX
		IX2
		IX1
		SP1
			45 jj kk
			55 dd
			32 hh ll
			9E AE
			9E BE ee ff
			9E CE ff
			9E FE ff
				3
				4
				5
				5
				6
				5
				5
					ppp
					rrpp
					prrpp
					prrfp
					pprrpp
					prrpp
					prrpp
						0 1 1 –	– ↕ ↕ –

LDX #opr8i
LDX opr8a
LDX opr16a
LDX oprx16,X
LDX oprx8,X
LDX ,X
LDX oprx16,SP
LDX oprx8,SP
	Load X (Index Register Low) from Memory
	X ← (M)
		IMM
		DIR
		EXT
		IX2
		IX1
		IX
		SP2
		SP1
			AE ii
			BE dd
			CE hh ll
			DE ee ff
			EE ff
			FE
			9E DE ee ff
			9E EE ff
				2
				3
				4
				4
				3
				3
				5
				4
					pp
					rpp
					prpp
					prpp
					rpp
					rfp
					pprpp
					prpp
						0 1 1 –	– ↕ ↕ –

LSL opr8a LSLA LSLX LSL oprx8,X LSL ,X LSL oprx8,SP	Logical Shift Left C ← [						] ← 0 b7 b0 (Same as ASL)	DIR INH INH IX1 IX SP1	38 dd 48 58 68 ff 78 9E 68 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕
LSR opr8a LSRA LSRX LSR oprx8,X LSR ,X LSR oprx8,SP	Logical Shift Right 0 → [						] → C b7 b0	DIR INH INH IX1 IX SP1	34 dd 44 54 64 ff 74 9E 64 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– 0 ↕ ↕

Table 7-2. Instruction Set Summary (Sheet 6 of 9)
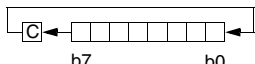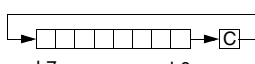
Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	V 1 1 H	I N Z C

MOV opr8a,opr8a
MOV opr8a,X+
MOV #opr8i,opr8a
MOV ,X+,opr8a
	Move
	(M)destination ← (M)source
	In IX+/DIR and DIR/IX+ Modes,
	H:X ← (H:X) + $0001
		DIR/DIR
		DIR/IX+
		IMM/DIR
		IX+/DIR
			4E dd dd
			5E dd
			6E ii dd
			7E dd
				5
				5
				4
				5
					rpwpp
					rfwpp
					pwpp
					rfwpp
						0 1 1 –	– ↕ ↕ –

MUL	Unsigned multiply X:A ← (X) × (A)	INH	42	5	ffffp	– 1 1 0	– – – 0

NEG opr8a
NEGA
NEGX
NEG oprx8,X
NEG ,X
NEG oprx8,SP
	Negate M ← − (M) = $00 − (M)
	(Two's Complement) A ← − (A) = $00 − (A)
	          X ← − (X) = $00 − (X)
	          M ← − (M) = $00 − (M)
	          M ← − (M) = $00 − (M)
	          M ← − (M) = $00 − (M)
		DIR
		INH
		INH
		IX1
		IX
		SP1
			30 dd
			40
			50
			60 ff
			70
			9E 60 ff
				5
				1
				1
				5
				4
				6
					rfwpp
					p
					p
					rfwpp
					rfwp
					prfwpp
						↕ 1 1 –	– ↕ ↕ ↕

NOP	No Operation — Uses 1 Bus Cycle	INH	9D	1	p	– 1 1 –	– – – –
NSA	Nibble Swap Accumulator A ← (A[3:0]:A[7:4])	INH	62	1	p	– 1 1 –	– – – –
ORA #opr8i ORA opr8a ORA opr16a ORA oprx16,X ORA oprx8,X ORA ,X ORA oprx16,SP ORA oprx8,SP	Inclusive OR Accumulator and Memory A ← (A) | (M)	IMM DIR EXT IX2 IX1 IX SP2 SP1	AA ii BA dd CA hh ll DA ee ff EA ff FA 9E DA ee ff 9E EA ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	0 1 1 –	– ↕ ↕ –
PSHA	Push Accumulator onto Stack Push (A); SP ← (SP) − $0001	INH	87	2	sp	– 1 1 –	– – – –
PSHH	Push H (Index Register High) onto Stack Push (H); SP ← (SP) − $0001	INH	8B	2	sp	– 1 1 –	– – – –
PSHX	Push X (Index Register Low) onto Stack Push (X); SP ← (SP) − $0001	INH	89	2	sp	– 1 1 –	– – – –
PULA	Pull Accumulator from Stack SP ← (SP + $0001); Pull (A)	INH	86	3	ufp	– 1 1 –	– – – –
PULH	Pull H (Index Register High) from Stack SP ← (SP + $0001); Pull (H)	INH	8A	3	ufp	– 1 1 –	– – – –
PULX	Pull X (Index Register Low) from Stack SP ← (SP + $0001); Pull (X)	INH	88	3	ufp	– 1 1 –	– – – –
ROL opr8a ROLA ROLX ROL oprx8,X ROL ,X ROL oprx8,SP	Rotate Left through Carry 	DIR INH INH IX1 IX SP1	39 dd 49 59 69 ff 79 9E 69 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕
ROR opr8a RORA RORX ROR oprx8,X ROR ,X ROR oprx8,SP	Rotate Right through Carry 	DIR INH INH IX1 IX SP1	36 dd 46 56 66 ff 76 9E 66 ff	5 1 1 5 4 6	rfwpp p p rfwpp rfwp prfwpp	↕ 1 1 –	– ↕ ↕ ↕

Table 7-2. Instruction Set Summary (Sheet 7 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR						
						V	**1**	**1**	**H**	**I**	**N**	**Z**	**C**
RSP	Reset Stack Pointer (Low Byte) SPL ← $FF (High Byte Not Affected)	INH	9C	1	p	–	1	1	–	–	–	–	–
RTI	Return from Interrupt SP ← (SP) + $0001; Pull (CCR) SP ← (SP) + $0001; Pull (A) SP ← (SP) + $0001; Pull (X) SP ← (SP) + $0001; Pull (PCH) SP ← (SP) + $0001; Pull (PCL)	INH	80	9	uuuuufppp	↕	1	1	↕	↕	↕	↕	↕
RTS	Return from Subroutine SP ← SP + $0001; Pull (PCH) SP ← SP + $0001; Pull (PCL)	INH	81	5	ufppp	–	1	1	–	–	–	–	–
SBC #opr8i SBC opr8a SBC opr16a SBC oprx16,X SBC oprx8,X SBC ,X SBC oprx16,SP SBC oprx8,SP	Subtract with Carry A ← (A) – (M) – (C)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A2 ii B2 dd C2 hh ll D2 ee ff E2 ff F2 9E D2 ee ff 9E E2 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↕	1	1	–	–	↕	↕	↕
SEC	Set Carry Bit (C ← 1)	INH	99	1	p	–	1	1	–	–	–	–	1
SEI	Set Interrupt Mask Bit (I ← 1)	INH	9B	1	p	–	1	1	–	1	–	–	–
STA opr8a STA opr16a STA oprx16,X STA oprx8,X STA ,X STA oprx16,SP STA oprx8,SP	Store Accumulator in Memory M ← (A)	DIR EXT IX2 IX1 IX SP2 SP1	B7 dd C7 hh ll D7 ee ff E7 ff F7 9E D7 ee ff 9E E7 ff	3 4 4 3 2 5 4	wpp pwpp pwpp wpp wp ppwpp pwpp	0	1	1	–	–	↕	↕	–
STHX opr8a STHX opr16a STHX oprx8,SP	Store H:X (Index Reg.) (M:M + $0001) ← (H:X)	DIR EXT SP1	35 dd 96 hh ll 9E FF ff	4 5 5	wwpp pwwpp pwwpp	0	1	1	–	–	↕	↕	–
STOP	Enable Interrupts: Stop Processing Refer to MCU Documentation I bit ← 0; Stop Processing	INH	8E	2	fp...	–	1	1	–	0	–	–	–
STX opr8a STX opr16a STX oprx16,X STX oprx8,X STX ,X STX oprx16,SP STX oprx8,SP	Store X (Low 8 Bits of Index Register) in Memory M ← (X)	DIR EXT IX2 IX1 IX SP2 SP1	BF dd CF hh ll DF ee ff EF ff FF 9E DF ee ff 9E EF ff	3 4 4 3 2 5 4	wpp pwpp pwpp wpp wp ppwpp pwpp	0	1	1	–	–	↕	↕	–

Table 7-2. Instruction Set Summary (Sheet 8 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR	
						V 1 1 H	**I N Z C**

SUB #opr8i
SUB opr8a
SUB opr16a
SUB oprx16,X
SUB oprx8,X
SUB ,X
SUB oprx16,SP
SUB oprx8,SP
	Subtract
	A ← (A) − (M)
		IMM
		DIR
		EXT
		IX2
		IX1
		IX
		SP2
		SP1
			A0 ii
			B0 dd
			C0 hh ll
			D0 ee ff
			E0 ff
			F0
			9E D0 ee ff
			9E E0 ff
				2
				3
				4
				4
				3
				3
				5
				4
					pp
					rpp
					prpp
					prpp
					rpp
					rfp
					pprpp
					prpp
						↕ 1 1 –	– ↕ ↕ ↕

SWI	Software Interrupt PC ← (PC) + $0001 Push (PCL); SP ← (SP) − $0001 Push (PCH); SP ← (SP) − $0001 Push (X); SP ← (SP) − $0001 Push (A); SP ← (SP) − $0001 Push (CCR); SP ← (SP) − $0001 I ← 1; PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte	INH	83	11	sssssvvfppp	– 1 1 –	1 – – –
TAP	Transfer Accumulator to CCR CCR ← (A)	INH	84	1	p	↕ 1 1 ↕	↕ ↕ ↕ ↕
TAX	Transfer Accumulator to X (Index Register Low) X ← (A)	INH	97	1	p	– 1 1 –	– – – –
TPA	Transfer CCR to Accumulator A ← (CCR)	INH	85	1	p	– 1 1 –	– – – –
TST opr8a TSTA TSTX TST oprx8,X TST ,X TST oprx8,SP	Test for Negative or Zero (M) − $00 (A) − $00 (X) − $00 (M) − $00 (M) − $00 (M) − $00	DIR INH INH IX1 IX SP1	3D dd 4D 5D 6D ff 7D 9E 6D ff	4 1 1 4 3 5	rfpp p p rfpp rfp prfpp	0 1 1 –	– ↕ ↕ –
TSX	Transfer SP to Index Reg. H:X ← (SP) + $0001	INH	95	2	fp	– 1 1 –	– – – –
TXA	Transfer X (Index Reg. Low) to Accumulator A ← (X)	INH	9F	1	p	– 1 1 –	– – – –

Table 7-2. Instruction Set Summary (Sheet 9 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR							
						V	1	1	**H**	**I**	**N**	**Z**	**C**
TXS	Transfer Index Reg. to SP SP ← (H:X) − $0001	INH	94	2	fp	−	1	1	−	−	−	−	−
WAIT	Enable Interrupts; Wait for Interrupt I bit ← 0; Halt CPU	INH	8F	2+	fp...	−	1	1	−	0	−	−	−

Source Form: Everything in the source forms columns, *except expressions in italic characters*, is literal information which must appear in the assembly source file exactly as shown. The initial 3- to 5-letter mnemonic and the characters (# , ( ) and +) are always a literal characters.

n   Any label or expression that evaluates to a single integer in the range 0-7.
opr8i   Any label or expression that evaluates to an 8-bit immediate value.
opr16i Any label or expression that evaluates to a 16-bit immediate value.
opr8a   Any label or expression that evaluates to an 8-bit direct-page address ($00xx).
opr16a Any label or expression that evaluates to a 16-bit address.
oprx8   Any label or expression that evaluates to an unsigned 8-bit value, used for indexed addressing.
oprx16 Any label or expression that evaluates to a 16-bit value, used for indexed addressing.
rel   Any label or expression that refers to an address that is within −128 to +127 locations from the start of the next instruction.

Operation Symbols:

A	Accumulator
CCR	Condition code register
H	Index register high byte
M	Memory location
n	Any bit
opr	Operand (one or two bytes)
PC	Program counter
PCH	Program counter high byte
PCL	Program counter low byte
rel	Relative program counter offset byte
SP	Stack pointer
SPL	Stack pointer low byte
X	Index register low byte
&	Logical AND
		Logical OR
⊕	Logical EXCLUSIVE OR
( )	Contents of
+	Add
−	Subtract, Negation (two's complement)
×	Multiply
÷	Divide
#	Immediate value
←	Loaded with
:	Concatenated with

Addressing Modes:

DIR	Direct addressing mode
EXT	Extended addressing mode
IMM	Immediate addressing mode
INH	Inherent addressing mode
IX	Indexed, no offset addressing mode
IX1	Indexed, 8-bit offset addressing mode
IX2	Indexed, 16-bit offset addressing mode
IX+	Indexed, no offset, post increment addressing mode
IX1+	Indexed, 8-bit offset, post increment addressing mode
REL	Relative addressing mode
SP1	Stack pointer, 8-bit offset addressing mode
SP2	Stack pointer 16-bit offset addressing mode

Cycle-by-Cycle Codes:

f	Free cycle. This indicates a cycle where the CPU does not require use of the system buses. An f cycle is always one cycle of the system bus clock and is always a read cycle.
p	Progryam fetch; read from next consecutive location in program memory
r	Read 8-bit operand
s	Push (write) one byte onto stack
u	Pop (read) one byte from stack
v	Read vector from $FFxx (high byte first)
w	Write 8-bit operand

CCR Bits:

V	Overflow bit
H	Half-carry bit
I	Interrupt mask
N	Negative bit
Z	Zero bit
C	Carry/borrow bit

CCR Effects:

↕	Set or cleared
−	Not affected
U	Undefined

Table 7-3. Opcode Map (Sheet 1 of 2)

Bit-Manipulation		Branch	Read-Modify-Write					Control		Register/Memory					
00 5 BRSET0 3 DIR	10 5 BSET0 3 DIR	20 3 BRA 2 REL	30 5 NEG 2 DIR	40 1 NEGA 1 INH	50 1 NEGX 1 INH	60 5 NEG 2 IX1	70 4 NEG 1 IX	80 9 RTI 1 INH	90 3 BGE 2 REL	A0 2 SUB 2 IMM	B0 3 SUB 2 DIR	C0 4 SUB 3 EXT	D0 4 SUB 3 IX2	E0 3 SUB 2 IX1	F0 3 SUB 1 IX
01 5 BRCLR0 3 DIR	11 5 BCLR0 3 DIR	21 3 BRN 2 REL	31 5 CBEQ 3 DIR	41 4 CBEQA 3 IMM	51 4 CBEQX 3 IMM	61 5 CBEQ 3 IX1+	71 5 CBEQ 2 IX+	81 6 RTS 1 INH	91 3 BLT 2 REL	A1 2 CMP 2 IMM	B1 3 CMP 2 DIR	C1 4 CMP 3 EXT	D1 4 CMP 3 IX2	E1 3 CMP 2 IX1	F1 3 CMP 1 IX
02 5 BRSET1 3 DIR	12 5 BSET1 3 DIR	22 3 BHI 2 REL	32 5 LDHX 3 EXT	42 5 MUL 1 INH	52 6 DIV 1 INH	62 1 NSA 1 INH	72 1 DAA 1 INH	82 5+ BGND 1 INH	92 3 BGT 2 REL	A2 2 SBC 2 IMM	B2 3 SBC 2 DIR	C2 4 SBC 3 EXT	D2 4 SBC 3 IX2	E2 3 SBC 2 IX1	F2 3 SBC 1 IX
03 5 BRCLR1 3 DIR	13 5 BCLR1 3 DIR	23 3 BLS 2 REL	33 5 COM 2 DIR	43 1 COMA 1 INH	53 1 COMX 1 INH	63 5 COM 2 IX1	73 4 COM 1 IX	83 11 SWI 1 INH	93 3 BLE 2 REL	A3 2 CPX 2 IMM	B3 3 CPX 2 DIR	C3 4 CPX 3 EXT	D3 4 CPX 3 IX2	E3 3 CPX 2 IX1	F3 3 CPX 1 IX
04 5 BRSET2 3 DIR	14 5 BSET2 3 DIR	24 3 BCC 2 REL	34 5 LSR 2 DIR	44 1 LSRA 1 INH	54 1 LSRX 1 INH	64 5 LSR 2 IX1	74 4 LSR 1 IX	84 1 TAP 1 INH	94 2 TXS 1 INH	A4 2 AND 2 IMM	B4 3 AND 2 DIR	C4 4 AND 3 EXT	D4 4 AND 3 IX2	E4 3 AND 2 IX1	F4 3 AND 1 IX
05 5 BRCLR2 3 DIR	15 5 BCLR2 3 DIR	25 3 BCS 2 REL	35 4 STHX 2 DIR	45 3 LDHX 3 IMM	55 4 LDHX 2 DIR	65 3 CPHX 3 IMM	75 5 CPHX 2 DIR	85 1 TPA 1 INH	95 2 TSX 1 INH	A5 2 BIT 2 IMM	B5 3 BIT 2 DIR	C5 4 BIT 3 EXT	D5 4 BIT 3 IX2	E5 3 BIT 2 IX1	F5 3 BIT 1 IX
06 5 BRSET3 3 DIR	16 5 BSET3 3 DIR	26 3 BNE 2 REL	36 5 ROR 2 DIR	46 1 RORA 1 INH	56 1 RORX 1 INH	66 5 ROR 2 IX1	76 4 ROR 1 IX	86 3 PULA 1 INH	96 5 STHX 3 EXT	A6 2 LDA 2 IMM	B6 3 LDA 2 DIR	C6 4 LDA 3 EXT	D6 4 LDA 3 IX2	E6 3 LDA 2 IX1	F6 3 LDA 1 IX
07 5 BRCLR3 3 DIR	17 5 BCLR3 3 DIR	27 3 BEQ 2 REL	37 5 ASR 2 DIR	47 1 ASRA 1 INH	57 1 ASRX 1 INH	67 5 ASR 2 IX1	77 4 ASR 1 IX	87 2 PSHA 1 INH	97 1 TAX 1 INH	A7 2 AIS 2 IMM	B7 3 STA 2 DIR	C7 4 STA 3 EXT	D7 4 STA 3 IX2	E7 3 STA 2 IX1	F7 2 STA 1 IX
08 5 BRSET4 3 DIR	18 5 BSET4 3 DIR	28 3 BHCC 2 REL	38 5 LSL 2 DIR	48 1 LSLA 1 INH	58 1 LSLX 1 INH	68 5 LSL 2 IX1	78 4 LSL 1 IX	88 3 PULX 1 INH	98 1 CLC 1 INH	A8 2 EOR 2 IMM	B8 3 EOR 2 DIR	C8 4 EOR 3 EXT	D8 4 EOR 3 IX2	E8 3 EOR 2 IX1	F8 3 EOR 1 IX
09 5 BRCLR4 3 DIR	19 5 BCLR4 3 DIR	29 3 BHCS 2 REL	39 5 ROL 2 DIR	49 1 ROLA 1 INH	59 1 ROLX 1 INH	69 5 ROL 2 IX1	79 4 ROL 1 IX	89 2 PSHX 1 INH	99 1 SEC 1 INH	A9 2 ADC 2 IMM	B9 3 ADC 2 DIR	C9 4 ADC 3 EXT	D9 4 ADC 3 IX2	E9 3 ADC 2 IX1	F9 3 ADC 1 IX
0A 5 BRSET5 3 DIR	1A 5 BSET5 3 DIR	2A 3 BPL 2 REL	3A 5 DEC 2 DIR	4A 1 DECA 1 INH	5A 1 DECX 1 INH	6A 5 DEC 2 IX1	7A 4 DEC 1 IX	8A 3 PULH 1 INH	9A 1 CLI 1 INH	AA 2 ORA 2 IMM	BA 3 ORA 2 DIR	CA 4 ORA 3 EXT	DA 4 ORA 3 IX2	EA 3 ORA 2 IX1	FA 3 ORA 1 IX
0B 5 BRCLR5 3 DIR	1B 5 BCLR5 3 DIR	2B 3 BMI 2 REL	3B 7 DBNZ 3 DIR	4B 4 DBNZA 2 INH	5B 4 DBNZX 2 INH	6B 7 DBNZ 3 IX1	7B 6 DBNZ 2 IX	8B 2 PSHH 1 INH	9B 1 SEI 1 INH	AB 2 ADD 2 IMM	BB 3 ADD 2 DIR	CB 4 ADD 3 EXT	DB 4 ADD 3 IX2	EB 3 ADD 2 IX1	FB 3 ADD 1 IX
0C 5 BRSET6 3 DIR	1C 5 BSET6 3 DIR	2C 3 BMC 2 REL	3C 5 INC 2 DIR	4C 1 INCA 1 INH	5C 1 INCX 1 INH	6C 5 INC 2 IX1	7C 4 INC 1 IX	8C 1 CLRH 1 INH	9C 1 RSP 1 INH		BC 3 JMP 2 DIR	CC 4 JMP 3 EXT	DC 4 JMP 3 IX2	EC 3 JMP 2 IX1	FC 3 JMP 1 IX
0D 5 BRCLR6 3 DIR	1D 5 BCLR6 3 DIR	2D 3 BMS 2 REL	3D 4 TST 2 DIR	4D 1 TSTA 1 INH	5D 1 TSTX 1 INH	6D 4 TST 2 IX1	7D 3 TST 1 IX		9D 1 NOP 1 INH	AD 5 BSR 2 REL	BD 5 JSR 2 DIR	CD 6 JSR 3 EXT	DD 6 JSR 3 IX2	ED 5 JSR 2 IX1	FD 5 JSR 1 IX
0E 5 BRSET7 3 DIR	1E 5 BSET7 3 DIR	2E 3 BIL 2 REL	3E 6 CPHX 3 EXT	4E 5 MOV 3 DD	5E 5 MOV 3 DIX+	6E 4 MOV 3 IMD	7E 5 MOV 2 IX+D	8E 2+ STOP 1 INH	9E Page 2	AE 2 LDX 2 IMM	BE 3 LDX 2 DIR	CE 4 LDX 3 EXT	DE 4 LDX 3 IX2	EE 3 LDX 2 IX1	FE 3 LDX 1 IX
0F 5 BRCLR7 3 DIR	1F 5 BCLR7 3 DIR	2F 3 BIH 2 REL	3F 5 CLR 2 DIR	4F 1 CLRA 1 INH	5F 1 CLRX 1 INH	6F 5 CLR 2 IX1	7F 4 CLR 1 IX	8F 2+ WAIT 1 INH	9F 1 TXA 1 INH	AF 2 AIX 2 IMM	BF 3 STX 2 DIR	CF 4 STX 3 EXT	DF 4 STX 3 IX2	EF 3 STX 2 IX1	FF 2 STX 1 IX

INH	Inherent	REL	Relative	SP1	Stack Pointer, 8-Bit Offset		
IMM	Immediate	IX	Indexed, No Offset	SP2	Stack Pointer, 16-Bit Offset		
DIR	Direct	IX1	Indexed, 8-Bit Offset	IX+	Indexed, No Offset with		
EXT	Extended	IX2	Indexed, 16-Bit Offset		Post Increment		
DD	DIR to DIR	IMD	IMM to DIR	IX1+	Indexed, 1-Byte Offset with		
IX+D	IX+ to DIR	DIX+	DIR to IX+		Post Increment		

Opcode in
Hexadecimal
Number of Bytes

F0	3
SUB	
1	IX

HCS08 Cycles
Instruction Mnemonic
Addressing Mode

Table 7-3. Opcode Map (Sheet 2 of 2)

Bit-Manipulation	Branch	Read-Modify-Write (9E6x)	Control (9EAx / 9EBx / 9ECx)	Register/Memory (9EDx)	Register/Memory (9EEx)	Register/Memory (9EFx)
		9E60 6 / NEG / 3 SP1		9ED0 5 / SUB / 4 SP2	9EE0 4 / SUB / 3 SP1	
		9E61 6 / CBEQ / 4 SP1		9ED1 5 / CMP / 4 SP2	9EE1 4 / CMP / 3 SP1	
				9ED2 5 / SBC / 4 SP2	9EE2 4 / SBC / 3 SP1	
		9E63 6 / COM / 3 SP1		9ED3 5 / CPX / 4 SP2	9EE3 4 / CPX / 3 SP1	9EF3 6 / CPHX / 3 SP1
		9E64 6 / LSR / 3 SP1		9ED4 5 / AND / 4 SP2	9EE4 4 / AND / 3 SP1	
				9ED5 5 / BIT / 4 SP2	9EE5 4 / BIT / 3 SP1	
		9E66 6 / ROR / 3 SP1		9ED6 5 / LDA / 4 SP2	9EE6 4 / LDA / 3 SP1	
		9E67 6 / ASR / 3 SP1		9ED7 5 / STA / 4 SP2	9EE7 4 / STA / 3 SP1	
		9E68 6 / LSL / 3 SP1		9ED8 5 / EOR / 4 SP2	9EE8 4 / EOR / 3 SP1	
		9E69 6 / ROL / 3 SP1		9ED9 5 / ADC / 4 SP2	9EE9 4 / ADC / 3 SP1	
		9E6A 6 / DEC / 3 SP1		9EDA 5 / ORA / 4 SP2	9EEA 4 / ORA / 3 SP1	
		9E6B 8 / DBNZ / 4 SP1		9EDB 5 / ADD / 4 SP2	9EEB 4 / ADD / 3 SP1	
		9E6C 6 / INC / 3 SP1				
		9E6D 5 / TST / 3 SP1				
			9EAE 5 / LDHX / 2 IX · 9EBE 6 / LDHX / 4 IX2 · 9ECE 5 / LDHX / 3 IX1	9EDE 5 / LDX / 4 SP2	9EEE 4 / LDX / 3 SP1	9EFE 5 / LDHX / 3 SP1
		9E6F 6 / CLR / 3 SP1		9EDF 5 / STX / 4 SP2	9EEF 4 / STX / 3 SP1	9EFF 5 / STHX / 3 SP1

INH	Inherent	REL	Relative
IMM	Immediate	IX	Indexed, No Offset
DIR	Direct	IX1	Indexed, 8-Bit Offset
EXT	Extended	IX2	Indexed, 16-Bit Offset
DD	DIR to DIR	IMD	IMM to DIR
IX+D	IX+ to DIR	DIX+	DIR to IX+

SP1	Stack Pointer, 8-Bit Offset
SP2	Stack Pointer, 16-Bit Offset
IX+	Indexed, No Offset with Post Increment
IX1+	Indexed, 1-Byte Offset with Post Increment

Note: All Sheet 2 Opcodes are Preceded by the Page 2 Prebyte (9E)

Prebyte (9E) and Opcode in Hexadecimal — 9E60 6 / NEG / 3 SP1 — HCS08 Cycles, Instruction Mnemonic, Number of Bytes, Addressing Mode

Chapter 8
Keyboard Interrupt (S08KBIV2)

8.1 Introduction

The keyboard interrupt (KBI) module provides up to eight independently enabled external interrupt sources. MC9S08SE8 series devices contain one KBI module with up to eight interrupt sources.

NOTE

When enabling the KBI pins for use, the KBF will be set, and must be cleared prior to enabling the interrupt. When configuring the pins for falling edge and level sensitivity in a 5 V system, wait at least 1 cycle between clearing the flag and enabling the interrupt.

Figure 8-1 shows the device-level block diagram with the KBI module highlighted.
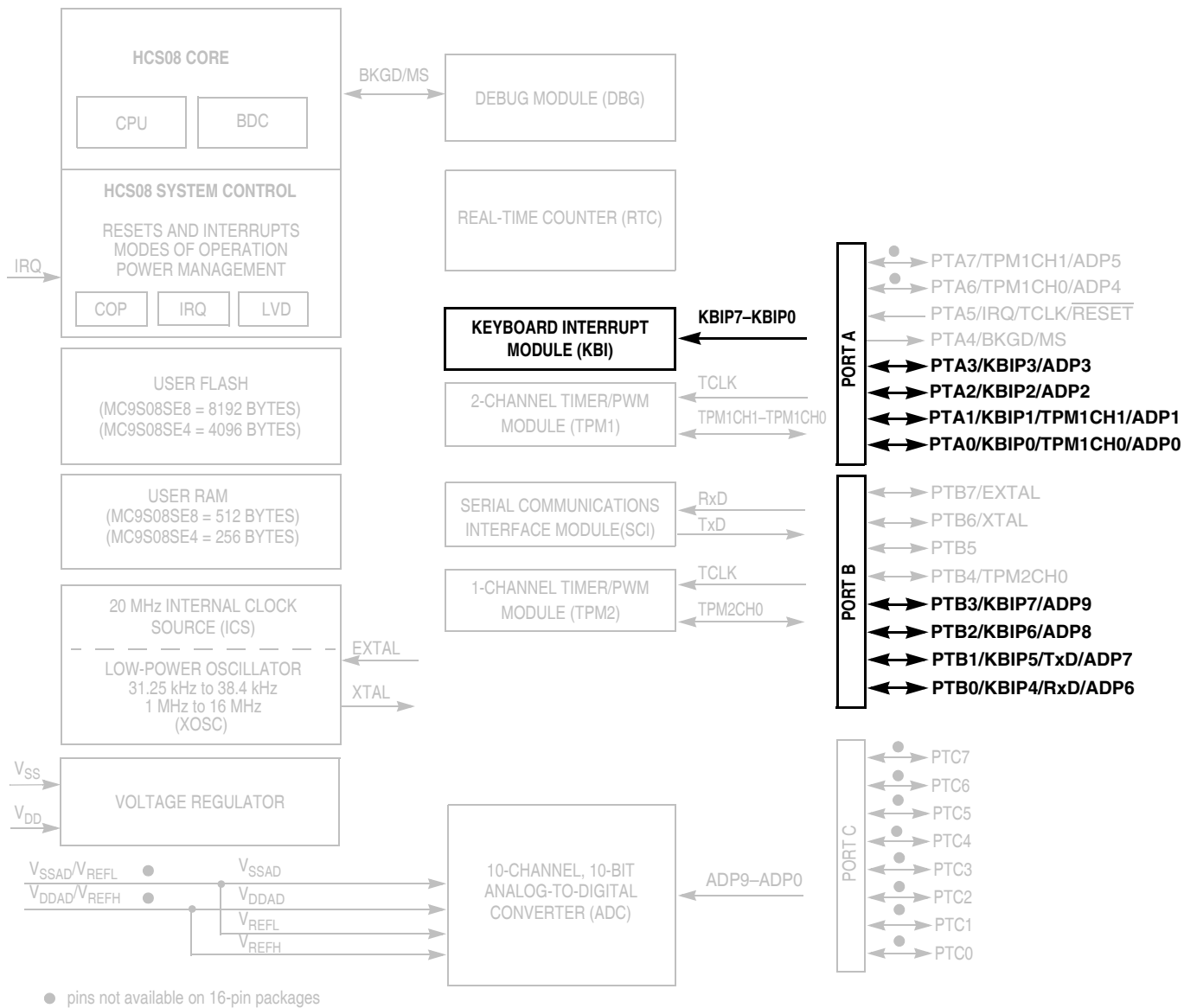
Figure 8-1. MC9S08SE8 Series Block Diagram Highlighting KBI Block and Pins

8.1.1   Features

The KBI features include:

- Up to eight keyboard interrupt pins with individual pin enable bits.
- Each keyboard interrupt pin is programmable as falling edge (or rising edge) only, or both falling edge and low level (or both rising edge and high level) interrupt sensitivity.
- One software enabled keyboard interrupt.
- Exit from low-power modes.

8.1.2   Modes of Operation

This section defines the KBI operation in wait, stop, and background debug modes.

8.1.2.1   KBI in Wait Mode

The KBI continues to operate in wait mode if enabled before executing the WAIT instruction. Therefore, an enabled KBI pin (KBPEx = 1) can be used to bring the MCU out of wait mode if the KBI interrupt is enabled (KBIE = 1).

8.1.2.2   KBI in Stop Modes

The KBI operates asynchronously in stop3 mode if enabled before executing the STOP instruction. Therefore, an enabled KBI pin (KBPEx = 1) can be used to bring the MCU out of stop3 mode if the KBI interrupt is enabled (KBIE = 1).

During either stop1 or stop2 mode, the KBI is disabled. In some systems, the pins associated with the KBI may be sources of wakeup from stop1 or stop2, see the stop modes section in the Modes of Operation chapter. Upon wakeup from stop1 or stop2 mode, the KBI module will be in the reset state.

8.1.2.3   KBI in Active Background Mode

When the microcontroller is in active background mode, the KBI will continue to operate normally.

8.1.3   Block Diagram

The block diagram for the keyboard interrupt module is shown Figure 8-2.
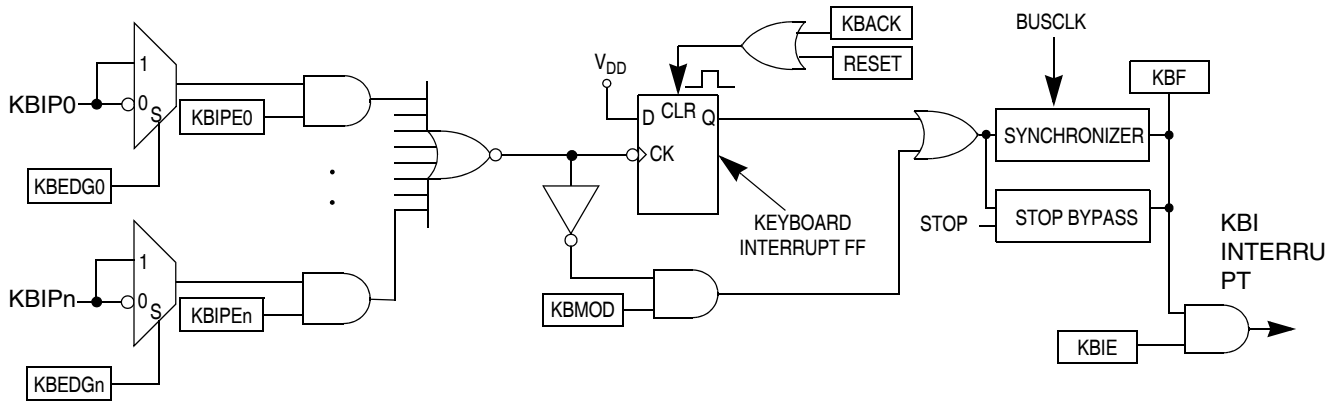
Figure 8-2. KBI Block Diagram

8.2 External Signal Description

The KBI input pins can be used to detect either falling edges, or both falling edge and low level interrupt requests. The KBI input pins can also be used to detect either rising edges, or both rising edge and high level interrupt requests.

The signal properties of KBI are shown in Table 8-1.

Table 8-1. Signal Properties

Signal	Function	I/O
KBIPn	Keyboard interrupt pins	I

8.3 Register Definition

The KBI includes three registers:

- An 8-bit pin status and control register.
- An 8-bit pin enable register.
- An 8-bit edge select register.

Refer to the direct-page register summary in the Memory chapter for the absolute address assignments for all KBI registers. This section refers to registers and control bits only by their names.

Some MCUs may have more than one KBI, so register names include placeholder characters to identify which KBI is being referenced.

8.3.1 KBI Status and Control Register (KBISC)

KBISC contains the status flag and control bits, which are used to configure the KBI.
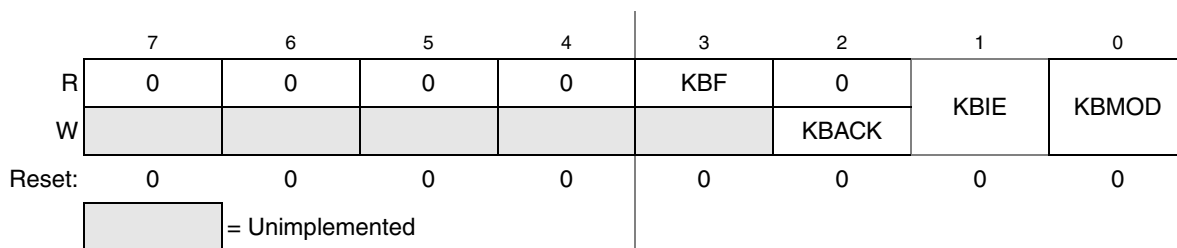
	7	6	5	4	3	2	1	0
R	0	0	0	0	KBF	0	KBIE	KBMOD
W						KBACK		
Reset:	0	0	0	0	0	0	0	0

☐ = Unimplemented

Figure 8-3. KBI Status and Control Register

Table 8-2. KBISC Register Field Descriptions

Field	Description
7:4	Unused register bits, always read 0.
3 KBF	**Keyboard Interrupt Flag** — KBF indicates when a keyboard interrupt is detected. Writes have no effect on KBF. 0 No keyboard interrupt detected. 1 Keyboard interrupt detected.
2 KBACK	**Keyboard Acknowledge** — Writing a 1 to KBACK is part of the flag clearing mechanism. KBACK always reads as 0.
1 KBIE	**Keyboard Interrupt Enable** — KBIE determines whether a keyboard interrupt is requested. 0 Keyboard interrupt request not enabled. 1 Keyboard interrupt request enabled.
0 KBMOD	**Keyboard Detection Mode** — KBMOD (along with the KBEDG bits) controls the detection mode of the keyboard interrupt pins.0Keyboard detects edges only. 1 Keyboard detects both edges and levels.

8.3.2   KBI Pin Enable Register (KBIPE)
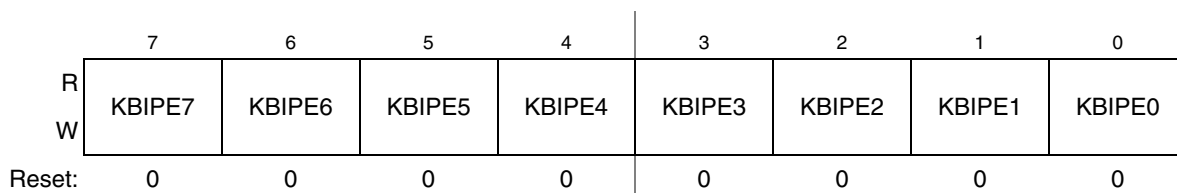
KBIPE contains the pin enable control bits.

	7	6	5	4	3	2	1	0
R W	KBIPE7	KBIPE6	KBIPE5	KBIPE4	KBIPE3	KBIPE2	KBIPE1	KBIPE0
Reset:	0	0	0	0	0	0	0	0

Figure 8-4. KBI Pin Enable Register

Table 8-3. KBIPE Register Field Descriptions

Field	Description
7:0 KBIPEn	**Keyboard Pin Enables** — Each of the KBIPEn bits enable the corresponding keyboard interrupt pin. 0 Pin not enabled as keyboard interrupt. 1 Pin enabled as keyboard interrupt.

8.3.3   KBI Edge Select Register (KBIES)

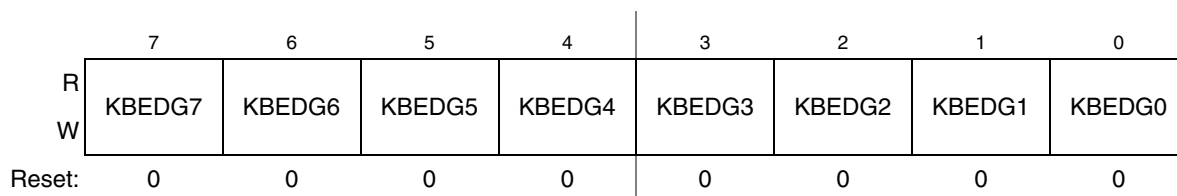KBIES contains the edge select control bits.

	7	6	5	4	3	2	1	0
R	KBEDG7	KBEDG6	KBEDG5	KBEDG4	KBEDG3	KBEDG2	KBEDG1	KBEDG0
W								
Reset:	0	0	0	0	0	0	0	0

Figure 8-5. KBI Edge Select Register

Table 8-4. KBIES Register Field Descriptions

Field	Description
7:0 KBEDGn	**Keyboard Edge Selects** — Each of the KBEDGn bits selects the falling edge/low level or rising edge/high level function of the corresponding pin). 0 Falling edge/low level. 1 Rising edge/high level.

8.4   Functional Description

This on-chip peripheral module is called a keyboard interrupt (KBI) module because originally it was designed to simplify the connection and use of row-column matrices of keyboard switches. However, these inputs are also useful as extra external interrupt inputs and as an external means of waking the MCU from stop or wait low-power modes.

The KBI module allows up to eight pins to act as additional interrupt sources. Writing to the KBIPEn bits in the keyboard interrupt pin enable register (KBIPE) independently enables or disables each KBI pin. Each KBI pin can be configured as edge sensitive or edge and level sensitive based on the KBMOD bit in the keyboard interrupt status and control register (KBISC). Edge sensitive can be software programmed to be either falling or rising; the level can be either low or high. The polarity of the edge or edge and level sensitivity is selected using the KBEDGn bits in the keyboard interrupt edge select register (KBIES).

8.4.1   Edge Only Sensitivity

Synchronous logic is used to detect edges. A falling edge is detected when an enabled keyboard interrupt (KBIPEn=1) input signal is seen as a logic 1 (the deasserted level) during one bus cycle and then a logic 0 (the asserted level) during the next cycle. A rising edge is detected when the input signal is seen as a logic 0 (the deasserted level) during one bus cycle and then a logic 1 (the asserted level) during the next cycle.Before the first edge is detected, all enabled keyboard interrupt input signals must be at the deasserted logic levels. After any edge is detected, all enabled keyboard interrupt input signals must return to the deasserted level before any new edge can be detected.

A valid edge on an enabled KBI pin will set KBF in KBISC. If KBIE in KBISC is set, an interrupt request will be presented to the CPU. Clearing of KBF is accomplished by writing a 1 to KBACK in KBISC.

8.4.2   Edge and Level Sensitivity

A valid edge or level on an enabled KBI pin will set KBF in KBISC. If KBIE in KBISC is set, an interrupt request will be presented to the CPU. Clearing of KBF is accomplished by writing a 1 to KBACK in

KBISC provided all enabled keyboard inputs are at their deasserted levels. KBF will remain set if any enabled KBI pin is asserted while attempting to clear by writing a 1 to KBACK.

8.4.3   KBI Pullup/Pulldown Resistors

The KBI pins can be configured to use an internal pullup/pulldown resistor using the associated I/O port pullup enable register. If an internal resistor is enabled, the KBIES register is used to select whether the resistor is a pullup (KBEDGn = 0) or a pulldown (KBEDGn = 1).

8.4.4   KBI Initialization

When a keyboard interrupt pin is first enabled it is possible to get a false keyboard interrupt flag. To prevent a false interrupt request during keyboard initialization, the user should do the following:

1. Mask keyboard interrupts by clearing KBIE in KBISC.
2. Enable the KBI polarity by setting the appropriate KBEDGn bits in KBIES.
3. If using internal pullup/pulldown device, configure the associated pullup enable bits in PTxPE.
4. Enable the KBI pins by setting the appropriate KBIPEn bits in KBIPE.
5. Write to KBACK in KBISC to clear any false interrupts.
6. Set KBIE in KBISC to enable interrupts.

Chapter 9
Analog-to-Digital Converter (S08ADCV1)

9.1   Introduction

The 10-bit analog-to-digital converter (ADC) is a successive approximation ADC designed for operation within an integrated microcontroller system-on-chip.

NOTE

The MC9S08SE8 series of devices do not include stop1 mode.

The ADC channel assignments, alternate clock function, and hardware trigger function are configured as described below for the MC9S08SE8 series family of devices.

9.1.1   Channel Assignments

The ADC channel assignments for the MC9S08SE8 series devices are shown in Table 9-1. Reserved channels convert to an unknown value.

Table 9-1. ADC Channel Assignment

ADCH	Channel	Input	ADCH	Channel	Input
00000	AD0	PTA0/AD0	10000	AD16	V_{SS}
00001	AD1	PTA1/ADP1	10001	AD17	V_{SS}
00010	AD2	PTA2/ADP2	10010	AD18	V_{SS}
00011	AD3	PTA3/ADP3	10011	AD19	V_{SS}
00100	AD4	PTA6/ADP4	10100	AD20	V_{SS}
00101	AD5	PTA7/ADP5	10101	AD21	V_{SS}
00110	AD6	PTB0/ADP6	10110	AD22	Reserved
00111	AD7	PTB1/ADP7	10111	AD23	Reserved
01000	AD8	PTB2/ADP8	11000	AD24	Reserved
01001	AD9	PTB3/ADP9	11001	AD25	Reserved
01010	AD10	V_{SS}	11010	AD26	Temperature Sensor[1]
01011	AD11	V_{SS}	11011	AD27	Internal Bandgap[2]
01100	AD12	V_{SS}	11100	—	Reserved
01101	AD13	V_{SS}	11101	V_{REFH}	V_{DD}
01110	AD14	V_{SS}	11110	V_{REFL}	V_{SS}
01111	AD15	V_{SS}	11111	Module Disabled	None

[1]   For information, see Section 9.1.4, "Temperature Sensor."

[2]   Requires BGBE =1 in SPMSC1 see Section 5.7.7, "System Power Management Status and Control 1 Register (SPMSC1)". For value of bandgap voltage reference see MC9S08SE8 Series *Data Sheet*.

9.1.2   Alternate Clock

The ADC module is capable of performing conversions using the MCU bus clock, the bus clock is divided by two, the local asynchronous clock (ADACK) within the module, or the alternate clock, ALTCLK. The alternate clock for the MC9S08SE8 series MCU devices is the external reference clock (ICSERCLK).

The selected clock source must run at a frequency that the ADC conversion clock (ADCK) runs at a frequency within its specified range (f_{ADCK}) after being divided down from the ALTCLK input as determined by the ADIV bits.

ALTCLK is active while the MCU is in wait mode provided the conditions described above are met. This allows ALTCLK to be used as the conversion clock source for the ADC while the MCU is in wait mode.

ALTCLK cannot be used as the ADC conversion clock source while the MCU is in stop2 or stop3.

9.1.3   Hardware Trigger

The ADC hardware trigger, ADHWT, is the output from the real time counter (RTC). The RTC counter can be clocked by either ICSERCLK, ICSIRCLK or a nominal 1 kHz clock source.

The period of the RTC is determined by the input clock frequency, the RTCPS bits, and the RTCMOD register. When the ADC hardware trigger is enabled, a conversion is initiated upon an RTC counter overflow. The RTIE does not have to be set for RTC to cause a hardware trigger.

The RTC can be configured to cause a hardware trigger in MCU run, wait, and stop3.

9.1.4   Temperature Sensor

To use the on-chip temperature sensor, the user must perform the following:

- Configure ADC for long sample with a maximum of 1 MHz clock
- Convert the bandgap voltage reference channel (AD27)
  - By converting the digital value of the bandgap voltage reference channel using the value of V_{BG}, the user can determine V_{DD}. For value of bandgap voltage, see MC9S08SE8 Series *Data Sheet*
- Convert the temperature sensor channel (AD26)
  - By using the calculated value of V_{DD}, convert the digital value of AD26 into a voltage, V_{TEMP}

Equation 9-1 provides an approximate transfer function of the on-chip temperature sensor for $V_{DD} = 5.0V$, Temp = 25°C, using the ADC1 at $f_{ADCK} = 1.0$ MHz and configured for long sample.

$$\text{Temp}_C = 25 - ((V_{TEMP} - 0.7013) / 0.0017)$$ *Eqn. 9-1*

0.0017 is the uncalibrated voltage versus temperature slope in V/°C. Uncalibrated accuracy of the temperature sensor is approximately ±12°C, using Equation 9-1.

To improve accuracy, the user must calibrate the bandgap voltage reference and temperature sensor.

Calibrating at 25°C will improve accuracy to ± 4.5°C.

Calibration at 3 points, –40°C, 25°C, and 125°C will improve accuracy to ± 2.5°C. Once calibration has been completed, the user will need to calculate the slope for both hot and cold. In application code, the user would then calculate the temperature using Equation 9-1 as detailed above and then determine if the temperature is above or below 25°C. Once determined if the temperature is above or below 25°C, the user can recalculate the temperature using the hot or cold slope value obtained during calibration.

Figure 9-1 shows the MC9S08SE8 with the ADC module and pins highlighted.
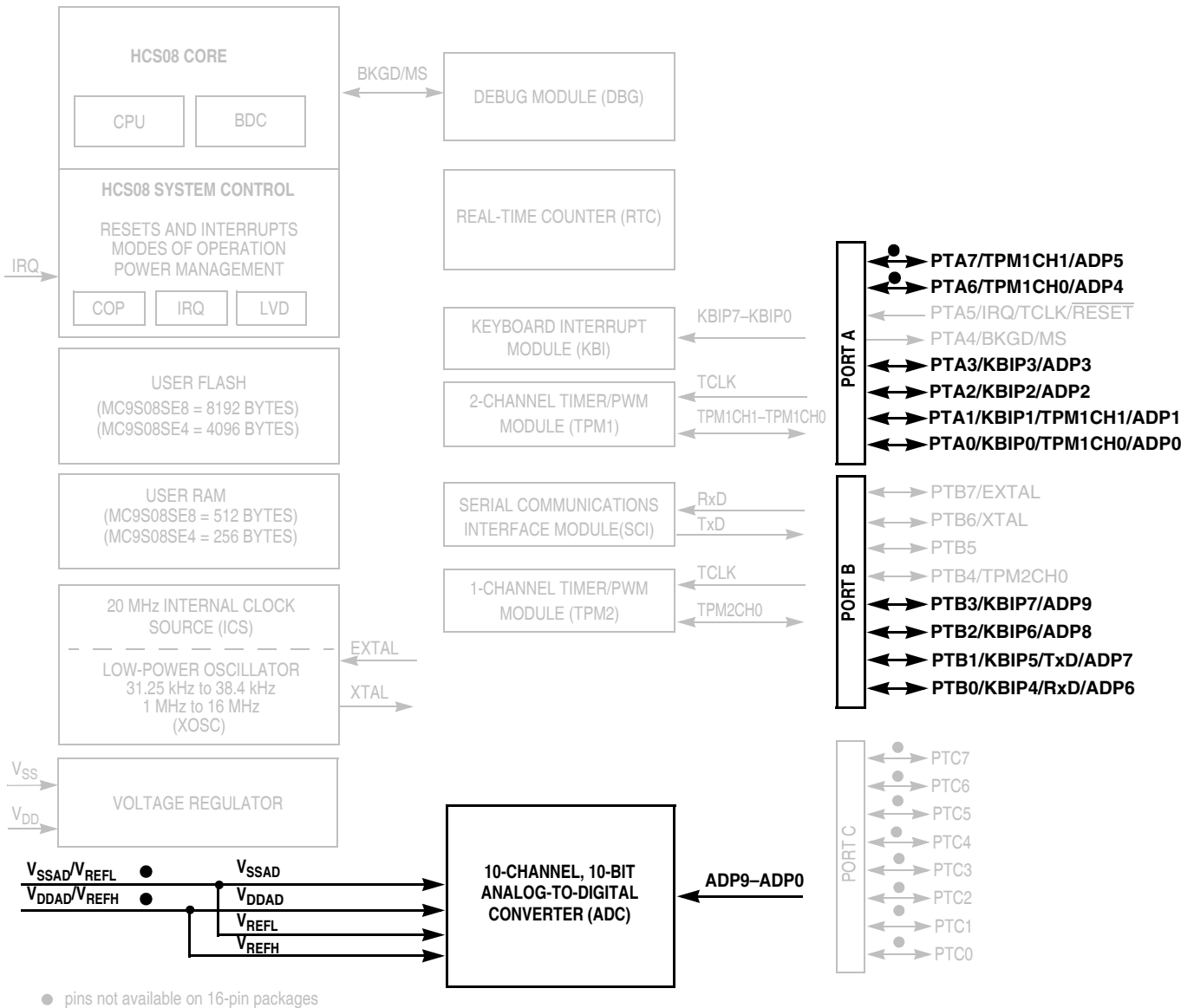
Figure 9-1. MC9S08SE8 Series Block Diagram Highlighting ADC Block and Pins

9.1.5 Features

Features of the ADC module include:

- Linear successive approximation algorithm with 10 bits resolution.
- Up to 28 analog inputs.
- Output formatted in 10- or 8-bit right-justified format.
- Single or continuous conversion (automatic return to idle after single conversion).
- Configurable sample time and conversion speed/power.
- Conversion complete flag and interrupt.
- Input clock selectable from up to four sources.
- Operation in wait or stop3 modes for lower noise operation.
- Asynchronous clock source for lower noise operation.
- Selectable asynchronous hardware conversion trigger.
- Automatic compare with interrupt for less-than, or greater-than or equal-to, programmable value.

9.1.6 Block Diagram

Figure 9-2 provides a block diagram of the ADC module
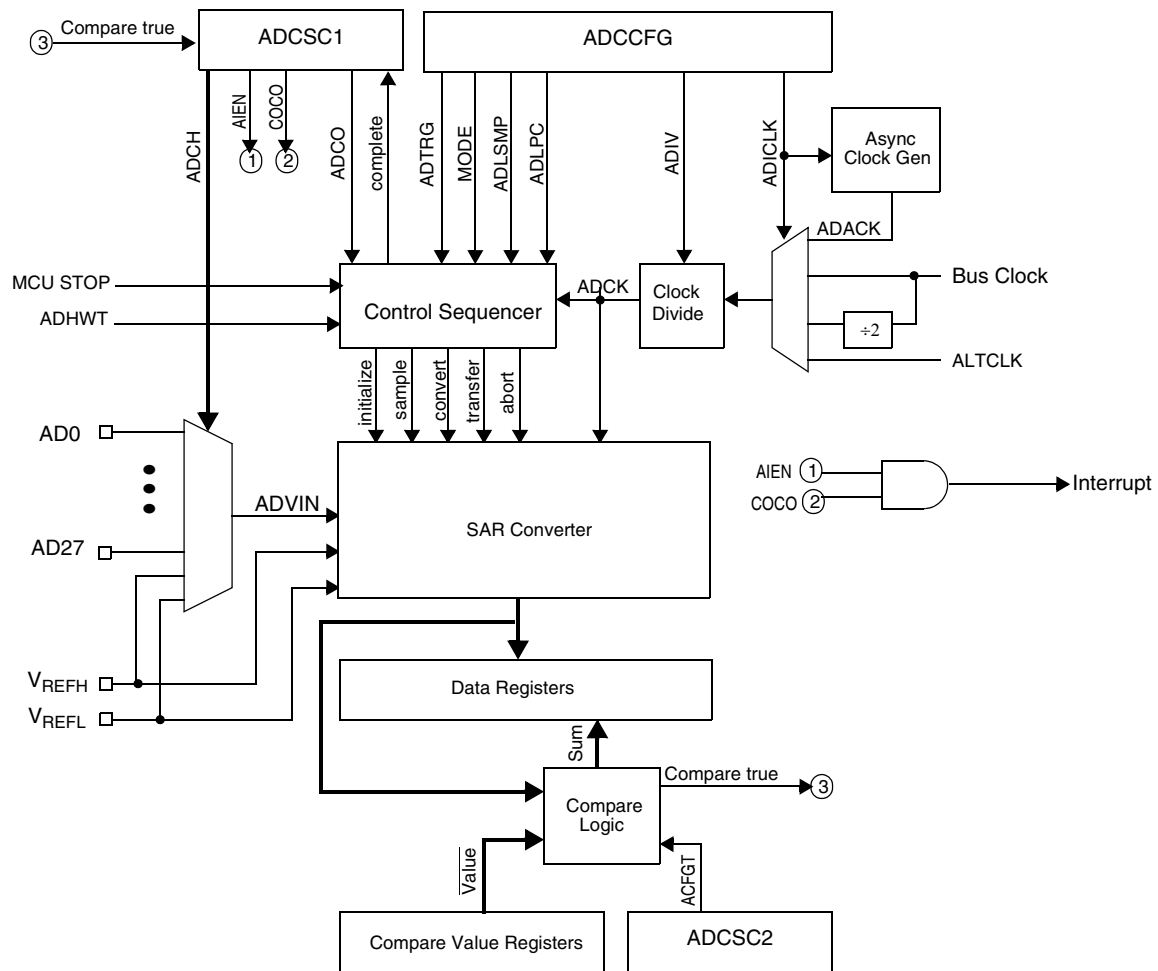
Figure 9-2. ADC Block Diagram

9.2 External Signal Description

The ADC module supports up to 28 separate analog inputs. It also requires four supply/reference/ground connections.

Table 9-2. Signal Properties

Name	Function
AD27–AD0	Analog Channel inputs
V_{REFH}	High reference voltage
V_{REFL}	Low reference voltage
V_{DDAD}	Analog power supply
V_{SSAD}	Analog ground

9.2.1 Analog Power (V$_{DDAD}$)

The ADC analog portion uses V$_{DDAD}$ as its power connection. In some packages, V$_{DDAD}$ is connected internally to V$_{DD}$. If externally available, connect the V$_{DDAD}$ pin to the same voltage potential as V$_{DD}$. External filtering may be necessary to ensure clean V$_{DDAD}$ for good results.

9.2.2 Analog Ground (V$_{SSAD}$)

The ADC analog portion uses V$_{SSAD}$ as its ground connection. In some packages, V$_{SSAD}$ is connected internally to V$_{SS}$. If externally available, connect the V$_{SSAD}$ pin to the same voltage potential as V$_{SS}$.

9.2.3 Voltage Reference High (V$_{REFH}$)

V$_{REFH}$ is the high reference voltage for the converter. In some packages, V$_{REFH}$ is connected internally to V$_{DDAD}$. If externally available, V$_{REFH}$ may be connected to the same potential as V$_{DDAD}$, or may be driven by an external source that is between the minimum V$_{DDAD}$ spec and the V$_{DDAD}$ potential (V$_{REFH}$ must never exceed V$_{DDAD}$).

9.2.4 Voltage Reference Low (V$_{REFL}$)

V$_{REFL}$ is the low reference voltage for the converter. In some packages, V$_{REFL}$ is connected internally to V$_{SSAD}$. If externally available, connect the V$_{REFL}$ pin to the same voltage potential as V$_{SSAD}$.

9.2.5 Analog Channel Inputs (ADx)

The ADC module supports up to 28 separate analog inputs. An input is selected for conversion through the ADCH channel select bits.

9.3 Register Definition

These memory mapped registers control and monitor operation of the ADC:

- Status and control register, ADCSC1
- Status and control register, ADCSC2
- Data result registers, ADCRH and ADCRL
- Compare value registers, ADCCVH and ADCCVL
- Configuration register, ADCCFG
- Pin enable registers, APCTL1, APCTL2, APCTL3

9.3.1 Status and Control Register 1 (ADCSC1)

This section describes the function of the ADC status and control register (ADCSC1). Writing ADCSC1 aborts the current conversion and initiates a new conversion (if the ADCH bits are equal to a value other than all 1s).

	7	6	5	4	3	2	1	0
R	COCO	AIEN	ADCO	ADCH				
W								
Reset:	0	0	0	1	1	1	1	1

☐ = Unimplemented or Reserved
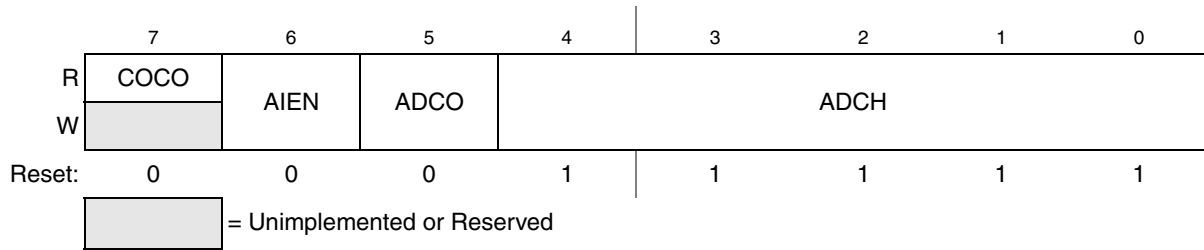
Figure 9-3. Status and Control Register (ADCSC1)

Table 9-3. ADCSC1 Register Field Descriptions

Field	Description
7 COCO	**Conversion Complete Flag** — The COCO flag is a read-only bit which is set each time a conversion is completed when the compare function is disabled (ACFE = 0). When the compare function is enabled (ACFE = 1) the COCO flag is set upon completion of a conversion only if the compare result is true. This bit is cleared whenever ADCSC1 is written or whenever ADCRL is read. 0 Conversion not completed 1 Conversion completed
6 AIEN	**Interrupt Enable** — AIEN is used to enable conversion complete interrupts. When COCO becomes set while AIEN is high, an interrupt is asserted. 0 Conversion complete interrupt disabled 1 Conversion complete interrupt enabled
5 ADCO	**Continuous Conversion Enable** — ADCO is used to enable continuous conversions. 0 One conversion following a write to the ADCSC1 when software triggered operation is selected, or one conversion following assertion of ADHWT when hardware triggered operation is selected. 1 Continuous conversions initiated following a write to ADCSC1 when software triggered operation is selected. Continuous conversions are initiated by an ADHWT event when hardware triggered operation is selected.
4:0 ADCH	**Input Channel Select** — The ADCH bits form a 5-bit field which is used to select one of the input channels. The input channels are detailed in Figure 9-4. The successive approximation converter subsystem is turned off when the channel select bits are all set to 1. This feature allows for explicit disabling of the ADC and isolation of the input channel from all sources. Terminating continuous conversions this way will prevent an additional, single conversion from being performed. It is not necessary to set the channel select bits to all 1s to place the ADC in a low-power state when continuous conversions are not enabled because the module automatically enters a low-power state when a conversion completes.

**Figure 9-4. Input Channel Select**

ADCH	Input Select
00000	AD0
00001	AD1
00010	AD2
00011	AD3
00100	AD4
00101	AD5
00110	AD6
00111	AD7

ADCH	Input Select
10000	AD16
10001	AD17
10010	AD18
10011	AD19
10100	AD20
10101	AD21
10110	AD22
10111	AD23

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Figure 9-4. Input Channel Select (continued)

ADCH	Input Select		ADCH	Input Select
01000	AD8		11000	AD24
01001	AD9		11001	AD25
01010	AD10		11010	AD26
01011	AD11		11011	AD27
01100	AD12		11100	Reserved
01101	AD13		11101	V_{REFH}
01110	AD14		11110	V_{REFL}
01111	AD15		11111	Module disabled

9.3.2   Status and Control Register 2 (ADCSC2)

The ADCSC2 register is used to control the compare function, conversion trigger and conversion active of the ADC module.
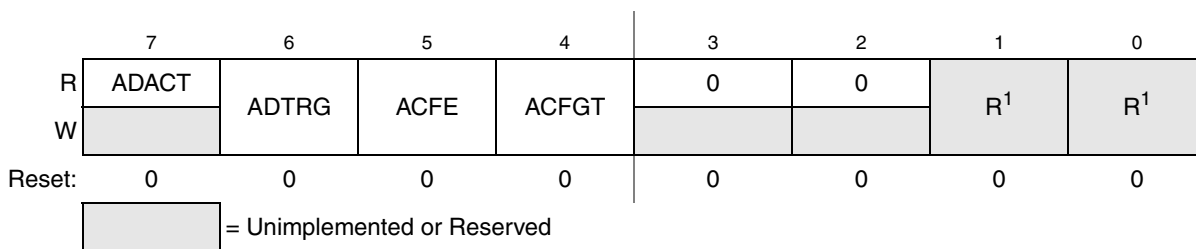
[1] Bits 1 and 0 are reserved bits that must always be written to 0.

Figure 9-5. Status and Control Register 2 (ADCSC2)

Table 9-4. ADCSC2 Register Field Descriptions

| Field	Description
7 ADACT	**Conversion Active** — ADACT indicates that a conversion is in progress. ADACT is set when a conversion is initiated and cleared when a conversion is completed or aborted. 0 Conversion not in progress 1 Conversion in progress
6 ADTRG	**Conversion Trigger Select** — ADTRG is used to select the type of trigger to be used for initiating a conversion. Two types of trigger are selectable: software trigger and hardware trigger. When software trigger is selected, a conversion is initiated following a write to ADCSC1. When hardware trigger is selected, a conversion is initiated following the assertion of the ADHWT input. 0 Software trigger selected 1 Hardware trigger selected

Table 9-4. ADCSC2 Register Field Descriptions (continued)

Field	Description
5 ACFE	**Compare Function Enable** — ACFE is used to enable the compare function. 0 Compare function disabled 1 Compare function enabled
4 ACFGT	**Compare Function Greater Than Enable** — ACFGT is used to configure the compare function to trigger when the result of the conversion of the input being monitored is greater than or equal to the compare value. The compare function defaults to triggering when the result of the compare of the input being monitored is less than the compare value. 0 Compare triggers when input is less than compare level 1 Compare triggers when input is greater than or equal to compare level

9.3.3   Data Result High Register (ADCRH)

ADCRH contains the upper two bits of the result of a 10-bit conversion. When configured for 8-bit conversions both ADR8 and ADR9 are equal to zero. ADCRH is updated each time a conversion completes except when automatic compare is enabled and the compare condition is not met. In 10-bit MODE, reading ADCRH prevents the ADC from transferring subsequent conversion results into the result registers until ADCRL is read. If ADCRL is not read until after the next conversion is completed, then the intermediate conversion result will be lost. In 8-bit mode there is no interlocking with ADCRL. In the case that the MODE bits are changed, any data in ADCRH becomes invalid.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	ADR9	ADR8
W								
Reset:	0	0	0	0	0	0	0	0

= Unimplemented or Reserved
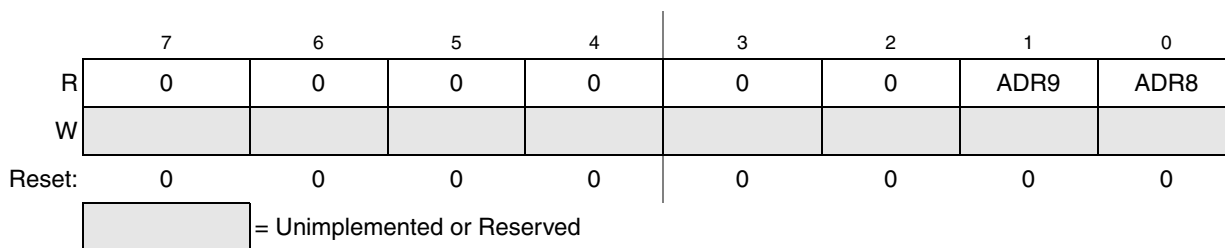
Figure 9-6. Data Result High Register (ADCRH)

## 9.3.4   Data Result Low Register (ADCRL)

ADCRL contains the lower eight bits of the result of a 10-bit conversion, and all eight bits of an 8-bit conversion. This register is updated each time a conversion completes except when automatic compare is enabled and the compare condition is not met. In 10-bit mode, reading ADCRH prevents the ADC from transferring subsequent conversion results into the result registers until ADCRL is read. If ADCRL is not read until the after next conversion is completed, then the intermediate conversion results will be lost. In 8-bit mode, there is no interlocking with ADCRH. In the case that the MODE bits are changed, any data in ADCRL becomes invalid.

	7	6	5	4	3	2	1	0
R	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0
W								
Reset:	0	0	0	0	0	0	0	0

☐ = Unimplemented or Reserved

Figure 9-7. Data Result Low Register (ADCRL)
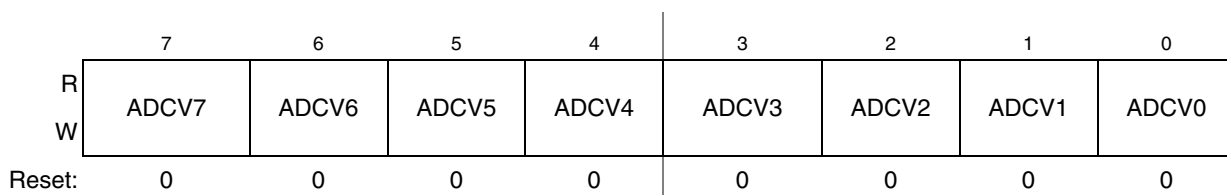
9.3.5 Compare Value High Register (ADCCVH)

This register holds the upper two bits of the 10-bit compare value. These bits are compared to the upper two bits of the result following a conversion in 10-bit mode when the compare function is enabled.In 8-bit operation, ADCCVH is not used during compare.

	7	6	5	4	3	2	1	0
R	0	0	0	0			ADCV9	ADCV8
W								
Reset:	0	0	0	0	0	0	0	0

☐ = Unimplemented or Reserved
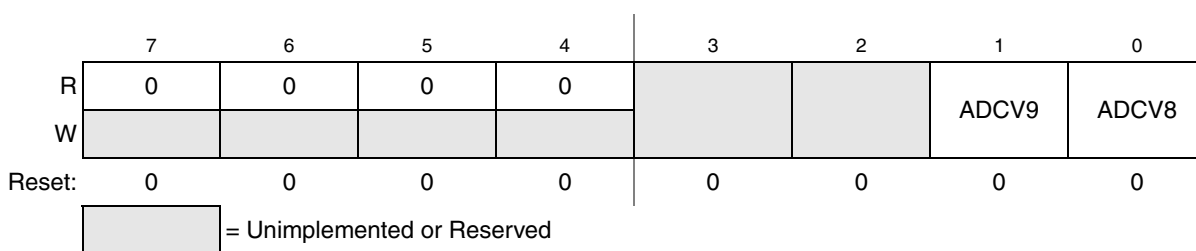
Figure 9-8. Compare Value High Register (ADCCVH)

9.3.6 Compare Value Low Register (ADCCVL)

This register holds the lower 8 bits of the 10-bit compare value, or all 8 bits of the 8-bit compare value. Bits ADCV7:ADCV0 are compared to the lower 8 bits of the result following a conversion in either 10-bit or 8-bit mode.

	7	6	5	4	3	2	1	0
R	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0
W								
Reset:	0	0	0	0	0	0	0	0

Figure 9-9. Compare Value Low Register(ADCCVL)

9.3.7 Configuration Register (ADCCFG)

ADCCFG is used to select the mode of operation, clock source, clock divide, and configure for low power or long sample time.

	7	6	5	4	3	2	1	0
R	ADLPC	ADIV		ADLSMP	MODE		ADICLK	
W								
Reset:	0	0	0	0	0	0	0	0
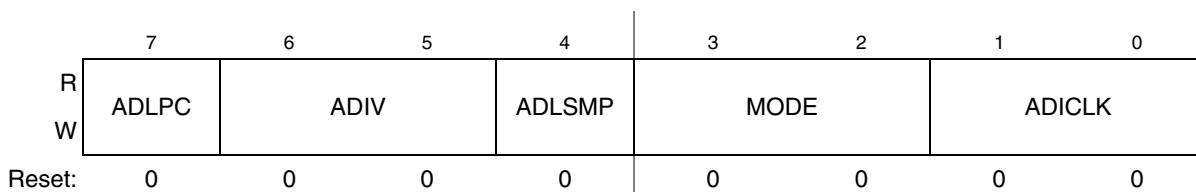
Figure 9-10. Configuration Register (ADCCFG)

Table 9-5. ADCCFG Register Field Descriptions

Field	Description
7 ADLPC	**Low Power Configuration** — ADLPC controls the speed and power configuration of the successive approximation converter. This is used to optimize power consumption when higher sample rates are not required. 0　High speed configuration 1　Low power configuration: {FC31}The power is reduced at the expense of maximum clock speed.
6:5 ADIV	**Clock Divide Select** — ADIV select the divide ratio used by the ADC to generate the internal clock ADCK. Table 9-6 shows the available clock configurations.
4 ADLSMP	**Long Sample Time Configuration** — ADLSMP selects between long and short sample time. This adjusts the sample period to allow higher impedance inputs to be accurately sampled or to maximize conversion speed for lower impedance inputs. Longer sample times can also be used to lower overall power consumption when continuous conversions are enabled if high conversion rates are not required. 0　Short sample time 1　Long sample time
3:2 MODE	**Conversion Mode Selection** — MODE bits are used to select between 10- or 8-bit operation. See Table 9-7.
1:0 ADICLK	**Input Clock Select** — ADICLK bits select the input clock source to generate the internal clock ADCK. See Table 9-8.

Table 9-6. Clock Divide Select

ADIV	Divide Ratio	Clock Rate
00	1	Input clock
01	2	Input clock ÷ 2
10	4	Input clock ÷ 4
11	8	Input clock ÷ 8

Table 9-7. Conversion Modes

MODE	Mode Description
00	8-bit conversion (N=8)
01	Reserved
10	10-bit conversion (N=10)
11	Reserved

Table 9-8. Input Clock Select

ADICLK	Selected Clock Source
00	Bus clock
01	Bus clock divided by 2
10	Alternate clock (ALTCLK)
11	Asynchronous clock (ADACK)

9.3.8 Pin Control 1 Register (APCTL1)

The pin control registers are used to disable the I/O port control of MCU pins used as analog inputs. APCTL1 is used to control the pins associated with channels 0–7 of the ADC module.

	7	6	5	4	3	2	1	0
R	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
W								
Reset:	0	0	0	0	0	0	0	0
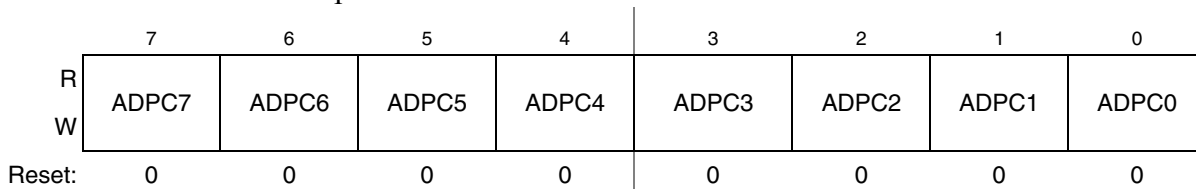
Figure 9-11. Pin Control 1 Register (APCTL1)

Table 9-9. APCTL1 Register Field Descriptions

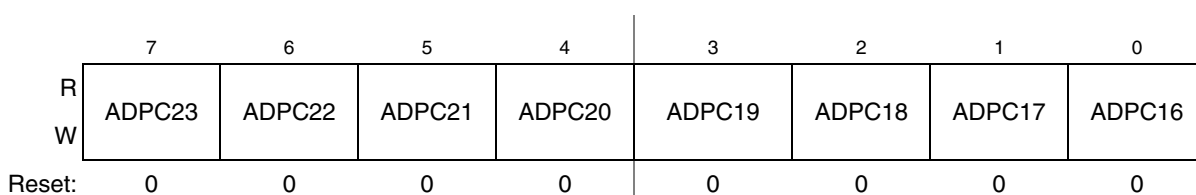| Field	Description
7 ADPC7	**ADC Pin Control 7** — ADPC7 is used to control the pin associated with channel AD7. 0 AD7 pin I/O control enabled 1 AD7 pin I/O control disabled
6 ADPC6	**ADC Pin Control 6** — ADPC6 is used to control the pin associated with channel AD6. 0 AD6 pin I/O control enabled 1 AD6 pin I/O control disabled
5 ADPC5	**ADC Pin Control 5** — ADPC5 is used to control the pin associated with channel AD5. 0 AD5 pin I/O control enabled 1 AD5 pin I/O control disabled
4 ADPC4	**ADC Pin Control 4** — ADPC4 is used to control the pin associated with channel AD4. 0 AD4 pin I/O control enabled 1 AD4 pin I/O control disabled
3 ADPC3	**ADC Pin Control 3** — ADPC3 is used to control the pin associated with channel AD3. 0 AD3 pin I/O control enabled 1 AD3 pin I/O control disabled
2 ADPC2	**ADC Pin Control 2** — ADPC2 is used to control the pin associated with channel AD2. 0 AD2 pin I/O control enabled 1 AD2 pin I/O control disabled

Table 9-9. APCTL1 Register Field Descriptions (continued)

Field	Description
1 ADPC1	**ADC Pin Control 1** — ADPC1 is used to control the pin associated with channel AD1. 0 AD1 pin I/O control enabled 1 AD1 pin I/O control disabled
0 ADPC0	**ADC Pin Control 0** — ADPC0 is used to control the pin associated with channel AD0. 0 AD0 pin I/O control enabled 1 AD0 pin I/O control disabled

9.3.9   Pin Control 2 Register (APCTL2)

APCTL2 is used to control channels 8–15 of the ADC module.

	7	6	5	4	3	2	1	0
R W	ADPC15	ADPC14	ADPC13	ADPC12	ADPC11	ADPC10	ADPC9	ADPC8
Reset:	0	0	0	0	0	0	0	0
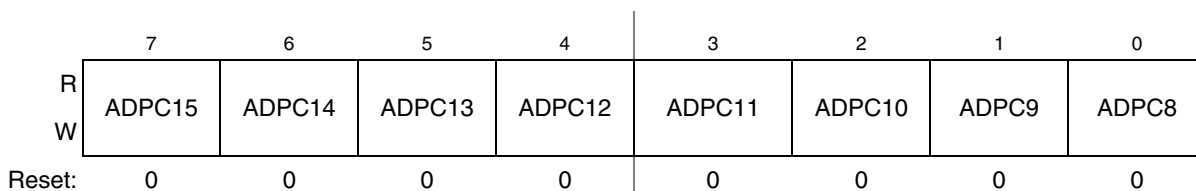
Figure 9-12. Pin Control 2 Register (APCTL2)

Table 9-10. APCTL2 Register Field Descriptions

Field	Description
7 ADPC15	**ADC Pin Control 15** — ADPC15 is used to control the pin associated with channel AD15. 0 AD15 pin I/O control enabled 1 AD15 pin I/O control disabled
6 ADPC14	**ADC Pin Control 14** — ADPC14 is used to control the pin associated with channel AD14. 0 AD14 pin I/O control enabled 1 AD14 pin I/O control disabled
5 ADPC13	**ADC Pin Control 13** — ADPC13 is used to control the pin associated with channel AD13. 0 AD13 pin I/O control enabled 1 AD13 pin I/O control disabled
4 ADPC12	**ADC Pin Control 12** — ADPC12 is used to control the pin associated with channel AD12. 0 AD12 pin I/O control enabled 1 AD12 pin I/O control disabled
3 ADPC11	**ADC Pin Control 11** — ADPC11 is used to control the pin associated with channel AD11. 0 AD11 pin I/O control enabled 1 AD11 pin I/O control disabled
2 ADPC10	**ADC Pin Control 10** — ADPC10 is used to control the pin associated with channel AD10. 0 AD10 pin I/O control enabled 1 AD10 pin I/O control disabled

Table 9-10. APCTL2 Register Field Descriptions (continued)

Field	Description
1 ADPC9	**ADC Pin Control 9** — ADPC9 is used to control the pin associated with channel AD9. 0 AD9 pin I/O control enabled 1 AD9 pin I/O control disabled
0 ADPC8	**ADC Pin Control 8** — ADPC8 is used to control the pin associated with channel AD8. 0 AD8 pin I/O control enabled 1 AD8 pin I/O control disabled

9.3.10   Pin Control 3 Register (APCTL3)

APCTL3 is used to control channels 16–23 of the ADC module.

	7	6	5	4	3	2	1	0
R W	ADPC23	ADPC22	ADPC21	ADPC20	ADPC19	ADPC18	ADPC17	ADPC16
Reset:	0	0	0	0	0	0	0	0

Figure 9-13. Pin Control 3 Register (APCTL3)

Table 9-11. APCTL3 Register Field Descriptions

Field	Description
7 ADPC23	**ADC Pin Control 23** — ADPC23 is used to control the pin associated with channel AD23. 0 AD23 pin I/O control enabled 1 AD23 pin I/O control disabled
6 ADPC22	**ADC Pin Control 22** — ADPC22 is used to control the pin associated with channel AD22. 0 AD22 pin I/O control enabled 1 AD22 pin I/O control disabled
5 ADPC21	**ADC Pin Control 21** — ADPC21 is used to control the pin associated with channel AD21. 0 AD21 pin I/O control enabled 1 AD21 pin I/O control disabled
4 ADPC20	**ADC Pin Control 20** — ADPC20 is used to control the pin associated with channel AD20. 0 AD20 pin I/O control enabled 1 AD20 pin I/O control disabled
3 ADPC19	**ADC Pin Control 19** — ADPC19 is used to control the pin associated with channel AD19. 0 AD19 pin I/O control enabled 1 AD19 pin I/O control disabled
2 ADPC18	**ADC Pin Control 18** — ADPC18 is used to control the pin associated with channel AD18. 0 AD18 pin I/O control enabled 1 AD18 pin I/O control disabled

Table 9-11. APCTL3 Register Field Descriptions (continued)

Field	Description
1 ADPC17	**ADC Pin Control 17** — ADPC17 is used to control the pin associated with channel AD17. 0 AD17 pin I/O control enabled 1 AD17 pin I/O control disabled
0 ADPC16	**ADC Pin Control 16** — ADPC16 is used to control the pin associated with channel AD16. 0 AD16 pin I/O control enabled 1 AD16 pin I/O control disabled

9.4 Functional Description

The ADC module is disabled during reset or when the ADCH bits are all high. The module is idle when a conversion has completed and another conversion has not been initiated. When idle, the module is in its lowest power state.

The ADC can perform an analog-to-digital conversion on any of the software selectable channels. The selected channel voltage is converted by a successive approximation algorithm into an 11-bit digital result. In 8-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 9-bit digital result.

When the conversion is completed, the result is placed in the data registers (ADCRH and ADCRL).In 10-bit mode, the result is rounded to 10 bits and placed in ADCRH and ADCRL. In 8-bit mode, the result is rounded to 8 bits and placed in ADCRL. The conversion complete flag (COCO) is then set and an interrupt is generated if the conversion complete interrupt has been enabled (AIEN = 1).

The ADC module has the capability of automatically comparing the result of a conversion with the contents of its compare registers. The compare function is enabled by setting the ACFE bit and operates in conjunction with any of the conversion modes and configurations.

9.4.1 Clock Select and Divide Control

One of four clock sources can be selected as the clock source for the ADC module. This clock source is then divided by a configurable value to generate the input clock to the converter (ADCK). The clock is selected from one of the following sources by means of the ADICLK bits.

- The bus clock, which is equal to the frequency at which software is executed. This is the default selection following reset.
- The bus clock divided by 2. For higher bus clock rates, this allows a maximum divide by 16 of the bus clock.
- ALTCLK, as defined for this MCU (See module section introduction).
- The asynchronous clock (ADACK) – This clock is generated from a clock source within the ADC module. When selected as the clock source this clock remains active while the MCU is in wait or stop3 mode and allows conversions in these modes for lower noise operation.

Whichever clock is selected, its frequency must fall within the specified frequency range for ADCK. If the available clocks are too slow, the ADC will not perform according to specifications. If the available clocks

are too fast, then the clock must be divided to the appropriate frequency. This divider is specified by the ADIV bits and can be divide-by 1, 2, 4, or 8.

9.4.2   Input Select and Pin Control

The pin control registers (APCTL3, APCTL2, and APCTL1) are used to disable the I/O port control of the pins used as analog inputs.When a pin control register bit is set, the following conditions are forced for the associated MCU pin:

- The output buffer is forced to its high impedance state.
- The input buffer is disabled. A read of the I/O port returns a zero for any pin with its input buffer disabled.
- The pullup is disabled.

9.4.3   Hardware Trigger

The ADC module has a selectable asynchronous hardware conversion trigger, ADHWT, that is enabled when the ADTRG bit is set. This source is not available on all MCUs. Consult the module introduction for information on the ADHWT source specific to this MCU.

When ADHWT source is available and hardware trigger is enabled (ADTRG=1), a conversion is initiated on the rising edge of ADHWT. If a conversion is in progress when a rising edge occurs, the rising edge is ignored. In continuous convert configuration, only the initial rising edge to launch continuous conversions is observed. The hardware trigger function operates in conjunction with any of the conversion modes and configurations.

9.4.4   Conversion Control

Conversions can be performed in either 10-bit mode or 8-bit mode as determined by the MODE bits. Conversions can be initiated by either a software or hardware trigger. In addition, the ADC module can be configured for low power operation, long sample time, continuous conversion, and automatic compare of the conversion result to a software determined compare value.

9.4.4.1   Initiating Conversions

A conversion is initiated:

- Following a write to ADCSC1 (with ADCH bits not all 1s) if software triggered operation is selected.
- Following a hardware trigger (ADHWT) event if hardware triggered operation is selected.
- Following the transfer of the result to the data registers when continuous conversion is enabled.

If continuous conversions are enabled a new conversion is automatically initiated after the completion of the current conversion. In software triggered operation, continuous conversions begin after ADCSC1 is written and continue until aborted. In hardware triggered operation, continuous conversions begin after a hardware trigger event and continue until aborted.

9.4.4.2 Completing Conversions

A conversion is completed when the result of the conversion is transferred into the data result registers, ADCRH and ADCRL. This is indicated by the setting of COCO. An interrupt is generated if AIEN is high at the time that COCO is set.

A blocking mechanism prevents a new result from overwriting previous data in ADCRH and ADCRL if the previous data is in the process of being read while in 10-bit MODE (the ADCRH register has been read but the ADCRL register has not). When blocking is active, the data transfer is blocked, COCO is not set, and the new result is lost. In the case of single conversions with the compare function enabled and the compare condition false, blocking has no effect and ADC operation is terminated. In all other cases of operation, when a data transfer is blocked, another conversion is initiated regardless of the state of ADCO (single or continuous conversions enabled).

If single conversions are enabled, the blocking mechanism could result in several discarded conversions and excess power consumption. To avoid this issue, the data registers must not be read after initiating a single conversion until the conversion completes.

9.4.4.3 Aborting Conversions

Any conversion in progress will be aborted when:

- A write to ADCSC1 occurs (the current conversion will be aborted and a new conversion will be initiated, if ADCH are not all 1s).
- A write to ADCSC2, ADCCFG, ADCCVH, or ADCCVL occurs. This indicates a mode of operation change has occurred and the current conversion is therefore invalid.
- The MCU is reset.
- The MCU enters stop mode with ADACK not enabled.

When a conversion is aborted, the contents of the data registers, ADCRH and ADCRL, are not altered but continue to be the values transferred after the completion of the last successful conversion. In the case that the conversion was aborted by a reset, ADCRH and ADCRL return to their reset states.

9.4.4.4 Power Control

The ADC module remains in its idle state until a conversion is initiated. If ADACK is selected as the conversion clock source, the ADACK clock generator is also enabled.

Power consumption when active can be reduced by setting ADLPC. This results in a lower maximum value for f_{ADCK} (see the electrical specifications).

9.4.4.5 Total Conversion Time

The total conversion time depends on the sample time (as determined by ADLSMP), the MCU bus frequency, the conversion mode (8-bit or 10-bit), and the frequency of the conversion clock (f_{ADCK}). After the module becomes active, sampling of the input begins. ADLSMP is used to select between short and long sample times.When sampling is complete, the converter is isolated from the input channel and a successive approximation algorithm is performed to determine the digital value of the analog signal. The

result of the conversion is transferred to ADCRH and ADCRL upon completion of the conversion algorithm.

If the bus frequency is less than the f_{ADCK} frequency, precise sample time for continuous conversions cannot be guaranteed when short sample is enabled (ADLSMP=0). If the bus frequency is less than 1/11th of the f_{ADCK} frequency, precise sample time for continuous conversions cannot be guaranteed when long sample is enabled (ADLSMP=1).

The maximum total conversion time for different conditions is summarized in Table 9-12.

Table 9-12. Total Conversion Time vs. Control Conditions

Conversion Type	ADICLK	ADLSMP	Max Total Conversion Time
Single or first continuous 8-bit	0x, 10	0	20 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit	0x, 10	0	23 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	0x, 10	1	40 ADCK cycles + 5 bus clock cycles
Single or first continuous 10-bit	0x, 10	1	43 ADCK cycles + 5 bus clock cycles
Single or first continuous 8-bit	11	0	5 μs + 20 ADCK + 5 bus clock cycles
Single or first continuous 10-bit	11	0	5 μs + 23 ADCK + 5 bus clock cycles
Single or first continuous 8-bit	11	1	5 μs + 40 ADCK + 5 bus clock cycles
Single or first continuous 10-bit	11	1	5 μs + 43 ADCK + 5 bus clock cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	17 ADCK cycles
Subsequent continuous 10-bit; $f_{BUS} \geq f_{ADCK}$	xx	0	20 ADCK cycles
Subsequent continuous 8-bit; $f_{BUS} \geq f_{ADCK}/11$	xx	1	37 ADCK cycles
Subsequent continuous 10-bit; $f_{BUS} \geq f_{ADCK}/11$	xx	1	40 ADCK cycles

The maximum total conversion time is determined by the clock source chosen and the divide ratio selected. The clock source is selectable by the ADICLK bits, and the divide ratio is specified by the ADIV bits. For example, in 10-bit mode, with the bus clock selected as the input clock source, the input clock divide-by-1 ratio selected, and a bus frequency of 8 MHz, then the conversion time for a single conversion is:

$$\text{Conversion time} = \frac{23 \text{ ADCK cyc}}{8 \text{ MHz}/1} + \frac{5 \text{ bus cyc}}{8 \text{ MHz}} = 3.5 \ \mu s$$

$$\text{Number of bus cycles} = 3.5 \ \mu s \times 8 \text{ MHz} = 28 \text{ cycles}$$

NOTE

The ADCK frequency must be between f_{ADCK} minimum and f_{ADCK} maximum to meet ADC specifications.

9.4.5   Automatic Compare Function

The compare function can be configured to check for either an upper limit or lower limit. After the input is sampled and converted, the result is added to the two's complement of the compare value (ADCCVH and ADCCVL). When comparing to an upper limit (ACFGT = 1), if the result is greater-than or equal-to the compare value, COCO is set. When comparing to a lower limit (ACFGT = 0), if the result is less than the compare value, COCO is set. The value generated by the addition of the conversion result and the two's complement of the compare value is transferred to ADCRH and ADCRL.

Upon completion of a conversion while the compare function is enabled, if the compare condition is not true, COCO is not set and no data is transferred to the result registers. An ADC interrupt is generated upon the setting of COCO if the ADC interrupt is enabled (AIEN = 1).

NOTE

The compare function can be used to monitor the voltage on a channel while the MCU is in either wait or stop3 mode. The ADC interrupt will wake the MCU when the compare condition is met.

9.4.6   MCU Wait Mode Operation

The WAIT instruction puts the MCU in a lower power-consumption standby mode from which recovery is very fast because the clock sources remain active. If a conversion is in progress when the MCU enters wait mode, it continues until completion. Conversions can be initiated while the MCU is in wait mode by means of the hardware trigger or if continuous conversions are enabled.

The bus clock, bus clock divided by two, and ADACK are available as conversion clock sources while in wait mode. The use of ALTCLK as the conversion clock source in wait is dependent on the definition of ALTCLK for this MCU. Consult the module introduction for information on ALTCLK specific to this MCU.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from wait mode if the ADC interrupt is enabled (AIEN = 1).

9.4.7   MCU Stop3 Mode Operation

The STOP instruction is used to put the MCU in a low power-consumption standby mode during which most or all clock sources on the MCU are disabled.

9.4.7.1   Stop3 Mode With ADACK Disabled

If the asynchronous clock, ADACK, is not selected as the conversion clock, executing a STOP instruction aborts the current conversion and places the ADC in its idle state. The contents of ADCRH and ADCRL are unaffected by stop3 mode.After exiting from stop3 mode, a software or hardware trigger is required to resume conversions.

9.4.7.2 Stop3 Mode With ADACK Enabled

If ADACK is selected as the conversion clock, the ADC continues operation during stop3 mode. For guaranteed ADC operation, the MCU's voltage regulator must remain active during stop3 mode. Consult the module introduction for configuration information for this MCU.

If a conversion is in progress when the MCU enters stop3 mode, it continues until completion. Conversions can be initiated while the MCU is in stop3 mode by means of the hardware trigger or if continuous conversions are enabled.

A conversion complete event sets the COCO and generates an ADC interrupt to wake the MCU from stop3 mode if the ADC interrupt is enabled (AIEN = 1).

NOTE

It is possible for the ADC module to wake the system from low power stop and cause the MCU to begin consuming run-level currents without generating a system level interrupt. To prevent this scenario, software should ensure that the data transfer blocking mechanism (discussed in Section 9.4.4.2, "Completing Conversions) is cleared when entering stop3 and continuing ADC conversions.

9.4.8 MCU Stop1 and Stop2 Mode Operation

The ADC module is automatically disabled when the MCU enters either stop1 or stop2 mode. All module registers contain their reset values following exit from stop1 or stop2. Therefore the module must be re-enabled and re-configured following exit from stop1 or stop2.

9.5 Initialization Information

This section gives an example which provides some basic direction on how a user would initialize and configure the ADC module. The user has the flexibility of choosing between configuring the module for 8-bit or 10-bit resolution, single or continuous conversion, and a polled or interrupt approach, among many other options. Refer to Table 9-6, Table 9-7, and Table 9-8 for information used in this example.

NOTE

Hexadecimal values designated by a preceding 0x, binary values designated by a preceding %, and decimal values have no preceding character.

9.5.1 ADC Module Initialization Example

9.5.1.1 Initialization Sequence

Before the ADC module can be used to complete conversions, an initialization procedure must be performed. A typical sequence is as follows:

1. Update the configuration register (ADCCFG) to select the input clock source and the divide ratio used to generate the internal clock, ADCK. This register is also used for selecting sample time and low-power configuration.

2. Update status and control register 2 (ADCSC2) to select the conversion trigger (hardware or software) and compare function options, if enabled.

3. Update status and control register 1 (ADCSC1) to select whether conversions will be continuous or completed only once, and to enable or disable conversion complete interrupts. The input channel on which conversions will be performed is also selected here.

9.5.1.2   Pseudo — Code Example

In this example, the ADC module will be set up with interrupts enabled to perform a single 10-bit conversion at low power with a long sample time on input channel 1, where the internal ADCK clock will be derived from the bus clock divided by 1.

ADCCFG = 0x98 (%10011000)

Bit 7	ADLPC	1	Configures for low power (lowers maximum clock speed)
Bit 6:5	ADIV	00	Sets the ADCK to the input clock ÷ 1
Bit 4	ADLSMP	1	Configures for long sample time
Bit 3:2	MODE	10	Sets mode at 10-bit conversions
Bit 1:0	ADICLK	00	Selects bus clock as input clock source

ADCSC2 = 0x00 (%00000000)

Bit 7	ADACT	0	Flag indicates if a conversion is in progress
Bit 6	ADTRG	0	Software trigger selected
Bit 5	ACFE	0	Compare function disabled
Bit 4	ACFGT	0	Not used in this example
Bit 3:2		00	Unimplemented or reserved, always reads zero
Bit 1:0		00	Reserved for Freescale's internal use; always write zero

ADCSC1 = 0x41 (%01000001)

Bit 7	COCO	0	Read-only flag which is set when a conversion completes
Bit 6	AIEN	1	Conversion complete interrupt enabled
Bit 5	ADCO	0	One conversion only (continuous conversions disabled)
Bit 4:0	ADCH	00001	Input channel 1 selected as ADC input channel

ADCRH/L = 0xxx

Holds results of conversion. Read high byte (ADCRH) before low byte (ADCRL) so that conversion data cannot be overwritten with data from the next conversion.

ADCCVH/L = 0xxx

Holds compare value when compare function enabled

APCTL1=0x02

AD1 pin I/O control disabled. All other AD pins remain general purpose I/O pins

APCTL2=0x00

All other AD pins remain general purpose I/O pins
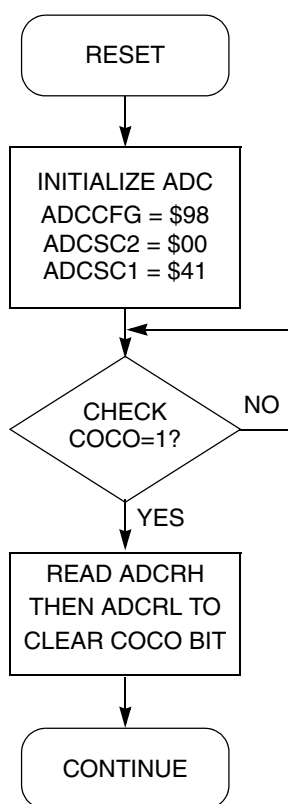
Figure 9-14. Initialization Flowchart for Example

9.6   Application Information

This section contains information for using the ADC module in applications. The ADC has been designed to be integrated into a microcontroller for use in embedded control applications requiring an A/D converter.

9.6.1   External Pins and Routing

The following sections discuss the external pins associated with the ADC module and how they should be used for best results.

9.6.1.1   Analog Supply Pins

The ADC module has analog power and ground supplies (V_{DDAD} and V_{SSAD}) which are available as separate pins on some devices. On other devices, V_{SSAD} is shared on the same pin as the MCU digital V_{SS}, and on others, both V_{SSAD} and V_{DDAD} are shared with the MCU digital supply pins. In these cases, there are separate pads for the analog supplies which are bonded to the same pin as the corresponding digital supply so that some degree of isolation between the supplies is maintained.

When available on a separate pin, both V_{DDAD} and V_{SSAD} must be connected to the same voltage potential as their corresponding MCU digital supply (V_{DD} and V_{SS}) and must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

In cases where separate power supplies are used for analog and digital power, the ground connection between these supplies must be at the V_{SSAD} pin. This should be the only ground connection between these supplies if possible. The V_{SSAD} pin makes a good single point ground location.

9.6.1.2   Analog Reference Pins

In addition to the analog supplies, the ADC module has connections for two reference voltage inputs. The high reference is V_{REFH}, which may be shared on the same pin as V_{DDAD} on some devices. The low reference is V_{REFL}, which may be shared on the same pin as V_{SSAD} on some devices.

When available on a separate pin, V_{REFH} may be connected to the same potential as V_{DDAD}, or may be driven by an external source that is between the minimum V_{DDAD} spec and the V_{DDAD} potential (V_{REFH} must never exceed V_{DDAD}). When available on a separate pin, V_{REFL} must be connected to the same voltage potential as V_{SSAD}. Both V_{REFH} and V_{REFL} must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

AC current in the form of current spikes required to supply charge to the capacitor array at each successive approximation step is drawn through the V_{REFH} and V_{REFL} loop. The best external component to meet this current demand is a 0.1 µF capacitor with good high frequency characteristics. This capacitor is connected between V_{REFH} and V_{REFL} and must be placed as near as possible to the package pins. Resistance in the path is not recommended because the current will cause a voltage drop which could result in conversion errors. Inductance in this path must be minimum (parasitic only).

9.6.1.3   Analog Input Pins

The external analog inputs are typically shared with digital I/O pins on MCU devices. The pin I/O control is disabled by setting the appropriate control bit in one of the pin control registers. Conversions can be performed on inputs without the associated pin control register bit set. It is recommended that the pin control register bit always be set when using a pin as an analog input. This avoids problems with contention because the output buffer will be in its high impedance state and the pullup is disabled. Also, the input buffer draws dc current when its input is not at either V_{DD} or V_{SS}. Setting the pin control register bits for all pins used as analog inputs should be done to achieve lowest operating current.

Empirical data shows that capacitors on the analog inputs improve performance in the presence of noise or when the source impedance is high. Use of 0.01 µF capacitors with good high-frequency characteristics is sufficient. These capacitors are not necessary in all cases, but when used they must be placed as near as possible to the package pins and be referenced to V_{SSA}.

For proper conversion, the input voltage must fall between V_{REFH} and V_{REFL}. If the input is equal to or exceeds V_{REFH}, the converter circuit converts the signal to $3FF (full scale 10-bit representation) or $FF (full scale 8-bit representation). If the input is equal to or less than V_{REFL}, the converter circuit converts it to $000. Input voltages between V_{REFH} and V_{REFL} are straight-line linear conversions. There will be a brief current associated with V_{REFL} when the sampling capacitor is charging. The input is sampled for 3.5 cycles of the ADCK source when ADLSMP is low, or 23.5 cycles when ADLSMP is high.

For minimal loss of accuracy due to current injection, pins adjacent to the analog input pins should not be transitioning during conversions.

9.6.2　Sources of Error

Several sources of error exist for A/D conversions. These are discussed in the following sections.

9.6.2.1　Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately 7kΩ and input capacitance of approximately 5.5 pF, sampling to within 1/4LSB (at 10-bit resolution) can be achieved within the minimum sample window (3.5 cycles @ 8 MHz maximum ADCK frequency) provided the resistance of the external analog source (R_{AS}) is kept below 5 kΩ.

Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

9.6.2.2　Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance (R_{AS}) is high. If this error cannot be tolerated by the application, keep R_{AS} lower than $V_{DDAD} / (2^N * I_{LEAK})$ for less than 1/4LSB leakage error (N = 8 in 8-bit mode or 10 in 10-bit mode).

9.6.2.3　Noise-Induced Errors

System noise which occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a 0.1 μF low-ESR capacitor from V_{REFH} to V_{REFL}.
- There is a 0.1 μF low-ESR capacitor from V_{DDAD} to V_{SSAD}.
- If inductive isolation is used from the primary supply, an additional 1 μF capacitor is placed from V_{DDAD} to V_{SSAD}.
- V_{SSAD} (and V_{REFL}, if connected) is connected to V_{SS} at a quiet point in the ground plane.
- Operate the MCU in wait or stop3 mode before initiating (hardware triggered conversions) or immediately after initiating (hardware or software triggered conversions) the ADC conversion.
  — For software triggered conversions, immediately follow the write to the ADCSC1 with a WAIT instruction or STOP instruction.
  — For stop3 mode operation, select ADACK as the clock source. Operation in stop3 reduces V_{DD} noise but increases effective conversion time due to stop recovery.
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive V_{DD} noise is coupled into the ADC. In these situations, or when the MCU cannot be placed in wait or stop3 or I/O activity cannot be halted, these recommended actions may reduce the effect of noise on the accuracy:

- Place a 0.01 μF capacitor (C_{AS}) on the selected input channel to V_{REFL} or V_{SSAD} (this will improve noise issues but will affect sample rate based on the external analog source resistance).

- Average the result by converting the analog input many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ADACK) and averaging. Noise that is synchronous to ADCK cannot be averaged out.

9.6.2.4 Code Width and Quantization Error

The ADC quantizes the ideal straight-line transfer function into 1024 steps (in 10-bit mode). Each step ideally has the same height (1 code) and width. The width is defined as the delta between the transition points to one code and the next. The ideal code width for an N bit converter (in this case N can be 8 or 10), defined as 1LSB, is:

$$1\text{LSB} = (V_{REFH} - V_{REFL}) / 2^N \qquad \textit{Eqn. 9-2}$$

There is an inherent quantization error due to the digitization of the result. For 8-bit or 10-bit conversions the code will transition when the voltage is at the midpoint between the points where the straight line transfer function is exactly represented by the actual transfer function. Therefore, the quantization error will be ± 1/2LSB in 8- or 10-bit mode. As a consequence, however, the code width of the first ($000) conversion is only 1/2LSB and the code width of the last ($FF or $3FF) is 1.5LSB.

9.6.2.5 Linearity Errors

The ADC may also exhibit non-linearity of several forms. Every effort has been made to reduce these errors but the system should be aware of them because they affect overall accuracy. These errors are:

- Zero-scale error (E_{ZS}) (sometimes called offset) — This error is defined as the difference between the actual code width of the first conversion and the ideal code width (1/2LSB). Note, if the first conversion is $001, then the difference between the actual $001 code width and its ideal (1LSB) is used.
- Full-scale error (E_{FS}) — This error is defined as the difference between the actual code width of the last conversion and the ideal code width (1.5LSB). Note, if the last conversion is $3FE, then the difference between the actual $3FE code width and its ideal (1LSB) is used.
- Differential non-linearity (DNL) — This error is defined as the worst-case difference between the actual code width and the ideal code width for all conversions.
- Integral non-linearity (INL) — This error is defined as the highest-value the (absolute value of the) running sum of DNL achieves. More simply, this is the worst-case difference of the actual transition voltage to a given code and its corresponding ideal transition voltage, for all codes.
- Total unadjusted error (TUE) — This error is defined as the difference between the actual transfer function and the ideal straight-line transfer function, and therefore includes all forms of error.

9.6.2.6 Code Jitter, Non-Monotonicity and Missing Codes

Analog-to-digital converters are susceptible to three special forms of error. These are code jitter, non-monotonicity, and missing codes.

Code jitter is when, at certain points, a given input voltage converts to one of two values when sampled repeatedly. Ideally, when the input voltage is infinitesimally smaller than the transition voltage, the

converter yields the lower code (and vice-versa). However, even very small amounts of system noise can cause the converter to be indeterminate (between two codes) for a range of input voltages around the transition voltage. This range is normally around ±1/2 LSB and will increase with noise. This error may be reduced by repeatedly sampling the input and averaging the result. Additionally the techniques discussed in Section 9.6.2.3 will reduce this error.

Non-monotonicity is defined as when, except for code jitter, the converter converts to a lower code for a higher input voltage. Missing codes are those values which are never converted for any input value.

In 8-bit or 10-bit mode, the ADC is guaranteed to be monotonic and to have no missing codes.

Chapter 10
Internal Clock Source (S08ICSV3)

10.1 Introduction

The internal clock source (ICS) module provides clock source choices for the MCU. The module contains a frequency locked loop (FLL) as a clock source that is controllable by an internal or an external reference clock. The module can provide this FLL clock, the internal or external reference clocks as a source for the MCU system clock. There are also signals provided to control a low power oscillator (XOSC) module to allow the use of an external crystal/resonator as the external reference clock.

Whichever clock source is chosen, it is passed through a reduced bus divider (BDIV) which allows a lower final output clock frequency to be derived.

The bus frequency will be one-half of the ICSOUT frequency.

10.1.1 Module Configuration

When the internal reference is enabled in stop mode (IREFSTEN = 1), the voltage regulator must also be enabled in stop mode by setting the LVDE and LVDSE bits in the SPMSC1 register.

Figure 10-1 shows the MC9S08SE8 block diagram with the ICS block and pins highlighted.
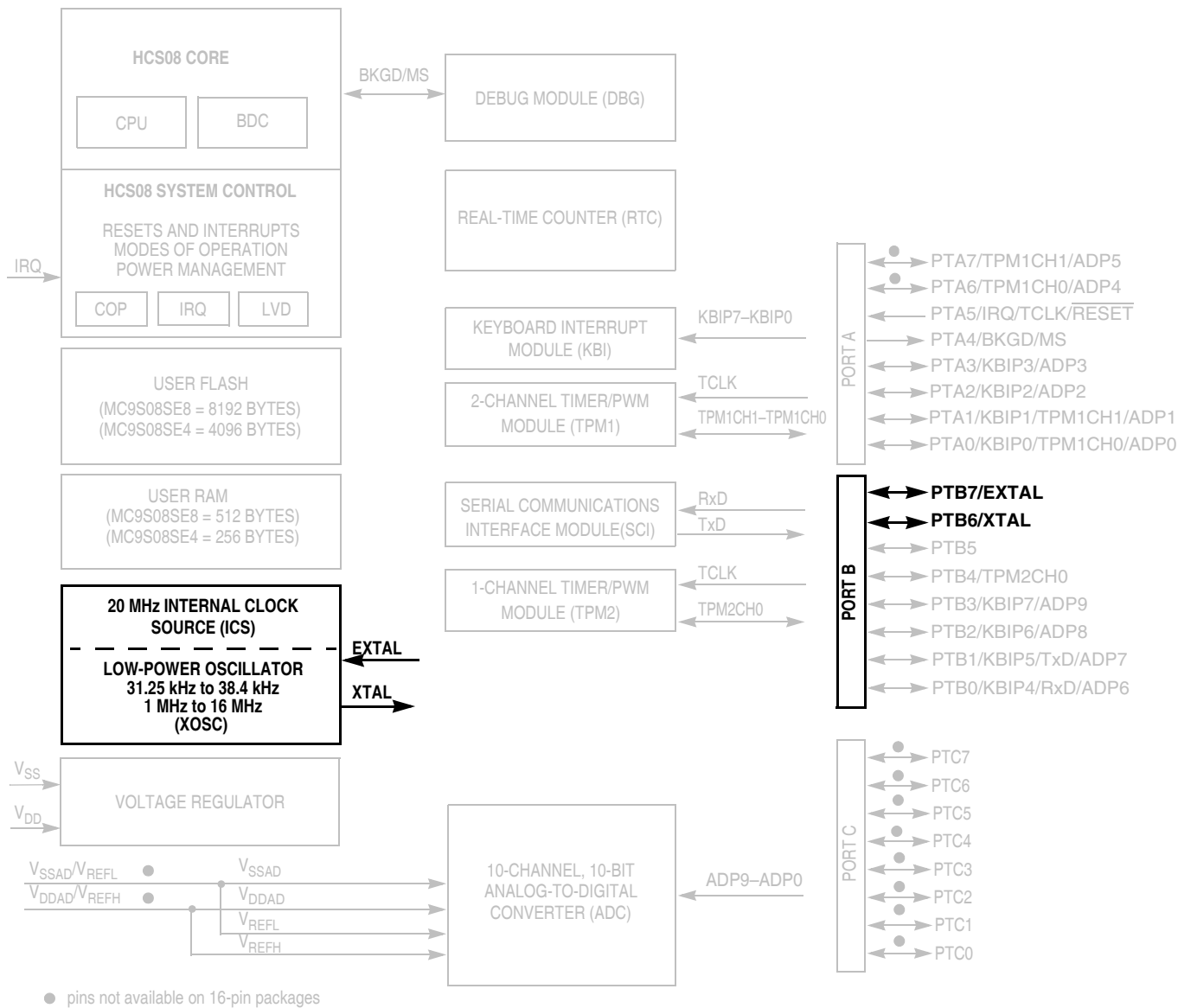
Figure 10-1. MC9S08SE8 Series Block Diagram Highlighting ICS Block and Pins

10.1.2 Features

Key features of the ICS module are:

- Frequency-locked loop (FLL) is trimmable for accuracy
- Internal or external reference clocks can be used to control the FLL
- Reference divider is provided for external clock
- Internal reference clock has 9 trim bits available
- Internal or external reference clocks can be selected as the clock source for the MCU
- Whichever clock is selected as the source can be divided down
  - 2-bit select for clock divider is provided
    - Allowable dividers are: 1, 2, 4, 8
- Control signals for a low power oscillator clock generator (OSCOUT) as the ICS external reference clock are provided
  - HGO, RANGE, EREFS, ERCLKEN, EREFSTEN
- FLL Engaged Internal mode is automatically selected out of reset
- BDC clock is provided as a constant divide by 2 of the low range DCO output
- Three selectable digitally-controlled oscillators (DCO) optimized for different frequency ranges.
- Option to maximize output frequency for a 32768 Hz external reference clock source.

10.1.3 Block Diagram

Figure 10-2 is the ICS block diagram.
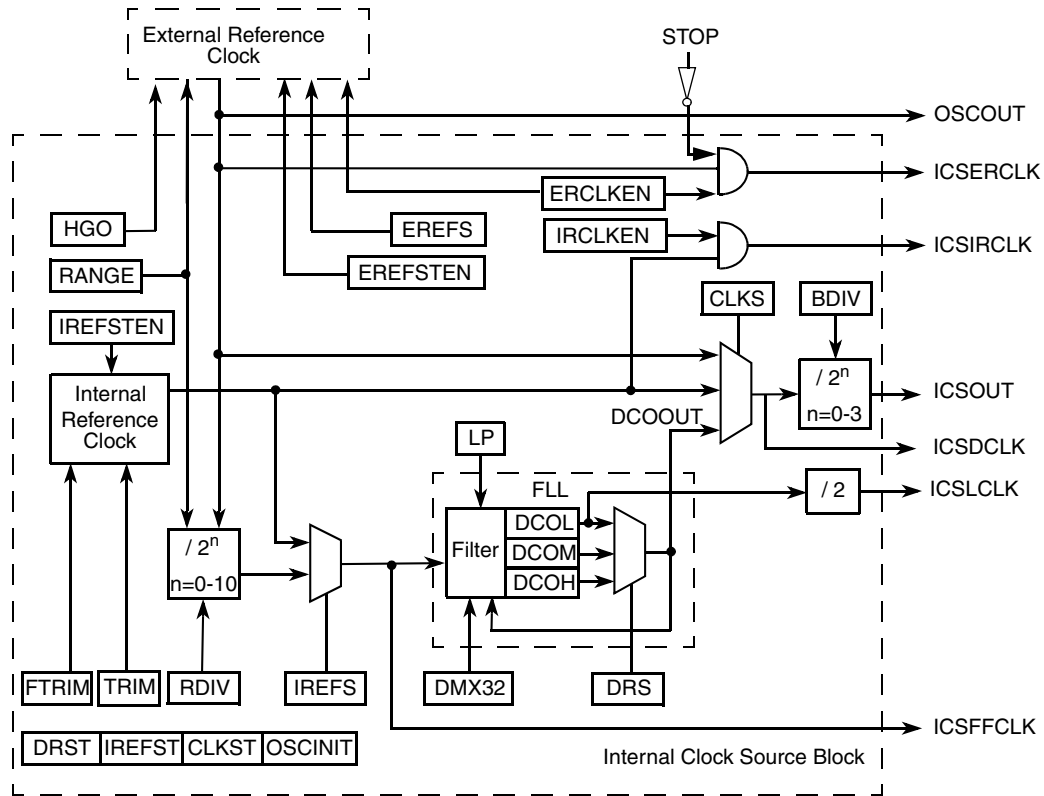
Figure 10-2. Internal Clock Source (ICS) Block Diagram

10.1.4   Modes of Operation

There are seven modes of operation for the ICS: FEI, FEE, FBI, FBILP, FBE, FBELP, and stop.

10.1.4.1   FLL Engaged Internal (FEI)

In FLL engaged internal mode, which is the default mode, the ICS supplies a clock derived from the FLL which is controlled by the internal reference clock. The BDC clock is supplied from the FLL.

10.1.4.2   FLL Engaged External (FEE)

In FLL engaged external mode, the ICS supplies a clock derived from the FLL which is controlled by an external reference clock source. The BDC clock is supplied from the FLL.

10.1.4.3   FLL Bypassed Internal (FBI)

In FLL bypassed internal mode, the FLL is enabled and controlled by the internal reference clock, but is bypassed. The ICS supplies a clock derived from the internal reference clock. The BDC clock is supplied from the FLL.

10.1.4.4 FLL Bypassed Internal Low Power (FBILP)

In FLL bypassed internal low power mode, the FLL is disabled and bypassed, and the ICS supplies a clock derived from the internal reference clock. The BDC clock is not available.

10.1.4.5 FLL Bypassed External (FBE)

In FLL bypassed external mode, the FLL is enabled and controlled by an external reference clock, but is bypassed. The ICS supplies a clock derived from the external reference clock source. The BDC clock is supplied from the FLL.

10.1.4.6 FLL Bypassed External Low Power (FBELP)

In FLL bypassed external low power mode, the FLL is disabled and bypassed, and the ICS supplies a clock derived from the external reference clock. The BDC clock is not available.

10.1.4.7 Stop (STOP)

In stop mode, the FLL is disabled and the internal or the ICS external reference clocks source (OSCOUT) can be selected to be enabled or disabled. The BDC clock is not available and the ICS does not provide an MCU clock source.

NOTE
The DCO frequency changes from the pre-stop value to its reset value and the FLL will need to re-acquire the lock before the frequency is stable. Timing sensitive operations should wait for the FLL acquisition time, tAquire, before executing.

10.2 External Signal Description

There are no ICS signals that connect off chip.

10.3 Register Definition

Figure 10-1 is a summary of ICS registers.

Table 10-1. ICS Register Summary

Name		7	6	5	4	3	2	1	0
ICSC1	R	CLKS		RDIV			IREFS	IRCLKEN	IREFSTEN
	W								
ICSC2	R	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
	W								
ICSTRM	R	TRIM							
	W								

Table 10-1. ICS Register Summary (continued)

Name		7	6	5	4	3	2	1	0
ICSSC	R	DRST		DMX32	IREFST	CLKST		OSCINIT	FTRIM
	W	DRS							

10.3.1 ICS Control Register 1 (ICSC1)

	7	6	5	4	3	2	1	0
R W	CLKS		RDIV			IREFS	IRCLKEN	IREFSTEN
Reset:	0	0	0	0	0	1	0	0
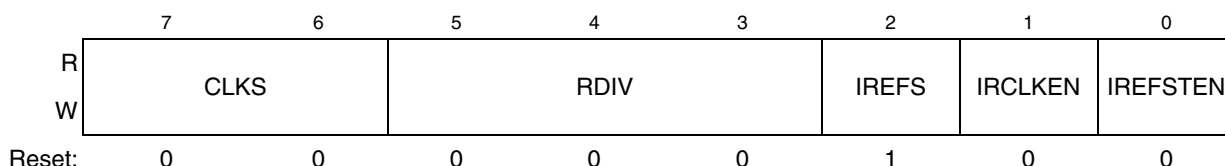
Figure 10-3. ICS Control Register 1 (ICSC1)

Table 10-2. ICS Control Register 1 Field Descriptions

Field	Description
7:6 CLKS	**Clock Source Select** — Selects the clock source that controls the bus frequency. The actual bus frequency depends on the value of the BDIV bits. 00 Output of FLL is selected. 01 Internal reference clock is selected. 10 External reference clock is selected. 11 Reserved, defaults to 00.
5:3 RDIV	**Reference Divider** — Selects the amount to divide down the external reference clock. Resulting frequency must be in the range 31.25 kHz to 39.0625 kHz. See Table 10-3 for the divide-by factors.
2 IREFS	**Internal Reference Select** — The IREFS bit selects the reference clock source for the FLL. 1 Internal reference clock selected. 0 External reference clock selected.
1 IRCLKEN	**Internal Reference Clock Enable** — The IRCLKEN bit enables the internal reference clock for use as ICSIRCLK. 1 ICSIRCLK active. 0 ICSIRCLK inactive.
0 IREFSTEN	**Internal Reference Stop Enable** — The IREFSTEN bit controls whether or not the internal reference clock remains enabled when the ICS enters stop mode. 1 Internal reference clock stays enabled in stop if IRCLKEN is set before entering stop. 0 Internal reference clock is disabled in stop.

Table 10-3. Reference Divide Factor

RDIV	RANGE=0	RANGE=1
0	1[1]	32
1	2	64
2	4	128
3	8	256

Table 10-3. Reference Divide Factor

RDIV	RANGE=0	RANGE=1
4	16	512
5	32	1024
6	64	Reserved
7	128	Reserved

[1] Reset default

10.3.2 ICS Control Register 2 (ICSC2)

	7	6	5	4	3	2	1	0
R	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
W								
Reset:	0	1	0	0	0	0	0	0
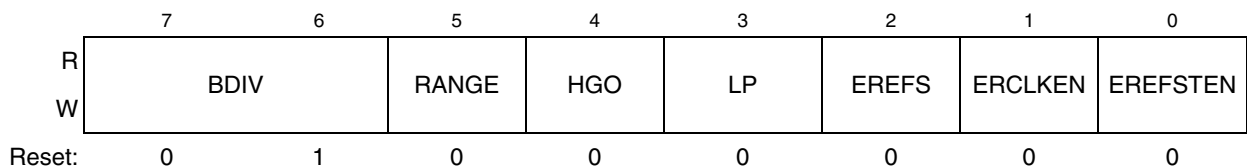
Figure 10-4. ICS Control Register 2 (ICSC2)

Table 10-4. ICS Control Register 2 Field Descriptions

Field	Description
7:6 BDIV	**Bus Frequency Divider** — Selects the amount to divide down the clock source selected by the CLKS bits. This controls the bus frequency. 00 Encoding 0 — Divides selected clock by 1. 01 Encoding 1 — Divides selected clock by 2 (reset default). 10 Encoding 2 — Divides selected clock by 4. 11 Encoding 3 — Divides selected clock by 8.
5 RANGE	**Frequency Range Select** — Selects the frequency range for the external oscillator. 1 High frequency range selected for the external oscillator. 0 Low frequency range selected for the external oscillator.
4 HGO	**High Gain Oscillator Select** — The HGO bit controls the external oscillator mode of operation. 1 Configure external oscillator for high gain operation. 0 Configure external oscillator for low power operation.
3 LP	**Low Power Select** — The LP bit controls whether the FLL is disabled in FLL bypassed modes. 1 FLL is disabled in bypass modes unless BDM is active. 0 FLL is not disabled in bypass mode.
2 EREFS	**External Reference Select** — The EREFS bit selects the source for the external reference clock. 1 Oscillator requested. 0 External Clock Source requested.
1 ERCLKEN	**External Reference Enable** — The ERCLKEN bit enables the external reference clock for use as ICSERCLK. 1 ICSERCLK active. 0 ICSERCLK inactive.
0 EREFSTEN	**External Reference Stop Enable** — The EREFSTEN bit controls whether or not the external reference clock source (OSCOUT) remains enabled when the ICS enters stop mode. 1 External reference clock source stays enabled in stop if ERCLKEN is set before entering stop. 0 External reference clock source is disabled in stop.

10.3.3   ICS Trim Register (ICSTRM)

	7	6	5	4	3	2	1	0
R								
W				TRIM				
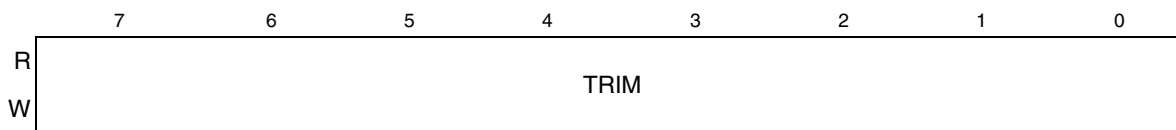
Reset: Note: TRIM is loaded during reset from a factory programmed location when not in BDM mode. If in a BDM mode, a default value of 0x80 is loaded.

Figure 10-5. ICS Trim Register (ICSTRM)

Table 10-5. ICS Trim Register Field Descriptions

Field	Description
7:0 TRIM	**ICS Trim Setting** — The TRIM bits control the internal reference clock frequency by controlling the internal reference clock period. The bits' effect are binary weighted (in other words, bit 1 adjusts twice as much as bit 0). Increasing the binary value in TRIM will increase the period, and decreasing the value will decrease the period. An additional fine trim bit is available in ICSSC as the FTRIM bit.

10.3.4   ICS Status and Control (ICSSC)

	7	6	5	4	3	2	1	0
R	DRST		DMX32	IREFST	CLKST		OSCINIT	FTRIM[1]
W	DRS							
Reset:	0	0	0	1	0	0	0	
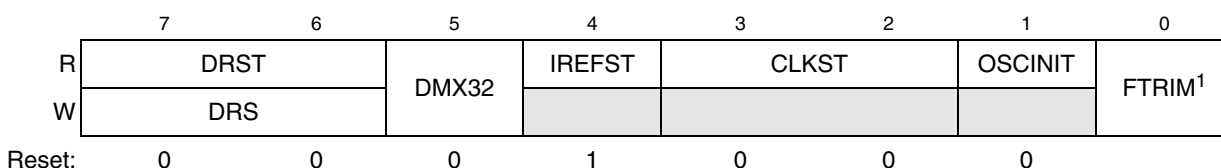
Figure 10-6. ICS Status and Control Register (ICSSC)

[1] FTRIM is loaded during reset from a factory programmed location when not in any BDM mode. If in a BDM mode, FTRIM gets loaded with a value of 1'b0.

Table 10-6. ICS Status and Control Register Field Descriptions

Field	Description
7-6 DRST DRS	**DCO Range Status** — The DRST read field indicates the current frequency range for the FLL output, DCOOUT. See Table 10-7. The DRST field does not update immediately after a write to the DRS field due to internal synchronization between clock domains. Writing the DRS bits to 2'b11 is ignored and the DRST bits remain with the current setting. **DCO Range Select** — The DRS field selects the frequency range for the FLL output, DCOOUT. Writes to the DRS field while the LP bit is set are ignored. 00 Low range. 01 Mid range. 10 High range. 11 Reserved.
5 DMX32	**DCO Maximum frequency with 32.768 kHz reference** — The DMX32 bit controls whether or not the DCO frequency range is narrowed to its maximum frequency with a 32.768 kHz reference. See Table 10-7. 0 DCO has default range of 25%. 1 DCO is fined tuned for maximum frequency with 32.768 kHz reference.

Table 10-6. ICS Status and Control Register Field Descriptions (continued)

Field	Description
4 IREFST	**Internal Reference Status** — The IREFST bit indicates the current source for the reference clock. The IREFST bit does not update immediately after a write to the IREFS bit due to internal synchronization between clock domains. 0 Source of reference clock is external clock. 1 Source of reference clock is internal clock.
3-2 CLKST	**Clock Mode Status** — The CLKST bits indicate the current clock mode. The CLKST bits don't update immediately after a write to the CLKS bits due to internal synchronization between clock domains. 00 Output of FLL is selected. 01 FLL Bypassed, Internal reference clock is selected. 10 FLL Bypassed, External reference clock is selected. 11 Reserved.
1 OSCINIT	**OSC Initialization** — If the external reference clock is selected by ERCLKEN or by the ICS being in FEE, FBE, or FBELP mode, and if EREFS is set, then this bit is set after the initialization cycles of the external oscillator clock have completed. This bit is only cleared when either ERCLKEN or EREFS are cleared.
0 FTRIM	**ICS Fine Trim** — The FTRIM bit controls the smallest adjustment of the internal reference clock frequency. Setting FTRIM will increase the period and clearing FTRIM will decrease the period by the smallest amount possible.

Table 10-7. DCO frequency range[1]

DRS	DMX32	Reference range	FLL factor	DCO range
00	**0**	31.25 - 39.0625 kHz	512	16 - 20 MHz
	1	32.768 kHz	608	19.92 MHz
01	**0**	31.25 - 39.0625 kHz	1024	32 - 40 MHz
	1	32.768 kHz	1216	39.85 MHz
10	**0**	31.25 - 39.0625 kHz	1536	48 - 60 MHz
	1	32.768 kHz	1824	59.77 MHz
11	Reserved			

[1] The resulting bus clock frequency should not exceed the maximum specified bus clock frequency of the device.

10.4   Functional Description

10.4.1   Operational Modes

IREFS=1
CLKS=00

FLL Engaged Internal (FEI)

IREFS=0
CLKS=10
BDM Enabled
or LP =0

IREFS=1
CLKS=01
BDM Enabled
or LP=0

FLL Bypassed External Low Power(FBELP)

FLL Bypassed External (FBE)

FLL Bypassed Internal (FBI)

FLL Bypassed Internal Low Power(FBILP)

IREFS=0
CLKS=10
BDM Disabled
and LP=1

IREFS=1
CLKS=01
BDM Disabled
and LP=1

FLL Engaged External (FEE)

IREFS=0
CLKS=00

Entered from any state
when MCU enters stop

Stop

Returns to state that was active
before MCU entered stop, unless
RESET occurs while in stop.

Figure 10-7. Clock Switching Modes

The seven states of the ICS are shown as a state diagram and are described below. The arrows indicate the allowed movements between the states.

10.4.1.1   FLL Engaged Internal (FEI)

FLL engaged internal (FEI) is the default mode of operation and is entered when all the following conditions occur:

- CLKS bits are written to 00.
- IREFS bit is written to 1.

In FLL engaged internal mode, the ICSOUT clock is derived from the FLL clock, which is controlled by the internal reference clock. The FLL loop locks the frequency to the FLL factor times the internal reference frequency. The ICSLCLK is available for BDC communications, and the internal reference clock is enabled.

10.4.1.2 FLL Engaged External (FEE)

The FLL engaged external (FEE) mode is entered when all the following conditions occur:

- CLKS bits are written to 00.
- IREFS bit is written to 0.
- RDIV bits are written to divide external reference clock to be within the range of 31.25 kHz to 39.0625 kHz.

In FLL engaged external mode, the ICSOUT clock is derived from the FLL clock which is controlled by the external reference clock source.The FLL loop locks the frequency to the FLL factor times the external reference frequency, as selected by the RDIV bits. The ICSLCLK is available for BDC communications, and the external reference clock is enabled.

10.4.1.3 FLL Bypassed Internal (FBI)

The FLL bypassed internal (FBI) mode is entered when all the following conditions occur:

- CLKS bits are written to 01.
- IREFS bit is written to 1.
- BDM mode is active or LP bit is written to 0.

In FLL bypassed internal mode, the ICSOUT clock is derived from the internal reference clock. The FLL clock is controlled by the internal reference clock, and the FLL loop locks the FLL frequency to the FLL factor times the internal reference frequency. The ICSLCLK will be available for BDC communications, and the internal reference clock is enabled.

10.4.1.4 FLL Bypassed Internal Low Power (FBILP)

The FLL bypassed internal low power (FBILP) mode is entered when all the following conditions occur:

- CLKS bits are written to 01.
- IREFS bit is written to 1.
- BDM mode is not active and LP bit is written to 1.

In FLL bypassed internal low power mode, the ICSOUT clock is derived from the internal reference clock and the FLL is disabled. The ICSLCLK will be not be available for BDC communications, and the internal reference clock is enabled.

10.4.1.5 FLL Bypassed External (FBE)

The FLL bypassed external (FBE) mode is entered when all the following conditions occur:

- CLKS bits are written to 10.
- IREFS bit is written to 0.
- RDIV bits are written to divide external reference clock to be within the range of 31.25 kHz to 39.0625 kHz.
- BDM mode is active or LP bit is written to 0.

In FLL bypassed external mode, the ICSOUT clock is derived from the external reference clock source. The FLL clock is controlled by the external reference clock, and the FLL loop locks the FLL frequency to the FLL factor times the external reference frequency, as selected by the RDIV bits, so that the ICSLCLK will be available for BDC communications, and the external reference clock is enabled.

10.4.1.6 FLL Bypassed External Low Power (FBELP)

The FLL bypassed external low power (FBELP) mode is entered when all the following conditions occur:

- CLKS bits are written to 10.
- IREFS bit is written to 0.
- BDM mode is not active and LP bit is written to 1.

In FLL bypassed external low power mode, the ICSOUT clock is derived from the external reference clock source and the FLL is disabled. The ICSLCLK will be not be available for BDC communications. The external reference clock source is enabled.

10.4.1.7 Stop

Stop mode is entered whenever the MCU enters a STOP state. In this mode, all ICS clock signals are static except in the following cases:

ICSIRCLK will be active in stop mode when all the following conditions occur:

- IRCLKEN bit is written to 1.
- IREFSTEN bit is written to 1.

OSCOUT will be active in stop mode when all the following conditions occur:

- ERCLKEN bit is written to 1.
- EREFSTEN bit is written to 1.

10.4.2 Mode Switching

The IREF bit can be changed at anytime, but the actual switch to the newly selected clock is shown by the IREFST bit. When switching between FLL engaged internal (FEI) and FLL engaged external (FEE) modes, the FLL begins locking again after the switch is completed.

The CLKS bits can also be changed at anytime, but the actual switch to the newly selected clock is shown by the CLKST bits. If the newly selected clock is not available, the previous clock remains selected.

The DRS bits can be changed at anytime except when LP bit is 1. If the DRS bits are changed while in FLL engaged internal (FEI) or FLL engaged external (FEE), the bus clock remains at the previous DCO range until the new DCO starts. When the new DCO starts the bus clock switches to it. After switching to the new DCO the FLL remains unlocked for several reference cycles. Once the selected DCO startup time is over, the FLL is locked. The completion of the switch is shown by the DRST bits.

10.4.3 Bus Frequency Divider

The BDIV bits can be changed at anytime and the actual switch to the new frequency occurs immediately.

10.4.4 Low Power Bit Usage

The low power bit (LP) is provided to allow the FLL to be disabled and thus conserve power when it is not being used. The DRS bits can not be written while LP bit is 1.

However, in some applications it may be desirable to allow the FLL to be enabled and to lock for maximum accuracy before switching to an FLL engaged mode. To do this, write the LP bit to 0.

10.4.5 DCO Maximum Frequency with 32.768 kHz Oscillator

The FLL has an option to change the clock multiplier for the selected DCO range such that it results in the maximum bus frequency with a common 32.768 kHz crystal reference clock.

10.4.6 Internal Reference Clock

When IRCLKEN is set the internal reference clock signal is presented as ICSIRCLK, which can be used as an additional clock source. To re-target the ICSIRCLK frequency, write a new value to the TRIM bits in the ICSTRM register to trim the period of the internal reference clock:

- Writing a larger value slows down the ICSIRCLK frequency.
- Writing a smaller value to the ICSTRM register speeds up the ICSIRCLK frequency.

The TRIM bits effect the ICSOUT frequency if the ICS is in FLL engaged internal (FEI), FLL bypassed internal (FBI), or FLL bypassed internal low power (FBILP) mode.

Until ICSIRCLK is trimmed, programming low reference divider (RDIV) factors may result in ICSOUT frequencies that exceed the maximum chip-level frequency and violate the chip-level clock timing specifications (see the Device Overview chapter).

If IREFSTEN is set and the IRCLKEN bit is written to 1, the internal reference clock keeps running during stop mode in order to provide a fast recovery upon exiting stop.

All MCU devices are factory programmed with a trim value in a reserved memory location. This value is uploaded to the ICSTRM register and ICS FTRIM register during any reset initialization. For finer precision, trim the internal oscillator in the application and set the FTRIM bit accordingly.

10.4.7 External Reference Clock

The ICS module supports an external reference clock with frequencies between 31.25 kHz to 40 MHz in all modes. When the ERCLKEN is set, the external reference clock signal is presented as ICSERCLK, which can be used as an additional clock source in run mode. When IREFS = 1, the external reference clock is not used by the FLL and will only be used as ICSERCLK. In these modes, the frequency can be equal to the maximum frequency the chip-level timing specifications support (see the Device Overview chapter).

If EREFSTEN is set and the ERCLKEN bit is written to 1, the external reference clock source (OSCOUT) keeps running during stop mode in order to provide a fast recovery upon exiting stop.

10.4.8 Fixed Frequency Clock

The ICS presents the divided FLL reference clock as ICSFFCLK for use as an additional clock source. ICSFFCLK frequency must be no more than 1/4 of the ICSOUT frequency to be valid.

10.4.9 Local Clock

The ICS presents the low range DCO output clock divided by two as ICSLCLK for use as a clock source for BDC communications. ICSLCLK is not available in FLL bypassed internal low power (FBILP) and FLL bypassed external low power (FBELP) modes.

Chapter 11
Real-Time Counter (S08RTCV1)

11.1 Introduction

The RTC module consists of one 8-bit counter, one 8-bit comparator, several binary based and decimal based prescaler dividers, two clock sources, and one programmable periodic interrupt. This module can be used for time-of-day, calendar or any task scheduling functions. It can also serve as a cyclic wakeup from low power modes without the need of external components.
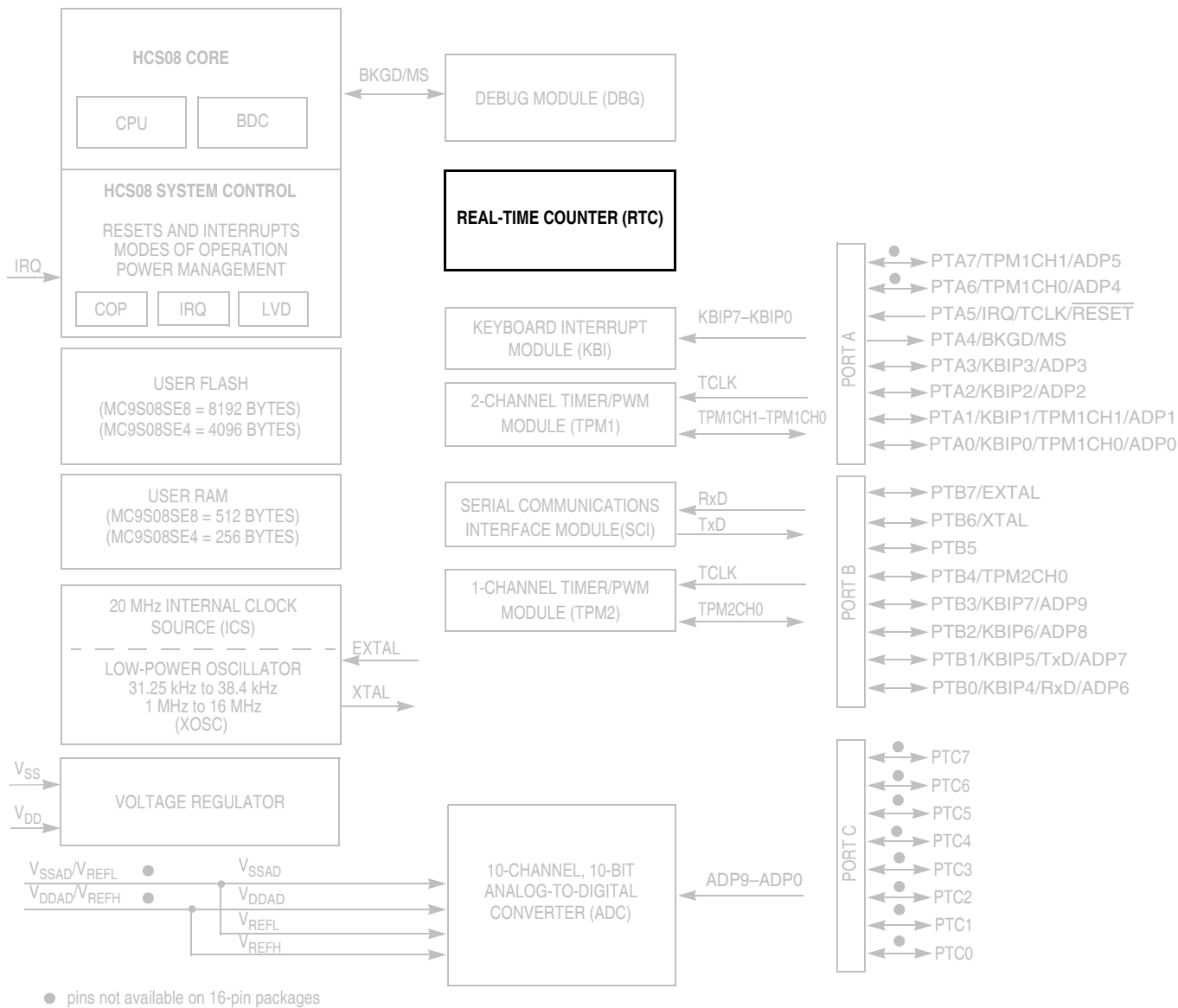
Figure 11-1. MC9S08SE8 Series Block Diagram Highlighting RTC Block

11.1.1 Features

Features of the RTC module include:

- 8-bit up-counter
    - 8-bit modulo match limit
    - Software controllable periodic interrupt on match
- Three software selectable clock sources for input to prescaler with selectable binary-based and decimal-based divider values
    - 1-kHz internal low-power oscillator (LPO)
    - External clock (ERCLK)
    - 32-kHz internal clock (IRCLK)

11.1.2 Modes of Operation

This section defines the operation in stop, wait and background debug modes.

11.1.2.1 Wait Mode

The RTC continues to run in wait mode if enabled before executing the appropriate instruction. Therefore, the RTC can bring the MCU out of wait mode if the real-time interrupt is enabled. For lowest possible current consumption, the RTC should be stopped by software if not needed as an interrupt source during wait mode.

11.1.2.2 Stop Modes

The RTC continues to run in stop2 or stop3 mode if the RTC is enabled before executing the STOP instruction. Therefore, the RTC can bring the MCU out of stop modes with no external components, if the real-time interrupt is enabled.

The LPO clock can be used in stop2 and stop3 modes. ERCLK and IRCLK clocks are only available in stop3 mode.

Power consumption is lower when all clock sources are disabled, but in that case, the real-time interrupt cannot wake up the MCU from stop modes.

11.1.2.3 Active Background Mode

The RTC suspends all counting during active background mode until the microcontroller returns to normal user operating mode. Counting resumes from the suspended value as long as the RTCMOD register is not written and the RTCPS and RTCLKS bits are not altered.

11.1.3   Block Diagram

The block diagram for the RTC module is shown in Figure 11-2.
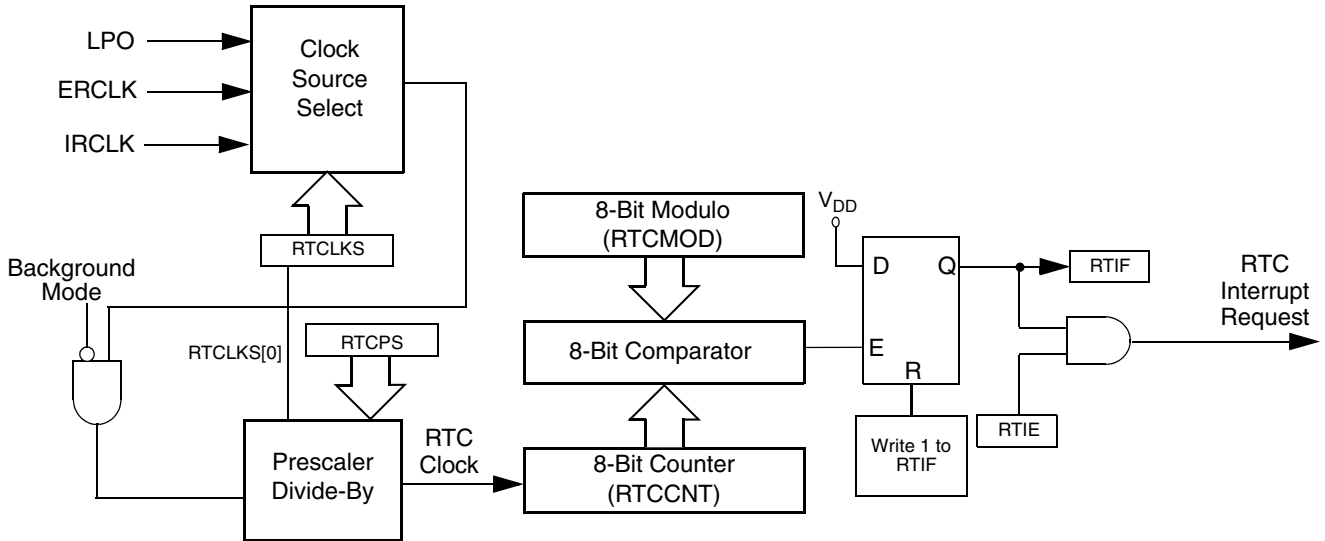
Figure 11-2. Real-Time Counter (RTC) Block Diagram

11.2   External Signal Description

The RTC does not include any off-chip signals.

11.3   Register Definition

The RTC includes a status and control register, an 8-bit counter register, and an 8-bit modulo register.

Refer to the direct-page register summary in the memory section of this document for the absolute address assignments for all RTC registers.This section refers to registers and control bits only by their names and relative address offsets.

Table 11-1 is a summary of RTC registers.

Table 11-1. RTC Register Summary

Name		7	6	5	4	3	2	1	0
RTCSC	R	RTIF	RTCLKS		RTIE	RTCPS			
	W								
RTCCNT	R	RTCCNT							
	W								
RTCMOD	R	RTCMOD							
	W								

11.3.1   RTC Status and Control Register (RTCSC)

RTCSC contains the real-time interrupt status flag (RTIF), the clock select bits (RTCLKS), the real-time interrupt enable bit (RTIE), and the prescaler select bits (RTCPS).

	7	6	5	4	3	2	1	0
R	RTIF	RTCLKS		RTIE	RTCPS			
W								
Reset:	0	0	0	0	0	0	0	0
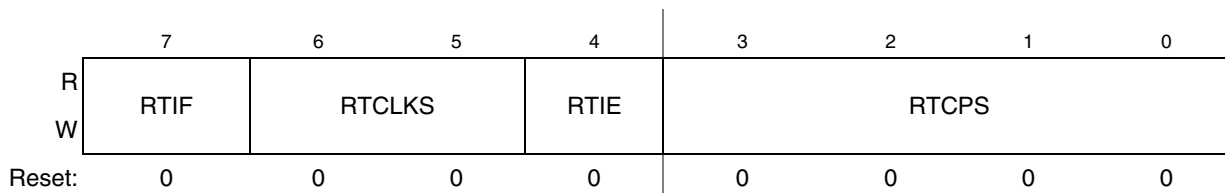
Figure 11-3. RTC Status and Control Register (RTCSC)

Table 11-2. RTCSC Field Descriptions

Field	Description
7 RTIF	**Real-Time Interrupt** Flag This status bit indicates the RTC counter register reached the value in the RTC modulo register. Writing a logic 0 has no effect. Writing a logic 1 clears the bit and the real-time interrupt request. Reset clears RTIF. 0 RTC counter has not reached the value in the RTC modulo register. 1 RTC counter has reached the value in the RTC modulo register.
6–5 RTCLKS	**Real-Time Clock Sou**rce Select. These two read/write bits select the clock source input to the RTC prescaler. Changing the clock source clears the prescaler and RTCCNT counters. When selecting a clock source, ensure that the clock source is properly enabled (if applicable) to ensure correct operation of the RTC. Reset clears RTCLKS. 00 Real-time clock source is the 1-kHz low power oscillator (LPO) 01 Real-time clock source is the external clock (ERCLK) 1x Real-time clock source is the internal clock (IRCLK)
4 RTIE	**Real-Tim**e **Interrupt En**able. This read/write bit enables real-time interrupts. If RTIE is set, then an interrupt is generated when RTIF is set. Reset clears RTIE. 0 Real-time interrupt requests are disabled. Use software polling. 1 Real-time interrupt requests are enabled.
3–0 RTCPS	**Real-Time Clock Prescaler Se**lect. These four read/write bits select binary-based or decimal-based divide-by values for the clock source. See Table 11-3. Changing the prescaler value clears the prescaler and RTCCNT counters. Reset clears RTCPS.

Table 11-3. RTC Prescaler Divide-by values

RTCLKS[0]	RTCPS															
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
0	Off	2^3	2^5	2^6	2^7	2^8	2^9	2^{10}	1	2	2^2	10	2^4	10^2	5×10^2	10^3
1	Off	2^{10}	2^{11}	2^{12}	2^{13}	2^{14}	2^{15}	2^{16}	10^3	2×10^3	5×10^3	10^4	2×10^4	5×10^4	10^5	2×10^5

11.3.2   RTC Counter Register (RTCCNT)

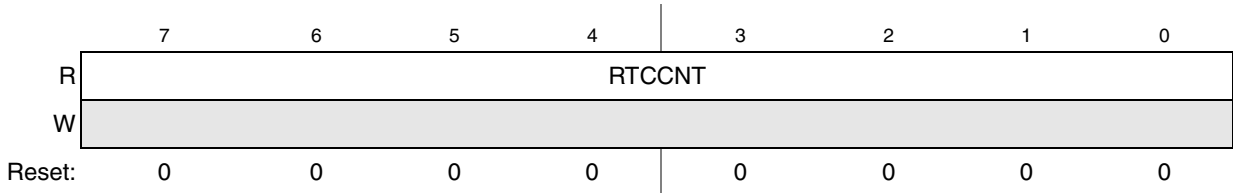RTCCNT is the read-only value of the current RTC count of the 8-bit counter.

	7	6	5	4	3	2	1	0
R				RTCCNT				
W								
Reset:	0	0	0	0	0	0	0	0

Figure 11-4. RTC Counter Register (RTCCNT)

Table 11-4. RTCCNT Field Descriptions

Field	Description
7:0 RTCCNT	RTC Count. These eight read-only bits contain the current value of the 8-bit counter. Writes have no effect to this register. Reset, writing to RTCMOD, or writing different values to RTCLKS and RTCPS clear the count to 0x00.

11.3.3   RTC Modulo Register (RTCMOD)

	7	6	5	4	3	2	1	0
R				RTCMOD				
W								
Reset:	0	0	0	0	0	0	0	0
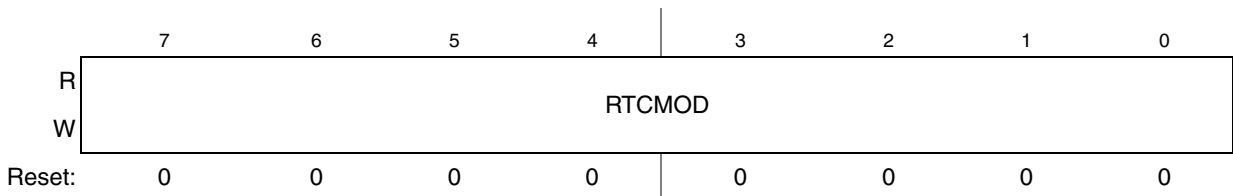
Figure 11-5. RTC Modulo Register (RTCMOD)

Table 11-5. RTCMOD Field Descriptions

Field	Description
7:0 RTCMOD	**RTC Modulo**. These eight read/write bits contain the modulo value used to reset the count to 0x00 upon a compare match and set the RTIF status bit. A value of 0x00 sets the RTIF bit on each rising edge of the prescaler output. Writing to RTCMOD resets the prescaler and the RTCCNT counters to 0x00. Reset sets the modulo to 0x00.

11.4   Functional Description

The RTC is composed of a main 8-bit up-counter with an 8-bit modulo register, a clock source selector, and a prescaler block with binary-based and decimal-based selectable values. The module also contains software selectable interrupt logic.

After any MCU reset, the counter is stopped and reset to 0x00, the modulus register is set to 0x00, and the prescaler is off. The 1-kHz internal oscillator clock is selected as the default clock source. To start the prescaler, write any value other than zero to the prescaler select bits (RTCPS).

Three clock sources are software selectable: the low power oscillator clock (LPO), the external clock (ERCLK), and the internal clock (IRCLK). The RTC clock select bits (RTCLKS) select the desired clock source. If a different value is written to RTCLKS, the prescaler and RTCCNT counters are reset to 0x00.

RTCPS and the RTCLKS[0] bit select the desired divide-by value. If a different value is written to RTCPS, the prescaler and RTCCNT counters are reset to 0x00. Table 11-6 shows different prescaler period values.

Table 11-6. Prescaler Period

RTCPS	1-kHz Internal Clock (RTCLKS = 00)	1-MHz External Clock (RTCLKS = 01)	32-kHz Internal Clock (RTCLKS = 10)	32-kHz Internal Clock (RTCLKS = 11)
0000	Off	Off	Off	Off
0001	8 ms	1.024 ms	250 μs	32 ms
0010	32 ms	2.048 ms	1 ms	64 ms
0011	64 ms	4.096 ms	2 ms	128 ms
0100	128 ms	8.192 ms	4 ms	256 ms
0101	256 ms	16.4 ms	8 ms	512 ms
0110	512 ms	32.8 ms	16 ms	1.024 s
0111	1.024 s	65.5 ms	32 ms	2.048 s
1000	1 ms	1 ms	31.25 μs	31.25 ms
1001	2 ms	2 ms	62.5 μs	62.5 ms
1010	4 ms	5 ms	125 μs	156.25 ms
1011	10 ms	10 ms	312.5 μs	312.5 ms
1100	16 ms	20 ms	0.5 ms	0.625 s
1101	0.1 s	50 ms	3.125 ms	1.5625 s
1110	0.5 s	0.1 s	15.625 ms	3.125 s
1111	1 s	0.2 s	31.25 ms	6.25 s

The RTC modulo register (RTCMOD) allows the compare value to be set to any value from 0x00 to 0xFF. When the counter is active, the counter increments at the selected rate until the count matches the modulo value. When these values match, the counter resets to 0x00 and continues counting. The real-time interrupt flag (RTIF) is set when a match occurs. The flag sets on the transition from the modulo value to 0x00. Writing to RTCMOD resets the prescaler and the RTCCNT counters to 0x00.

The RTC allows for an interrupt to be generated when RTIF is set. To enable the real-time interrupt, set the real-time interrupt enable bit (RTIE) in RTCSC. RTIF is cleared by writing a 1 to RTIF.

11.4.1 RTC Operation Example

This section shows an example of the RTC operation as the counter reaches a matching value from the modulo register.
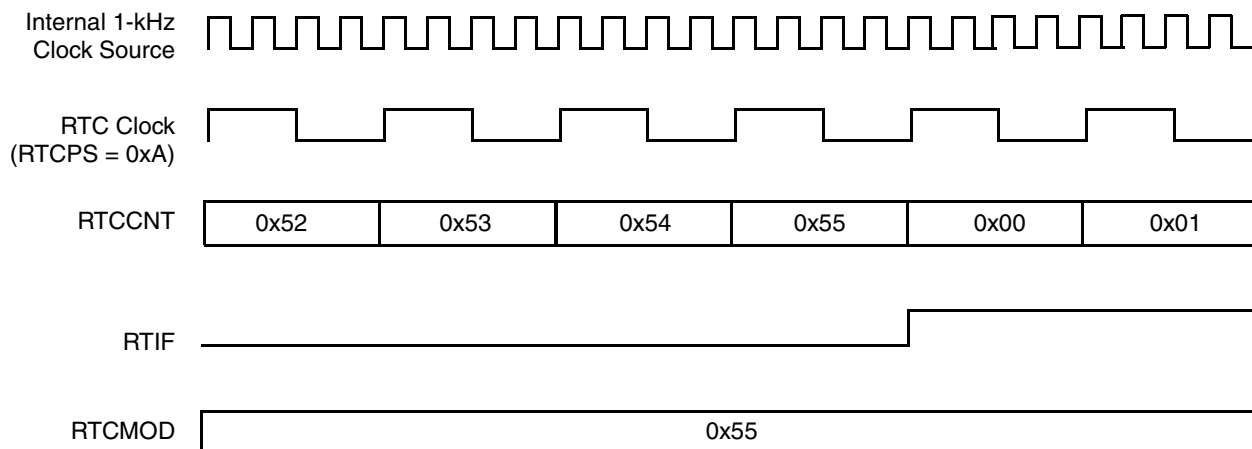
Figure 11-6. RTC Counter Overflow Example

In the example of Figure 11-6, the selected clock source is the 1-kHz internal oscillator clock source. The prescaler (RTCPS) is set to 0xA or divide-by-4. The modulo value in the RTCMOD register is set to 0x55. When the counter, RTCCNT, reaches the modulo value of 0x55, the counter overflows to 0x00 and continues counting. The real-time interrupt flag, RTIF, sets when the counter value changes from 0x55 to 0x00. A real-time interrupt is generated when RTIF is set, if RTIE is set.

11.5   Initialization/Application Information

This section provides example code to give some basic direction to a user on how to initialize and configure the RTC module. The example software is implemented in C language.

The example below shows how to implement time of day with the RTC using the 1-kHz clock source to achieve the lowest possible power consumption. Because the 1-kHz clock source is not as accurate as a crystal, software can be added for any adjustments. For accuracy without adjustments at the expense of additional power consumption, the external clock (ERCLK) or the internal clock (IRCLK) can be selected with appropriate prescaler and modulo values.

```
/* Initialize the elapsed time counters */
Seconds = 0;
Minutes = 0;
Hours = 0;
Days=0;

/* Configure RTC to interrupt every 1 second from 1-kHz clock source */
RTCMOD.byte = 0x00;
RTCSC.byte = 0x1F;


/***********************************************************************
Function Name : RTC_ISR
Notes : Interrupt service routine for RTC module.
***********************************************************************/
#pragma TRAP_PROC
void RTC_ISR(void)
{
        /* Clear the interrupt flag */
```

```
RTCSC.byte = RTCSC.byte | 0x80;
/* RTC interrupts every 1 Second */
Seconds++;
/* 60 seconds in a minute */
if (Seconds > 59){
Minutes++;
Seconds = 0;
}
/* 60 minutes in an hour */
if (Minutes > 59){
Hours++;
Minutes = 0;
}
/* 24 hours in a day */
if (Hours > 23){
Days ++;
Hours = 0;
}
```

Chapter 12
Serial Communications Interface (S08SCIV4)

12.1 Introduction

Figure 12-1 shows the MC9S08SE8 series block diagram with the ICS module highlighted.

NOTE

MC9S08SE8 series devices do not include stop1 mode. Therefore, please disregard the references to stop1 in this reference manual.
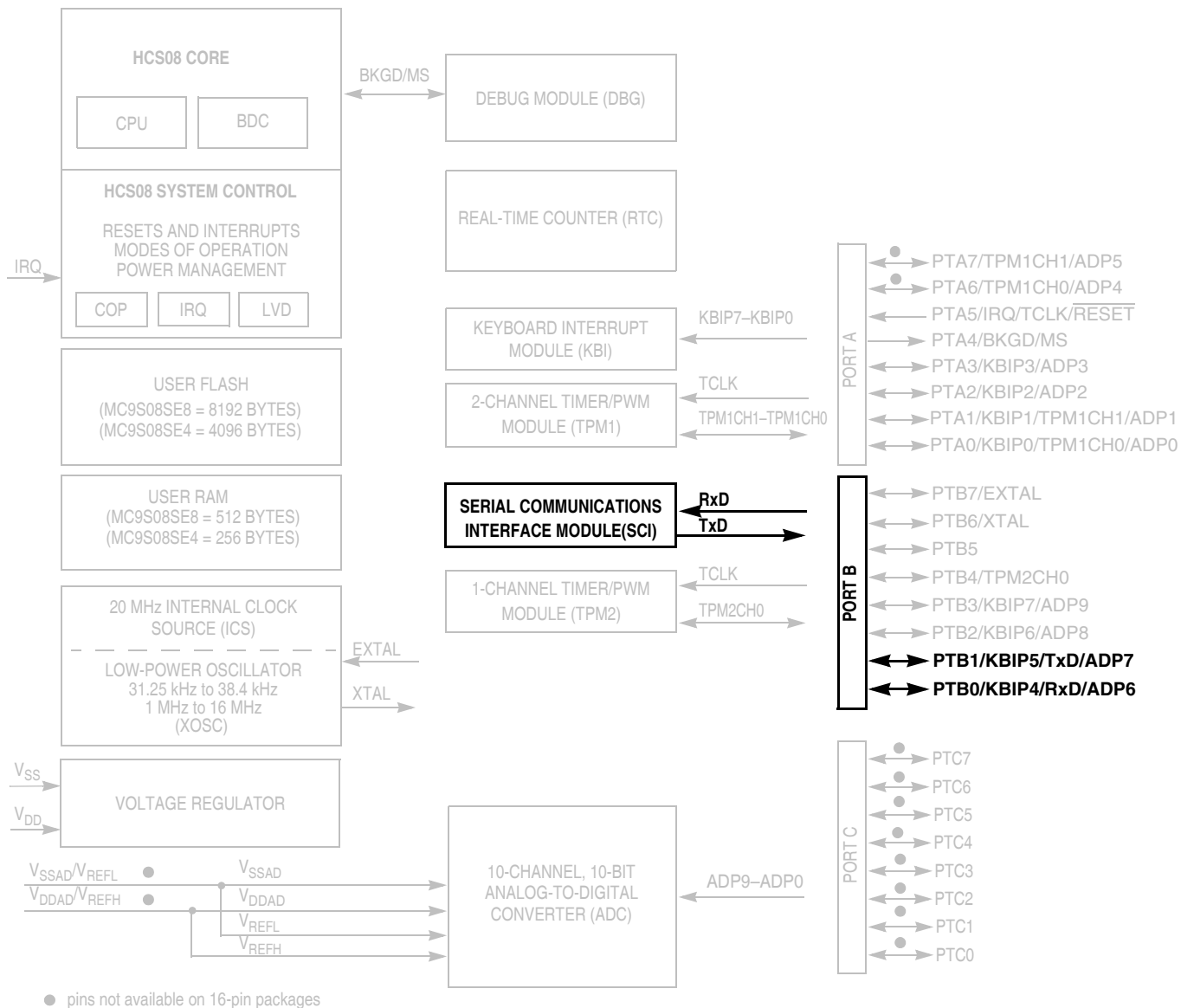
Figure 12-1. MC9S08SE8 Series Block Diagram Highlighting SCI Block and Pins

12.1.1 Features

Features of SCI module include:

- Full-duplex, standard non-return-to-zero (NRZ) format
- Double-buffered transmitter and receiver with separate enables
- Programmable baud rates (13-bit modulo divider)
- Interrupt-driven or polled operation:
  — Transmit data register empty and transmission complete
  — Receive data register full
  — Receive overrun, parity error, framing error, and noise error
  — Idle receiver detect
  — Active edge on receive pin
  — Break detect supporting LIN
- Hardware parity generation and checking
- Programmable 8-bit or 9-bit character length
- Receiver wakeup by idle-line or address-mark
- Optional 13-bit break character generation / 11-bit break character detection
- Selectable transmitter output polarity

12.1.2 Modes of Operation

See Section 12.3, "Functional Description," For details concerning SCI operation in these modes:

- 8- and 9-bit data modes
- Stop mode operation
- Loop mode
- Single-wire mode

12.1.3 Block Diagram

Figure 12-2 shows the transmitter portion of the SCI.
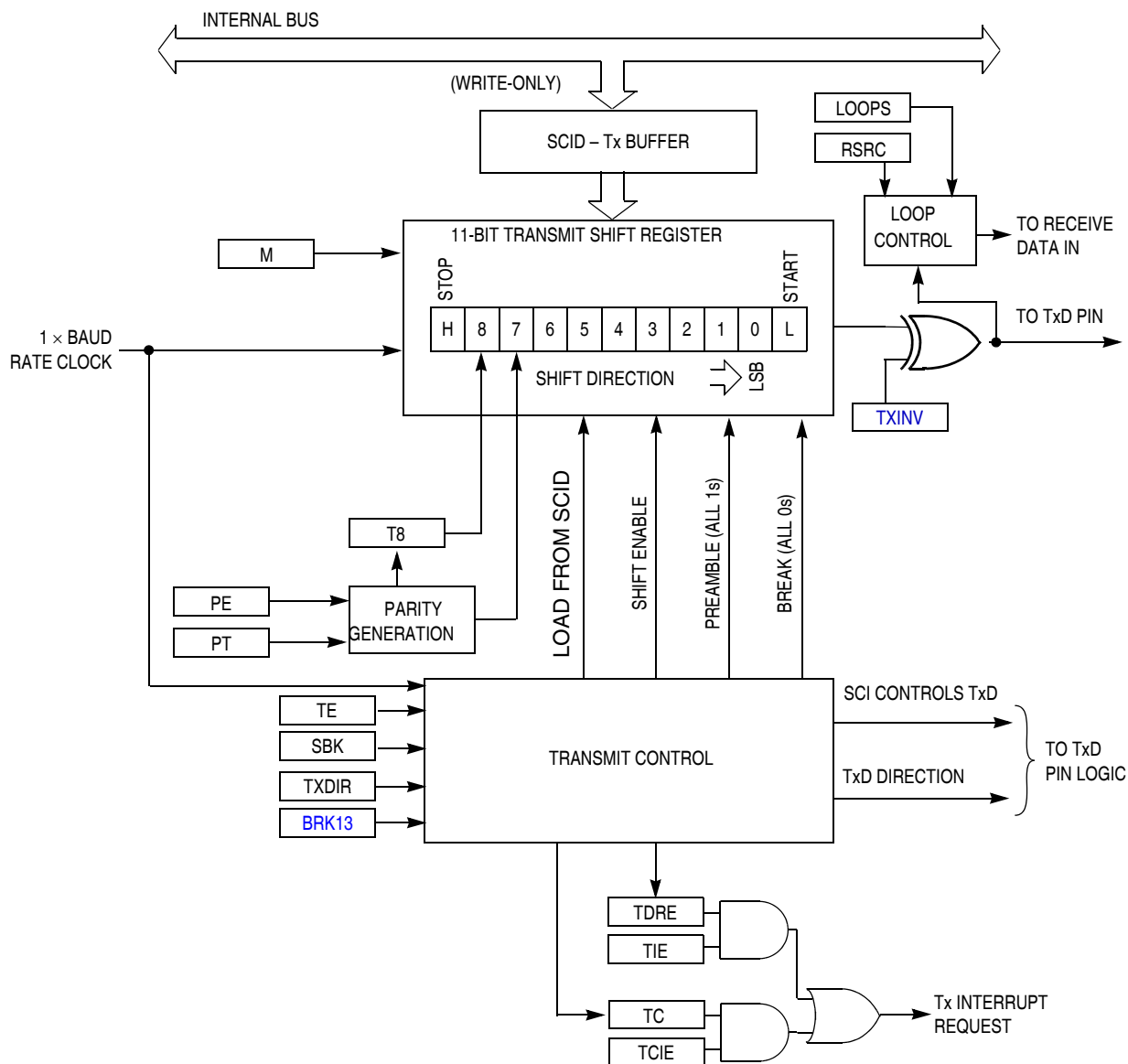
Figure 12-2. SCI Transmitter Block Diagram

Figure 12-3 shows the receiver portion of the SCI.
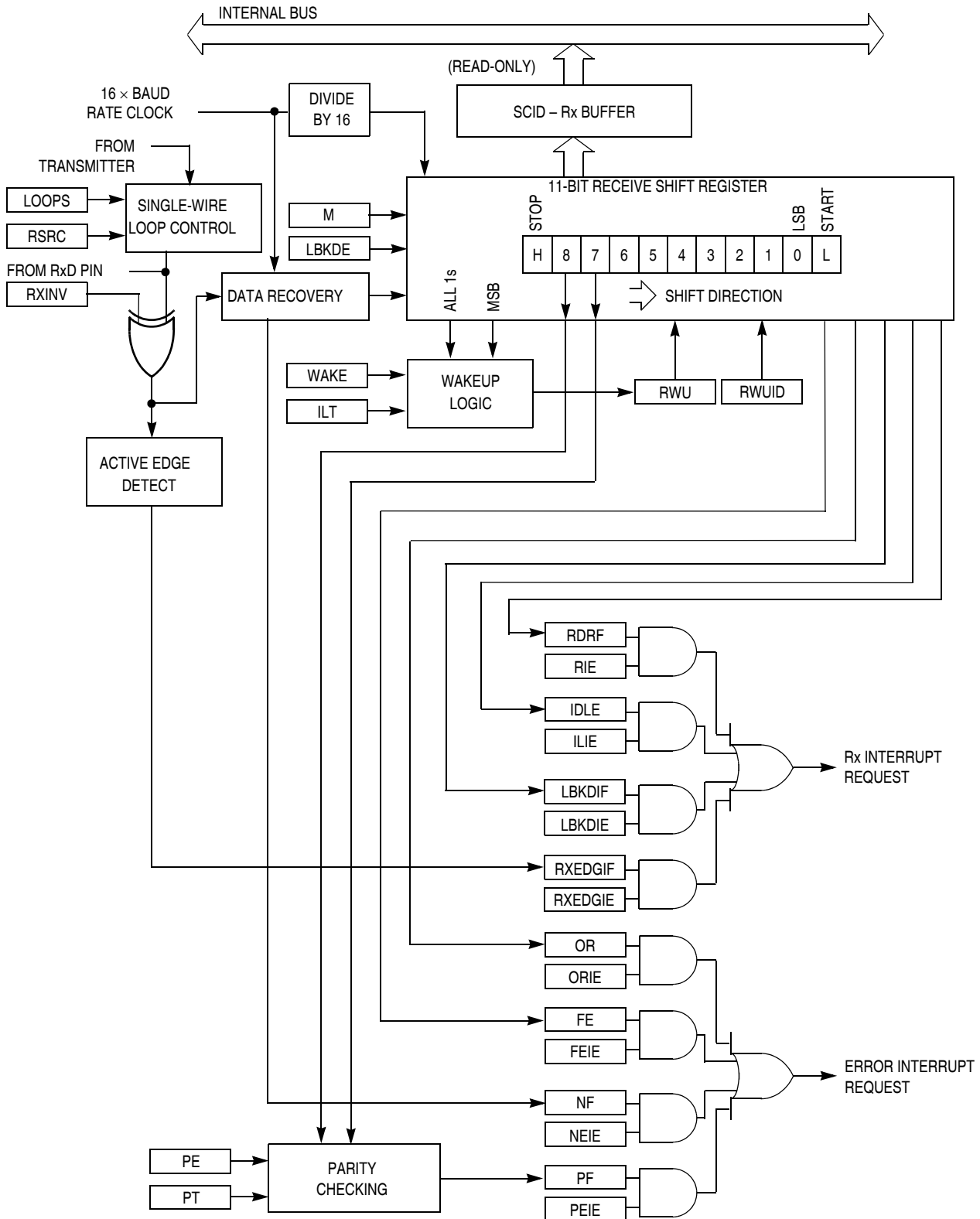
Figure 12-3. SCI Receiver Block Diagram

12.2   Register Definition

The SCI has eight 8-bit registers to control baud rate, select SCI options, report SCI status, and for transmit/receive data.

Refer to the direct-page register summary in the Memory chapter of this data sheet for the absolute address assignments for all SCI registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

12.2.1   SCI Baud Rate Registers (SCIBDH, SCIBDL)

This pair of registers controls the prescale divisor for SCI baud rate generation. To update the 13-bit baud rate setting [SBR12:SBR0], first write to SCIBDH to buffer the high half of the new value and then write to SCIBDL. The working value in SCIBDH does not change until SCIBDL is written.

SCIBDL is reset to a non-zero value, so after reset the baud rate generator remains disabled until the first time the receiver or transmitter is enabled (RE or TE bits in SCIC2 are written to 1).

	7	6	5	4	3	2	1	0
R	LBKDIE	RXEDGIE	0	SBR12	SBR11	SBR10	SBR9	SBR8
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved
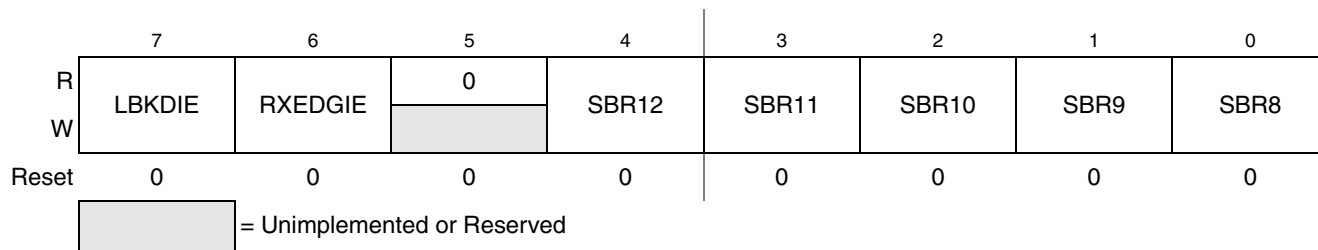
Figure 12-4. SCI Baud Rate Register (SCIBDH)

Table 12-1. SCIBDH Field Descriptions

Field	Description
7 LBKDIE	**LIN Break Detect Interrupt Enable (for LBKDIF)** 0 Hardware interrupts from LBKDIF disabled (use polling). 1 Hardware interrupt requested when LBKDIF flag is 1.
6 RXEDGIE	**RxD Input Active Edge Interrupt Enable (for RXEDGIF)** 0 Hardware interrupts from RXEDGIF disabled (use polling). 1 Hardware interrupt requested when RXEDGIF flag is 1.
4:0 SBR[12:8]	**Baud Rate Modulo Divisor** — The 13 bits in SBR[12:0] are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = BUSCLK/(16×BR). See also BR bits in Table 12-2.

	7	6	5	4	3	2	1	0
R	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
W								
Reset	0	0	0	0	0	1	0	0
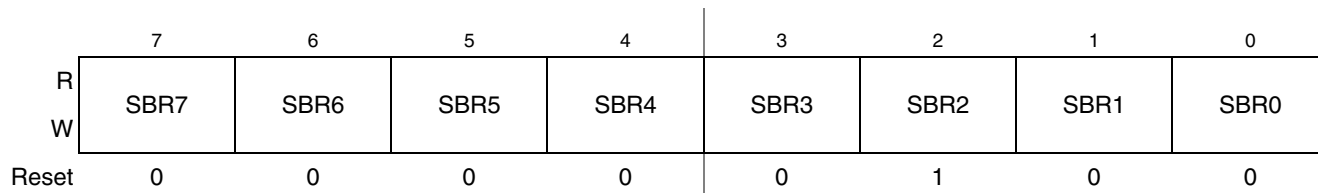
Figure 12-5. SCI Baud Rate Register (SCIBDL)

Table 12-2. SCIBDL Field Descriptions

Field	Description
7:0 SBR[7:0]	**Baud Rate Modulo Divisor** — These 13 bits in SBR[12:0] are referred to collectively as BR, and they set the modulo divide rate for the SCI baud rate generator. When BR = 0, the SCI baud rate generator is disabled to reduce supply current. When BR = 1 to 8191, the SCI baud rate = BUSCLK/(16×BR). See also BR bits in Table 12-1.

12.2.2   SCI Control Register 1 (SCIC1)

This read/write register is used to control various optional features of the SCI system.

	7	6	5	4	3	2	1	0
R W	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
Reset	0	0	0	0	0	0	0	0
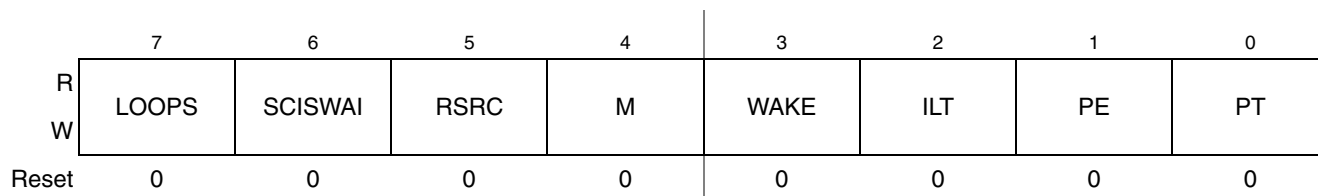
Figure 12-6. SCI Control Register 1 (SCIC1)

Table 12-3. SCIC1 Field Descriptions

Field	Description
7 LOOPS	**Loop Mode Select** — Selects between loop back modes and normal 2-pin full-duplex modes. When LOOPS = 1, the transmitter output is internally connected to the receiver input. 0 Normal operation — RxD and TxD use separate pins. 1 Loop mode or single-wire mode where transmitter outputs are internally connected to receiver input. (See RSRC bit.) RxD pin is not used by SCI.
6 SCISWAI	**SCI Stops in Wait Mode** 0 SCI clocks continue to run in wait mode so the SCI can be the source of an interrupt that wakes up the CPU. 1 SCI clocks freeze while CPU is in wait mode.
5 RSRC	**Receiver Source Select** — This bit has no meaning or effect unless the LOOPS bit is set to 1. When LOOPS = 1, the receiver input is internally connected to the TxD pin and RSRC determines whether this connection is also connected to the transmitter output. 0 Provided LOOPS = 1, RSRC = 0 selects internal loop back mode and the SCI does not use the RxD pins. 1 Single-wire SCI mode where the TxD pin is connected to the transmitter output and receiver input.
4 M	**9-Bit or 8-Bit Mode Select** 0 Normal — start + 8 data bits (LSB first) + stop. 1 Receiver and transmitter use 9-bit data characters start + 8 data bits (LSB first) + 9th data bit + stop.
3 WAKE	**Receiver Wakeup Method Select** — Refer to Section 12.3.3.2, "Receiver Wakeup Operation" for more information. 0 Idle-line wakeup. 1 Address-mark wakeup.
2 ILT	**Idle Line Type Select** — Setting this bit to 1 ensures that the stop bit and logic 1 bits at the end of a character do not count toward the 10 or 11 bit times of logic high level needed by the idle line detection logic. Refer to Section 12.3.3.2.1, "Idle-Line Wakeup" for more information. 0 Idle character bit count starts after start bit. 1 Idle character bit count starts after stop bit.

Table 12-3. SCIC1 Field Descriptions (continued)

Field	Description
1 PE	**Parity Enable** — Enables hardware parity generation and checking. When parity is enabled, the most significant bit (MSB) of the data character (eighth or ninth data bit) is treated as the parity bit. 0 No hardware parity generation or checking. 1 Parity enabled.
0 PT	**Parity Type** — Provided parity is enabled (PE = 1), this bit selects even or odd parity. Odd parity means the total number of 1s in the data character, including the parity bit, is odd. Even parity means the total number of 1s in the data character, including the parity bit, is even. 0 Even parity. 1 Odd parity.

12.2.3   SCI Control Register 2 (SCIC2)

This register can be read or written at any time.

	7	6	5	4	3	2	1	0
R W	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
Reset	0	0	0	0	0	0	0	0
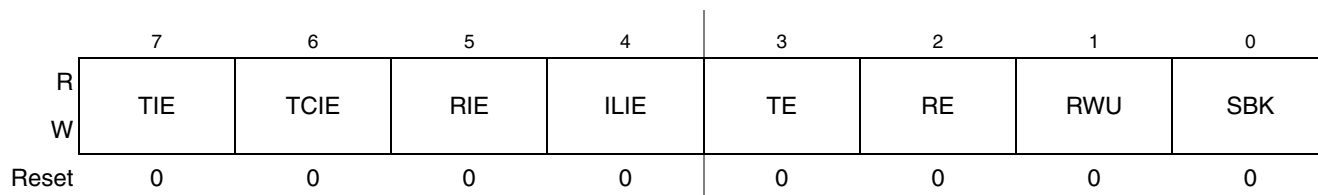
Figure 12-7. SCI Control Register 2 (SCIC2)

Table 12-4. SCIC2 Field Descriptions

Field	Description
7 TIE	**Transmit Interrupt Enable (for TDRE)** 0 Hardware interrupts from TDRE disabled (use polling). 1 Hardware interrupt requested when TDRE flag is 1.
6 TCIE	**Transmission Complete Interrupt Enable (for TC)** 0 Hardware interrupts from TC disabled (use polling). 1 Hardware interrupt requested when TC flag is 1.
5 RIE	**Receiver Interrupt Enable (for RDRF)** 0 Hardware interrupts from RDRF disabled (use polling). 1 Hardware interrupt requested when RDRF flag is 1.
4 ILIE	**Idle Line Interrupt Enable (for IDLE)** 0 Hardware interrupts from IDLE disabled (use polling). 1 Hardware interrupt requested when IDLE flag is 1.
3 TE	**Transmitter Enable** 0 Transmitter off. 1 Transmitter on. TE must be 1 in order to use the SCI transmitter. When TE = 1, the SCI forces the TxD pin to act as an output for the SCI system. When the SCI is configured for single-wire operation (LOOPS = RSRC = 1), TXDIR controls the direction of traffic on the single SCI communication line (TxD pin). TE also can be used to queue an idle character by writing TE = 0 then TE = 1 while a transmission is in progress. Refer to Section 12.3.2.1, "Send Break and Queued Idle" for more details. When TE is written to 0, the transmitter keeps control of the port TxD pin until any data, queued idle, or queued break character finishes transmitting before allowing the pin to revert to a general-purpose I/O pin.

Table 12-4. SCIC2 Field Descriptions (continued)

Field	Description
2 RE	**Receiver Enable** — When the SCI receiver is off, the RxD pin reverts to being a general-purpose port I/O pin. If LOOPS = 1 the RxD pin reverts to being a general-purpose I/O pin even if RE = 1. 0 Receiver off. 1 Receiver on.
1 RWU	**Receiver Wakeup Control** — This bit can be written to 1 to place the SCI receiver in a standby state where it waits for automatic hardware detection of a selected wakeup condition. The wakeup condition is either an idle line between messages (WAKE = 0, idle-line wakeup), or a logic 1 in the most significant data bit in a character (WAKE = 1, address-mark wakeup). Application software sets RWU and (normally) a selected hardware condition automatically clears RWU. Refer to Section 12.3.3.2, "Receiver Wakeup Operation" for more details. 0 Normal SCI receiver operation. 1 SCI receiver in standby waiting for wakeup condition.
0 SBK	**Send Break** — Writing a 1 and then a 0 to SBK queues a break character in the transmit data stream. Additional break characters of 10 or 11 (13 or 14 if BRK13 = 1) bit times of logic 0 are queued as long as SBK = 1. Depending on the timing of the set and clear of SBK relative to the information currently being transmitted, a second break character may be queued before software clears SBK. Refer to Section 12.3.2.1, "Send Break and Queued Idle" for more details. 0 Normal transmitter operation. 1 Queue break character(s) to be sent.

12.2.4   SCI Status Register 1 (SCIS1)

This register has eight read-only status flags. Writes have no effect. Special software sequences (which do not involve writing to this register) are used to clear these status flags.

	7	6	5	4	3	2	1	0
R	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
W								
Reset	1	1	0	0	0	0	0	0

           = Unimplemented or Reserved
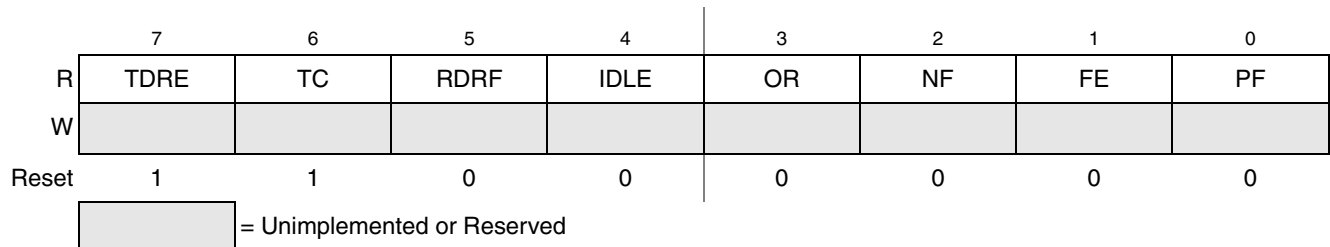
Figure 12-8. SCI Status Register 1 (SCIS1)

Table 12-5. SCIS1 Field Descriptions

Field	Description
7 TDRE	**Transmit Data Register Empty Flag** — TDRE is set out of reset and when a transmit data value transfers from the transmit data buffer to the transmit shifter, leaving room for a new character in the buffer. To clear TDRE, read SCIS1 with TDRE = 1 and then write to the SCI data register (SCID). 0　Transmit data register (buffer) full. 1　Transmit data register (buffer) empty.
6 TC	**Transmission Complete Flag** — TC is set out of reset and when TDRE = 1 and no data, preamble, or break character is being transmitted. 0　Transmitter active (sending data, a preamble, or a break). 1　Transmitter idle (transmission activity complete). TC is cleared automatically by reading SCIS1 with TC = 1 and then doing one of the following three things: 　• Write to the SCI data register (SCID) to transmit new data 　• Queue a preamble by changing TE from 0 to 1 　• Queue a break character by writing 1 to SBK in SCIC2
5 RDRF	**Receive Data Register Full Flag** — RDRF becomes set when a character transfers from the receive shifter into the receive data register (SCID). To clear RDRF, read SCIS1 with RDRF = 1 and then read the SCI data register (SCID). 0　Receive data register empty. 1　Receive data register full.
4 IDLE	**Idle Line Flag** — IDLE is set when the SCI receive line becomes idle for a full character time after a period of activity. When ILT = 0, the receiver starts counting idle bit times after the start bit. So if the receive character is all 1s, these bit times and the stop bit time count toward the full character time of logic high (10 or 11 bit times depending on the M control bit) needed for the receiver to detect an idle line. When ILT = 1, the receiver doesn't start counting idle bit times until after the stop bit. So the stop bit and any logic high bit times at the end of the previous character do not count toward the full character time of logic high needed for the receiver to detect an idle line. To clear IDLE, read SCIS1 with IDLE = 1 and then read the SCI data register (SCID). After IDLE has been cleared, it cannot become set again until after a new character has been received and RDRF has been set. IDLE will get set only once even if the receive line remains idle for an extended period. 0　No idle line detected. 1　Idle line was detected.
3 OR	**Receiver Overrun Flag** — OR is set when a new serial character is ready to be transferred to the receive data register (buffer), but the previously received character has not been read from SCID yet. In this case, the new character (and all associated error information) is lost because there is no room to move it into SCID. To clear OR, read SCIS1 with OR = 1 and then read the SCI data register (SCID). 0　No overrun. 1　Receive overrun (new SCI data lost).
2 NF	**Noise Flag** — The advanced sampling technique used in the receiver takes seven samples during the start bit and three samples in each data bit and the stop bit. If any of these samples disagrees with the rest of the samples within any bit time in the frame, the flag NF will be set at the same time as the flag RDRF gets set for the character. To clear NF, read SCIS1 and then read the SCI data register (SCID). 0　No noise detected. 1　Noise detected in the received character in SCID.

Table 12-5. SCIS1 Field Descriptions (continued)

Field	Description
1 FE	**Framing Error Flag** — FE is set at the same time as RDRF when the receiver detects a logic 0 where the stop bit was expected. This suggests the receiver was not properly aligned to a character frame. To clear FE, read SCIS1 with FE = 1 and then read the SCI data register (SCID). 0 No framing error detected. This does not guarantee the framing is correct. 1 Framing error.
0 PF	**Parity Error Flag** — PF is set at the same time as RDRF when parity is enabled (PE = 1) and the parity bit in the received character does not agree with the expected parity value. To clear PF, read SCIS1 and then read the SCI data register (SCID). 0 No parity error. 1 Parity error.

12.2.5   SCI Status Register 2 (SCIS2)

This register has one read-only status flag.

	7	6	5	4	3	2	1	0
R	LBKDIF	RXEDGIF	0	RXINV	RWUID	BRK13	LBKDE	RAF
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved
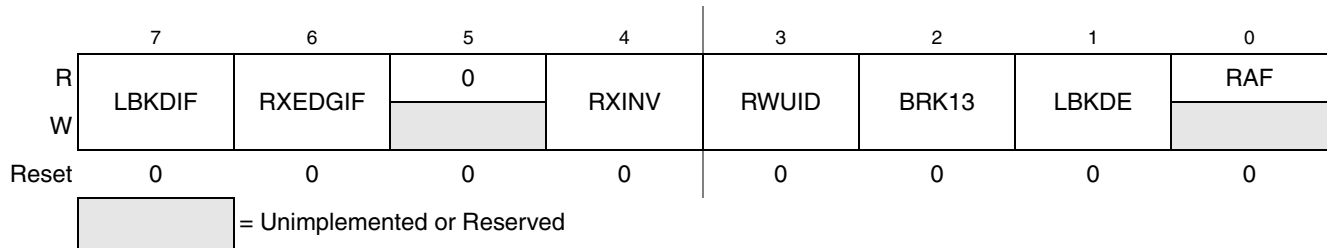
Figure 12-9. SCI Status Register 2 (SCIS2)

Table 12-6. SCIS2 Field Descriptions

Field	Description
7 LBKDIF	**LIN Break Detect Interrupt Flag** — LBKDIF is set when the LIN break detect circuitry is enabled and a LIN break character is detected. LBKDIF is cleared by writing a "1" to it. 0 No LIN break character has been detected. 1 LIN break character has been detected.
6 RXEDGIF	**RxD Pin Active Edge Interrupt Flag** — RXEDGIF is set when an active edge (falling if RXINV = 0, rising if RXINV=1) on the RxD pin occurs. RXEDGIF is cleared by writing a "1" to it. 0 No active edge on the receive pin has occurred. 1 An active edge on the receive pin has occurred.
4 RXINV[1]	**Receive Data Inversion** — Setting this bit reverses the polarity of the received data input. 0 Receive data not inverted 1 Receive data inverted
3 RWUID	**Receive Wake Up Idle Detect**— RWUID controls whether the idle character that wakes up the receiver sets the IDLE bit. 0 During receive standby state (RWU = 1), the IDLE bit does not get set upon detection of an idle character. 1 During receive standby state (RWU = 1), the IDLE bit gets set upon detection of an idle character.
2 BRK13	**Break Character Generation Length** — BRK13 is used to select a longer transmitted break character length. Detection of a framing error is not affected by the state of this bit. 0 Break character is transmitted with length of 10 bit times (11 if M = 1) 1 Break character is transmitted with length of 13 bit times (14 if M = 1)

Table 12-6. SCIS2 Field Descriptions (continued)

Field	Description
1 LBKDE	**LIN Break Detection Enable**— LBKDE is used to select a longer break character detection length. While LBKDE is set, framing error (FE) and receive data register full (RDRF) flags are prevented from setting. 0 Break character is detected at length of 10 bit times (11 if M = 1). 1 Break character is detected at length of 11 bit times (12 if M = 1).
0 RAF	**Receiver Active Flag** — RAF is set when the SCI receiver detects the beginning of a valid start bit, and RAF is cleared automatically when the receiver detects an idle line. This status flag can be used to check whether an SCI character is being received before instructing the MCU to go to stop mode. 0 SCI receiver idle waiting for a start bit. 1 SCI receiver active (RxD input not idle).

1   Setting RXINV inverts the RxD input for all cases: data bits, start and stop bits, break, and idle.

When using an internal oscillator in a LIN system, it is necessary to raise the break detection threshold by one bit time. Under the worst case timing conditions allowed in LIN, it is possible that a 0x00 data character can appear to be 10.26 bit times long at a slave which is running 14% faster than the master. This would trigger normal break detection circuitry which is designed to detect a 10 bit break symbol. When the LBKDE bit is set, framing errors are inhibited and the break detection threshold changes from 10 bits to 11 bits, preventing false detection of a 0x00 data character as a LIN break symbol.

12.2.6   SCI Control Register 3 (SCIC3)

	7	6	5	4	3	2	1	0
R	R8	T8	TXDIR	TXINV	ORIE	NEIE	FEIE	PEIE
W								
Reset	0	0	0	0	0	0	0	0

☐ = Unimplemented or Reserved
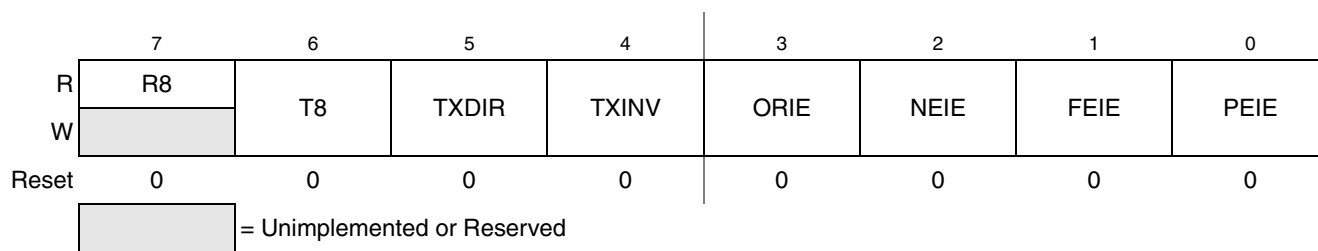
Figure 12-10. SCI Control Register 3 (SCIC3)

Table 12-7. SCIC3 Field Descriptions

Field	Description
7 R8	**Ninth Data Bit for Receiver** — When the SCI is configured for 9-bit data (M = 1), R8 can be thought of as a ninth receive data bit to the left of the MSB of the buffered data in the SCID register. When reading 9-bit data, read R8 before reading SCID because reading SCID completes automatic flag clearing sequences which could allow R8 and SCID to be overwritten with new data.
6 T8	**Ninth Data Bit for Transmitter** — When the SCI is configured for 9-bit data (M = 1), T8 may be thought of as a ninth transmit data bit to the left of the MSB of the data in the SCID register. When writing 9-bit data, the entire 9-bit value is transferred to the SCI shift register after SCID is written so T8 should be written (if it needs to change from its previous value) before SCID is written. If T8 does not need to change in the new value (such as when it is used to generate mark or space parity), it need not be written each time SCID is written.
5 TXDIR	**TxD Pin Direction in Single-Wire Mode** — When the SCI is configured for single-wire half-duplex operation (LOOPS = RSRC = 1), this bit determines the direction of data at the TxD pin. 0 TxD pin is an input in single-wire mode. 1 TxD pin is an output in single-wire mode.

Table 12-7. SCIC3 Field Descriptions (continued)

Field	Description
4 TXINV[1]	**Transmit Data Inversion** — Setting this bit reverses the polarity of the transmitted data output. 0 Transmit data not inverted 1 Transmit data inverted
3 ORIE	**Overrun Interrupt Enable** — This bit enables the overrun flag (OR) to generate hardware interrupt requests. 0 OR interrupts disabled (use polling). 1 Hardware interrupt requested when OR = 1.
2 NEIE	**Noise Error Interrupt Enable** — This bit enables the noise flag (NF) to generate hardware interrupt requests. 0 NF interrupts disabled (use polling). 1 Hardware interrupt requested when NF = 1.
1 FEIE	**Framing Error Interrupt Enable** — This bit enables the framing error flag (FE) to generate hardware interrupt requests. 0 FE interrupts disabled (use polling). 1 Hardware interrupt requested when FE = 1.
0 PEIE	**Parity Error Interrupt Enable** — This bit enables the parity error flag (PF) to generate hardware interrupt requests. 0 PF interrupts disabled (use polling). 1 Hardware interrupt requested when PF = 1.

[1] Setting TXINV inverts the TxD output for all cases: data bits, start and stop bits, break, and idle.

12.2.7 SCI Data Register (SCID)

This register is actually two separate registers. Reads return the contents of the read-only receive data buffer and writes go to the write-only transmit data buffer. Reads and writes of this register are also involved in the automatic flag clearing mechanisms for the SCI status flags.

	7	6	5	4	3	2	1	0
R	R7	R6	R5	R4	R3	R2	R1	R0
W	T7	T6	T5	T4	T3	T2	T1	T0
Reset	0	0	0	0	0	0	0	0

Figure 12-11. SCI Data Register (SCID)

12.3 Functional Description

The SCI allows full-duplex, asynchronous, NRZ serial communication among the MCU and remote devices, including other MCUs. The SCI comprises a baud rate generator, transmitter, and receiver block. The transmitter and receiver operate independently, although they use the same baud rate generator. During normal operation, the MCU monitors the status of the SCI, writes the data to be transmitted, and processes received data. The following describes each of the blocks of the SCI.

12.3.1 Baud Rate Generation

As shown in Figure 12-12, the clock source for the SCI baud rate generator is the bus-rate clock.
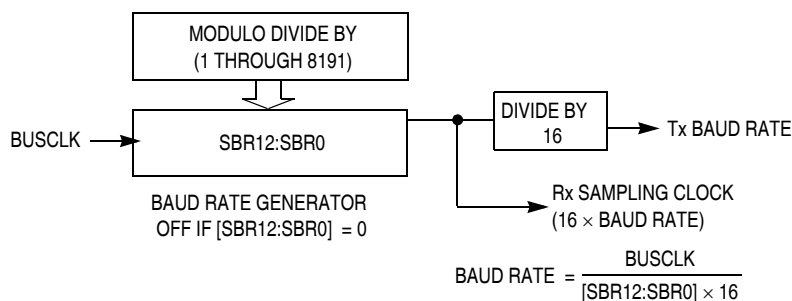
Figure 12-12. SCI Baud Rate Generation

SCI communications require the transmitter and receiver (which typically derive baud rates from independent clock sources) to use the same baud rate. Allowed tolerance on this baud frequency depends on the details of how the receiver synchronizes to the leading edge of the start bit and how bit sampling is performed.

The MCU resynchronizes to bit boundaries on every high-to-low transition, but in the worst case, there are no such transitions in the full 10- or 11-bit time character frame so any mismatch in baud rate is accumulated for the whole character time. For a Freescale Semiconductor SCI system whose bus frequency is driven by a crystal, the allowed baud rate mismatch is about ±4.5 percent for 8-bit data format and about ±4 percent for 9-bit data format. Although baud rate modulo divider settings do not always produce baud rates that exactly match standard rates, it is normally possible to get within a few percent, which is acceptable for reliable communications.

12.3.2   Transmitter Functional Description

This section describes the overall block diagram for the SCI transmitter, as well as specialized functions for sending break and idle characters. The transmitter block diagram is shown in Figure 12-2.

The transmitter output (TxD) idle state defaults to logic high (TXINV = 0 following reset). The transmitter output is inverted by setting TXINV = 1. The transmitter is enabled by setting the TE bit in SCIC2. This queues a preamble character that is one full character frame of the idle state. The transmitter then remains idle until data is available in the transmit data buffer. Programs store data into the transmit data buffer by writing to the SCI data register (SCID).

The central element of the SCI transmitter is the transmit shift register that is either 10 or 11 bits long depending on the setting in the M control bit. For the remainder of this section, we will assume M = 0, selecting the normal 8-bit data mode. In 8-bit data mode, the shift register holds a start bit, eight data bits, and a stop bit. When the transmit shift register is available for a new SCI character, the value waiting in the transmit data register is transferred to the shift register (synchronized with the baud rate clock) and the transmit data register empty (TDRE) status flag is set to indicate another character may be written to the transmit data buffer at SCID.

If no new character is waiting in the transmit data buffer after a stop bit is shifted out the TxD pin, the transmitter sets the transmit complete flag and enters an idle mode, with TxD high, waiting for more characters to transmit.

Writing 0 to TE does not immediately release the pin to be a general-purpose I/O pin. Any transmit activity that is in progress must first be completed. This includes data characters in progress, queued idle characters, and queued break characters.

12.3.2.1 Send Break and Queued Idle

The SBK control bit in SCIC2 is used to send break characters which were originally used to gain the attention of old teletype receivers. Break characters are a full character time of logic 0 (10 bit times including the start and stop bits). A longer break of 13 bit times can be enabled by setting BRK13 = 1. Normally, a program would wait for TDRE to become set to indicate the last character of a message has moved to the transmit shifter, then write 1 and then write 0 to the SBK bit. This action queues a break character to be sent as soon as the shifter is available. If SBK is still 1 when the queued break moves into the shifter (synchronized to the baud rate clock), an additional break character is queued. If the receiving device is another Freescale Semiconductor SCI, the break characters will be received as 0s in all eight data bits and a framing error (FE = 1) occurs.

When idle-line wakeup is used, a full character time of idle (logic 1) is needed between messages to wake up any sleeping receivers. Normally, a program would wait for TDRE to become set to indicate the last character of a message has moved to the transmit shifter, then write 0 and then write 1 to the TE bit. This action queues an idle character to be sent as soon as the shifter is available. As long as the character in the shifter does not finish while TE = 0, the SCI transmitter never actually releases control of the TxD pin. If there is a possibility of the shifter finishing while TE = 0, set the general-purpose I/O controls so the pin that is shared with TxD is an output driving a logic 1. This ensures that the TxD line will look like a normal idle line even if the SCI loses control of the port pin between writing 0 and then 1 to TE.

The length of the break character is affected by the BRK13 and M bits as shown below.

Table 12-8. Break Character Length

BRK13	M	Break Character Length
0	0	10 bit times
0	1	11 bit times
1	0	13 bit times
1	1	14 bit times

12.3.3 Receiver Functional Description

In this section, the receiver block diagram (Figure 12-3) is used as a guide for the overall receiver functional description. Next, the data sampling technique used to reconstruct receiver data is described in more detail. Finally, two variations of the receiver wakeup function are explained.

The receiver input is inverted by setting RXINV = 1. The receiver is enabled by setting the RE bit in SCIC2. Character frames consist of a start bit of logic 0, eight (or nine) data bits (LSB first), and a stop bit of logic 1. For information about 9-bit data mode, refer to Section 12.3.5.1, "8- and 9-Bit Data Modes." For the remainder of this discussion, we assume the SCI is configured for normal 8-bit data mode.

After receiving the stop bit into the receive shifter, and provided the receive data register is not already full, the data character is transferred to the receive data register and the receive data register full (RDRF)

status flag is set. If RDRF was already set indicating the receive data register (buffer) was already full, the overrun (OR) status flag is set and the new data is lost. Because the SCI receiver is double-buffered, the program has one full character time after RDRF is set before the data in the receive data buffer must be read to avoid a receiver overrun.

When a program detects that the receive data register is full (RDRF = 1), it gets the data from the receive data register by reading SCID. The RDRF flag is cleared automatically by a 2-step sequence which is normally satisfied in the course of the user's program that handles receive data. Refer to Section 12.3.4, "Interrupts and Status Flags" for more details about flag clearing.

12.3.3.1 Data Sampling Technique

The SCI receiver uses a 16× baud rate clock for sampling. The receiver starts by taking logic level samples at 16 times the baud rate to search for a falling edge on the RxD serial data input pin. A falling edge is defined as a logic 0 sample after three consecutive logic 1 samples. The 16× baud rate clock is used to divide the bit time into 16 segments labeled RT1 through RT16. When a falling edge is located, three more samples are taken at RT3, RT5, and RT7 to make sure this was a real start bit and not merely noise. If at least two of these three samples are 0, the receiver assumes it is synchronized to a receive character.

The receiver then samples each bit time, including the start and stop bits, at RT8, RT9, and RT10 to determine the logic level for that bit. The logic level is interpreted to be that of the majority of the samples taken during the bit time. In the case of the start bit, the bit is assumed to be 0 if at least two of the samples at RT3, RT5, and RT7 are 0 even if one or all of the samples taken at RT8, RT9, and RT10 are 1s. If any sample in any bit time (including the start and stop bits) in a character frame fails to agree with the logic level for that bit, the noise flag (NF) will be set when the received character is transferred to the receive data buffer.

The falling edge detection logic continuously looks for falling edges, and if an edge is detected, the sample clock is resynchronized to bit times. This improves the reliability of the receiver in the presence of noise or mismatched baud rates. It does not improve worst case analysis because some characters do not have any extra falling edges anywhere in the character frame.

In the case of a framing error, provided the received character was not a break character, the sampling logic that searches for a falling edge is filled with three logic 1 samples so that a new start bit can be detected almost immediately.

In the case of a framing error, the receiver is inhibited from receiving any new characters until the framing error flag is cleared. The receive shift register continues to function, but a complete character cannot transfer to the receive data buffer if FE is still set.

12.3.3.2 Receiver Wakeup Operation

Receiver wakeup is a hardware mechanism that allows an SCI receiver to ignore the characters in a message that is intended for a different SCI receiver. In such a system, all receivers evaluate the first character(s) of each message, and as soon as they determine the message is intended for a different receiver, they write logic 1 to the receiver wake up (RWU) control bit in SCIC2. When RWU bit is set, the status flags associated with the receiver (with the exception of the idle bit, IDLE, when RWUID bit is set) are inhibited from setting, thus eliminating the software overhead for handling the unimportant message

characters. At the end of a message, or at the beginning of the next message, all receivers automatically force RWU to 0 so all receivers wake up in time to look at the first character(s) of the next message.

12.3.3.2.1 Idle-Line Wakeup

When WAKE = 0, the receiver is configured for idle-line wakeup. In this mode, RWU is cleared automatically when the receiver detects a full character time of the idle-line level. The M control bit selects 8-bit or 9-bit data mode that determines how many bit times of idle are needed to constitute a full character time (10 or 11 bit times because of the start and stop bits).

When RWU is one and RWUID is zero, the idle condition that wakes up the receiver does not set the IDLE flag. The receiver wakes up and waits for the first data character of the next message which will set the RDRF flag and generate an interrupt if enabled. When RWUID is one, any idle condition sets the IDLE flag and generates an interrupt if enabled, regardless of whether RWU is zero or one.

The idle-line type (ILT) control bit selects one of two ways to detect an idle line. When ILT = 0, the idle bit counter starts after the start bit so the stop bit and any logic 1s at the end of a character count toward the full character time of idle. When ILT = 1, the idle bit counter does not start until after a stop bit time, so the idle detection is not affected by the data in the last character of the previous message.

12.3.3.2.2 Address-Mark Wakeup

When WAKE = 1, the receiver is configured for address-mark wakeup. In this mode, RWU is cleared automatically when the receiver detects a logic 1 in the most significant bit of a received character (eighth bit in M = 0 mode and ninth bit in M = 1 mode).

Address-mark wakeup allows messages to contain idle characters but requires that the MSB be reserved for use in address frames. The logic 1 MSB of an address frame clears the RWU bit before the stop bit is received and sets the RDRF flag. In this case the character with the MSB set is received even though the receiver was sleeping during most of this character time.

12.3.4 Interrupts and Status Flags

The SCI system has three separate interrupt vectors to reduce the amount of software needed to isolate the cause of the interrupt. One interrupt vector is associated with the transmitter for TDRE and TC events. Another interrupt vector is associated with the receiver for RDRF, IDLE, RXEDGIF and LBKDIF events, and a third vector is used for OR, NF, FE, and PF error conditions. Each of these ten interrupt sources can be separately masked by local interrupt enable masks. The flags can still be polled by software when the local masks are cleared to disable generation of hardware interrupt requests.

The SCI transmitter has two status flags that optionally can generate hardware interrupt requests. Transmit data register empty (TDRE) indicates when there is room in the transmit data buffer to write another transmit character to SCID. If the transmit interrupt enable (TIE) bit is set, a hardware interrupt will be requested whenever TDRE = 1. Transmit complete (TC) indicates that the transmitter is finished transmitting all data, preamble, and break characters and is idle with TxD at the inactive level. This flag is often used in systems with modems to determine when it is safe to turn off the modem. If the transmit complete interrupt enable (TCIE) bit is set, a hardware interrupt will be requested whenever TC = 1.

Instead of hardware interrupts, software polling may be used to monitor the TDRE and TC status flags if the corresponding TIE or TCIE local interrupt masks are 0s.

When a program detects that the receive data register is full (RDRF = 1), it gets the data from the receive data register by reading SCID. The RDRF flag is cleared by reading SCIS1 while RDRF = 1 and then reading SCID.

When polling is used, this sequence is naturally satisfied in the normal course of the user program. If hardware interrupts are used, SCIS1 must be read in the interrupt service routine (ISR). Normally, this is done in the ISR anyway to check for receive errors, so the sequence is automatically satisfied.

The IDLE status flag includes logic that prevents it from getting set repeatedly when the RxD line remains idle for an extended period of time. IDLE is cleared by reading SCIS1 while IDLE = 1 and then reading SCID. After IDLE has been cleared, it cannot become set again until the receiver has received at least one new character and has set RDRF.

If the associated error was detected in the received character that caused RDRF to be set, the error flags — noise flag (NF), framing error (FE), and parity error flag (PF) — get set at the same time as RDRF. These flags are not set in overrun cases.

If RDRF was already set when a new character is ready to be transferred from the receive shifter to the receive data buffer, the overrun (OR) flag gets set instead the data along with any associated NF, FE, or PF condition is lost.

At any time, an active edge on the RxD serial data input pin causes the RXEDGIF flag to set. The RXEDGIF flag is cleared by writing a "1" to it. This function does depend on the receiver being enabled (RE = 1).

12.3.5   Additional SCI Functions

The following sections describe additional SCI functions.

12.3.5.1   8- and 9-Bit Data Modes

The SCI system (transmitter and receiver) can be configured to operate in 9-bit data mode by setting the M control bit in SCIC1. In 9-bit mode, there is a ninth data bit to the left of the MSB of the SCI data register. For the transmit data buffer, this bit is stored in T8 in SCIC3. For the receiver, the ninth bit is held in R8 in SCIC3.

For coherent writes to the transmit data buffer, write to the T8 bit before writing to SCID.

If the bit value to be transmitted as the ninth bit of a new character is the same as for the previous character, it is not necessary to write to T8 again. When data is transferred from the transmit data buffer to the transmit shifter, the value in T8 is copied at the same time data is transferred from SCID to the shifter.

9-bit data mode typically is used in conjunction with parity to allow eight bits of data plus the parity in the ninth bit. Or it is used with address-mark wakeup so the ninth data bit can serve as the wakeup bit. In custom protocols, the ninth bit can also serve as a software-controlled marker.

12.3.5.2 Stop Mode Operation

During all stop modes, clocks to the SCI module are halted.

In stop1 and stop2 modes, all SCI register data is lost and must be re-initialized upon recovery from these two stop modes. No SCI module registers are affected in stop3 mode.

The receive input active edge detect circuit is still active in stop3 mode, but not in stop2. An active edge on the receive input brings the CPU out of stop3 mode if the interrupt is not masked (RXEDGIE = 1).

Note, because the clocks are halted, the SCI module will resume operation upon exit from stop (only in stop3 mode). Software should ensure stop mode is not entered while there is a character being transmitted out of or received into the SCI module.

12.3.5.3 Loop Mode

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Loop mode is sometimes used to check software, independent of connections in the external system, to help isolate system problems. In this mode, the transmitter output is internally connected to the receiver input and the RxD pin is not used by the SCI, so it reverts to a general-purpose port I/O pin.

12.3.5.4 Single-Wire Operation

When LOOPS = 1, the RSRC bit in the same register chooses between loop mode (RSRC = 0) or single-wire mode (RSRC = 1). Single-wire mode is used to implement a half-duplex serial connection. The receiver is internally connected to the transmitter output and to the TxD pin. The RxD pin is not used and reverts to a general-purpose port I/O pin.

In single-wire mode, the TXDIR bit in SCIC3 controls the direction of serial data on the TxD pin. When TXDIR = 0, the TxD pin is an input to the SCI receiver and the transmitter is temporarily disconnected from the TxD pin so an external device can send serial data to the receiver. When TXDIR = 1, the TxD pin is an output driven by the transmitter. In single-wire mode, the internal loop back connection from the transmitter to the receiver causes the receiver to receive characters that are sent out by the transmitter.

Chapter 13
Timer Pulse-Width Modulator (S08TPMV3)

13.1 TPMV3 Differences from Previous Versions

The TPMV3 is the latest version of the Timer/PWM module that addresses errata found in previous versions. The following section outlines the differences between TPMV3 and TPMV2 modules, and any considerations that should be taken when porting code.

Table 13-1. TPMV2 and TPMV3 Porting Considerations

Action	TPMV3	TPMV2
Write to TPMxCnTH:L registers[1]		
Any write to TPMCNTH or TPMCNTL registers	Clears the TPM counter (TPMCNTH:L) and the prescaler counter.	Clears the TPM counter (TPMCNTH:L) only.
Read of TPMxCNTH:L registers[1]		
In BDM mode, any read of TPMCNTH:L registers	Returns the value of the TPM counter that is frozen.	If only one byte of the TPMCNTH:L registers was read before the BDM mode became active, returns the latched value of TPMCNTH:L from the read buffer (instead of the frozen TPM counter value).
In BDM mode, a write to TPMSC, TPMCNTH or TPMCNTL	Clears this read coherency mechanism.	Does not clear this read coherency mechanism.
Read of TPMCnVH:L registers[2]		
In BDM mode, any read of TPMCnVH:L registers	Returns the value of the TPMCnVH:L register.	If only one byte of the TPMCnVH:L registers was read before the BDM mode became active, returns the latched value of TPMCNTH:L from the read buffer (instead of the value in the TPMCnVH:L registers).
In BDM mode, a write to TPMCnSC	Clears this read coherency mechanism.	Does not clear this read coherency mechanism.
Write to TPMCnVH:L registers		
In Input Capture mode, writes to TPMCnVH:L registers[3]	Not allowed.	Allowed.

Table 13-1. TPMV2 and TPMV3 Porting Considerations (continued)

Action	TPMV3	TPMV2
In Output Compare mode, when (CLKSB:CLKSA not = 0:0), writes to TPMCnVH:L registers[3]	Update the TPMCnVH:L registers with the value of their write buffer at the next change of the TPM counter (end of the prescaler counting) after the second byte is written.	Always update these registers when their second byte is written.
In Edge-Aligned PWM mode when (CLKSB:CLKSA not = 00), writes to TPMCnVH:L registers	Update the TPMCnVH:L registers with the value of their write buffer after both bytes were written and when the TPM counter changes from (TPMMODH:L – 1) to (TPMMODH:L). **Note:** If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from 0xFFFE to 0xFFFF.	Update after both bytes are written and when the TPM counter changes from TPMMODH:L to 0x0000.
In Center-Aligned PWM mode when (CLKSB:CLKSA not = 00), writes to TPMCnVH:L registers[4]	Update the TPMxCnVH:L registers with the value of their write buffer after both bytes are written and when the TPM counter changes from (TPMMODH:L – 1) to (TPMMODH:L). **Note:** If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from 0xFFFE to 0xFFFF.	Update after both bytes are written and when the TPM counter changes from TPMMODH:L to (TPMMODH:L – 1).
Center-Aligned PWM		
When TPMCnVH:L = TPMMODH:L[5]	Produces 100% duty cycle.	Produces 0% duty cycle.
When TPMCnVH:L = (TPMMODH:L – 1)[6]	Produces a near 100% duty cycle.	Produces 0% duty cycle.
TPMCnVH:L is changed from 0x0000 to a non-zero value[7]	Waits for the start of a new PWM period to begin using the new duty cycle setting.	Changes the channel output at the middle of the current PWM period (when the count reaches 0x0000).
TPMCnVH:L is changed from a non-zero value to 0x0000[8]	Finishes the current PWM period using the old duty cycle setting.	Finishes the current PWM period using the new duty cycle setting.
Write to TPMMODH:L registers in BDM mode		
In BDM mode, a write to TPMxSC register	Clears the write coherency mechanism of TPMxMODH:L registers.	Does not clear the write coherency mechanism.

[1] For more information, refer to Section 13.4.2, "TPM-Counter Registers (TPMxCNTH:TPMxCNTL)." [SE110-TPM case 7]

[2] For more information, refer to Section 13.4.5, "TPM Channel Value Registers (TPMxCnVH:TPMxCnVL)."

[3] For more information, refer to Section 13.5.2.1, "Input Capture Mode."

[4] For more information, refer to Section 13.5.2.4, "Center-Aligned PWM Mode."

[5] For more information, refer to Section 13.5.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 1]

[6] For more information, refer to Section 13.5.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 2]

[7] For more information, refer to Section 13.5.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 3 and 5]

[8] For more information, refer to Section 13.5.2.4, "Center-Aligned PWM Mode." [SE110-TPM case 4]

13.1.1 Migrating from TPMV1

In addition to Section 13.1, "TPMV3 Differences from Previous Versions," keep in mind the following considerations when migrating from a device that uses TPMV1.

- You can write to the Channel Value register (TPMCnV) when the timer is not in input capture mode for TPMV2, not TPMV3.
- In edge- or center- aligned modes, the Channel Value register (TPMCnV) registers only update when the timer changes from TPMMOD-1 to TPMMOD, or in the case of a free running timer from 0xFFFE to 0xFFFF.
- Also, when configuring the TPM modules, it is best to write to TPMSC before TPMCnV as a write to TPMxSC resets the coherency mechanism on the TPMCnV registers.

Table 13-2. Migrating to TPMV3 Considerations

When...	Action / Best Practice
Writing to the Channel Value Register (TPMCnV) register...	Timer must be in Input Capture mode.
Updating the Channel Value Register (TPMCnV) register in edge-aligned or center-aligned modes...	Only occurs when the timer changes from TPMMOD – 1 to TPMMOD (or in the case of a free running timer, from 0xFFFE to 0xFFFF).
Resetting the coherency mechanism for the Channel Value Register (TPMCnV) register...	Write to TPMSC.
Configuring the TPM modules...	Write first to TPMSC and then to TPMCnV register.

13.2 Introduction

The TPM uses one input/output (I/O) pin per channel, TPMxCHn where x is the TPM number (for example, 1 or 2) and n is the channel number (for example, 0–1). The TPM shares its I/O pins with I/O port pins (refer to the Chapter 2, "Pins and Connections," for more information).

All MC9S08SE8 series MCUs have two TPM modules.

Figure 13-1 shows the MC9S08SE8 series block diagram with the TPM modules and pins highlighted.

13.2.1 TPM Configuration Information

The external clock for the TPM modules, TPMCLK, is selected by setting CLKS = 1:1 in TPMxSC, which selects the TCLK pin input. The TCLK input on PTA5 can be enabled as external clock inputs to both the TPM modules simultaneously.

13.2.2   TPM Pin Repositioning

The TPM modules pins, TPM1CHx and TPM2CHx can be repositioned under software control using TPMxPS bits in SOPT1 as shown in Table 13-3.

Table 13-3. TPM Position Options

TPMxPS in SOPT2	Port Pin for TPM1CH1	Port Pin for TPM1CH0
0 (default)	PTA1	PTA0
1	PTA7	PTA6
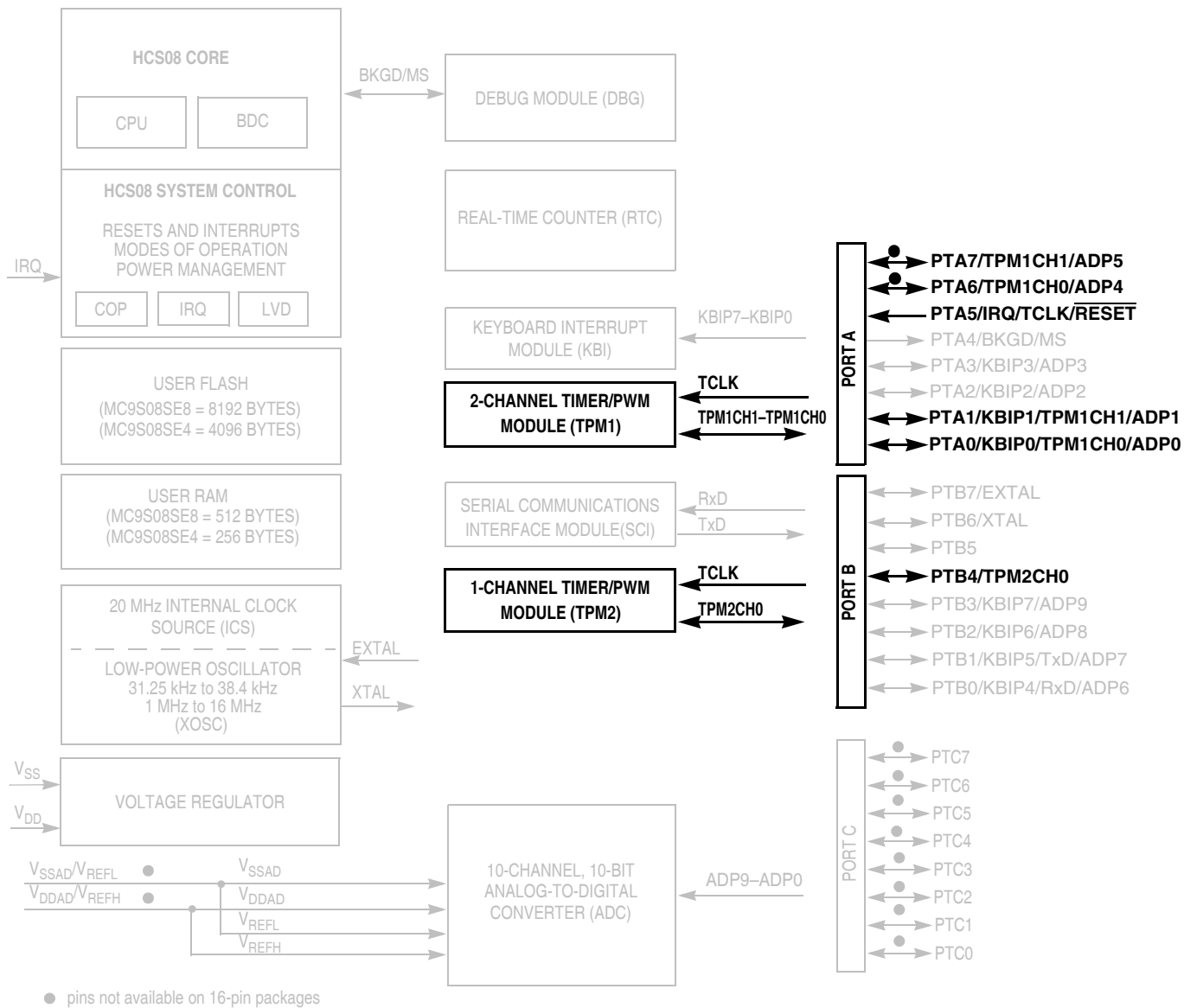
Figure 13-1. MC9S08SE8 Series Block Diagram Highlighting TPM Blocks and Pins

13.2.3   Features

The TPM includes these distinctive features:

- One to eight channels:
  - Each channel may be input capture, output compare, or edge-aligned PWM
  - Rising-Edge, falling-edge, or any-edge input capture trigger
  - Set, clear, or toggle output compare action
  - Selectable polarity on PWM outputs
- Module may be configured for buffered, center-aligned pulse-width-modulation (CPWM) on all channels
- Timer clock source selectable as prescaled bus clock, fixed system clock, or an external clock pin
  - Prescale taps for divide-by 1, 2, 4, 8, 16, 32, 64, or 128
  - Fixed system clock source are synchronized to the bus clock by an on-chip synchronization circuit
  - External clock pin may be shared with any timer channel pin or a separated input pin
- 16-bit free-running or modulo up/down count operation
- Timer system enable
- One interrupt per channel plus terminal count interrupt

13.2.4   Modes of Operation

In general, TPM channels may be independently configured to operate in input capture, output compare, or edge-aligned PWM modes. A control bit allows the whole TPM (all channels) to switch to center-aligned PWM mode. When center-aligned PWM mode is selected, input capture, output compare, and edge-aligned PWM functions are not available on any channels of this TPM module.

When the microcontroller is in active BDM background or BDM foreground mode, the TPM temporarily suspends all counting until the microcontroller returns to normal user operating mode. During stop mode, all system clocks, including the main oscillator, are stopped; therefore, the TPM is effectively disabled until clocks resume. During wait mode, the TPM continues to operate normally. Provided the TPM does not need to produce a real time reference or provide the interrupt source(s) needed to wake the MCU from wait mode, the user can save power by disabling TPM functions before entering wait mode.

- Input capture mode

  When a selected edge event occurs on the associated MCU pin, the current value of the 16-bit timer counter is captured into the channel value register and an interrupt flag bit is set. Rising edges, falling edges, any edge, or no edge (disable channel) may be selected as the active edge which triggers the input capture.

- Output compare mode

  When the value in the timer counter register matches the channel value register, an interrupt flag bit is set, and a selected output action is forced on the associated MCU pin. The output compare action may be selected to force the pin to zero, force the pin to one, toggle the pin, or ignore the pin (used for software timing functions).

- Edge-aligned PWM mode

  The value of a 16-bit modulo register plus 1 sets the period of the PWM output signal. The channel value register sets the duty cycle of the PWM output signal. The user may also choose the polarity of the PWM output signal. Interrupts are available at the end of the period and at the duty-cycle transition point. This type of PWM signal is called edge-aligned because the leading edges of all PWM signals are aligned with the beginning of the period, which is the same for all channels within a TPM.

- Center-aligned PWM mode

  Twice the value of a 16-bit modulo register sets the period of the PWM output, and the channel-value register sets the half-duty-cycle duration. The timer counter counts up until it reaches the modulo value and then counts down until it reaches zero. As the count matches the channel value register while counting down, the PWM output becomes active. When the count matches the channel value register while counting up, the PWM output becomes inactive. This type of PWM signal is called center-aligned because the centers of the active duty cycle periods for all channels are aligned with a count value of zero. This type of PWM is required for types of motors used in small appliances.

This is a high-level description only. Detailed descriptions of operating modes are in later sections.

13.2.5   Block Diagram

The TPM uses one input/output (I/O) pin per channel, TPMxCHn (timer channel n) where n is the channel number (1-8). The TPM shares its I/O pins with general purpose I/O port pins (refer to I/O pin descriptions in full-chip specification for the specific chip implementation).

Figure 13-2 shows the TPM structure. The central component of the TPM is the 16-bit counter that can operate as a free-running counter or a modulo up/down counter. The TPM counter (when operating in normal up-counting mode) provides the timing reference for the input capture, output compare, and edge-aligned PWM functions. The timer counter modulo registers, TPMxMODH:TPMxMODL, control the modulo value of the counter (the values 0x0000 or 0xFFFF effectively make the counter free running). Software can read the counter value at any time without affecting the counting sequence. Any write to either half of the TPMxCNT counter resets the counter, regardless of the data value written.
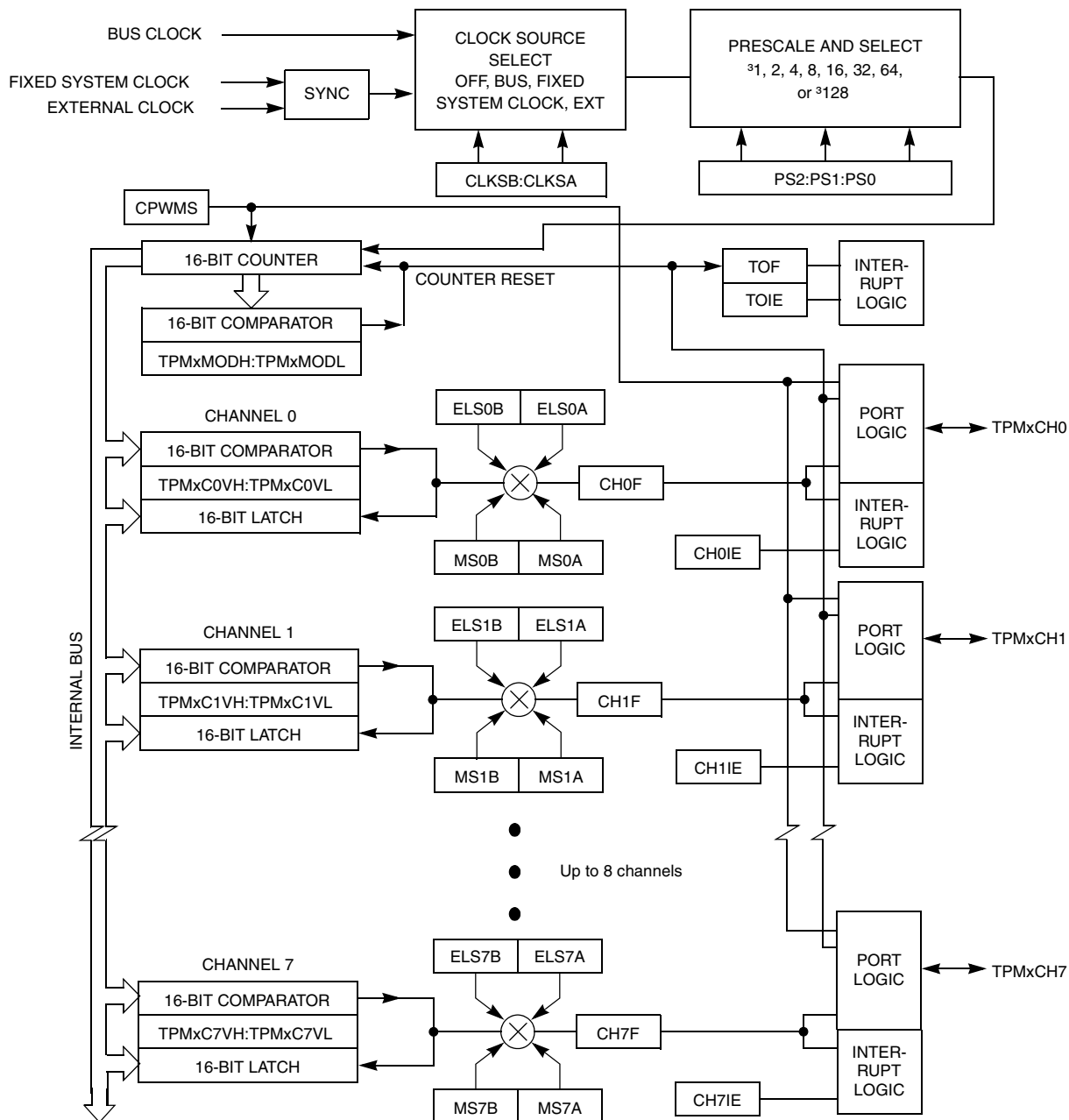
Figure 13-2. TPM Block Diagram

The TPM channels are programmable independently as input capture, output compare, or edge-aligned PWM channels. Alternately, the TPM can be configured to produce CPWM outputs on all channels. When the TPM is configured for CPWMs, the counter operates as an up/down counter; input capture, output compare, and EPWM functions are not practical.

If a channel is configured as input capture, an internal pullup device may be enabled for that channel. The details of how a module interacts with pin controls depends upon the chip implementation because the I/O pins and associated general purpose I/O controls are not part of the module. Refer to the discussion of the I/O port logic in a full-chip specification.

Because center-aligned PWMs are usually used to drive 3-phase AC-induction motors and brushless DC motors, they are typically used in sets of three or six channels.

13.3 Signal Description

Table 13-4 shows the user-accessible signals for the TPM. The number of channels may be varied from one to eight. When an external clock is included, it can be shared with the same pin as any TPM channel; however, it could be connected to a separate input pin. Refer to the I/O pin descriptions in full-chip specification for the specific chip implementation.

Table 13-4. Signal Properties

Name	Function
EXTCLK[1]	External clock source which may be selected to drive the TPM counter.
TPMxCHn[2]	I/O pin associated with TPM channel n

[1] When preset, this signal can share any channel pin; however depending upon full-chip implementation, this signal could be connected to a separate external pin.

[2] n=channel number (1 to 8)

Refer to documentation for the full-chip for details about reset states, port connections, and whether there is any pullup device on these pins.

TPM channel pins can be associated with general purpose I/O pins and have passive pullup devices which can be enabled with a control bit when the TPM or general purpose I/O controls have configured the associated pin as an input. When no TPM function is enabled to use a corresponding pin, the pin reverts to being controlled by general purpose I/O controls, including the port-data and data-direction registers. Immediately after reset, no TPM functions are enabled, so all associated pins revert to general purpose I/O control.

13.3.1 Detailed Signal Descriptions

This section describes each user-accessible pin signal in detail. Although Table 13-4 grouped all channel pins together, any TPM pin can be shared with the external clock source signal. Since I/O pin logic is not part of the TPM, refer to full-chip documentation for a specific derivative for more details about the interaction of TPM pin functions and general purpose I/O controls including port data, data direction, and pullup controls.

13.3.1.1 EXTCLK — External Clock Source

Control bits in the timer status and control register allow the user to select nothing (timer disable), the bus-rate clock (the normal default source), a crystal-related clock, or an external clock as the clock which drives the TPM prescaler and subsequently the 16-bit TPM counter. The external clock source is synchronized in the TPM. The bus clock clocks the synchronizer; the frequency of the external source must be no more than one-fourth the frequency of the bus-rate clock, to meet Nyquist criteria and allowing for jitter.

The external clock signal shares the same pin as a channel I/O pin, so the channel pin will not be usable for channel I/O function when selected as the external clock source. It is the user's responsibility to avoid such settings. If this pin is used as an external clock source (CLKSB:CLKSA = 1:1), the channel can still be used in output compare mode as a software timer (ELSnB:ELSnA = 0:0).

13.3.1.2 TPMxCHn — TPM Channel n I/O Pin(s)

Each TPM channel is associated with an I/O pin on the MCU. The function of this pin depends on the channel configuration. The TPM pins share with general purpose I/O pins, where each pin has a port data register bit, and a data direction control bit, and the port has optional passive pullups which may be enabled whenever a port pin is acting as an input.

The TPM channel does not control the I/O pin when (ELSnB:ELSnA = 0:0) or when (CLKSB:CLKSA = 0:0) so it normally reverts to general purpose I/O control. When CPWMS = 1 (and ELSnB:ELSnA not = 0:0), all channels within the TPM are configured for center-aligned PWM and the TPMxCHn pins are all controlled by the TPM system. When CPWMS=0, the MSnB:MSnA control bits determine whether the channel is configured for input capture, output compare, or edge-aligned PWM.

When a channel is configured for input capture (CPWMS=0, MSnB:MSnA = 0:0 and ELSnB:ELSnA not = 0:0), the TPMxCHn pin is forced to act as an edge-sensitive input to the TPM. ELSnB:ELSnA control bits determine what polarity edge or edges will trigger input-capture events. A synchronizer based on the bus clock is used to synchronize input edges to the bus clock. This implies the minimum pulse width—that can be reliably detected—on an input capture pin is four bus clock periods (with ideal clock pulses as near as two bus clocks can be detected). TPM uses this pin as an input capture input to override the port data and data direction controls for the same pin.

When a channel is configured for output compare (CPWMS=0, MSnB:MSnA = 0:1 and ELSnB:ELSnA not = 0:0), the associated data direction control is overridden, the TPMxCHn pin is considered an output controlled by the TPM, and the ELSnB:ELSnA control bits determine how the pin is controlled. The remaining three combinations of ELSnB:ELSnA determine whether the TPMxCHn pin is toggled, cleared, or set each time the 16-bit channel value register matches the timer counter.

When the output compare toggle mode is initially selected, the previous value on the pin is driven out until the next output compare event—then the pin is toggled.
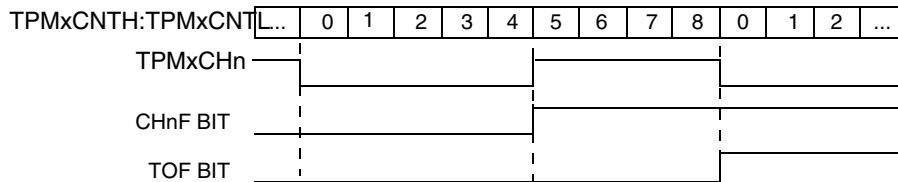
When a channel is configured for edge-aligned PWM (CPWMS=0, MSnB=1 and ELSnB:ELSnA not = 0:0), the data direction is overridden, the TPMxCHn pin is forced to be an output controlled by the TPM, and ELSnA controls the polarity of the PWM output signal on the pin. When ELSnB:ELSnA=1:0, the TPMxCHn pin is forced high at the start of each new period (TPMxCNT=0x0000), and the pin is forced low when the channel value register matches the timer counter. When ELSnA=1, the TPMxCHn pin is forced low at the start of each new period (TPMxCNT=0x0000), and the pin is forced high when the channel value register matches the timer counter.

TPMxMODH:TPMxMODL = 0x0008
TPMxMODH:TPMxMODL = 0x0005
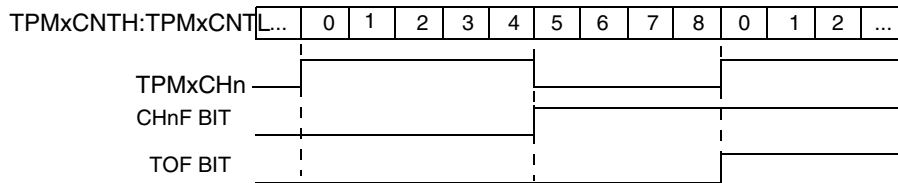
Figure 13-3. High-True Pulse of an Edge-Aligned PWM

TPMxMODH:TPMxMODL = 0x0008
TPMxMODH:TPMxMODL = 0x0005

Figure 13-4. Low-True Pulse of an Edge-Aligned PWM

When the TPM is configured for center-aligned PWM (and ELSnB:ELSnA not = 0:0), the data direction for all channels in this TPM are overridden, the TPMxCHn pins are forced to be outputs controlled by the TPM, and the ELSnA bits control the polarity of each TPMxCHn output. If ELSnB:ELSnA=1:0, the corresponding TPMxCHn pin is cleared when the timer counter is counting up, and the channel value register matches the timer counter; the TPMxCHn pin is set when the timer counter is counting down, and the channel value register matches the timer counter. If ELSnA=1, the corresponding TPMxCHn pin is set when the timer counter is counting up and the channel value register matches the timer counter; the TPMxCHn pin is cleared when the timer counter is counting down and the channel value register matches the timer counter.

TPMxMODH:TPMxMODL = 0x0008
TPMxMODH:TPMxMODL = 0x0005
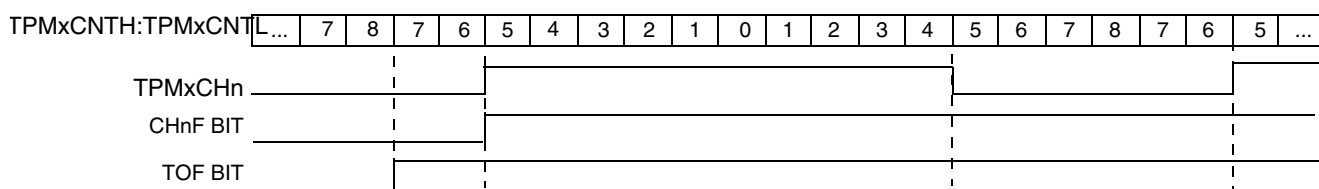
Figure 13-5. High-True Pulse of a Center-Aligned PWM

TPMxMODH:TPMxMODL = 0x0008
TPMxMODH:TPMxMODL = 0x0005
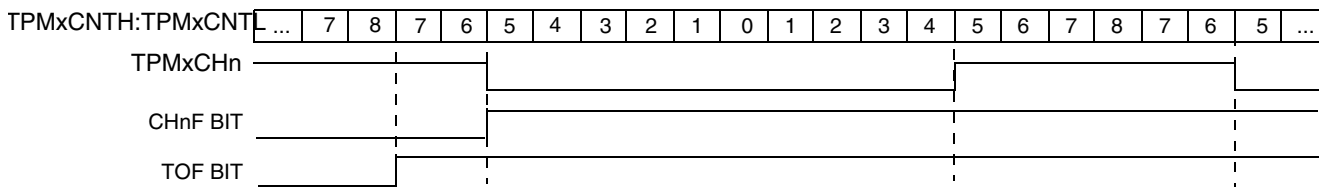
Figure 13-6. Low-True Pulse of a Center-Aligned PWM

13.4   Register Definition

This section consists of register descriptions in address order. A typical MCU system may contain multiple TPMs, and each TPM may have one to eight channels, so register names include placeholder characters to identify which TPM and which channel is being referenced. For example, TPMxCnSC refers to timer (TPM) x, channel n. TPM1C2SC would be the status and control register for channel 2 of timer 1.

13.4.1   TPM Status and Control Register (TPMxSC)

TPMxSC contains the overflow status flag and control bits used to configure the interrupt enable, TPM configuration, clock source, and prescale factor. These controls relate to all channels within this timer module.

	7	6	5	4	3	2	1	0
R	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
W	0							
Reset	0	0	0	0	0	0	0	0

Figure 13-7. TPM Status and Control Register (TPMxSC)

Table 13-5. TPMxSC Field Descriptions

Field	Description
7 TOF	Timer overflow flag. This read/write flag is set when the TPM counter resets to 0x0000 after reaching the modulo value programmed in the TPM counter modulo registers. Clear TOF by reading the TPM status and control register when TOF is set and then writing a logic 0 to TOF. If another TPM overflow occurs before the clearing sequence is complete, the sequence is reset so TOF would remain set after the clear sequence was completed for the earlier TOF. This is done so a TOF interrupt request cannot be lost during the clearing sequence for a previous TOF. Reset clears TOF. Writing a logic 1 to TOF has no effect. 0 TPM counter has not reached modulo value or overflow 1 TPM counter has overflowed
6 TOIE	Timer overflow interrupt enable. This read/write bit enables TPM overflow interrupts. If TOIE is set, an interrupt is generated when TOF equals one. Reset clears TOIE. 0 TOF interrupts inhibited (use for software polling) 1 TOF interrupts enabled
5 CPWMS	Center-aligned PWM select. When present, this read/write bit selects CPWM operating mode. By default, the TPM operates in up-counting mode for input capture, output compare, and edge-aligned PWM functions. Setting CPWMS reconfigures the TPM to operate in up/down counting mode for CPWM functions. Reset clears CPWMS. 0 All channels operate as input capture, output compare, or edge-aligned PWM mode as selected by the MSnB:MSnA control bits in each channel's status and control register. 1 All channels operate in center-aligned PWM mode.

Table 13-5. TPMxSC Field Descriptions (continued)

Field	Description
4–3 CLKS[B:A]	Clock source selects. As shown in Table 13-6, this 2-bit field is used to disable the TPM system or select one of three clock sources to drive the counter prescaler. The fixed system clock source is only meaningful in systems with a PLL-based or FLL-based system clock. When there is no PLL or FLL, the fixed-system clock source is the same as the bus rate clock. The external source is synchronized to the bus clock by TPM module, and the fixed system clock source (when a PLL or FLL is present) is synchronized to the bus clock by an on-chip synchronization circuit. When a PLL or FLL is present but not enabled, the fixed-system clock source is the same as the bus-rate clock.
2–0 PS[2:0]	Prescale factor select. This 3-bit field selects one of 8 division factors for the TPM clock input as shown in Table 13-7. This prescaler is located after any clock source synchronization or clock source selection so it affects the clock source selected to drive the TPM system. The new prescale factor will affect the clock source on the next system clock cycle after the new value is updated into the register bits.

Table 13-6. TPM-Clock-Source Selection

CLKSB:CLKSA	TPM Clock Source to Prescaler Input
00	No clock selected (TPM counter disable)
01	Bus rate clock
10	Fixed system clock
11	External source

Table 13-7. Prescale Factor Selection

PS2:PS1:PS0	TPM Clock Source Divided-by
000	1
001	2
010	4
011	8
100	16
101	32
110	64
111	128

13.4.2   TPM-Counter Registers (TPMxCNTH:TPMxCNTL)

The two read-only TPM counter registers contain the high and low bytes of the value in the TPM counter. Reading either byte (TPMxCNTH or TPMxCNTL) latches the contents of both bytes into a buffer where they remain latched until the other half is read. This allows coherent 16-bit reads in either big-endian or little-endian order which makes this more friendly to various compiler implementations. The coherency mechanism is automatically restarted by an MCU reset or any write to the timer status/control register (TPMxSC).

Reset clears the TPM counter registers. Writing any value to TPMxCNTH or TPMxCNTL also clears the TPM counter (TPMxCNTH:TPMxCNTL) and resets the coherency mechanism, regardless of the data involved in the write.

	7	6	5	4	3	2	1	0
R	Bit 15	14	13	12	11	10	9	Bit 8
W	Any write to TPMxCNTH clears the 16-bit counter							
Reset	0	0	0	0	0	0	0	0
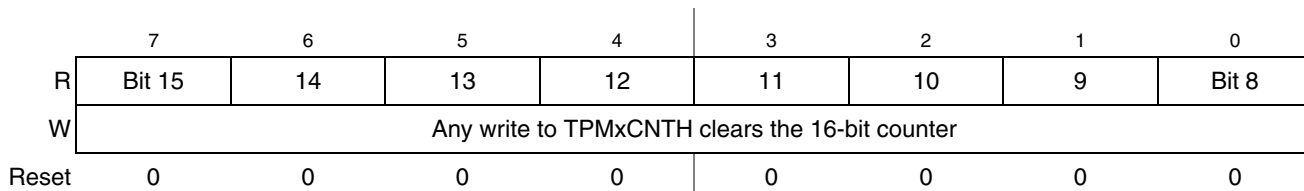
Figure 13-8. TPM Counter Register High (TPMxCNTH)

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	2	1	Bit 0
W	Any write to TPMxCNTL clears the 16-bit counter							
Reset	0	0	0	0	0	0	0	0
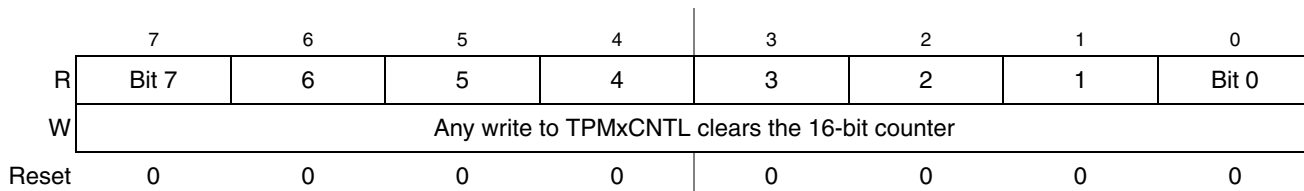
Figure 13-9. TPM Counter Register Low (TPMxCNTL)

When BDM is active, the timer counter is frozen (this is the value that will be read by user); the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active, even if one or both counter halves are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution.

In BDM mode, writing any value to TPMxSC, TPMxCNTH or TPMxCNTL registers resets the read coherency mechanism of the TPMxCNTH:L registers, regardless of the data involved in the write.

13.4.3   TPM Counter Modulo Registers (TPMxMODH:TPMxMODL)

The read/write TPM modulo registers contain the modulo value for the TPM counter. After the TPM counter reaches the modulo value, the TPM counter resumes counting from 0x0000 at the next clock, and the overflow flag (TOF) becomes set. Writing to TPMxMODH or TPMxMODL inhibits the TOF bit and overflow interrupts until the other byte is written. Reset sets the TPM counter modulo registers to 0x0000 which results in a free running timer counter (modulo disabled).

Writing to either byte (TPMxMODH or TPMxMODL) latches the value into a buffer and the registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), then the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), then the registers are updated after both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFE to 0xFFFF

The latching mechanism may be manually reset by writing to the TPMxSC address (whether BDM is active or not).

When BDM is active, the coherency mechanism is frozen (unless reset by writing to TPMxSC register) such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the modulo register are written while BDM is active. Any write to the modulo registers bypasses the buffer latches and directly writes to the modulo register while BDM is active.
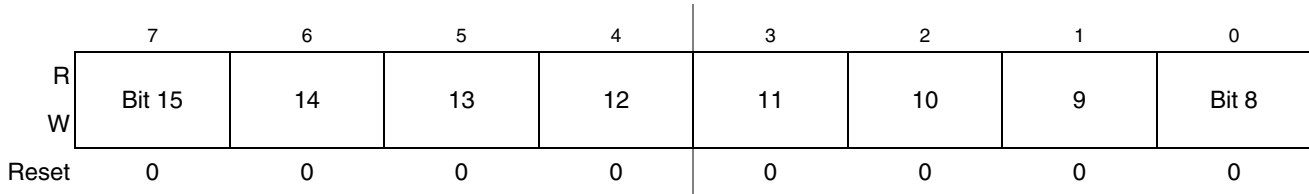
	7	6	5	4	3	2	1	0
R	Bit 15	14	13	12	11	10	9	Bit 8
W								
Reset	0	0	0	0	0	0	0	0

Figure 13-10. TPM Counter Modulo Register High (TPMxMODH)

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	2	1	Bit 0
W								
Reset	0	0	0	0	0	0	0	0
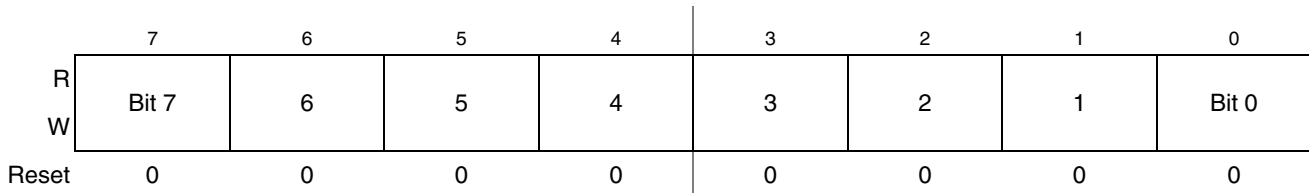
Figure 13-11. TPM Counter Modulo Register Low (TPMxMODL)

Reset the TPM counter before writing to the TPM modulo registers to avoid confusion about when the first counter overflow will occur.

13.4.4 TPM Channel n Status and Control Register (TPMxCnSC)

TPMxCnSC contains the channel-interrupt-status flag and control bits used to configure the interrupt enable, channel configuration, and pin function.

	7	6	5	4	3	2	1	0
R	CHnF	CHnIE	MSnB	MSnA	ELSnB	ELSnA	0	0
W	0							
Reset	0	0	0	0	0	0	0	0

	= Unimplemented or Reserved
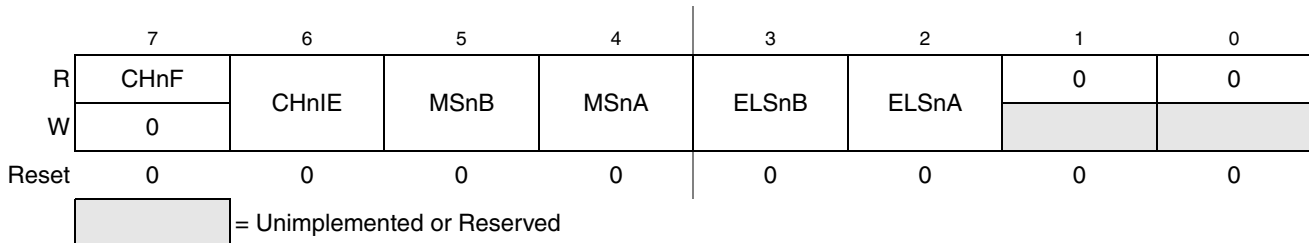
Figure 13-12. TPM Channel n Status and Control Register (TPMxCnSC)

Table 13-8. TPMxCnSC Field Descriptions

Field	Description
7 CHnF	Channel n flag. When channel n is an input-capture channel, this read/write bit is set when an active edge occurs on the channel n pin. When channel n is an output compare or edge-aligned/center-aligned PWM channel, CHnF is set when the value in the TPM counter registers matches the value in the TPM channel n value registers. When channel n is an edge-aligned/center-aligned PWM channel and the duty cycle is set to 0% or 100%, CHnF will not be set even when the value in the TPM counter registers matches the value in the TPM channel n value registers. A corresponding interrupt is requested when CHnF is set and interrupts are enabled (CHnIE = 1). Clear CHnF by reading TPMxCnSC while CHnF is set and then writing a logic 0 to CHnF. If another interrupt request occurs before the clearing sequence is complete, the sequence is reset so CHnF remains set after the clear sequence completed for the earlier CHnF. This is done so a CHnF interrupt request cannot be lost due to clearing a previous CHnF. Reset clears the CHnF bit. Writing a logic 1 to CHnF has no effect. 0 No input capture or output compare event occurred on channel n 1 Input capture or output compare event on channel n
6 CHnIE	Channel n interrupt enable. This read/write bit enables interrupts from channel n. Reset clears CHnIE. 0 Channel n interrupt requests disabled (use for software polling) 1 Channel n interrupt requests enabled
5 MSnB	Mode select B for TPM channel n. When CPWMS=0, MSnB=1 configures TPM channel n for edge-aligned PWM mode. Refer to the summary of channel mode and setup controls in Table 13-9.
4 MSnA	Mode select A for TPM channel n. When CPWMS=0 and MSnB=0, MSnA configures TPM channel n for input-capture mode or output compare mode. Refer to Table 13-9 for a summary of channel mode and setup controls. **Note:** If the associated port pin is not stable for at least two bus clock cycles before changing to input capture mode, it is possible to get an unexpected indication of an edge trigger.
3–2 ELSnB ELSnA	Edge/level select bits. Depending upon the operating mode for the timer channel as set by CPWMS:MSnB:MSnA and shown in Table 13-9, these bits select the polarity of the input edge that triggers an input capture event, select the level that will be driven in response to an output compare match, or select the polarity of the PWM output. Setting ELSnB:ELSnA to 0:0 configures the related timer pin as a general purpose I/O pin not related to any timer functions. This function is typically used to temporarily disable an input capture channel or to make the timer pin available as a general purpose I/O pin when the associated timer channel is set up as a software timer that does not require the use of a pin.

**Table 13-9. Mode, Edge, and Level Selection**

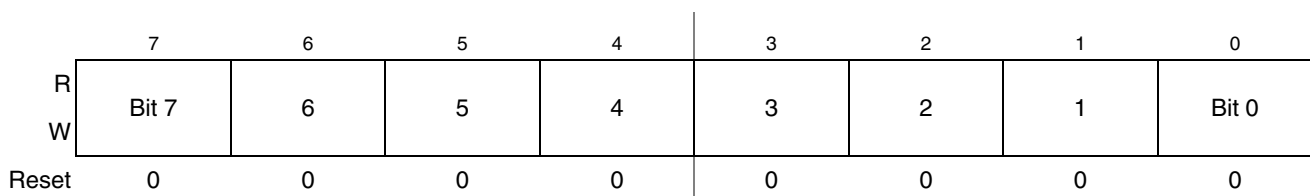| CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
X	XX	00	Pin not used for TPM - revert to general purpose I/O or other peripheral control	

Table 13-9. Mode, Edge, and Level Selection

CPWMS	MSnB:MSnA	ELSnB:ELSnA	Mode	Configuration
0	00	01	Input capture	Capture on rising edge only
		10		Capture on falling edge only
		11		Capture on rising or falling edge
	01	01	Output compare	Toggle output on compare
		10		Clear output on compare
		11		Set output on compare
	1X	10	Edge-aligned PWM	High-true pulses (clear output on compare)
		X1		Low-true pulses (set output on compare)
1	XX	10	Center-aligned PWM	High-true pulses (clear output on compare-up)
		X1		Low-true pulses (set output on compare-up)

13.4.5 TPM Channel Value Registers (TPMxCnVH:TPMxCnVL)

These read/write registers contain the captured TPM counter value of the input capture function or the output compare value for the output compare or PWM functions. The channel registers are cleared by reset.

	7	6	5	4	3	2	1	0
R	Bit 15	14	13	12	11	10	9	Bit 8
W								
Reset	0	0	0	0	0	0	0	0
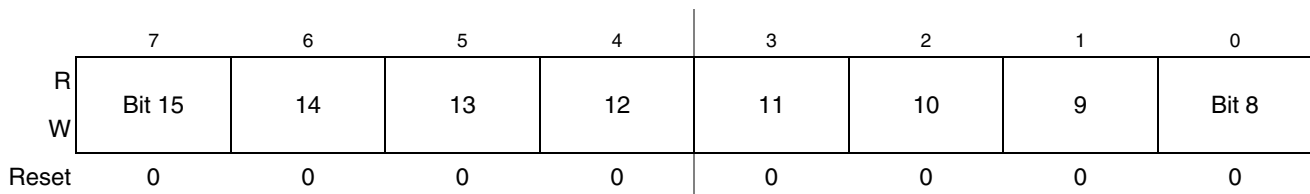
Figure 13-13. TPM Channel Value Register High (TPMxCnVH)

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	2	1	Bit 0
W								
Reset	0	0	0	0	0	0	0	0

Figure 13-14. TPM Channel Value Register Low (TPMxCnVL)

In input capture mode, reading either byte (TPMxCnVH or TPMxCnVL) latches the contents of both bytes into a buffer where they remain latched until the other half is read. This latching mechanism also resets

(becomes unlatched) when the TPMxCnSC register is written (whether BDM mode is active or not). Any write to the channel registers will be ignored during the input capture mode.

When BDM is active, the coherency mechanism is frozen (unless reset by writing to TPMxCnSC register) such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the channel register are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution. The value read from the TPMxCnVH and TPMxCnVL registers in BDM mode is the value of these registers and not the value of their read buffer.

In output compare or PWM modes, writing to either byte (TPMxCnVH or TPMxCnVL) latches the value into a buffer. After both bytes are written, they are transferred as a coherent 16-bit value into the timer-channel registers according to the value of CLKSB:CLKSA bits and the selected mode, so:

- If (CLKSB:CLKSA = 0:0), then the registers are updated when the second byte is written.
- If (CLKSB:CLKSA not = 0:0 and in output compare mode) then the registers are updated after the second byte is written and on the next change of the TPM counter (end of the prescaler counting).
- If (CLKSB:CLKSA not = 0:0 and in EPWM or CPWM modes), then the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter then the update is made when the TPM counter changes from 0xFFFE to 0xFFFF.

The latching mechanism may be manually reset by writing to the TPMxCnSC register (whether BDM mode is active or not). This latching mechanism allows coherent 16-bit writes in either big-endian or little-endian order which is friendly to various compiler implementations.

When BDM is active, the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active even if one or both halves of the channel register are written while BDM is active. Any write to the channel registers bypasses the buffer latches and directly write to the channel register while BDM is active. The values written to the channel register while BDM is active are used for PWM & output compare operation once normal execution resumes. Writes to the channel registers while BDM is active do not interfere with partial completion of a coherency sequence. After the coherency mechanism has been fully exercised, the channel registers are updated using the buffered values written (while BDM was not active) by the user.

13.5 Functional Description

All TPM functions are associated with a central 16-bit counter which allows flexible selection of the clock source and prescale factor. There is also a 16-bit modulo register associated with the main counter.

The CPWMS control bit chooses between center-aligned PWM operation for all channels in the TPM (CPWMS=1) or general purpose timing functions (CPWMS=0) where each channel can independently be configured to operate in input capture, output compare, or edge-aligned PWM mode. The CPWMS control bit is located in the main TPM status and control register because it affects all channels within the TPM and influences the way the main counter operates. (In CPWM mode, the counter changes to an up/down mode rather than the up-counting mode used for general purpose timer functions.)

The following sections describe the main counter and each of the timer operating modes (input capture, output compare, edge-aligned PWM, and center-aligned PWM). Because details of pin operation and interrupt activity depend upon the operating mode, these topics will be covered in the associated mode explanation sections.

13.5.1 Counter

All timer functions are based on the main 16-bit counter (TPMxCNTH:TPMxCNTL). This section discusses selection of the clock source, end-of-count overflow, up-counting vs. up/down counting, and manual counter reset.

13.5.1.1 Counter Clock Source

The 2-bit field, CLKSB:CLKSA, in the timer status and control register (TPMxSC) selects one of three possible clock sources or OFF (which effectively disables the TPM). See Table 13-6. After any MCU reset, CLKSB:CLKSA=0:0 so no clock source is selected, and the TPM is in a very low power state. These control bits may be read or written at any time and disabling the timer (writing 00 to the CLKSB:CLKSA field) does not affect the values in the counter or other timer registers.

Table 13-10. TPM Clock Source Selection

CLKSB:CLKSA	TPM Clock Source to Prescaler Input
00	No clock selected (TPM counter disabled)
01	Bus rate clock
10	Fixed system clock
11	External source

The bus rate clock is the main system bus clock for the MCU. This clock source requires no synchronization because it is the clock that is used for all internal MCU activities including operation of the CPU and buses.

In MCUs that have no PLL and FLL or the PLL and FLL are not engaged, the fixed system clock source is the same as the bus-rate-clock source, and it does not go through a synchronizer. When a PLL or FLL is present and engaged, a synchronizer is required between the crystal divided-by two clock source and the timer counter so counter transitions will be properly aligned to bus-clock transitions. A synchronizer will be used at chip level to synchronize the crystal-related source clock to the bus clock.

The external clock source may be connected to any TPM channel pin. This clock source always has to pass through a synchronizer to assure that counter transitions are properly aligned to bus clock transitions. The bus-rate clock drives the synchronizer; therefore, to meet Nyquist criteria even with jitter, the frequency of the external clock source must not be faster than the bus rate divided-by four. With ideal clocks the external clock can be as fast as bus clock divided by four.

When the external clock source shares the TPM channel pin, this pin should not be used for other channel timing functions. For example, it would be ambiguous to configure channel 0 for input capture when the TPM channel 0 pin was also being used as the timer external clock source. (It is the user's responsibility to avoid such settings.) The TPM channel could still be used in output compare mode for software timing functions (pin controls set not to affect the TPM channel pin).

13.5.1.2 Counter Overflow and Modulo Reset

An interrupt flag and enable are associated with the 16-bit main counter. The flag (TOF) is a software-accessible indication that the timer counter has overflowed. The enable signal selects between software polling (TOIE=0) where no hardware interrupt is generated, or interrupt-driven operation (TOIE=1) where a static hardware interrupt is generated whenever the TOF flag is equal to one.

The conditions causing TOF to become set depend on whether the TPM is configured for center-aligned PWM (CPWMS=1). In the simplest mode, there is no modulus limit and the TPM is not in CPWMS=1 mode. In this case, the 16-bit timer counter counts from 0x0000 through 0xFFFF and overflows to 0x0000 on the next counting clock. TOF becomes set at the transition from 0xFFFF to 0x0000. When a modulus limit is set, TOF becomes set at the transition from the value set in the modulus register to 0x0000. When the TPM is in center-aligned PWM mode (CPWMS=1), the TOF flag gets set as the counter changes direction at the end of the count value set in the modulus register (that is, at the transition from the value set in the modulus register to the next lower count value). This corresponds to the end of a PWM period (the 0x0000 count value corresponds to the center of a period).

13.5.1.3 Counting Modes

The main timer counter has two counting modes. When center-aligned PWM is selected (CPWMS=1), the counter operates in up/down counting mode. Otherwise, the counter operates as a simple up counter. As an up counter, the timer counter counts from 0x0000 through its terminal count and then continues with 0x0000. The terminal count is 0xFFFF or a modulus value in TPMxMODH:TPMxMODL.

When center-aligned PWM operation is specified, the counter counts up from 0x0000 through its terminal count and then down to 0x0000 where it changes back to up counting. Both 0x0000 and the terminal count value are normal length counts (one timer clock period long). In this mode, the timer overflow flag (TOF) becomes set at the end of the terminal-count period (as the count changes to the next lower count value).

13.5.1.4 Manual Counter Reset

The main timer counter can be manually reset at any time by writing any value to either half of TPMxCNTH or TPMxCNTL. Resetting the counter in this manner also resets the coherency mechanism in case only half of the counter was read before resetting the count.

13.5.2 Channel Mode Selection

Provided CPWMS=0, the MSnB and MSnA control bits in the channel n status and control registers determine the basic mode of operation for the corresponding channel. Choices include input capture, output compare, and edge-aligned PWM.

13.5.2.1 Input Capture Mode

With the input-capture function, the TPM can capture the time at which an external event occurs. When an active edge occurs on the pin of an input-capture channel, the TPM latches the contents of the TPM counter into the channel-value registers (TPMxCnVH:TPMxCnVL). Rising edges, falling edges, or any edge may be chosen as the active edge that triggers an input capture.

In input capture mode, the TPMxCnVH and TPMxCnVL registers are read only.

When either half of the 16-bit capture register is read, the other half is latched into a buffer to support coherent 16-bit accesses in big-endian or little-endian order. The coherency sequence can be manually reset by writing to the channel status/control register (TPMxCnSC).

An input capture event sets a flag bit (CHnF) which may optionally generate a CPU interrupt request.

While in BDM, the input capture function works as configured by the user. When an external event occurs, the TPM latches the contents of the TPM counter (which is frozen because of the BDM mode) into the channel value registers and sets the flag bit.

13.5.2.2 Output Compare Mode

With the output-compare function, the TPM can generate timed pulses with programmable position, polarity, duration, and frequency. When the counter reaches the value in the channel-value registers of an output-compare channel, the TPM can set, clear, or toggle the channel pin.

In output compare mode, values are transferred to the corresponding timer channel registers only after both 8-bit halves of a 16-bit register have been written and according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated at the next change of the TPM counter (end of the prescaler counting) after the second byte is written.

The coherency sequence can be manually reset by writing to the channel status/control register (TPMxCnSC).

An output compare event sets a flag bit (CHnF) which may optionally generate a CPU-interrupt request.

13.5.2.3 Edge-Aligned PWM Mode

This type of PWM output uses the normal up-counting mode of the timer counter (CPWMS=0) and can be used when other channels in the same TPM are configured for input capture or output compare functions. The period of this PWM signal is determined by the value of the modulus register (TPMxMODH:TPMxMODL) plus 1. The duty cycle is determined by the setting in the timer channel register (TPMxCnVH:TPMxCnVL). The polarity of this PWM signal is determined by the setting in the ELSnA control bit. 0% and 100% duty cycle cases are possible.

The output compare value in the TPM channel registers determines the pulse width (duty cycle) of the PWM signal (Figure 13-15). The time between the modulus overflow and the output compare is the pulse width. If ELSnA=0, the counter overflow forces the PWM signal high, and the output compare forces the PWM signal low. If ELSnA=1, the counter overflow forces the PWM signal low, and the output compare forces the PWM signal high.
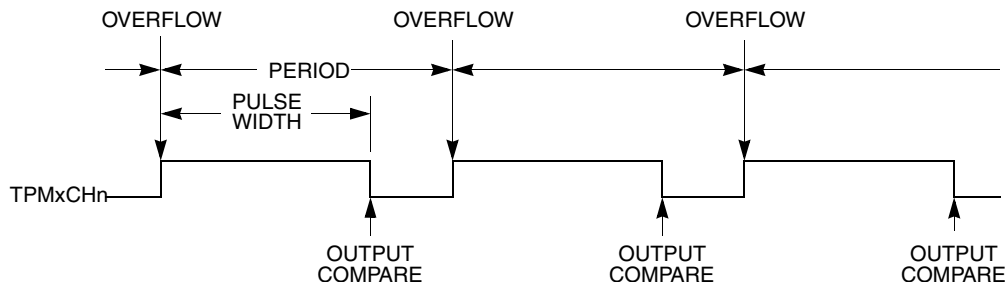
Figure 13-15. PWM Period and Pulse Width (ELSnA=0)

When the channel value register is set to 0x0000, the duty cycle is 0%. 100% duty cycle can be achieved by setting the timer-channel register (TPMxCnVH:TPMxCnVL) to a value greater than the modulus setting. This implies that the modulus setting must be less than 0xFFFF in order to get 100% duty cycle.

Because the TPM may be used in an 8-bit MCU, the settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers TPMxCnVH and TPMxCnVL, actually write to buffer registers. In edge-aligned PWM mode, values are transferred to the corresponding timer-channel registers according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If

the TPM counter is a free-running counter then the update is made when the TPM counter changes from 0xFFFE to 0xFFFF.

13.5.2.4 Center-Aligned PWM Mode

This type of PWM output uses the up/down counting mode of the timer counter (CPWMS=1). The output compare value in TPMxCnVH:TPMxCnVL determines the pulse width (duty cycle) of the PWM signal while the period is determined by the value in TPMxMODH:TPMxMODL. TPMxMODH:TPMxMODL should be kept in the range of 0x0001 to 0x7FFF because values outside this range can produce ambiguous results. ELSnA will determine the polarity of the CPWM output.

pulse width = 2 x (TPMxCnVH:TPMxCnVL)

period = 2 x (TPMxMODH:TPMxMODL); TPMxMODH:TPMxMODL=0x0001-0x7FFF

If the channel-value register TPMxCnVH:TPMxCnVL is zero or negative (bit 15 set), the duty cycle will be 0%. If TPMxCnVH:TPMxCnVL is a positive value (bit 15 clear) and is greater than the (non-zero) modulus setting, the duty cycle will be 100% because the duty cycle compare will never occur. This implies the usable range of periods set by the modulus register is 0x0001 through 0x7FFE (0x7FFF if you do not need to generate 100% duty cycle). This is not a significant limitation. The resulting period would be much longer than required for normal applications.

TPMxMODH:TPMxMODL=0x0000 is a special case that should not be used with center-aligned PWM mode. When CPWMS=0, this case corresponds to the counter running free from 0x0000 through 0xFFFF, but when CPWMS=1 the counter needs a valid match to the modulus register somewhere other than at 0x0000 in order to change directions from up-counting to down-counting.

The output compare value in the TPM channel registers (times 2) determines the pulse width (duty cycle) of the CPWM signal (Figure 13-16). If ELSnA=0, a compare occurred while counting up forces the CPWM output signal low and a compare occurred while counting down forces the output high. The counter counts up until it reaches the modulo setting in TPMxMODH:TPMxMODL, then counts down until it reaches zero. This sets the period equal to two times TPMxMODH:TPMxMODL.
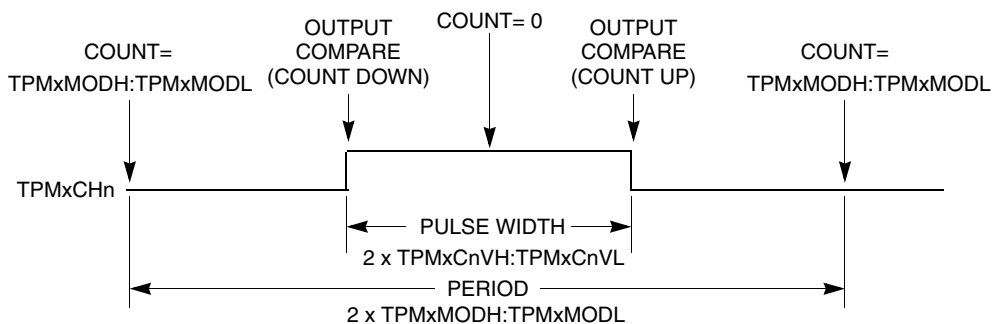
Figure 13-16. CPWM Period and Pulse Width (ELSnA=0)

Center-aligned PWM outputs typically produce less noise than edge-aligned PWMs because fewer I/O pin transitions are lined up at the same system clock edge. This type of PWM is also required for some types of motor drives.

Input capture, output compare, and edge-aligned PWM functions do not make sense when the counter is operating in up/down counting mode so this implies that all active channels within a TPM must be used in CPWM mode when CPWMS=1.

The TPM may be used in an 8-bit MCU. The settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers TPMxMODH, TPMxMODL, TPMxCnVH, and TPMxCnVL, actually write to buffer registers.

In center-aligned PWM mode, the TPMxCnVH:L registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), the registers are updated after the both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFE to 0xFFFF.

When TPMxCNTH:TPMxCNTL=TPMxMODH:TPMxMODL, the TPM can optionally generate a TOF interrupt (at the end of this count).

Writing to TPMxSC cancels any values written to TPMxMODH and/or TPMxMODL and resets the coherency mechanism for the modulo registers. Writing to TPMxCnSC cancels any values written to the channel value registers and resets the coherency mechanism for TPMxCnVH:TPMxCnVL.

13.6 Reset Overview

13.6.1 General

The TPM is reset whenever any MCU reset occurs.

13.6.2 Description of Reset Operation

Reset clears the TPMxSC register which disables clocks to the TPM and disables timer overflow interrupts (TOIE=0). CPWMS, MSnB, MSnA, ELSnB, and ELSnA are all cleared which configures all TPM channels for input-capture operation with the associated pins disconnected from I/O pin logic (so all MCU pins related to the TPM revert to general purpose I/O pins).

13.7 Interrupts

13.7.1 General

The TPM generates an optional interrupt for the main counter overflow and an interrupt for each channel. The meaning of channel interrupts depends on each channel's mode of operation. If the channel is configured for input capture, the interrupt flag is set each time the selected input capture edge is recognized. If the channel is configured for output compare or PWM modes, the interrupt flag is set each time the main timer counter matches the value in the 16-bit channel value register.

All TPM interrupts are listed in Table 13-11 which shows the interrupt name, the name of any local enable that can block the interrupt request from leaving the TPM and getting recognized by the separate interrupt processing logic.

Table 13-11. Interrupt Summary

Interrupt	Local Enable	Source	Description
TOF	TOIE	Counter overflow	Set each time the timer counter reaches its terminal count (at transition to next count value which is usually 0x0000)
CHnF	CHnIE	Channel event	An input capture or output compare event took place on channel n

The TPM module will provide a high-true interrupt signal. Vectors and priorities are determined at chip integration time in the interrupt module so refer to the user's guide for the interrupt module or to the chip's complete documentation for details.

13.7.2   Description of Interrupt Operation

For each interrupt source in the TPM, a flag bit is set upon recognition of the interrupt condition such as timer overflow, channel-input capture, or output-compare events. This flag may be read (polled) by software to determine that the action has occurred, or an associated enable bit (TOIE or CHnIE) can be set to enable hardware interrupt generation. While the interrupt enable bit is set, a static interrupt will generate whenever the associated interrupt flag equals one. The user's software must perform a sequence of steps to clear the interrupt flag before returning from the interrupt-service routine.

TPM interrupt flags are cleared by a two-step process including a read of the flag bit while it is set (1) followed by a write of zero (0) to the bit. If a new event is detected between these two steps, the sequence is reset and the interrupt flag remains set after the second step to avoid the possibility of missing the new event.

13.7.2.1   Timer Overflow Interrupt (TOF) Description

The meaning and details of operation for TOF interrupts varies slightly depending upon the mode of operation of the TPM system (general purpose timing functions versus center-aligned PWM operation). The flag is cleared by the two step sequence described above.

13.7.2.1.1   Normal Case

Normally TOF is set when the timer counter changes from 0xFFFF to 0x0000. When the TPM is not configured for center-aligned PWM (CPWMS=0), TOF gets set when the timer counter changes from the terminal count (the value in the modulo register) to 0x0000. This case corresponds to the normal meaning of counter overflow.

13.7.2.1.2   Center-Aligned PWM Case

When CPWMS=1, TOF gets set when the timer counter changes direction from up-counting to down-counting at the end of the terminal count (the value in the modulo register). In this case the TOF corresponds to the end of a PWM period.

13.7.2.2   Channel Event Interrupt Description

The meaning of channel interrupts depends on the channel's current mode (input-capture, output-compare, edge-aligned PWM, or center-aligned PWM).

13.7.2.2.1   Input Capture Events

When a channel is configured as an input capture channel, the ELSnB:ELSnA control bits select no edge (off), rising edges, falling edges or any edge as the edge which triggers an input capture event. When the selected edge is detected, the interrupt flag is set. The flag is cleared by the two-step sequence described in Section 13.7.2, "Description of Interrupt Operation."

13.7.2.2.2   Output Compare Events

When a channel is configured as an output compare channel, the interrupt flag is set each time the main timer counter matches the 16-bit value in the channel value register. The flag is cleared by the two-step sequence described Section 13.7.2, "Description of Interrupt Operation."

13.7.2.2.3   PWM End-of-Duty-Cycle Events

For channels configured for PWM operation there are two possibilities. When the channel is configured for edge-aligned PWM, the channel flag gets set when the timer counter matches the channel value register which marks the end of the active duty cycle period. When the channel is configured for center-aligned PWM, the timer count matches the channel value register twice during each PWM cycle. In this CPWM case, the channel flag is set at the start and at the end of the active duty cycle period which are the times when the timer counter matches the channel value register. The flag is cleared by the two-step sequence described Section 13.7.2, "Description of Interrupt Operation."

1. Write to TPMxCnTH:L registers (Section 13.4.2, "TPM-Counter Registers (TPMxCNTH:TPMxCNTL)) [SE110-TPM case 7]

   Any write to TPMxCNTH or TPMxCNTL registers in TPM v3 clears the TPM counter (TPMxCNTH:L) and the prescaler counter. Instead, in the TPM v2 only the TPM counter is cleared in this case.

2. Read of TPMxCNTH:L registers (Section 13.4.2, "TPM-Counter Registers (TPMxCNTH:TPMxCNTL))

   — In TPM v3, any read of TPMxCNTH:L registers during BDM mode returns the value of the TPM counter that is frozen. In TPM v2, if only one byte of the TPMxCNTH:L registers was read before the BDM mode became active, then any read of TPMxCNTH:L registers during BDM mode returns the latched value of TPMxCNTH:L from the read buffer instead of the frozen TPM counter value.

— This read coherency mechanism is cleared in TPM v3 in BDM mode if there is a write to TPMxSC, TPMxCNTH or TPMxCNTL. Instead, in these conditions the TPM v2 does not clear this read coherency mechanism.

3. Read of TPMxCnVH:L registers (Section 13.4.5, "TPM Channel Value Registers (TPMxCnVH:TPMxCnVL))

   — In TPM v3, any read of TPMxCnVH:L registers during BDM mode returns the value of the TPMxCnVH:L register. In TPM v2, if only one byte of the TPMxCnVH:L registers was read before the BDM mode became active, then any read of TPMxCnVH:L registers during BDM mode returns the latched value of TPMxCNTH:L from the read buffer instead of the value in the TPMxCnVH:L registers.

   — This read coherency mechanism is cleared in TPM v3 in BDM mode if there is a write to TPMxCnSC. Instead, in this condition the TPM v2 does not clear this read coherency mechanism.

4. Write to TPMxCnVH:L registers

   — Input Capture Mode (Section 13.5.2.1, "Input Capture Mode)

   In this mode the TPM v3 does not allow the writes to TPMxCnVH:L registers. Instead, the TPM v2 allows these writes.

   — Output Compare Mode (Section 13.5.2.2, "Output Compare Mode)

   In this mode and if (CLKSB:CLKSA not = 0:0), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer at the next change of the TPM counter (end of the prescaler counting) after the second byte is written. Instead, the TPM v2 always updates these registers when their second byte is written.

   — Edge-Aligned PWM (Section 13.5.2.3, "Edge-Aligned PWM Mode)

   In this mode and if (CLKSB:CLKSA not = 00), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer after that the both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from $FFFE to $FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to $0000.

   — Center-Aligned PWM (Section 13.5.2.4, "Center-Aligned PWM Mode)

   In this mode and if (CLKSB:CLKSA not = 00), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer after that the both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from $FFFE to $FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to (TPMxMODH:L - 1).

5. Center-Aligned PWM (Section 13.5.2.4, "Center-Aligned PWM Mode)

   — TPMxCnVH:L = TPMxMODH:L [SE110-TPM case 1]

   In this case, the TPM v3 produces 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.

   — TPMxCnVH:L = (TPMxMODH:L - 1) [SE110-TPM case 2]

In this case, the TPM v3 produces almost 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.

— TPMxCnVH:L is changed from 0x0000 to a non-zero value [SE110-TPM case 3 and 5]

In this case, the TPM v3 waits for the start of a new PWM period to begin using the new duty cycle setting. Instead, the TPM v2 changes the channel output at the middle of the current PWM period (when the count reaches 0x0000).

— TPMxCnVH:L is changed from a non-zero value to 0x0000 [SE110-TPM case 4]

In this case, the TPM v3 finishes the current PWM period using the old duty cycle setting. Instead, the TPM v2 finishes the current PWM period using the new duty cycle setting.

6. Write to TPMxMODH:L registers in BDM mode (Section 13.4.3, "TPM Counter Modulo Registers (TPMxMODH:TPMxMODL))

In the TPM v3 a write to TPMxSC register in BDM mode clears the write coherency mechanism of TPMxMODH:L registers. Instead, in the TPM v2 this coherency mechanism is not cleared when there is a write to TPMxSC register.

Chapter 14
Development Support

14.1   Introduction

Development support systems in the HCS08 include the background debug controller (BDC) and the on-chip debug module (DBG). The BDC provides a single-wire debug interface to the target MCU that provides a convenient interface for programming the on-chip flash and other nonvolatile memories. The BDC is also the primary debug interface for development and allows non-intrusive access to memory data and traditional debug features such as CPU register modify, breakpoints, and single instruction trace commands.

In the HCS08 family, address and data bus signals are not available on external pins (not even in test modes). Debug is done through commands fed into the target MCU via the single-wire background debug interface. The debug module provides a means to selectively trigger and capture bus information so an external development system can reconstruct what happened inside the MCU on a cycle-by-cycle basis without having external access to the address and data signals.

14.1.1   Forcing Active Background

- The method for forcing active background mode depends on the specific HCS08 derivative. For the 9S08xxxx, you can force active background after a power-on reset by holding the BKGD pin low as the device exits the reset condition. You can also force active background by driving BKGD low immediately after a serial background command that writes a one to the BDFR bit in the SBDFR register. Other causes of reset including an external pin reset or an internally generated error reset ignore the state of the BKGD pin and reset into normal user mode. If no debug pod is connected to the BKGD pin, the MCU will always reset into normal operating mode.

14.1.2 Features

Features of the BDC module include:

- Single pin for mode selection and background communications
- BDC registers are not located in the memory map
- SYNC command to determine target communications rate
- Non-intrusive commands for memory access
- Active background mode commands for CPU register access
- GO and TRACE1 commands
- BACKGROUND command can wake CPU from stop or wait modes
- One hardware address breakpoint built into BDC
- Oscillator runs in stop mode, if BDC enabled
- COP watchdog disabled while in active background mode

Features of the ICE system include:

- Two trigger comparators: Two address + read/write (R/W) or one full address + data + R/W
- Flexible 8-word by 16-bit FIFO (first-in, first-out) buffer for capture information:
  — Change-of-flow addresses or
  — Event-only data
- Two types of breakpoints:
  — Tag breakpoints for instruction opcodes
  — Force breakpoints for any address access
- Nine trigger modes:
  — Basic: A-only, A OR B
  — Sequence: A then B
  — Full: A AND B data, A AND NOT B data
  — Event (store data): Event-only B, A then event-only B
  — Range: Inside range (A $\leq$ address $\leq$ B), outside range (address $<$ A or address $>$ B)

14.2 Background Debug Controller (BDC)

All MCUs in the HCS08 Family contain a single-wire background debug interface that supports in-circuit programming of on-chip nonvolatile memory and sophisticated non-intrusive debug capabilities. Unlike debug interfaces on earlier 8-bit MCUs, this system does not interfere with normal application resources. It does not use any user memory or locations in the memory map and does not share any on-chip peripherals.

BDC commands are divided into two groups:

- Active background mode commands require that the target MCU is in active background mode (the user program is not running). Active background mode commands allow the CPU registers to be

read or written, and allow the user to trace one user instruction at a time, or GO to the user program from active background mode.

- Non-intrusive commands can be executed at any time even while the user's program is running. Non-intrusive commands allow a user to read or write MCU memory locations or access status and control registers within the background debug controller.

Typically, a relatively simple interface pod is used to translate commands from a host computer into commands for the custom serial interface to the single-wire background debug system. Depending on the development tool vendor, this interface pod may use a standard RS-232 serial port, a parallel printer port, or some other type of communications such as a universal serial bus (USB) to communicate between the host PC and the pod. The pod typically connects to the target system with ground, the BKGD pin, $\overline{RESET}$, and sometimes V_{DD}. An open-drain connection to reset allows the host to force a target system reset, which is useful to regain control of a lost target system or to control startup of a target system before the on-chip nonvolatile memory has been programmed. Sometimes V_{DD} can be used to allow the pod to use power from the target system to avoid the need for a separate power supply. However, if the pod is powered separately, it can be connected to a running target system without forcing a target system reset or otherwise disturbing the running application program.

```
BKGD        1  ■  ●  2  GND
NO CONNECT  3  ●  ●  4  RESET
NO CONNECT  5  ●  ●  6  VDD
```
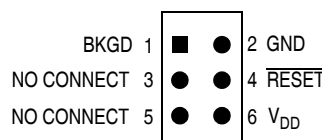
Figure 14-1. BDM Tool Connector

14.2.1 BKGD Pin Description

BKGD is the single-wire background debug interface pin. The primary function of this pin is for bidirectional serial communication of active background mode commands and data. During reset, this pin is used to select between starting in active background mode or starting the user's application program. This pin is also used to request a timed sync response pulse to allow a host development tool to determine the correct clock frequency for background debug serial communications.

BDC serial communications use a custom serial protocol first introduced on the M68HC12 Family of microcontrollers. This protocol assumes the host knows the communication clock rate that is determined by the target BDC clock rate. All communication is initiated and controlled by the host that drives a high-to-low edge to signal the beginning of each bit time. Commands and data are sent most significant bit first (MSB first). For a detailed description of the communications protocol, refer to Section 14.2.2, "Communication Details."

If a host is attempting to communicate with a target MCU that has an unknown BDC clock rate, a SYNC command may be sent to the target MCU to request a timed sync response signal from which the host can determine the correct communication speed.

BKGD is a pseudo-open-drain pin and there is an on-chip pullup so no external pullup resistor is required. Unlike typical open-drain pins, the external RC time constant on this pin, which is influenced by external capacitance, plays almost no role in signal rise time. The custom protocol provides for brief, actively

driven speedup pulses to force rapid rise times on this pin without risking harmful drive level conflicts. Refer to Section 14.2.2, "Communication Details," for more detail.

When no debugger pod is connected to the 6-pin BDM interface connector, the internal pullup on BKGD chooses normal operating mode. When a debug pod is connected to BKGD it is possible to force the MCU into active background mode after reset. The specific conditions for forcing active background depend upon the HCS08 derivative (refer to the introduction to this Development Support section). It is not necessary to reset the target MCU to communicate with it through the background debug interface.

14.2.2 Communication Details

The BDC serial interface requires the external controller to generate a falling edge on the BKGD pin to indicate the start of each bit time. The external controller provides this falling edge whether data is transmitted or received.

BKGD is a pseudo-open-drain pin that can be driven either by an external controller or by the MCU. Data is transferred MSB first at 16 BDC clock cycles per bit (nominal speed). The interface times out if 512 BDC clock cycles occur between falling edges from the host. Any BDC command that was in progress when this timeout occurs is aborted without affecting the memory or operating mode of the target MCU system.

The custom serial protocol requires the debug pod to know the target BDC communication clock speed.

The clock switch (CLKSW) control bit in the BDC status and control register allows the user to select the BDC clock source. The BDC clock source can either be the bus or the alternate BDC clock source.

The BKGD pin can receive a high or low level or transmit a high or low level. The following diagrams show timing for each of these cases. Interface timing is synchronous to clocks in the target BDC, but asynchronous to the external host. The internal BDC clock signal is shown for reference in counting cycles.

Figure 14-2 shows an external host transmitting a logic 1 or 0 to the BKGD pin of a target HCS08 MCU. The host is asynchronous to the target so there is a 0-to-1 cycle delay from the host-generated falling edge to where the target perceives the beginning of the bit time. Ten target BDC clock cycles later, the target senses the bit level on the BKGD pin. Typically, the host actively drives the pseudo-open-drain BKGD pin during host-to-target transmissions to speed up rising edges. Because the target does not drive the BKGD pin during the host-to-target transmission period, there is no need to treat the line as an open-drain signal during this period.
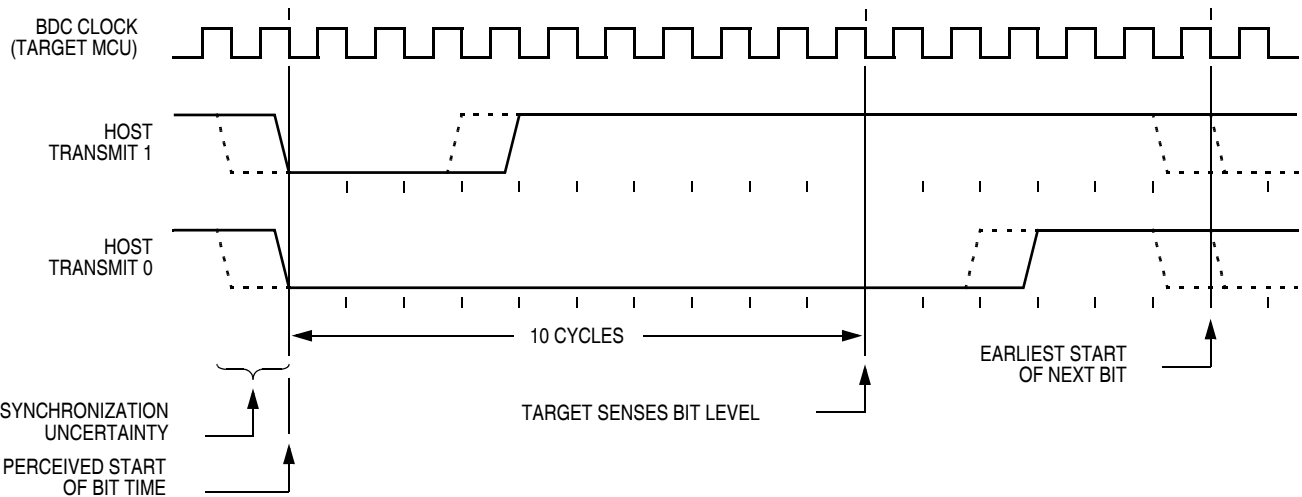
Figure 14-2. BDC Host-to-Target Serial Bit Timing

Figure 14-3 shows the host receiving a logic 1 from the target HCS08 MCU. Because the host is asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on BKGD to the perceived start of the bit time in the target MCU. The host holds the BKGD pin low long enough for the target to recognize it (at least two target BDC cycles). The host must release the low drive before the target MCU drives a brief active-high speedup pulse seven cycles after the perceived start of the bit time. The host should sample the bit level about 10 cycles after it started the bit time.
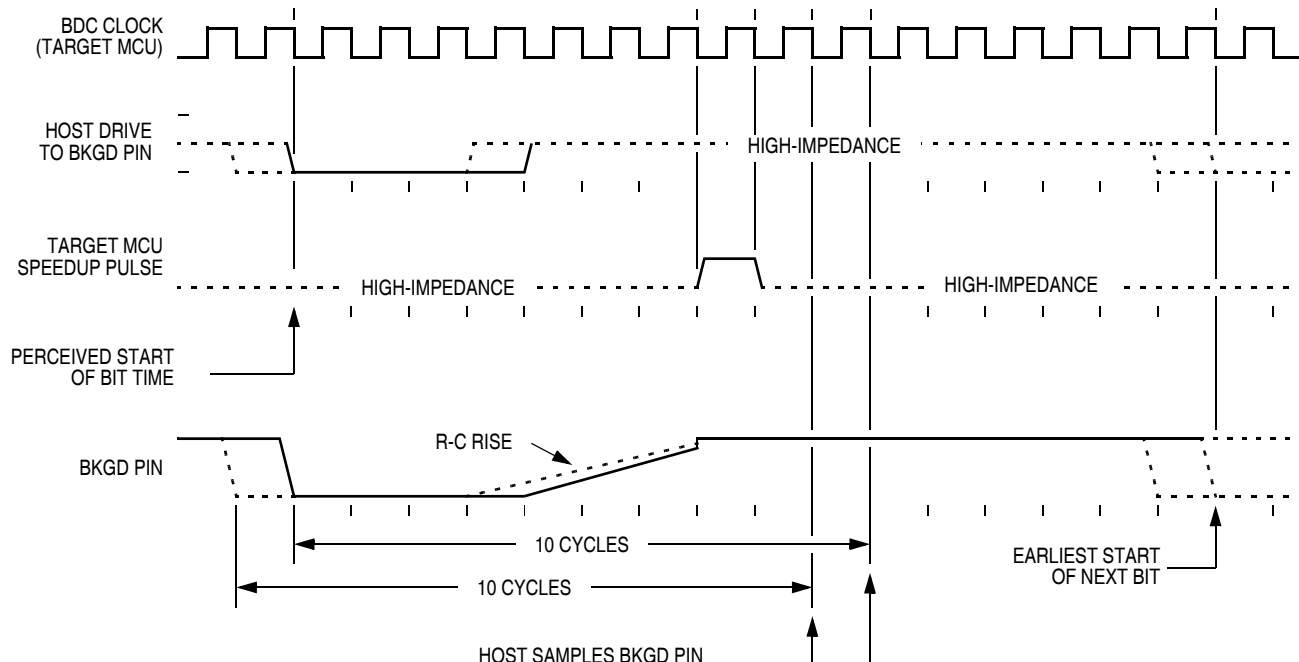
Figure 14-3. BDC Target-to-Host Serial Bit Timing (Logic 1)

Figure 14-4 shows the host receiving a logic 0 from the target HCS08 MCU. Because the host is
asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on
BKGD to the start of the bit time as perceived by the target MCU. The host initiates the bit time but the
target HCS08 finishes it. Because the target wants the host to receive a logic 0, it drives the BKGD pin low
for 13 BDC clock cycles, then briefly drives it high to speed up the rising edge. The host samples the bit
level about 10 cycles after starting the bit time.
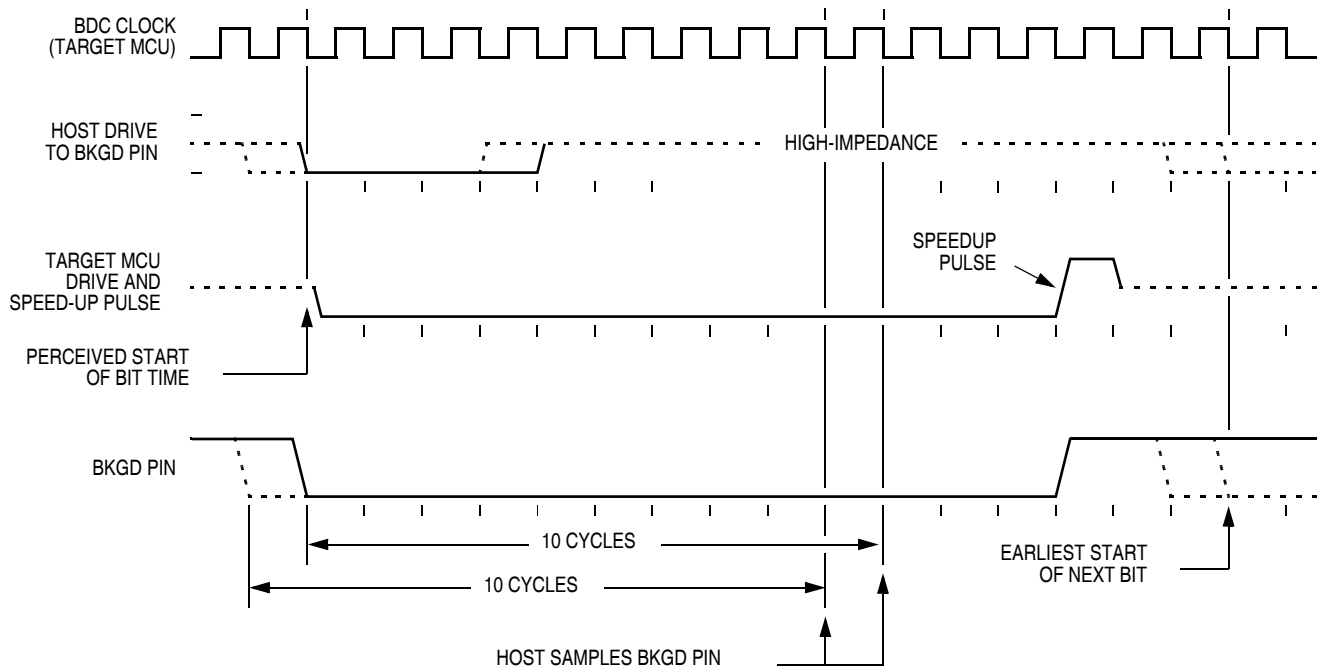
Figure 14-4. BDM Target-to-Host Serial Bit Timing (Logic 0)

14.2.3   BDC Commands

BDC commands are sent serially from a host computer to the BKGD pin of the target HCS08 MCU. All commands and data are sent MSB-first using a custom BDC communications protocol. Active background mode commands require that the target MCU is currently in the active background mode while non-intrusive commands may be issued at any time whether the target MCU is in active background mode or running a user application program.

Table 14-1 shows all HCS08 BDC commands, a shorthand description of their coding structure, and the meaning of each command.

Coding Structure Nomenclature

This nomenclature is used in Table 14-1 to describe the coding structure of the BDC commands.

Commands begin with an 8-bit hexadecimal command code in the host-to-target direction (most significant bit first)

/	=	separates parts of the command
d	=	delay 16 target BDC clock cycles
AAAA	=	a 16-bit address in the host-to-target direction
RD	=	8 bits of read data in the target-to-host direction
WD	=	8 bits of write data in the host-to-target direction
RD16	=	16 bits of read data in the target-to-host direction
WD16	=	16 bits of write data in the host-to-target direction
SS	=	the contents of BDCSCR in the target-to-host direction (STATUS)
CC	=	8 bits of write data for BDCSCR in the host-to-target direction (CONTROL)
RBKP	=	16 bits of read data in the target-to-host direction (from BDCBKPT breakpoint register)
WBKP	=	16 bits of write data in the host-to-target direction (for BDCBKPT breakpoint register)

Table 14-1. BDC Command Summary

Command Mnemonic	Active BDM/ Non-intrusive	Coding Structure	Description
SYNC	Non-intrusive	n/a[1]	Request a timed reference pulse to determine target BDC communication speed
ACK_ENABLE	Non-intrusive	D5/d	Enable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
ACK_DISABLE	Non-intrusive	D6/d	Disable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
BACKGROUND	Non-intrusive	90/d	Enter active background mode if enabled (ignore if ENBDM bit equals 0)
READ_STATUS	Non-intrusive	E4/SS	Read BDC status from BDCSCR
WRITE_CONTROL	Non-intrusive	C4/CC	Write BDC controls in BDCSCR
READ_BYTE	Non-intrusive	E0/AAAA/d/RD	Read a byte from target memory
READ_BYTE_WS	Non-intrusive	E1/AAAA/d/SS/RD	Read a byte and report status
READ_LAST	Non-intrusive	E8/SS/RD	Re-read byte from address just read and report status
WRITE_BYTE	Non-intrusive	C0/AAAA/WD/d	Write a byte to target memory
WRITE_BYTE_WS	Non-intrusive	C1/AAAA/WD/d/SS	Write a byte and report status
READ_BKPT	Non-intrusive	E2/RBKP	Read BDCBKPT breakpoint register
WRITE_BKPT	Non-intrusive	C2/WBKP	Write BDCBKPT breakpoint register
GO	Active BDM	08/d	Go to execute the user application program starting at the address currently in the PC
TRACE1	Active BDM	10/d	Trace 1 user instruction at the address in the PC, then return to active background mode
TAGGO	Active BDM	18/d	Same as GO but enable external tagging (HCS08 devices have no external tagging pin)
READ_A	Active BDM	68/d/RD	Read accumulator (A)
READ_CCR	Active BDM	69/d/RD	Read condition code register (CCR)
READ_PC	Active BDM	6B/d/RD16	Read program counter (PC)
READ_HX	Active BDM	6C/d/RD16	Read H and X register pair (H:X)
READ_SP	Active BDM	6F/d/RD16	Read stack pointer (SP)
READ_NEXT	Active BDM	70/d/RD	Increment H:X by one then read memory byte located at H:X
READ_NEXT_WS	Active BDM	71/d/SS/RD	Increment H:X by one then read memory byte located at H:X. Report status and data.
WRITE_A	Active BDM	48/WD/d	Write accumulator (A)
WRITE_CCR	Active BDM	49/WD/d	Write condition code register (CCR)
WRITE_PC	Active BDM	4B/WD16/d	Write program counter (PC)
WRITE_HX	Active BDM	4C/WD16/d	Write H and X register pair (H:X)
WRITE_SP	Active BDM	4F/WD16/d	Write stack pointer (SP)
WRITE_NEXT	Active BDM	50/WD/d	Increment H:X by one, then write memory byte located at H:X
WRITE_NEXT_WS	Active BDM	51/WD/d/SS	Increment H:X by one, then write memory byte located at H:X. Also report status.

[1] The SYNC command is a special operation that does not have a command code.

The SYNC command is unlike other BDC commands because the host does not necessarily know the correct communications speed to use for BDC communications until after it has analyzed the response to the SYNC command.

To issue a SYNC command, the host:

- Drives the BKGD pin low for at least 128 cycles of the slowest possible BDC clock (The slowest clock is normally the reference oscillator/64 or the self-clocked rate/64.)
- Drives BKGD high for a brief speedup pulse to get a fast rise time (This speedup pulse is typically one cycle of the fastest clock in the system.)
- Removes all drive to the BKGD pin so it reverts to high impedance
- Monitors the BKGD pin for the sync response pulse

The target, upon detecting the SYNC request from the host (which is a much longer low time than would ever occur during normal BDC communications):

- Waits for BKGD to return to a logic high
- Delays 16 cycles to allow the host to stop driving the high speedup pulse
- Drives BKGD low for 128 BDC clock cycles
- Drives a 1-cycle high speedup pulse to force a fast rise time on BKGD
- Removes all drive to the BKGD pin so it reverts to high impedance

The host measures the low time of this 128-cycle sync response pulse and determines the correct speed for subsequent BDC communications. Typically, the host can determine the correct communication speed within a few percent of the actual target speed and the communication protocol can easily tolerate speed errors of several percent.

14.2.4 BDC Hardware Breakpoint

The BDC includes one relatively simple hardware breakpoint that compares the CPU address bus to a 16-bit match value in the BDCBKPT register. This breakpoint can generate a forced breakpoint or a tagged breakpoint. A forced breakpoint causes the CPU to enter active background mode at the first instruction boundary following any access to the breakpoint address. The tagged breakpoint causes the instruction opcode at the breakpoint address to be tagged so that the CPU will enter active background mode rather than executing that instruction if and when it reaches the end of the instruction queue. This implies that tagged breakpoints can only be placed at the address of an instruction opcode while forced breakpoints can be set at any address.

The breakpoint enable (BKPTEN) control bit in the BDC status and control register (BDCSCR) is used to enable the breakpoint logic (BKPTEN = 1). When BKPTEN = 0, its default value after reset, the breakpoint logic is disabled and no BDC breakpoints are requested regardless of the values in other BDC breakpoint registers and control bits. The force/tag select (FTS) control bit in BDCSCR is used to select forced (FTS = 1) or tagged (FTS = 0) type breakpoints.

The on-chip debug module (DBG) includes circuitry for two additional hardware breakpoints that are more flexible than the simple breakpoint in the BDC module.

14.3 On-Chip Debug System (DBG)

Because HCS08 devices do not have external address and data buses, the most important functions of an in-circuit emulator have been built onto the chip with the MCU. The debug system consists of an 8-stage FIFO that can store address or data bus information, and a flexible trigger system to decide when to capture bus information and what information to capture. The system relies on the single-wire background debug system to access debug control registers and to read results out of the eight stage FIFO.

The debug module includes control and status registers that are accessible in the user's memory map. These registers are located in the high register space to avoid using valuable direct page memory space.

Most of the debug module's functions are used during development, and user programs rarely access any of the control and status registers for the debug module. The one exception is that the debug system can provide the means to implement a form of ROM patching. This topic is discussed in greater detail in Section 14.3.6, "Hardware Breakpoints."

14.3.1 Comparators A and B

Two 16-bit comparators (A and B) can optionally be qualified with the R/W signal and an opcode tracking circuit. Separate control bits allow you to ignore R/W for each comparator. The opcode tracking circuitry optionally allows you to specify that a trigger will occur only if the opcode at the specified address is actually executed as opposed to only being read from memory into the instruction queue. The comparators are also capable of magnitude comparisons to support the inside range and outside range trigger modes. Comparators are disabled temporarily during all BDC accesses.

The A comparator is always associated with the 16-bit CPU address. The B comparator compares to the CPU address or the 8-bit CPU data bus, depending on the trigger mode selected. Because the CPU data bus is separated into a read data bus and a write data bus, the RWAEN and RWA control bits have an additional purpose, in full address plus data comparisons they are used to decide which of these buses to use in the comparator B data bus comparisons. If RWAEN = 1 (enabled) and RWA = 0 (write), the CPU's write data bus is used. Otherwise, the CPU's read data bus is used.

The currently selected trigger mode determines what the debugger logic does when a comparator detects a qualified match condition. A match can cause:

- Generation of a breakpoint to the CPU
- Storage of data bus values into the FIFO
- Starting to store change-of-flow addresses into the FIFO (begin type trace)
- Stopping the storage of change-of-flow addresses into the FIFO (end type trace)

14.3.2 Bus Capture Information and FIFO Operation

The usual way to use the FIFO is to setup the trigger mode and other control options, then arm the debugger. When the FIFO has filled or the debugger has stopped storing data into the FIFO, you would read the information out of it in the order it was stored into the FIFO. Status bits indicate the number of words of valid information that are in the FIFO as data is stored into it. If a trace run is manually halted by writing 0 to ARM before the FIFO is full (CNT = 1:0:0:0), the information is shifted by one position and

the host must perform ((8 – CNT) – 1) dummy reads of the FIFO to advance it to the first significant entry in the FIFO.

In most trigger modes, the information stored in the FIFO consists of 16-bit change-of-flow addresses. In these cases, read DBGFH then DBGFL to get one coherent word of information out of the FIFO. Reading DBGFL (the low-order byte of the FIFO data port) causes the FIFO to shift so the next word of information is available at the FIFO data port. In the event-only trigger modes (see Section 14.3.5, "Trigger Modes"), 8-bit data information is stored into the FIFO. In these cases, the high-order half of the FIFO (DBGFH) is not used and data is read out of the FIFO by simply reading DBGFL. Each time DBGFL is read, the FIFO is shifted so the next data value is available through the FIFO data port at DBGFL.

In trigger modes where the FIFO is storing change-of-flow addresses, there is a delay between CPU addresses and the input side of the FIFO. Because of this delay, if the trigger event itself is a change-of-flow address or a change-of-flow address appears during the next two bus cycles after a trigger event starts the FIFO, it will not be saved into the FIFO. In the case of an end-trace, if the trigger event is a change-of-flow, it will be saved as the last change-of-flow entry for that debug run.

The FIFO can also be used to generate a profile of executed instruction addresses when the debugger is not armed. When ARM = 0, reading DBGFL causes the address of the most-recently fetched opcode to be saved in the FIFO. To use the profiling feature, a host debugger would read addresses out of the FIFO by reading DBGFH then DBGFL at regular periodic intervals. The first eight values would be discarded because they correspond to the eight DBGFL reads needed to initially fill the FIFO. Additional periodic reads of DBGFH and DBGFL return delayed information about executed instructions so the host debugger can develop a profile of executed instruction addresses.

14.3.3   Change-of-Flow Information

To minimize the amount of information stored in the FIFO, only information related to instructions that cause a change to the normal sequential execution of instructions is stored. With knowledge of the source and object code program stored in the target system, an external debugger system can reconstruct the path of execution through many instructions from the change-of-flow information stored in the FIFO.

For conditional branch instructions where the branch is taken (branch condition was true), the source address is stored (the address of the conditional branch opcode). Because BRA and BRN instructions are not conditional, these events do not cause change-of-flow information to be stored in the FIFO.

Indirect JMP and JSR instructions use the current contents of the H:X index register pair to determine the destination address, so the debug system stores the run-time destination address for any indirect JMP or JSR. For interrupts, RTI, or RTS, the destination address is stored in the FIFO as change-of-flow information.

14.3.4   Tag vs. Force Breakpoints and Triggers

Tagging is a term that refers to identifying an instruction opcode as it is fetched into the instruction queue, but not taking any other action until and unless that instruction is actually executed by the CPU. This distinction is important because any change-of-flow from a jump, branch, subroutine call, or interrupt causes some instructions that have been fetched into the instruction queue to be thrown away without being executed.

A force-type breakpoint waits for the current instruction to finish and then acts upon the breakpoint request. The usual action in response to a breakpoint is to go to active background mode rather than continuing to the next instruction in the user application program.

The tag vs. force terminology is used in two contexts within the debug module. The first context refers to breakpoint requests from the debug module to the CPU. The second refers to match signals from the comparators to the debugger control logic. When a tag-type break request is sent to the CPU, a signal is entered into the instruction queue along with the opcode so that if/when this opcode ever executes, the CPU will effectively replace the tagged opcode with a BGND opcode so the CPU goes to active background mode rather than executing the tagged instruction. When the TRGSEL control bit in the DBGT register is set to select tag-type operation, the output from comparator A or B is qualified by a block of logic in the debug module that tracks opcodes and only produces a trigger to the debugger if the opcode at the compare address is actually executed. There is separate opcode tracking logic for each comparator so more than one compare event can be tracked through the instruction queue at a time.

14.3.5 Trigger Modes

The trigger mode controls the overall behavior of a debug run. The 4-bit TRG field in the DBGT register selects one of nine trigger modes. When TRGSEL = 1 in the DBGT register, the output of the comparator must propagate through an opcode tracking circuit before triggering FIFO actions. The BEGIN bit in DBGT chooses whether the FIFO begins storing data when the qualified trigger is detected (begin trace), or the FIFO stores data in a circular fashion from the time it is armed until the qualified trigger is detected (end trigger).

A debug run is started by writing a 1 to the ARM bit in the DBGC register, which sets the ARMF flag and clears the AF and BF flags and the CNT bits in DBGS. A begin-trace debug run ends when the FIFO gets full. An end-trace run ends when the selected trigger event occurs. Any debug run can be stopped manually by writing a 0 to ARM or DBGEN in DBGC.

In all trigger modes except event-only modes, the FIFO stores change-of-flow addresses. In event-only trigger modes, the FIFO stores data in the low-order eight bits of the FIFO.

The BEGIN control bit is ignored in event-only trigger modes and all such debug runs are begin type traces. When TRGSEL = 1 to select opcode fetch triggers, it is not necessary to use R/W in comparisons because opcode tags would only apply to opcode fetches that are always read cycles. It would also be unusual to specify TRGSEL = 1 while using a full mode trigger because the opcode value is normally known at a particular address.

The following trigger mode descriptions only state the primary comparator conditions that lead to a trigger. Either comparator can usually be further qualified with R/W by setting RWAEN (RWBEN) and the corresponding RWA (RWB) value to be matched against R/W. The signal from the comparator with optional R/W qualification is used to request a CPU breakpoint if BRKEN = 1 and TAG determines whether the CPU request will be a tag request or a force request.

A-Only — Trigger when the address matches the value in comparator A

A OR B — Trigger when the address matches either the value in comparator A or the value in comparator B

A Then B — Trigger when the address matches the value in comparator B but only after the address for another cycle matched the value in comparator A. There can be any number of cycles after the A match and before the B match.

A AND B Data (Full Mode) — This is called a full mode because address, data, and R/W (optionally) must match within the same bus cycle to cause a trigger event. Comparator A checks address, the low byte of comparator B checks data, and R/W is checked against RWA if RWAEN = 1. The high-order half of comparator B is not used.

In full trigger modes it is not useful to specify a tag-type CPU breakpoint (BRKEN = TAG = 1), but if you do, the comparator B data match is ignored for the purpose of issuing the tag request to the CPU and the CPU breakpoint is issued when the comparator A address matches.

A AND NOT B Data (Full Mode) — Address must match comparator A, data must not match the low half of comparator B, and R/W must match RWA if RWAEN = 1. All three conditions must be met within the same bus cycle to cause a trigger.

In full trigger modes it is not useful to specify a tag-type CPU breakpoint (BRKEN = TAG = 1), but if you do, the comparator B data match is ignored for the purpose of issuing the tag request to the CPU and the CPU breakpoint is issued when the comparator A address matches.

Event-Only B (Store Data) — Trigger events occur each time the address matches the value in comparator B. Trigger events cause the data to be captured into the FIFO. The debug run ends when the FIFO becomes full.

A Then Event-Only B (Store Data) — After the address has matched the value in comparator A, a trigger event occurs each time the address matches the value in comparator B. Trigger events cause the data to be captured into the FIFO. The debug run ends when the FIFO becomes full.

Inside Range (A $\leq$ Address $\leq$ B) — A trigger occurs when the address is greater than or equal to the value in comparator A and less than or equal to the value in comparator B at the same time.

Outside Range (Address < A or Address > B) — A trigger occurs when the address is either less than the value in comparator A or greater than the value in comparator B.

14.3.6   Hardware Breakpoints

The BRKEN control bit in the DBGC register may be set to 1 to allow any of the trigger conditions described in Section 14.3.5, "Trigger Modes," to be used to generate a hardware breakpoint request to the CPU. TAG in DBGC controls whether the breakpoint request will be treated as a tag-type breakpoint or a force-type breakpoint. A tag breakpoint causes the current opcode to be marked as it enters the instruction queue. If a tagged opcode reaches the end of the pipe, the CPU executes a BGND instruction to go to active background mode rather than executing the tagged opcode. A force-type breakpoint causes the CPU to finish the current instruction and then go to active background mode.

If the background mode has not been enabled (ENBDM = 1) by a serial WRITE_CONTROL command through the BKGD pin, the CPU will execute an SWI instruction instead of going to active background mode.

14.4   Register Definition

This section contains the descriptions of the BDC and DBG registers and control bits.

Refer to the high-page register summary in the device overview chapter of this reference manual for the absolute address assignments for all DBG registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.

14.4.1   BDC Registers and Control Bits

The BDC has two registers:

- The BDC status and control register (BDCSCR) is an 8-bit register containing control and status bits for the background debug controller.
- The BDC breakpoint match register (BDCBKPT) holds a 16-bit breakpoint match address.

These registers are accessed with dedicated serial BDC commands and are not located in the memory space of the target MCU (so they do not have addresses and cannot be accessed by user programs).

Some of the bits in the BDCSCR have write limitations; otherwise, these registers may be read or written at any time. For example, the ENBDM control bit may not be written while the MCU is in active background mode. (This prevents the ambiguous condition of the control bit forbidding active background mode while the MCU is already in active background mode.) Also, the four status bits (BDMACT, WS, WSF, and DVF) are read-only status indicators and can never be written by the WRITE_CONTROL serial BDC command. The clock switch (CLKSW) control bit may be read or written at any time.

14.4.1.1 BDC Status and Control Register (BDCSCR)

This register can be read or written by serial BDC commands (READ_STATUS and WRITE_CONTROL) but is not accessible to user programs because it is not located in the normal memory map of the MCU.

	7	6	5	4	3	2	1	0
R	ENBDM	BDMACT	BKPTEN	FTS	CLKSW	WS	WSF	DVF
W	ENBDM		BKPTEN	FTS	CLKSW			
Normal Reset	0	0	0	0	0	0	0	0
Reset in Active BDM:	1	1	0	0	1	0	0	0

☐ = Unimplemented or Reserved
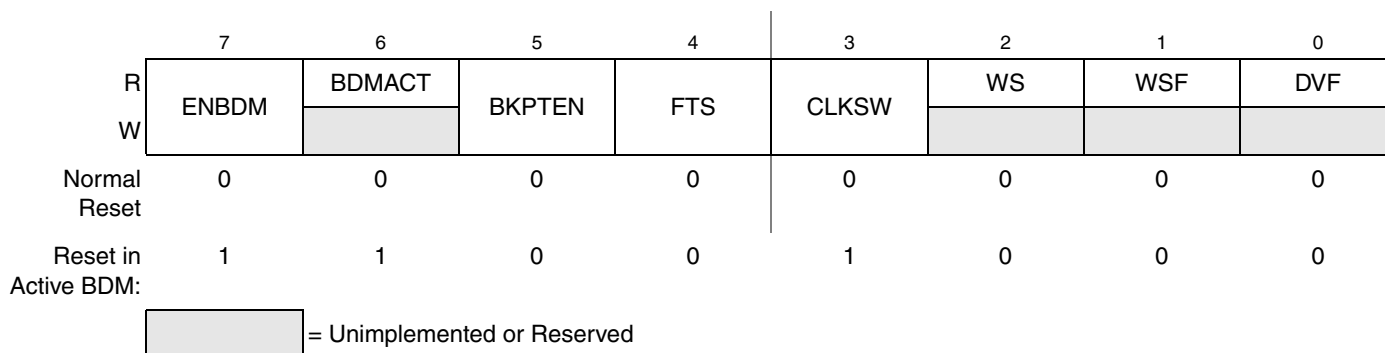
Figure 14-5. BDC Status and Control Register (BDCSCR)

Table 14-2. BDCSCR Register Field Descriptions

Field	Description
7 ENBDM	**Enable BDM (Permit Active Background Mode)** — Typically, this bit is written to 1 by the debug host shortly after the beginning of a debug session or whenever the debug host resets the target and remains 1 until a normal reset clears it. 0 BDM cannot be made active (non-intrusive commands still allowed) 1 BDM can be made active to allow active background mode commands
6 BDMACT	**Background Mode Active Status** — This is a read-only status bit. 0 BDM not active (user application program running) 1 BDM active and waiting for serial commands
5 BKPTEN	**BDC Breakpoint Enable** — If this bit is clear, the BDC breakpoint is disabled and the FTS (force tag select) control bit and BDCBKPT match register are ignored. 0 BDC breakpoint disabled 1 BDC breakpoint enabled
4 FTS	**Force/Tag Select** — When FTS = 1, a breakpoint is requested whenever the CPU address bus matches the BDCBKPT match register. When FTS = 0, a match between the CPU address bus and the BDCBKPT register causes the fetched opcode to be tagged. If this tagged opcode ever reaches the end of the instruction queue, the CPU enters active background mode rather than executing the tagged opcode. 0 Tag opcode at breakpoint address and enter active background mode if CPU attempts to execute that instruction 1 Breakpoint match forces active background mode at next instruction boundary (address need not be an opcode)
3 CLKSW	**Select Source for BDC Communications Clock** — CLKSW defaults to 0, which selects the alternate BDC clock source. 0 Alternate BDC clock source 1 MCU bus clock

Table 14-2. BDCSCR Register Field Descriptions (continued)

Field	Description
2 WS	**Wait or Stop Status** — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands. 0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active) 1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode
1 WSF	**Wait or Stop Failure Status** — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.) 0 Memory access did not conflict with a wait or stop instruction 1 Memory access command failed because the CPU entered wait or stop mode
0 DVF	**Data Valid Failure Status** — This status bit is not used in the MC9S08SE8 Series because it does not have any slow access memory. 0 Memory access did not conflict with a slow memory access 1 Memory access command failed because CPU was not finished with a slow memory access

14.4.1.2   BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ_BKPT and WRITE_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to Section 14.2.4, "BDC Hardware Breakpoint."

14.4.2   System Background Debug Force Reset Register (SBDFR)

This register contains a single write-only control bit. A serial background mode command such as WRITE_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								BDFR[1]
Reset	0	0	0	0	0	0	0	0

☐ = Unimplemented or Reserved
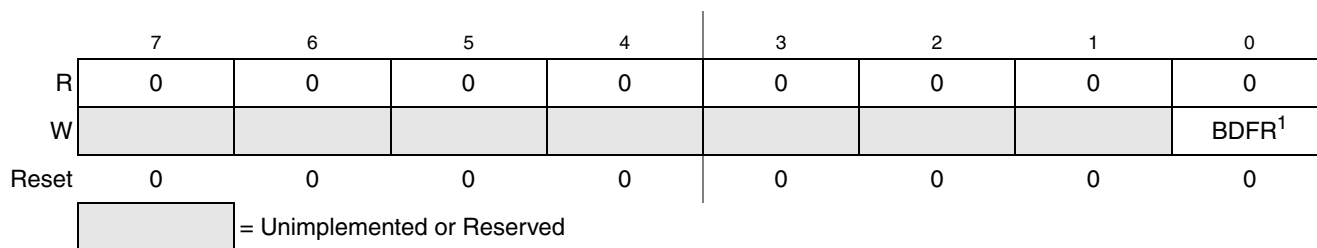
[1] BDFR is writable only through serial background mode debug commands, not from user programs.

Figure 14-6. System Background Debug Force Reset Register (SBDFR)

Table 14-3. SBDFR Register Field Description

Field	Description
0 BDFR	**Background Debug Force Reset** — A serial active background mode command such as WRITE_BYTE allows an external debug host to force a target system reset. Writing 1 to this bit forces an MCU reset. This bit cannot be written from a user program.

14.4.3   DBG Registers and Control Bits

The debug module includes nine bytes of register space for three 16-bit registers and three 8-bit control and status registers. These registers are located in the high register space of the normal memory map so they are accessible to normal application programs. These registers are rarely if ever accessed by normal user application programs with the possible exception of a ROM patching mechanism that uses the breakpoint logic.

14.4.3.1   Debug Comparator A High Register (DBGCAH)

This register contains compare value bits for the high-order eight bits of comparator A. This register is forced to 0x00 at reset and can be read at any time or written at any time unless ARM = 1.

14.4.3.2   Debug Comparator A Low Register (DBGCAL)

This register contains compare value bits for the low-order eight bits of comparator A. This register is forced to 0x00 at reset and can be read at any time or written at any time unless ARM = 1.

14.4.3.3   Debug Comparator B High Register (DBGCBH)

This register contains compare value bits for the high-order eight bits of comparator B. This register is forced to 0x00 at reset and can be read at any time or written at any time unless ARM = 1.

14.4.3.4   Debug Comparator B Low Register (DBGCBL)

This register contains compare value bits for the low-order eight bits of comparator B. This register is forced to 0x00 at reset and can be read at any time or written at any time unless ARM = 1.

14.4.3.5   Debug FIFO High Register (DBGFH)

This register provides read-only access to the high-order eight bits of the FIFO. Writes to this register have no meaning or effect. In the event-only trigger modes, the FIFO only stores data into the low-order byte of each FIFO word, so this register is not used and will read 0x00.

Reading DBGFH does not cause the FIFO to shift to the next word. When reading 16-bit words out of the FIFO, read DBGFH before reading DBGFL because reading DBGFL causes the FIFO to advance to the next word of information.

14.4.3.6   Debug FIFO Low Register (DBGFL)

This register provides read-only access to the low-order eight bits of the FIFO. Writes to this register have no meaning or effect.

Reading DBGFL causes the FIFO to shift to the next available word of information. When the debug module is operating in event-only modes, only 8-bit data is stored into the FIFO (high-order half of each FIFO word is unused). When reading 8-bit words out of the FIFO, simply read DBGFL repeatedly to get successive bytes of data from the FIFO. It isn't necessary to read DBGFH in this case.

Do not attempt to read data from the FIFO while it is still armed (after arming but before the FIFO is filled or ARMF is cleared) because the FIFO is prevented from advancing during reads of DBGFL. This can interfere with normal sequencing of reads from the FIFO.

Reading DBGFL while the debugger is not armed causes the address of the most-recently fetched opcode to be stored to the last location in the FIFO. By reading DBGFH then DBGFL periodically, external host software can develop a profile of program execution. After eight reads from the FIFO, the ninth read will return the information that was stored as a result of the first read. To use the profiling feature, read the FIFO eight times without using the data to prime the sequence and then begin using the data to get a delayed picture of what addresses were being executed. The information stored into the FIFO on reads of DBGFL (while the FIFO is not armed) is the address of the most-recently fetched opcode.

14.4.3.7 Debug Control Register (DBGC)

This register can be read or written at any time.

	7	6	5	4	3	2	1	0
R	DBGEN	ARM	TAG	BRKEN	RWA	RWAEN	RWB	RWBEN
W								
Reset	0	0	0	0	0	0	0	0
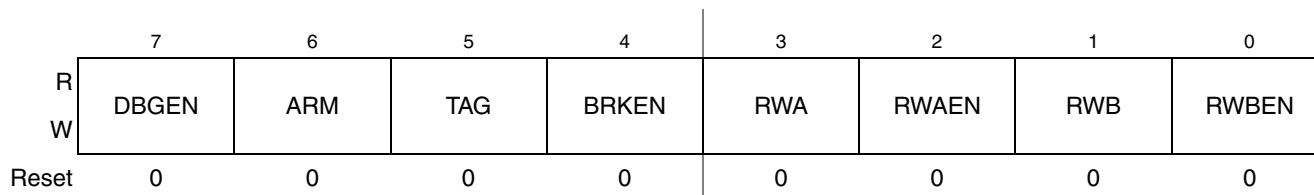
Figure 14-7. Debug Control Register (DBGC)

Table 14-4. DBGC Register Field Descriptions

Field	Description
7 DBGEN	**Debug Module Enable** — Used to enable the debug module. DBGEN cannot be set to 1 if the MCU is secure. 0 DBG disabled 1 DBG enabled
6 ARM	**Arm Control** — Controls whether the debugger is comparing and storing information in the FIFO. A write is used to set this bit (and ARMF) and completion of a debug run automatically clears it. Any debug run can be manually stopped by writing 0 to ARM or to DBGEN. 0 Debugger not armed 1 Debugger armed
5 TAG	**Tag/Force Select** — Controls whether break requests to the CPU will be tag or force type requests. If BRKEN = 0, this bit has no meaning or effect. 0 CPU breaks requested as force type requests 1 CPU breaks requested as tag type requests
4 BRKEN	**Break Enable** — Controls whether a trigger event will generate a break request to the CPU. Trigger events can cause information to be stored in the FIFO without generating a break request to the CPU. For an end trace, CPU break requests are issued to the CPU when the comparator(s) and R/W meet the trigger requirements. For a begin trace, CPU break requests are issued when the FIFO becomes full. TRGSEL does not affect the timing of CPU break requests. 0 CPU break requests not enabled 1 Triggers cause a break request to the CPU
3 RWA	**R/W Comparison Value for Comparator A** — When RWAEN = 1, this bit determines whether a read or a write access qualifies comparator A. When RWAEN = 0, RWA and the R/W signal do not affect comparator A. 0 Comparator A can only match on a write cycle 1 Comparator A can only match on a read cycle
2 RWAEN	**Enable R/W for Comparator A** — Controls whether the level of R/W is considered for a comparator A match. 0 R/W is not used in comparison A 1 R/W is used in comparison A
1 RWB	**R/W Comparison Value for Comparator B** — When RWBEN = 1, this bit determines whether a read or a write access qualifies comparator B. When RWBEN = 0, RWB and the R/W signal do not affect comparator B. 0 Comparator B can match only on a write cycle 1 Comparator B can match only on a read cycle
0 RWBEN	**Enable R/W for Comparator B** — Controls whether the level of R/W is considered for a comparator B match. 0 R/W is not used in comparison B 1 R/W is used in comparison B

14.4.3.8 Debug Trigger Register (DBGT)

This register can be read any time, but may be written only if ARM = 0, except bits 4 and 5 are hard-wired to 0s.
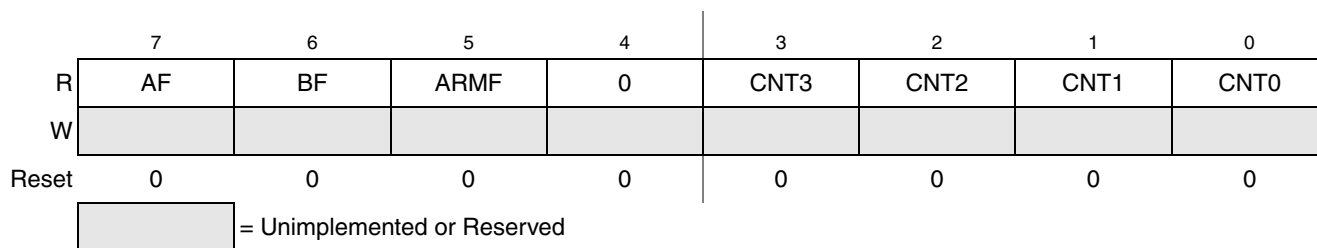
	7	6	5	4	3	2	1	0
R	TRGSEL	BEGIN	0	0	TRG3	TRG2	TRG1	TRG0
W								
Reset	0	0	0	0	0	0	0	0

☐ = Unimplemented or Reserved
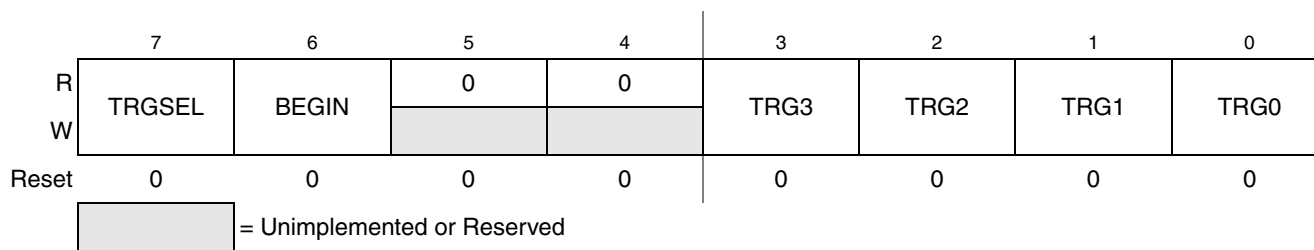
Figure 14-8. Debug Trigger Register (DBGT)

Table 14-5. DBGT Register Field Descriptions

Field	Description
7 TRGSEL	**Trigger Type** — Controls whether the match outputs from comparators A and B are qualified with the opcode tracking logic in the debug module. If TRGSEL is set, a match signal from comparator A or B must propagate through the opcode tracking logic and a trigger event is only signalled to the FIFO logic if the opcode at the match address is actually executed. 0 Trigger on access to compare address (force) 1 Trigger if opcode at compare address is executed (tag)
6 BEGIN	**Begin/End Trigger Select** — Controls whether the FIFO starts filling at a trigger or fills in a circular manner until a trigger ends the capture of information. In event-only trigger modes, this bit is ignored and all debug runs are assumed to be begin traces. 0 Data stored in FIFO until trigger (end trace) 1 Trigger initiates data storage (begin trace)
3:0 TRG[3:0]	**Select Trigger Mode** — Selects one of nine triggering modes, as described below. 0000 A-only 0001 A OR B 0010 A Then B 0011 Event-only B (store data) 0100 A then event-only B (store data) 0101 A AND B data (full mode) 0110 A AND NOT B data (full mode) 0111 Inside range: A ≤ address ≤ B 1000 Outside range: address < A or address > B 1001 – 1111 (No trigger)

14.4.3.9 Debug Status Register (DBGS)

This is a read-only status register.

	7	6	5	4	3	2	1	0
R	AF	BF	ARMF	0	CNT3	CNT2	CNT1	CNT0
W								
Reset	0	0	0	0	0	0	0	0

☐ = Unimplemented or Reserved

Figure 14-9. Debug Status Register (DBGS)

Table 14-6. DBGS Register Field Descriptions

Field	Description
7 AF	**Trigger Match A Flag** — AF is cleared at the start of a debug run and indicates whether a trigger match A condition was met since arming. 0 Comparator A has not matched 1 Comparator A match
6 BF	**Trigger Match B Flag** — BF is cleared at the start of a debug run and indicates whether a trigger match B condition was met since arming. 0 Comparator B has not matched 1 Comparator B match
5 ARMF	**Arm Flag** — While DBGEN = 1, this status bit is a read-only image of ARM in DBGC. This bit is set by writing 1 to the ARM control bit in DBGC (while DBGEN = 1) and is automatically cleared at the end of a debug run. A debug run is completed when the FIFO is full (begin trace) or when a trigger event is detected (end trace). A debug run can also be ended manually by writing 0 to ARM or DBGEN in DBGC. 0 Debugger not armed 1 Debugger armed
3:0 CNT[3:0]	**FIFO Valid Count** — These bits are cleared at the start of a debug run and indicate the number of words of valid data in the FIFO at the end of a debug run. The value in CNT does not decrement as data is read out of the FIFO. The external debug host is responsible for keeping track of the count as information is read out of the FIFO. 0000 Number of valid words in FIFO = No valid data 0001 Number of valid words in FIFO = 1 0010 Number of valid words in FIFO = 2 0011 Number of valid words in FIFO = 3 0100 Number of valid words in FIFO = 4 0101 Number of valid words in FIFO = 5 0110 Number of valid words in FIFO = 6 0111 Number of valid words in FIFO = 7 1000 Number of valid words in FIFO = 8

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